

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Confirmation No. 1464

Natsuki MAKINO et al.

Atty Docket No. 2004-0738

Serial No. 10/724,044

Group Art Unit 1753

Filed December 1, 2003

Mail Stop: PETITION

ELECTROLYTIC PROCESSING APPARATUS AND METHOD

PATENT OFFICE FEE TRANSMITTAL FORM

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

Attached hereto is a check in the amount of \$130.00 to cover Patent Office fees relating to filing the following attached papers:

A duplicate copy of this paper is being submitted for use in the Accounting Division, Office of Finance.

The Commissioner is authorized to charge any deficiency or to credit any overpayment associated with this communication to Deposit Account No. 23-0975, with the EXCEPTION of deficiencies in fees for multiple dependent claims in new applications.

Respectfully submitted,

THE COMMISSIONER IS AUTHORIZED TO CHARGE ANY DEFICIENCY IN THE FEES FOR THIS PAPER TO DEPOSIT **ACCOUNT NO. 23-0975**

Natsuki MAKINO et al.

Nils E. Pedersen

Registration No. 33,145 Attorney for Applicants

NEP/krg

WENDEROTH, LIND & PONACK, L.L.P.

2033 K St., N.W., Suite 800 Washington, D.C. 20006-1021

Telephone (202) 721-8200

November 19, 2004

[Check No. _65244

HOV 1.9 2004 EAST THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 1464

Natsuki MAKINO et al. : Docket No. 2003 1739A

Serial No. 10/724,044 : Group Art Unit 1753

Filed December 1, 2003 : Mail Stop: PETITION

ELECTROLYTIC PROCESSING APPARATUS AND METHOD

PETITION FOR RETROACTIVE LICENSE UNDER 35 U.S.C. 184

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Sir:

Applicants in the above-referenced U.S. patent hereby petition for a retroactive foreign filing license under 35 U.S.C. 184 and in accordance with 37 C.F.R. § 5.25 and 5.14(a).

The corresponding United States application, currently on file, for which this petition for license is sought is identified above by its application number, filing date, inventors and title. In accordance with 37 C.F.R. § 5.14, no copy of this material is, accordingly, attached. Applicants understand that the licensed subject matter will be measured by the disclosure of the above-referenced U.S. patent application.

The list of foreign countries in which the unlicensed patent application material was filed is as follows:

Japan

The material was filed in Japan on December 2, 2002 and on November 28, 2003.

Japanese patent application No. 2003-350529, the first filed application, was revised and refiled as application 2003-399443, the later filed application. The above-referenced U.S. patent application claims priority on both of these applications.

11/22/2004 LWONDIM1 00000089 10724044

130.00 OP

THE COMMISSIONER IS AUTHORIZED TO CHARGE ANY DEFICIENCY IN THE FEES FOR THIS PAPER TO DEPOSIT ACCOUNT NO. 23-0975

Verified statements by Mr. Kenichi Sasabe and Mr. Yukio Fukanaga including the required parts identified in 37 C.F.R. § 5.25(3) are attached. Also attached are support documents referenced in their statements.

It is noted that many of the support documents are submitted to establish the simple fact of a communication or meeting, e.g., and not for the specific contents thereof. The contents have been redacted in many instances to protect confidential, proprietary, and trade secret information and to maintain privilege based on attorney-client communications and/or attorney work product. While some of the support documents are submitted to establish the fact of an attorney-client communication or attorney work product, the contents thereof have been redacted and no waiver of privilege is made or intended.

It is respectfully submitted that these statements make it clear that the subject matter in the present application was not under a secrecy order at the time it was filed in Japan, that it is not currently under a secrecy order, that the license has been diligently sought after discovery of the proscribed foreign filing and that the foreign filing without the required license under § 5.11 was through error and without deceptive intent.

Further, the fee set forth in § 1.17(h) is attached.

Accordingly, it is respectfully submitted that this petition is complete and proper, and the grant of the petition is requested.

Respectfully submitted,

Natsuki MAKINO et al.

Nils E. Pedersen

Registration No. 33,145 Attorney for Applicants

NEP/krg Washington, D.C. 20006-1021 Telephone (202) 721-8200 Facsimile (202) 721-8250 November 19, 2004



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of : Confirmation No. 1464

Natsuki MAKINO et al. : Docket No. 2003-1739A

Serial No. 10/724,044 : Group Art Unit 1753

Filed December 1, 2003

ELECTROLYTIC PROCESSING APPARATUS AND METHOD

VERIFIED STATEMENT UNDER 37 C.F.R. 5.25(a)(3) IN SUPPORT OF PETITION FOR RETROACTIVE FOREIGN FILING LICENSE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

This statement is being made by Yukio Fukunaga of Ebara Corporation, the Assignee of U.S. Patent Application 10/724,044 referenced above. I was assigned as a team leader in Ebara of a Joint development project, which will be discussed below, in August 2002. I have personal knowledge of the acts regarding the filing of Japanese patent applications 2002-350529 and 2003-399443, which acts are discussed below. I am also attaching copies of a number of supporting documents, labeled and referenced herein as documents A-L.

Ebara Corporation began to study the feasability of a joint development program for the development of technology for plating and planarizing of copper interconnects on semiconductor substrates. This began in July 2002. Mutual presentations between Ebara and a US company as a potential joint development partner were made. Ebara made a presentation in July 2002 in US regarding their plating tool, which had been in development in Japan since 1998. Ebara made a demonstration using test wafers supplied by the US company in Japan and presented the test results to the US company and the US company made a presentation and an explanation of a very

limited disclosure of technological concepts that they intended to develop as part of the proposed joint development program. This disclosure took place in the United States in August of 2002, however, the joint development program agreement was not reached until August of 2003.

The inventors of the above-referenced U.S. patent application, Mr. Natsuki Makino and Mr. Junji Kunisawa, had been working in Japan on the electrolytic processing apparatus and method which is the subject matter of the Japanese patent applications.

In the fall of 2002 I instructed the inventors to prepare a draft of their disclosure and to send it to Ebara Intellectual Property Department with a request for the preparation of a patent application for filing in Japan directed to their invention. However, part of what became the first-filed Japanese patent application included material which arose out of presentations in the United States. At that time, I did not realize that the application we were preparing to file in Japan included material that was developed in the United States. While I understood that the invention for which we were filing an application in Japan related to the joint development project with our U.S. partner, I did not appreciate that the application that we were filing included material which could be said to constitute an invention made in the United States for which a foreign filing license should be sought before filing in Japan.

I sought to file the application quickly in Japan, because in Japan a patent it is issued to the first applicant that files for the invention. It is thus very important for the applicant to file as soon as possible after an invention is made. We had not reached any agreement with respect to the joint development project about how intellectual property was to be protected and in what manner patents might be sought so at that point I believed it was most important for us to proceed in Japan as soon as possible. It was not my intent to be deceptive on this point.

The attached documents A reference agenda and minutes of a pre-meeting I chaired on August 30 2002 for preparation of an in-house kick-off meeting. Makino and Kunisawa, who are the inventors of Japanese applications 2002-350529 and 2003-399443, were present at this meeting. These documents include a copy of memorandum of discussion on the tool specification based on discussion in a meeting held in the US between Ebara and the US company.

The attached documents B reference a copy of a white board used in an Ebara in-house meeting held on September 3, 2002 in Japan for discussing the tool specification and tool

schedule.

The attached documents C reference a copy of copyable board used at a meeting between Kunisawa, Makino, who are the inventors of Japanese applications 2002-350529 and 2003-399443, and Mr. Kosugi, a patent agent, who prepared the application document for the inventors based on the explanation given to him by the inventors. This meeting was held on November 18, 2002 in Japan.

The attached documents D reference the request for preparation of patent application for filing in Japan and the draft of the disclosure prepared by inventors Makino and Kunisawa to proceed with the filing of the application in Japan. I was aware that this application included a pad attached to a high resistant structure when I checked the draft made by the inventors and I knew that a pad disposed on the high resistant structure was shown in the presentation by our US partner in August 2002. As I knew a plating method using a pad at that time I did not think that using a pad disposed on a high resistance structure was their new idea. I also thought that if our US partner claims that the application should be a co-application, we could modify our application to include their inventors and to make the application a co-application between Ebara and our US partner. I had no knowledge that the invention made in US must be filed in US first at that time. It was approved by me and sent to IP department in the headquarters through Patent department in Precision machinery group.

Please also note the additional request for preparation of patent application referenced as documents E which involve my approval regarding the revision application of 2002-350529 filed on November 28 of 2003.

Please also note the additional request for preparation of foreign patent application referenced as documents F which I approved to file in US with priority date of Japanese filing date of 2002-350529. This application was filed in US application serial number 10/724044 on December 1, 2003.

At the time we filed these applications abroad, i.e. on December 2, 2002 and November 28, 2003, they were not under a secrecy order, and they are not currently under a secrecy order.

We began discussing these applications and the U.S. application for the U.S. joint development project partner in February of 2004. Before the meeting with our US partner, we discussed in Ebara and ETI on the applications and ownership based on the list. We noticed that

two of the applications might include information given by our US partner to Ebara in the meeting in August 2002. After discussing the contents of the applications in the meeting in February 2004, our US partner insisted that some the applications in the list included material that was developed by them in the United States. Because we had only a list of applications which included a plain abstract of each application at that time, we prepared full translations of the claims of each application and asked them to study which applications included material developed by them in the US. We agreed in March 2004 that these two applications 2002-350529 and 2003-399442 and the U.S. application for which this statement is prepared included material developed in US.

Please see the accompanying documents G which evidence the list of our patents discussed at the meeting on February 6, 2004. In a discussion in Ebara preparing this document, we found that #22 and #24 may include invention made by our US partner in US. We indicated on the list that these two applications might be co-applications between Ebara and our US partner.

Document H is minutes of the meeting between Ebara and our US partner on February 5 and 6, 2004 in US. Technical discussions, which contain confidential items between Ebara and our US partner, are redacted from this minutes and only IP issues are left on the document.

This discussion was mainly made between Mr. Sasabe, General manager of Patent department of Ebara, Mr. Musaka, Technical coordinator for Ebara of this joint development project, me, and engineers and an in-house attorney of the US partner.

Document I is a copy of an e-mail sent on March 9, 2004 by Mr. Musaka to a technical coordinator of our US partner of the JDP. Application #2 stands for Japanese application 2003-350529, #22 stands for 2003-399443.

Document J is a copy of an e-mail, which I sent to Mr. Musaka on May 7, 2004, asking not to agree to make some Japanese applications co-applications between Ebara and our US partner on a meeting held on May 7, 2004, because we were trying to get approval of Mr. Tsujimura on making them co-applications.

Document K is a copy of a meeting agenda and a copy of white board used at a meeting to investigate the history of these applications held on May 27, 2004 in Japan.

Document L is a copy of an e-mail from Mr. Musaka on June 10, 2004 reporting a result

of a meeting between the Project manager of the JDP of our US partner and Mr. Kimura, Project manager of the JDP of Ebara.

We reached an agreement in June 2004 about which applications in all the applications listed and presented by Ebara at the meeting in February 2004 included material that was developed by them in the United States. And, we agreed to a process to clarify the ownership of the invention before filing an application, except those clearly belonging to Ebara only, in the US first.

I have diligently sought this retroactive foreign filing license after I discovered that our foreign filings were in fact proscribed.

I declare that all statements that I have made herein of my knowledge are true, and that all statements on information belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under § 1,001 of Title 18 of the United States code, and that such willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Respectfully submitted,

Yukio Fukanaga

Mukio Fukuraga

Date: Oct. 27, '04



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

VERIFIED STATEMENT UNDER 37 C.F.R. 5.25(a)(3) IN SUPPORT OF PETITION FOR RETROACTIVE FOREIGN FILING LICENSE

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

This statement is being made by Kenichi Sasabe of Ebara Corporation, the Assignee of applications listed below. I was promoted in 1998 to be a general manager of the Patent Department in the Precision Machinery Group of Ebara Corporation, in which position I still remain now. I was assigned in August 2003 as Patent/IP leader of a Joint development project in Ebara. I have personal knowledge of the acts regarding the preparation for this foreign filing license petition relating to the following applications that have been filed outside of the United States:

Japan

1. 2002-350529	December 2, 2002
2. 2003-015236	January 3, 2003
3. 2003-149827	May 27, 2003
4. 2003-161237	June 5, 2003
5. 2003-195406	July 10, 2003
6. 2003-310355	September 2, 2003
7. 2003-399443	November 28, 2003
8. 2003-431211	December 25, 2003
9. 2004-022178	January 29, 2004
10. 2004-023256	January 30, 2004
11. 2004-082102	March 20, 2004

PCT

PCT/JP2004/000528 filed January 22, 2004, related to JP#2, JP#3 and JP#4 above as well as one other Japanese application which includes no invention made in the U.S., and designating all countries except Japan

Taiwan

TW93101713 filed January 27, 2004 and related to JP#2, JP#3 and JP#4 above as well as one other Japanese application which includes no invention made in the U.S.

Three applications were filed in the US related to four of the Japanese applications listed above:

US Patent Application Serial No. 10/724,044, which is related to JP#s 1 and 7 above;

US Patent Application Serial No. 10/886,716 which is related to related to JP# 5 above; and

US Patent Application Serial No. (New), filed September 1, 2004 in the name of Keiichi KURASHINA et al. and related to JP#6 above.

I am also attaching copies of a number of supporting documents, labeled and referenced herein as documents L-BB.

As the joint development project was prepared in a highly secret condition in Ebara, I knew little of this project before I was asked to be a Patent/IP leader in the project in August 2003. I remember two acts in which I was involved before August 2003.

One action is that I prepared a list of patent applications Ebara filed in Japan for plating technology of copper interconnect on a semiconductor substrate. I prepared this list to show Ebara's background technology that Ebara had before Ebara got into the joint development project. I listed Ebara applications and the development people selected applications which were

necessary as background technology. This list was prepared in around September 2002 and updated in March 2003.

The second action I was involved in was a discussion of the ideas between Ebara Technologies Incorporated (ETI) and our US partner. A list of ideas to be developed was sent to Ebara engineers in Japan and the Ebara engineers and I discussed the ownership of the ideas to advise ETI engineers. These ideas were prepared in the US by ETI and our US partner. We found some of the ideas had already been filed in Japan by Ebara and some ideas were being prepared for filing by Ebara.

After an inventor invents something in the Precision Machinery Group in Ebara, a disclosure of the invention is made by the inventor and sent to the IP department in the headquarter of Ebara through a patent liaison in the same department as the inventor, managers supervising the inventor, and the Patent Department in the Precision Machinery Group. I check and approve the disclosure to be filed as a patent application.

If the inventors indicated that the invention included some inventions or ideas made in the US, the patent department should have noticed the error in filing in Japan first. But there was no indication that the applications included any inventions made in the US, so I did not notice that there were inventions made in the US in the applications until January 2004 when Ebara engineers and I prepared the list of Ebara applications.

In January 2004, Ebara development engineers and I prepared a list of Ebara's applications filed in Japan for a meeting held in the US between Ebara, ETI and the US partner. I made a list of Ebara applications filed later than August 2002 in Japan. Ebara engineers selected the applications which may have some relation with the joint development project. I made a table of Ebara applications to be submitted in the meeting. In the discussion for preparing the list with the Ebara engineers we noticed that two of the applications might include information given by our US partner to Ebara in a presentation in August 2002. We indicated the ownership as joint between US partner and Ebara in the table. I noticed that if the application included an invention made in the US, we must prepare a petition for a retroactive foreign filing license for the filing of the application first in Japan.

I discussed the necessity of the petition for a retroactive foreign filing license with an

attorney of our US partner at the meeting. As the table has 29 applications, it took a long time to decide ownership of each of the applications and to clarify the inventors of each invention. It was finally decided in June of 2004.

Document M is the list of Ebara patent applications filed in Japan later than August 2002, which was submitted to the meeting.

Document N is the minutes of the second workshop meeting between Ebara and our US partner held on February 5 and 6, 2004 in US. These minutes briefly describe the discussion in the meeting.

Document O is a Facsimile letter to Deputy General Manager Kondo of IP department and Manager Sakaguchi of Patent department of Ebara, which I sent on February 8, 2004 to instruct to check if there were other applications related to this joint development project filed before August 2002, which used a pad on an impregnated material, and also to instruct to make English translations of abstract and claims of some applications filed in Japan.

I have diligently sought this retroactive foreign filing license after I discovered that our foreign filings were in fact proscribed. We began discussing these applications and the U.S. application for the U.S. joint development project partner in February of 2004. As I have little experience in this matter of foreign filing licenses and obtaining retroactive foreign filing licenses, it has taken me some time to study the situation, discuss the matter with my colleagues and obtain appropriate advice in order to make this statement in support of the accompanying petition.

On February 8, 2004 I discussed briefly this problem with an attorney in the US different from Mr. Pedersen, who is filing this statement for us. I asked him his advice by e-mail on February 28, and a partner attorney sent me advice on March 3, 2004.

Document P is a copy of an e-mail I sent to an attorney for his advice on February 28, 2004. As the attorney, licensed in New York, is Japanese, this e-mail was written in Japanese.

Document Q is advice from the partner attorney sent on March 3, 2004. As the attorney from whom I asked advice is from a firm with which we consult on general advice or litigation matters, I asked Mr. Pedersen, an atto rney who is a representative of Ebara in filing patent applications in the US, to proceed with the actual filing for the foreign filing license in May 2004.

Document R is a copy of an e-mail I sent to Mr. Pedersen to ask his advice on May 11, 2004.

Document S is a copy of an e-mail I sent to Mr. Pedersen on May 15, 2004 with an attachment of a draft to explain a reason why Ebara filed in Japan before filing in US.

Document T is a copy of an e-mail I sent to Mr. Pedersen on May 18, 2004.

Document U is a copy of an e-mail I sent to Mr. Musaka on May 19, 2004 regarding an advice from Mr. Pedersen.

Document V is a copy of an e-mail I sent to Mr. Fukunaga asking for preparing his statement. This e-mail includes e-mail from Mr. Pedersen on May 24, 2004.

Document AJ is a copy of e-mail I sent on June 2, 2004 to Mr. Pedersen, our attorney, asking for advice.

Document AN is a copy of e-mail from Mr. Pedersen which shows that I visited his firm on June 23, 2004 for discussion on this issue.

Document AO is a copy of e-mail I sent to Mr. Pedersen on June 26 for instruction on this issue.

Document AP is a copy of e-mail I sent to Mr. Musaka on June 29, 2004 regarding petitions based on the advice from Mr. Pedersen.

Document AS is a copy of e-mail I sent to Ms. Matsuo of Kontecs whom we asked translation of support documents for this petition and statements. This e-mail respond to her e-mail referring her e-mail. This e-mail shows that we asked translation of our support documents on July 3, 2004.

Document AV is a copy of e-mail I received from Mr. Pedersen on July 20, 2004 in reply to my e-mail on July 13, 2004.

Document AW is a copy of e-mail I sent on July 22, 2004 to inform Ms. Matsuo that I received the English translation of support documents for this petition and stat ements.

Beside these contacts with attorneys for the preparation of the foreign filing license, I contacted often with Mr. Musaka, who is a technical coordinator of Ebara in the Joint Development, and he contacted with the technical coordinator of our US partner to discuss about the ownership of the applications. In this discussion our US partner requested to some of the

applications to be joint applications, which include their inventions made in US. As we decided to make the Japanese applications 2002-350529 and 2003-399443 joint applications after the meeting held in February 2004, we started to prepare to submit a petition for these two Japanese applications and one US application based on one of the Japanese applications. But through the discussion with our US partner, the number of applications that they requested us to change to joint applications increased. We investigated the history of inventions and we reported the reason why we considered the inventions were made by Ebara inventors. The discussion on the ownership of the applications continued until June 2004.

In March 2004 we tried to file a petition for the two Japanese applications. After some discussions with our US partner, we tried to treat all applications requested to be joint applications together in one foreign filing license. But after precise study of the applications, we found that the general manager in development department was Mr. Fukunaga for the two Japanese applications and was Mr. Mishima for other applications. We decided in June 2004 to file the petitions in two groups to clarify the situation.

Document W is a copy of an e-mail I sent to Mr. Musaka on March 6, 2004 to send English translations of some Japanese applications for which our US partner requested to send English translations of abstracts and claims. This e-mail also explains the Japanese application 2002-350529 referred as application No.2 and Japanese application 2003-399443 referred as application No.22.

Document I is a copy of an e-mail sent on March 9, 2004 by Mr. Musaka to a technical coordinator of our US partner of the JDP for sending English translation of abstracts and claims of the Japanese applications.

Document X is a copy of an e-mail I sent to Mr. Musaka on March 9, 2004. This e-mail explains the relation of Japanese applications 2002-350529, 2003-399443 and US application based on 2002-350529.

Document BB is a copy of an e-mail Mr. Musaka sent to the US partner for sending English translation of the application on March 12, 2004.

Document Y is a copy of an e-mail I sent to General Manager Nakashiba, Deputy General Manager Akai, Deputy General Manager Kondo and Manager Shinozuka of Intellectual Property

Department in Ebara Headquarters on March 17, 2004 to propose a filing procedure for patent applications related to the JDP.

Document AZ is a copy of e-mail I sent to Mr. Nakashiba and Mr. Akai about filing petition for export license on March 24, 2004.

Document BA is a copy of e-mail I sent to Mr. Akai on March 25, 2004 reporting the result of a discussion between Mr. Musaka and our US partner. The e-mail from Mr. Musaka to me following the e-mail to Mr. Akai shows the request from our US partner expressed in the discussion.

Document AY is a copy of my notebook which shows a memo of a meeting between Mr. Fukunaga, Mr. Mishima, Mr. Kurashina and me on March 31. The reasons why Ebara considered the inventions were Ebara inventions were discussed in this meeting.

Document AG is a copy of a white board used in a meeting by Mr. Fukunaga, Mr. Mishima, Mr. Sakaguchi and me for a study of ownership of several Ebara applications on April 19, 2004.

Document Z is a copy of an e-mail I sent to Mr. Musaka and Mr. Mishima with an attachment describing Ebara's opinion explained to Mr. Musaka on April 24 on the ownershi p of some applications which were studied in the meeting held on April 19, 2004.

Document AA is a copy of e-mail I sent to Mr. Fukunaga on May 6, 2004 responding to e-mail from Mr. Musaka requesting a telephone conference with our US partner on May 7 at 6:00 AM in Japan time on patent applications.

Document AB is a copy of e-mail replying on May 7, 2004 to e-mail from Mr. Fukunaga requesting my checking of a draft before he reports the progress of the patent issue to Mr. Tsujimura, Director of Advanced Technology Division,.

Document J is a copy of an e-mail, which Mr. Fukunaga sent to Mr. Musaka on May 7, 2004, asking not to agree to make some Japanese applications co-applications between Ebara and our US partner on a meeting held on May 7, 2004, because we were trying to get approval of Mr. Tsujimura on making them co-applications.

Document AC is a copy of an e-mail I sent on May 8, 2004 to an attorney of our US partner, in return to an e-mail I received from him. He advised me of preparing petition for

foreign filing license after a telephone conference of the Joint Development Program on May 7, 2004.

Document AI is a copy of e-mail I sent on May 18 to Mr. Musaka sending English translation of specification of application JP #9 (2004-022178) which is referred as #26. (#26 is a number in the patent list of Document M.) On a telephone conference held May 7, 2004 Mr. Mishima explained the contents of this application and he explained that this application should be Ebara sole application.

Document AH is a copy of e-mail I sent on May 20, 2004 to Messrs. Musaka, Fukunaga and Mishima explaining the result of my check for claims including pad in Ebara applications. I explained my consideration on some of the applications in this e-mail.

Document K is a copy of e-mail I sent on May 21, 2004 of a meeting agenda, and a copy of white board used at a meeting to investigate the history of applications JP#1 and # 7 held on May 27, 2004.

Document AD is a copy of e-mail I sent to Mr. Mishima on May 29, 2004 for asking to submit related documents to the applications in relation to the meeting on May 27, 2004 described in Document K.

Document AK is a copy of e-mail I sent on June 8, 2004 to Mr. Musaka for sending English translation of application JP#5 (2003-195406) to be checked by our US partner before filing in US.

Document AE is a copy of e-mail I sent on June 8 to inventors of the applications for sending a questionnaire.

Document AF is a copy of an e-mail I received from Mr. Musaka and transferred to General Manager Akai and Manager Shinozuka of Ebara IP department on June 11, 2004 after a meeting between representatives of Ebara and our US partner for discussion about IP issue in JDP. In this meeting both agreed to make Japanese applications in concern to be co-applications between Ebara and our US partner.

Document AL is a copy of Agenda of #3 workshop meeting held on June 21, 2004.

Document AM is a copy of e-mail I sent to Mr. Musaka on June 18, 2004 sending documents for #3 workshop meeting. In this meeting I explaine d that we will make 11

applications co-applications and asked them to reconsider about two applications different from the 11 applications.

Document AQ is a copy of e-mail I sent to Mr. Musaka for sending English translation of application JP #10 which is referred as #28 (2004-23256).

Document AR is a copy of e-mail I sent to Mr. Musaka on July 9, 2004 asking any response from our US partner on two JP applications including JP #6 which are referred as #13 and #16 respectively.

Document AX is a copy of e-mail which Mr. Fukunaga sent to Mr. Musaka on July 6, 2004 inquiring the name on inventors of our US partner for filing application JP # 5 in US as a joint application.

Document AT is a copy of e-mail I sent to Mr. Shinozuka of IP Department on July 16, 2004 asking to send me copies of "Notification of invention" which are Document BC-BM respectively, and confirming who was the General manager at the time of filing.

Document AU is a copy of e-mail I received from Mr. Musaka on July 18, 2004 in response to my e-mail sent on July 9, 2004 regarding two JP applications including JP #6 which are referred #13 and #16 respectively in the e-mail.

I declare that all statements that I have made herein of my knowledge are true, and that all statements on information belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under § 1,001 of Title 18 of the United States code, and that suc h willful false statements may jeopardize the validity of the application or any patent issuing thereon.

Respectfully submitted,

Kenichi Sasabe

Kenichi Sasabe

Date: October 30, 2004

辻村様" ,"福永様"< fukunaga.akira@ebara.com>, "徳重様"<tokushig, 午前 08:42 02/08/28 +090(

To: "辻村様" <tsujimura.manabu@ebara.com>,"福永様"< fukunaga.akira@ebara.com>, "德重様" <tokushige.katsuhiko@ebara.com>, "三島様" <mishima.koji@ebara.com>, "勝岡様" <katsuoka.seiji@ebara.com>, "国澤様" <kunisawa.junji@ebara.com>, "牧野様" <makino.natsuki@ebara.com>, "神田様" <kanda.hiroyuki@ebara.com>, "並木様" <namiki.keisuke@ebara.com>, "蓬台様" <hodai@m.email.ne.jp>, "南條様(大石****)" <a href="title="color: blue:color: blue:colo 様)"<oishi.kunio@ebara.com>

From: Yukio Fukunaga <fukunaga yukio@ebara.com> Subject: PaPキックオフ会議開催の件

Bcc: fukunaga.yukio@ebara.com

Attached:

各位殿

題記の件、reductedキックオフミーティングを下記のとおり

◆ 日時: 8月30日(金) 9時~11時

◆ 場所: V2棟 第一会議室

当日出席できない方は、予め福永(由)まで 連絡下さい。

第一開発センタ 第二プロセス開発室 福永(由) (Tel. 8970) -

~10/\$0 min OP. Menue Control 2-hot/on. 10312 71 (7/1/5) X Water Rotation/Oscillation table recipe (clostep) (JU) 10stop. 罗说六件数 如你就有了一个可能 Control dan tolca). 13th 7 A Polisty Pad with holes Hadula (1977) (11) inch 2 And solution line Switchig (B 主任水河海? Ceramic plate (~21%) of AZZ Fellen? △ 河電制(即ante(下的?) Wy a(E) I backing sheet. भेरतार भुक्ताः to lungers. " polishing ladalliti. A127211 12 * Ansak rotation. Anodeontiti A, Bo 7:53 (立置制(部四分) 8 A30 B reducted The Welling Anode with full contect " Ind solution like. (XX) Water Support 2-motion.

Support Document A

Tusjimura", "Fukunaga "<fukunaga.akira@ebara.com>," Tokushige"<tokushige AM 08:42 02/0828+0900

To: "Tsujimura"

<tsujimura.manabu@ebara.com>,"Fukunaga"<fukunaga.akira@ebara.com>,"Tokushige"<tokushige.katsuhiko@ebara.com>,"Mishima"

<mishima.koji@ebara.com>,"Katsuoka"<katsuoka.seiji@ebara.com>,"Kunisawa"<kunisawa.junji@ebara.com>,"Makino"<makino.natsuki@ebara.com>,"Kanda"<kanda.hiroyuki@ebara.com>,"Namiki"<namiki.keisuke@ebara.com>,"Hodai"<hodai@m.email.ne.jp>,"Nanjo (Oishi)"<oishi.kunio@ebara.com>

From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: Call-up of kickoff meeting for reducted

Cc:

Bcc: fukunaga.yukp@ebara.com

Attached:

To all concerned,

This message requests all concerned members to attend the kickoff meeting for the redacted project scheduled as below.

Mr. Tsujimura, Chief of Technology Div., will have a speech.

Date: Friday, August 30. From 9:00 a. m. to 11:00 a.m.

Place: Meeting room 1, Building V2

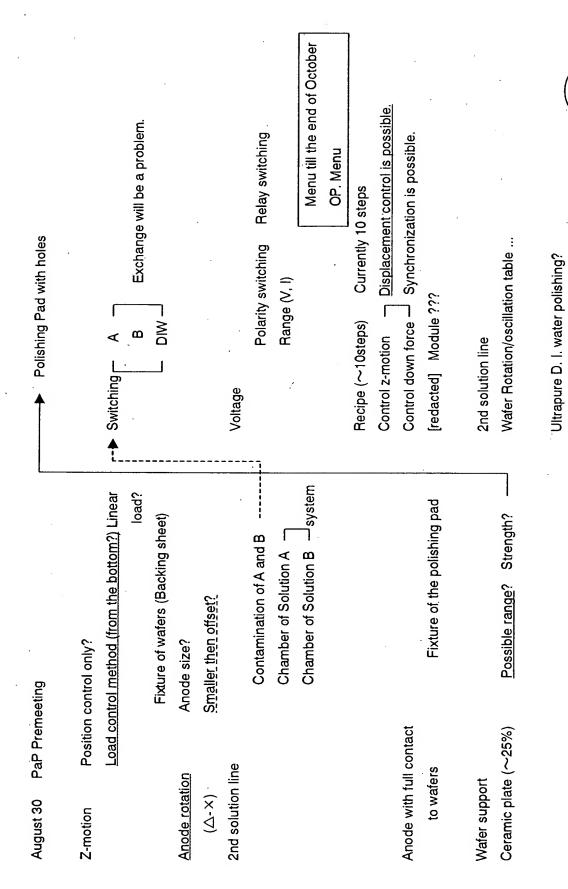
Please inform Y. Fukunaga of your absence in advance.

Y. Fukunaga

Process Development Office 2

Development Center 1

Phone: 8970 (Extension)



Fukunaga 02.8.10 redacted 検討会(#2)議事録. txt

redacted プロジェクトメンバ各位殿

議事録送付致します。

(#2)redacted 検討会 議事録二

・日時: '02. 9. 3. (火) 8:30-10:20

V2-第一会議室 ・場所:

·出席者(敬称略): 木村、徳重、三島、神田、勝岡、国澤、牧野、南條、 (記)

「redacted 」装置の客先の提案仕様に関し理解を深め、最適対応策を検討す 【主旨】 る。

- 「redacted 」 開発の背景と、客先の提案仕様について … 木村センタ長 ・ 客先 J D A P r o p o s a l に基づく開発内容説明

 - ・redactedとの協業は"深く静かに"推進したい。 情報はメンバ以外門外不出とする
- ・ φ200実験モジュールを3ヶ所 (redacted / , サンノゼ、藤沢) に設置し、開 発を加速したい。
 - ・ めっきとポリッシュは最終的には一つの装置にまとめる。
 - redacted ?

および redacted は、別途検討とする。

- 2. 実験モジュールの改造仕様について … 論議 ・ 客先提示の改造項目案に関して、実現性を論議した。 ・ 今秋設置のゆ200モジュールは含浸めっきモジュールをベースにし、 めっきモジュールとポリッシュモジュールとを別々に設置するのが効率的。 (改造少なく、早期対応可。 個々のフプロセスをコンタミなしに検証可)
 - 改造に供試可能なモジュールと引き当て(案)

redacted

サンノゼ

藤沢

ch.

te

β2モジュール

1: et

DRモジュール

: p

β2機(11月~)

1 : etch. 1: plate 1 : etch 1 : plate

3. メンバ

当面のメンバ:

福永(由)

DR機

蓬台

(めっき) 三島、神田、井出

(ポリッシンク)徳重、並木

(設計) 勝岡、国澤、牧野

(制御) 南條

4. 次回打ち合せ

・自時: 9月9日(月) 10時~12時

V2棟 第5会議室 ・場所:

装置仕様、 ユーティリティリスト、

以上

Meeting Minute for the [redacted(project name)] Project (#2)

To all concerned members of the [redacted(project name)] project, This document is the meeting minute for circulation.

- = Meeting Minute for the [redacted(project name)] project (#2) =
- Date: Tuesday, September 3, 2002. From 8:30 a. m. to 10:20 a. m.
- · Place: Meeting room 1, Building V2
- Attendants (title omitted): Kimura, Tokushige, Mishima, Kanda, Katsuoka, Kunisawa, Makino, Nanjo, Y. Fukunaga (Minute originator)

Fukunaga '02.9.3 08594

[Purpose of the meeting]: To understand the proposal of specification change for [redacted(project name)] tool made by the customer and to discuss the optimal actions.

- 1. Background of the "[redacted(project name)]" development and the customer-proposed specifications ... Executive General Manager Kimura
- Mr. Kimura explained the development based on the JDA Proposal of the customer.
- Ebara wants to develop the ties for collaboration with [redacted: the US company] "densely and silently". Information on the collaboration must be off-limit to others except for the concerned members.
- Ebara wants to implement the test modules for 200-mm wafer in three sites ([redacted: the US company], San Jose, Fujisawa) to accelerate the development.
- The plating module and the polishing module will finally be integrated.
- [redacted] and [redacted] will be discussed separately.
- 2. Change of the test module specification ... Discussion
- The members discussed feasibility of the specification change proposed by the customer.
- It is efficient to manufacture the test modules for 200-mm wafers for the site implementation in coming autumn based on Ebara's impregnation plating module and to separately install the plating module and the polishing module. (Using this configuration, we do not require large-scaled modification; thus, can respond faster. We can verify individual processes without contamination.)
- The members discussed where the modules, which can be modified, are implemented (proposal).

· β2 module · DR module	[redacted: the US company]	San Jose	Fujisawa 1: etch. 1: plate
· β2 unit (from Nov.)	1: etch.	1: etch.	·
· DR unit	1: plate	1: plate	

3. Members

Members assigned for the present are as follows.

	.ou .oo p. 000	in are as removes.	
Y. Fukunaga			Hodai
	•••	(Plating)	Mishima, Kanda, Ide
	•••	(Polishing)	Tokushige, Namiki
	•••	(Design)	Katsuoka, Kunisawa, Makino
	•••	(Control)	Nanjo

4. Next meeting

Support Document B

- Date: Monday, September 9. From 10:00 a. m. to 12:00 a. m. Place: Meeting room 5, Building V2 Agendas: Unit specifications, utility test, schedule, etc.

END OF DOCUMENT

54, 3 Solution Surriy N (CV) Manage (新流) (Current) Pressure 开土

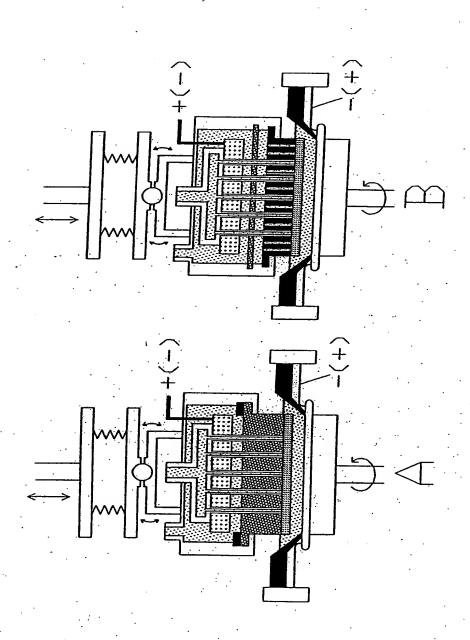
知的難部久保課長殿之国沢

発明等届	出書(1/2)		1.特許	2.意匠		その他)**			(2.無)		社外秘
Post (718)				、て特許出版とする。 ost ()	・但し、 Post	専用新案で出願した (52) 知的財産部	い場合は、「3.その他」に	OSAL	如的財產部。	と相談す	3.
发野 国际 2007 国际 11 国际 2007 国际 11 国际 1	夏) (リエゾン) (福出	1	関係部門 -		長郎郎	// /	音視谜	图 受付日	/No.	
2/2の依頼	記上長記入欄の袋印掘もお	En#	く御捺印下さ	is.			大頼日(西暦) 大頼元 Doc.No.		年	月	日
						11	X対人 DOC.NO.	718	- E2N		1 合研究所
依 (部門コート) 頼 部門名 元 書類送付 部 担当者 門	第-開発セン	野: 2	夏木	ス開発室	分(本)	l. 管理 2. 情報·通信 3. 営業 1. 環境エンジェア 5. 風水力	6. 新球件・⑦ 特密・電子		9. # 10. # 11. #	生原 ボー 生原 工	イラ 業洗浄 熱システム
TYPE AT A A Sh	T- 077 5	-67 -	12 TF	<u>.</u>					···		
発明等の名称	電解処			* - 4 -	NI T	1	Tar				
関連する製品			<u>4 d)っ</u> 浸めっき	きエッチン	N NO	庞 電解	加定				
	1) 重点拡販機和			. 重点拡販	機種で	ない。研	番成果 研N	o. L –	02Ð5	470	9
職務発明 ①					:				者記入概		
cont 2.							(X 9 2)	E 66 F1 (8)	に捺印し		5911
3.	職務発明ではな その譲渡につい				— 9 30)	権利につざ	(2007)			•	
	→右欄に捺印して	て知的	財産部に記	送付してくださ		の社内発明者記	己入樹の	•			İ
(0)	ところの譲渡確						·	· · ·			
	原製作所(EBR)、在原総合研	#究所(E		1ラ(EB)、在原工業 属部門名	_				14 EU	sari-	
下欄は EBR の発明者 上記の職務発明等 I	等たけに適用する。 こ関し、私(発明者・	社	1 1914	光可心力	Post		氏 名	1	権利 譲 辞分 確	認印	米国 ^{※ 3} 在住
考案者・創作者)は	発明等の時点におい	社内発明者	1 7-	- ペニク学問	bis	-1	(, , , , , , , , , , , , , , , , , , ,		50 (KSE K	1
	おける一切の権利を 原製作所)に譲渡し	男	事	2002年教皇	905	20307	牧野夏	たド	50		1 1
たことを確認します	r	記	9 塩_	開メナーター	718		國澤淳次	2 1	50 (1
	Sの発明者等だけに適用す	<i>a</i> (70七人開発室	9488	21105	四件净小	10			
る。 上記の職務発明等に	・闘」、私(発明者・		3		ļ	-			%		
考案者・創作者) は多	発明等の時点におい	多	4		-			-	%		
て日本及び外国に↓ 会社(おける一切の権利を)に譲渡し	* 2					·		·		1
たことを確認します			5	-					%	:	
	لـــــــــــــــــــــــــــــــــــــ						* 2				
4-22211	DDD WAR O	mn	D b Dr	ארו מני	L 0 1	t⊟ o n			ている場合は		すける.
出願形式 (1)				3R 以外の者			BR 以外の者の		4. そ	の他	
	(英統神(EICC)、在原冷熱沙					入する。荏原総合	研究所(ER)は記入要領を	き照のこと	•		
出願手続会社 費用負担	(1) EBR (1) EBR 負担			R 以外の者 発負担 3	、 .その) 4h					
EBR 以外の	会社名又は氏名			(住所、Tel、			· 名等)		権利持	分 費	用負担
出願人名義 ^{※4}					747.4			•	9	6	%
(計 名)	<u> </u>	_					<u></u>		·		
			•						%	6	%
5 (社外発明者)棚には荏肓	U製作所(EBR)、在原総合研		i)、在原ポイ	ラ(EB)、荏原工業 8	ŧ∌ŒICC) 、在原冷熱システム(E	ERS)以外の発明者等を記	入する。 .			
1 1 4 4		E				住 所				権和	利持分
計計							•			1.	%
発 明		-									%
好			<u> </u>						•		/0
* (1)											%

### 1		(4))		•								•		
契約関係 ³⁶ 共同出版契約書 1. 在 (相手:) (2.) 無(型末) (2.) 未(型ま) (2.) 未(型素) (願 (2	1. 普通 2. 至急 _.	(/2 月)			h ^y	8社先願公	開期限	人)		年	月	日
大同田顧契約書 1 要 (作成担当: a. 当社 b. 相手先(-	契約賬	12×6	共同研究等	契 約建	1 方	(胡毛・					1 (2	ATTE COM 1	 -
3	Ŧ	- 1					1. 要	(作成担	当:a. 当	i社 b.	. 相手:	先() (2.)	/無(少女)))
調査実験状況 関連出籍・公知例 当在のもの ①. 有 (特別・ 2000 - 364 201	٦		£ 6 4 5 14 5 1	HALE MORE	55 L-4- 7 55 Ma L 1 -	C \$77 6 5 (P) - 4 C + - 7 (· · · · · · · · · · · · · · · · · · ·				
1. 調査済み 出頭内容に近い公知例 を2部係付する。 2. 無 特殊 2000-232078 (東文) 2. 無 性社のもの ① 有 (特開 2000-232078 (東文)) 2. 無 性社のもの ② 有 (特開 2000-232078 (東文)) 2. 無 性社のもの ② 有 (特開 2000-232078 (東文)) 2. 無 性社のもの ② 方有 (特開 2000-232078 (東文)) 2. 無 性社のもの ② 方有 (特開 2000-232078 (東文)) ② 差別 表現在製品・技術の発明 ② 海事業製品・技術の発明 ② 光行アイデア発明	7	$\mathscr{U}_{\mathbf{I}}$								/ ut 7	· 107	37	Dat 4		
② 未調査		ł	1. 調	査済み	出顯内容	に近い公知	例		2. 無	特点	類 20	00-36	1201	(東芝山)
	,	Ľ	②. 未	調査		•			2. 無		.,,				
	. (12)					•								
日本の	'	T		· ¥	発明の性質	発明の	4質によ	na B	Cのうt	5一列を	· 違択 · ((記号を(1.7	亚 /邢	•
① 一次行技術に対する技術的 日、同等 2. 岩千優位 ② 相当優位 4. 断然優位 優位性 ②課題・手段の重要性 日、不明 2. 普通 3. 重要 (4.) 最重要 3. 中 4. 大 (4.) 表別が対象とする製品 1. 開発計画の終了段階である 3. 開発計画の中間段階である 3. 開発計画の中間段階である 3. 開発計画の初期段階である 3. 開発計画の初期段階である 3. 開発計画の初期段階である 3. 所発的 (3.) 中 4. 大きい 優 (4.) 優 (4.) 日本の代表合評価 1. 本度 (4.) 第 (4		I	評価項			A.現在	製品・技術	の発明							明
②課題・手段の重要性 1. 不明 2. 普通 3. 重要 4. 最重要 3. 重要 4. 最重要 3. 重要 1. 不明 2. 小 3. 中 4. 大 9. 円 4. 大 1. 本 9. 日 1. 本 9	7		①先行	支術に対す	る技術的	-8 .							54		
③独創性	ì	<i>i</i>)													
②本発明が対象とする製品 の開発計画 の開発計画 の開発計画の終了段階である 3. 中 4. 大 の開発計画 の開発計画の終了段階である 3. 用発計画のが開展階である 3. 用発計画の初期段階である 3. 用発計画の初期段階である 3. 用発計画の初期段階である 3. 用発計画の初期段階である 3. 中 4. 大きい 要度 ⑥依頼元総合評価 1. 軽度 (1倍) 2. 通常 (2倍) (3) 重要 (3倍) 4. 最重要 (4倍)	::				要性	1. 不	明	2	. 普通		3. 1	重要			
(4) 本発明が対象とする製品		1	3/共和1	£						:			11	· - ·	
2. 開発計画の必開設性である (国発計画の加限とである (国発計画の加限とである (国発計画の加限とである (国発計画の加限とである (国発計画の加限とである (国内の (国内の (国内の (国内の (国内の (国内の (国内の (国内の		1	4)本発明	明が対象と	とする製品	1. 開务	を計画は	Z1/2		•			3. T	4. 人	
(3) 年発明が製品に占める重 1. 小さい 2. やや小さい 3) やや大きい 4. 大きい 要度 (6) 依頼元総合評価 1. 軽度 (1倍) 2. 通常、(2倍) (3) 重要 (3倍) 4. 最重要 (4倍)						2. 開発	計画の	冬了段階						-	
 ⑤本発明が製品に占める重要度 ⑥佐頼元総合評価 月 経度(1倍) 2 通常(2倍) (3) 重要(3倍) 4 最重要(4倍) 3 重要(3倍) 4 最重要(4倍) 3 不要(理由:) 外国出願 (1)・②・公・ア・フ・ア・フ・ア・フ・ア・フ・ア・フ・ア・フ・ア・フ・ア・フ・ア・フ・ア		ł		•								•			• •
要度		1	5)未器服	日が制旦い	上める電					: 1.5	12) 4	シャンナーキ	15 4	4-3-17	
① 依頼元総合評価		1		777 - 20C BD 47	-ロのる産	1. 71	C V 1	۷.	6646	. V 1	۱۰ رق	5773	V1 4.	八名以	
日本		(総合評価		1. 軽	度(1倍)	2.	通常、(2 倍	f) (3))重要	(3 倍)	4. f	重要(4倍	7
日 列の発明	3					·									لنب
日 例の発明	•	· 🔐	平 A 列	の発明		+ <u>(6)</u>	= 42		出願要否	1	要	2	2. 公開	支報でよい	
算									• •)
特記事項	ı			の発明	(()+(2)+(3)	+⑤)×⑥=	= .	l f	外国出願)
特記事項	-	。	7					J . L		2.	不要	3	. 未定		
評価 ①特許性 1. なし 2. 小 3. 中 4. 大 ②権利の広さ 1. 狭い 2. やや狭い 3. やや広い 4. 広い ③本発明の回避困難度 1. 容易 2. やや困難 3. かなり困難 4. 不可 ④特許的総合評価 1. 軽度(1倍) 2. 通常(2倍) 3. 重要(3倍) 4. 最重要(4倍) 知財部評価点:(①+②+③)×④= 総合評価*8 84以上 → S:重点 64~83 → A:重要 28~63 → B:通常 27以下 → C:出願せず 評価 無限 28~63 → B:通常 取認者 即 日間 出 1. 通常出願 2. 国内優先権主張 基礎出願番号: **8 異当の再編ランクに〇を付ける. 特許事務所 特許事務所 出 2. 支給する 2. 支給しない(理由:))						'								N.
評価 ①特許性 1. なし 2. 小 3. 中 4. 大 ②権利の広さ 1. 狭い 2. やや狭い 3. やや広い 4. 広い ③本発明の回避困難度 1. 容易 2. やや困難 3. かなり困難 4. 不可 ④特許的総合評価 1. 軽度(1倍) 2. 通常(2倍) 3. 重要(3倍) 4. 最重要(4倍) 知財部評価点:(①+②+③)×④= 総合評価*8 84以上 → S:重点 64~83 → A:重要 28~63 → B:通常 27以下 → C:出願せず 評価 無限 28~63 → B:通常 取認者 即 日間 出 1. 通常出願 2. 国内優先権主張 基礎出願番号: **8 異当の再編ランクに〇を付ける. 特許事務所 特許事務所 出 2. 支給する 2. 支給しない(理由:)		书	持記事項	Cumos	とメットの	-1, -5,	いすい	なる	经一少不	الإلى (CMP 3	1程页	うと小さ	(土)	I FRO
 価 ②権利の広さ 1. 狭い 2. やや狭い 3. やや広い 4. 広い 3本発明の回避困難度 1. 容易 2. やや困難 3. かなり困難 4. 不可 4特許的総合評価 1. 軽度 (1倍) 2. 通常 (2倍) 3. 重要 (3倍) 4. 最重要 (4倍) 知財部評価点: (①+②+③)×④= ※*64~83 → A: 重要 28~63 → B: 通常 27 以下 → C: 出願せず 28 公63 → B: 通常 27 以下 → C: 出願せず 4. 産設者 申 4. 本で 28 との 28 との 3 を 3 を 3 を 4 を 4 を 4 を 4 を 4 を 4 を 4 を		_		C.5 ?	LUNE	ファチス	五 2 1	97-2	ルエイート	FACE	-119	るだり	₹ H -	(08:	594
 価 ②権利の広さ 1. 狭い 2. やや狭い 3. やや広い 4. 広い 3本発明の回避困難度 1. 容易 2. やや困難 3. かなり困難 4. 不可 4特許的総合評価 1. 軽度 (1倍) 2. 通常 (2倍) 3. 重要 (3倍) 4. 最重要 (4倍) 知財部評価点: (①+②+③)×④= ※*64~83 → A: 重要 28~63 → B: 通常 27 以下 → C: 出願せず 28 公63 → B: 通常 27 以下 → C: 出願せず 4. 産設者 申 4. 本で 28 との 28 との 3 を 3 を 3 を 4 を 4 を 4 を 4 を 4 を 4 を 4 を															
③本発明の回避困難度 1. 容易 2. やや困難 3. かなり困難 4. 不可 ④特許的総合評価 1. 軽度 (1倍) 2. 通常 (2倍) 3. 重要 (3倍) 4. 最重要 (4倍) 知財部評価点: (①+②+③)×④=	1			許性		1. な	<u> </u>	2. /	<u> </u>	3	3. 中		4.	大	·
 ④特許的総合評価 1. 軽度(1倍) 2. 通常(2倍) 3. 重要(3倍) 4. 最重要(4倍) 知財部評価点:(①+②+③)×④= 総合評価※8 64~83 → A: 重要 28~63 → B: 通常 27以下 → C: 出願せず 単準 申申 1. 通常出願 2. 国内優先権主張 基礎出願番号: 形 3. 分割 は、変更 出算 支給する 支給しない(理由: 	ı	価	②権	利の広さ		1. 狭り	ζ.	2. 4	や狭い	.3	3. PF	広い	4.	広い	
知財部評価点: (①+②+③)×④= 総合評価*8 84以上 → S:重点 64~83 → A:重要 28~63 → B:通常 27以下 → C:出願せず 平 版点を配入する。 **8 英当の評価ランクに○を付ける。 特許事務所 額 2. 国内優先権主張 基礎出願番号: 形 3. 分割 態 4. 変更 出願賞 1. 支給する 2. 支給しない (理由:	I		③本	発明の回	避困難度	1. 容易	易,	2. 4	類困ゆら	. 3	3. かな	り困難	4.	不可	
知財部評価点:(①+②+③)×④= 総合評価*8 84以上 → S:重点 64~83 → A:重要 28~63 → B:通常 27以下 → C:出願せず 平 62 を 63 を B を 63 を B を 64	ı		④特	許的総合	評価	1. 軽	度 (1倍)	2.	通常(2 倍	3.	重要	(3 倍)	4. 最	重要(4倍))
※7 64~83 → A:重要 28~63 → B:通常 27 以下 → C:出願せず 押価点を配入する。 ※8 は当の評価ランクに○を付ける。 特許事務所 1. 通常出願 基礎出願番号: 形 3. 分割)			· · · · · · · · · · · · · · · · · · ·										•	
依頼元評価点+知財部評価点=		知	財部評価	• -	+②+③)×④)=	総	合評価*	64~8	3 → A	A:重要	Ę	評価		
出 1. 通常出願 特許事務所 願 2. 国内優先権主張 基礎出願番号: 形 3. 分割 態 4. 変更 出願賞 1. 支給する 2. 支給しない (理由:)		依	賴元評值	西点+知 與	※7			•	27以7	F → (C:出源	n	承認者	,	
願 2. 国内優先権主張 基礎出願番号: 形 3. 分割 態 4. 変更 出願賞 1. 支給する 2. 支給しない(理由:)	1		 	₩ AL 111000	^{并 7} 評価点	を記入する。		*	⁸ 鉄当の評価ラン	クに〇を付い	to.				
形 3. 分割 態 4. 変更 出願賞 1. 支給する 2. 支給しない (理由:)					· 	† Z#k L∐ 1855 3112	.e					特語	许事務所]
態 4. 変更 出願賞 1. 支給する 2. 支給しない (理由:)					土工水	。	う ・			•			•		7
出願賞 1. 支給する 2. 支給しない (理由:)						٠.	ė		-						
	-				合する	2. 支統	しない	(理由:	· · · · · · · · · · · · · · · · · · ·	:	:) .
V. DIA	_			1		, , , , ,	· ·		 				· · · · · · · · · · · · · · · · · · ·		

- 1. 電極と基盤の間に気孔率及び気孔径ともに任意な多孔体。
- 2. 多孔体は樹脂・セラミック・金属の単体及び複合体であり、織布・不織布を含む。
- 3. 多孔体を通して基盤表面への通液路がある。(連続気孔)
- 4. 多孔体はその気孔内に液体を保持することが可。
- 5. 多孔体の厚みは 1~20mm。
- 6. 電極と基盤の間には1つ以上の多孔体が存在。(複数可)
- 7. 多孔体を通じて電極側から基盤側へ及びその逆への液移動が可。(連続気孔)
- 8. 多孔体の一部及び全部をコーティング・燒結・封孔等の改質・表面処理してもよい。
- 9. 対抗電極は基盤最外周に存在する。
- 10. 電極は基盤表面に対し正・逆の電圧を時間軸に対して任意に印加することが可。
- 11. 多孔体の一部と基盤の一部は液体の薄膜を介して接触している。
- 12. その薄膜の厚さは0~1mm とする。
- 13. 基盤処理中は液体薄膜厚さを任意に変更できる。(手段を有す)
- シ、14. 電極と多孔体は同じ空間にケーシングされている。
 - 15. そのケースは基盤処理位置と非処理位置を任意に移動できる。(手段を有す)
 - 16. 非処理位置では多孔体のコンディショニング(置換・洗浄・電解)が可。
 - 17. 多孔体の一部には多孔体でない樹脂・セラミック・金属を含む。
 - 18. 基盤処理中に多孔体と基盤との接触圧力を任意に変更できる。(手段を有す) 0~200g/cm2
 - 19. ケースは基盤に対してチルト機構を有す。

20.



*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS)

The column below is	1	T					· ·	7	
			Dept.	Post	Employee	Name	Share	Seal for	Living
applicable only to inventors in EBR.		1		Tel	No. (five		of the	confirming the transfer	in U.S. ^{*3}
					digits)		rights	the transfer	0.5.
Regarding to the service		<u></u>							
invention described above, I		1	Design	718	20307	Natsuki -	50%	Makino	
(inventor, deviser, or creator)	5	1	Department	9057		Makino	1		
acknowledge that any and	١ż	1	Process			ļ	į		
all rights to the invention in	In-hous		Development				J		
Japan and other countries	(O)		Office 2			[İ		
have been transferred to the	≦.		Development			-	1		
Company (Ebara	entor		Center 1					i	
Corporation) upon invention.]ਰੂ	i							
The column below is	1	L							
applicable only to inventors	(Total:	2	Design	718	21105	Junji	50%	Kunisawa	-
in ER, EB, EICC, and ERS.		·	Department	9488		Kunisawa			
	I		Process			·			
Regarding to the service	inventor(s))		Development			•			
invention described above, I	19		Office 2						
(inventor, deviser, or creator)	ᅙ		Development			•			
acknowledge that any and	(S)		Center 1				· ·	1	
all rights to the invention in	ঠ	3 .							
Japan and other countries	1 1							1	
have been transferred to the	i 1	4			•				
Company ()			Ī			·			
upon invention.		5						· -	
		1	·		i			1	

Application type

1. Sole application by EBR 2. Joint application by EBR and acompany other than EBR
3. Sole application by a company other than EBR 4. Other

The "Applicant other than EBR" column is for inventors in EB, EICC, and ERS; for inventors in ER, see the instructions on the form. Patent prosecution by: 1. EBR 2. Other than EBR (Expense is: 1. Paid by EBR 2. Equally shared 3. Paid otherwise Applicant other than Company/ Contact (address, Tel, and Share of the rights Share of the cost EBR*4 personal name responsible in Intellectual (Total: applicant(s)) Property Dept. % %

*The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor	Company	Name	Address	Share of the interest
(Total: inventor(s))*5				%
			·	%

if descriptions of in-house//external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

IPW-001 (Rev. 1.5)

1	•								;					
Intellect	ual Property	Dept.	Mr. Ku	bo (Man	ager) <= Kun	isawa	a '				FAX 03-3	745-5745	
Notifica	ual Property ation of Inve	ntion (1/2) (10	Patent	2. De	sign 3.C	Other)	1 (Suppler	ment: 1	. Attac			Confid	ential
			¹ Use	this form	for p	atent appli	ication	filing. For u	ıtilit y m	odel a	pplica	ation, enclos	e "3. Other"	witha
Poşt (718	u		circle	and cons	ult w			operty Dept.	O) 14-1	41	_		•	
This for		er	Patent	Gener	cal	Relate	ost (General	Z) Intel	ectual ager:		erty Dept.	Data of	rossint
filled b			liaison:	manag		dept.:		manager.	IVIAI	ayei.	1 "	bersou:	Date of by Intel	
Makin	19/	/	j	Fukuna	igal	·			j	•			Prop	erty
Be sure to	o affix the seal	in the and	propriate s	pace of th	e "Fo	or the hoss	of the	requesting	lent " c	olumn	<u> </u>	<u></u>	Dept.	/No.
		чр	opnato o	paoc 01 iii	•	" the 5000	, 01 1110	requesting c	iepi. c	Oldiiiii	UH 2/	۷.		
				•				Date of	reque	est (Cl	hristi	ian year): \	YYYY/MM	ממע
								Reques	sting d	ept. D	1.00	No.: 718-E	2N20-1	,00
2			•				•			•				
	thin heavy-lin		s.											
д (De	ept. code)	(718)			0	1 Com	porate				8.	Ebara Re	search	
Det Det	pt. name		ss Develo	pment	Category			: Information a	and		9.		iler Co.,Ltd	
ĘĘ	•	Center	2 Develo	pment	go			cation Syste		€	10.	Ebara Ind	lustrial Clea	aning
F Por	son		Natsuki	Makina	Ž	3. Sale	es .	-	•		11	Co.,Ltd. Ebara Re	frigeration	
	ponsible for		yee No.:		(Group)	4. Envi	ironm	ental Engine	ering	(Affiliate)			nt & System	ns Co
the	documents		718 Tel		2	5. Fluid 6. New	u Mac	hinery & Sys Renewable I	stems Enorm	· ·		Ltd.	•	·
	:			. 000.,	D			Machinery	Litergy		12.	Other ()
3											<u> </u>			
Title of	the invention		Electrod	hemical	pro	cessing a	appar	atus						
Keywor	ď							ng, polishir	ng. an	d elec	trope	olishina		
	product or to		gy	Impregn	atior	n plating	арра	ratus	<u> </u>					
Charact	ter of the pro	duct	(1)Sales	-focused	d ·			ult of:			.] .	Job No. L-	02D54709	•
•			2. Not s	ales-focu	used	1	<u> </u>							:
·		···												
About	1. Yes									-> Af	fix th	e seal in t	he approp	riate
service	2. No; h	owever,	, i transfe	r the inv	entic	on to the	Com	pany under	r l			the "In-hou	use invent	or"
inventio								vice inventi				elow.		
	3. NO, 1	negoua	ite with th of any and	ie Compi	any .	about ter	rms a	nd conditio	ns of	(Affix	the	seal here.)	
	-> Affix th	e seat i	n any and n the righ	a an nyni Toolumr	າ ຈຸນ. ເຂີເດ	uie ilivei d sand th	nuon. vie fer	m to Intelle	otusi					J
	Property	Dept. D	o not affi	x the se	ı anı al in	the "In-he	101 CH	inventor"	ciuai					İ
	column b	elow.			AI .II I		cuse	III V CI ILOI				•		
									1			 		

Notification of Invention (2/2)

the invention

9						•			[14 0.74
Urgency of		1. Nor						Release	ed on: YYYY/I	MM/DD
application t	iling	(2.)Hig	h (by Dec	ember 2.)				Release		VIIVI, DD
		Reas	on: a. Ex	ternal release	e (Fill the	right colu	ımn.)			
		1	b. De	adline for pul	blication c	f our pric	or application			
			C. De	adline for cla	uming don	nestic pri	ority			
10		L	Colla	boration cont	ract					
Related	Mritton	contract	for joint	rooperah		144		 ,		
contract ^{*6}	Written	contract	for joint	filing of paten		1. Avai	lable (partner:		2.)N/A (curren	t)
- Compact	applicat		i ioi joint i	illing of paten	it	1. Red	uired (Prepare required	ed by: a. I	Us b. Partne	er ())
⁶ When there is	a written o	ontract th	at justifies	the joint filing or	filing unde	r other na	ne, a ttach a cor	6 14 4 - 41	-i- 4	
11				,	g undo	outer na	ne, a nacma cop	by Of It to th	ns ionn.	
Prior-art sea	rch		Relate	d	Ours	(1)Avail	able (Applicat	ion No. H	leisei 11-3677	54
				ation and			Applicat	ion No. 2	2000-369201)	O- T ,
1.5			prior a			2. N/A			,	
1. Done (Fill	the right o	:olumn.)	Attach t	wo items of related to the	Others'	1) Avail	able (Publicati	ion No. 2	000-232078 (Toshiba))
2.Not done			applicat	ion		2. N/A		•	•	• • • • • • • • • • • • • • • • • • • •
12			<u> </u>		<u></u>					
N	ature of ir	vention	Choos	e A, B, or C (enclose w	ith a circ	ele), considerir	ng the na	ture of the inv	ontion
			A. Inve	ention for curr	ent (E	3.)Inventi	on for new	C	nvention of ne	w ideas
Evaluation ite			produc	ts/technologic	es p	roducts/	technologies	i		W Ideas
(1) Technica	l superiori	ty over	1. Non	e 2. A little	(3) Consi	derable	4 Very large	·	·	
prior art (2) Severity			1							
challenge			I. Unki	nown 2. Nor	rmal 3. I	High (4.)	Very high			
(3) Originality			 				4 (1-1			
(4) Developn		ct for	1. N/A	· .	·	·	1. Unknown	2. Low	3. Medium	4. High
	based on			e final stage					-	
invention			3. In the	e intermediate	e stage					
(5)		<u></u>	4.In the	e early stage				•		
(5) Important		d	1. Low	2. Rather lo	w (3.)Co	nsiderab	ly high 4. Hi	gh		
invention (6) Overall ju			1 1	:						
requesting		y ujie	1. Less	. Less important (single) 2. Moderate (double) (3.)Important (triple) . Significant (quadruple)						
3	·		1 4. Olgili	ilcant (quaurt	upie)	·		·		
Calculation	For	11	(1)+(2)+(4	4)+(5))×(6) =	42	Filing	of the (1.	\Di	_	
for rating of	invention		(,) , (-) , (-	1)1(0))	72			Require		
the evaluation	of A or	В		•	ı	paten	ation is:		uired; it should ed on Journal o	
					İ	Αρσ			al Disclosure.	JI
				•			3.		ired (reason:)
	For	1 ((1)+(2)+(3	$(3)+(5))\times(6) =$		Foreig	n filing (1.) Require	ed (country na	me:
	invention	ons		•	- 1	of the	patent	U.S, Eu	rope, and Ko	rea)
	of C	1				applic	ation is: 2.	Not req	uired	
1				· · · · · · · · · · · · · · · · · · ·			3.	Not det	ermined	
	This is a									
Special note	roduces	ention re	elates to a	next-genera	tion platin	g appara	atus that great	ly	Boss's s	seal of
	and ite h	overpia	ung of CL	Wiring to mir	nimize the	load of	the CMP proc	ess	appro	
5	and its ii	eau sut	icture or i	the key eleme	ent of the	apparati	JS. ·		Fukun	aga
	ntability			1 None 2	1 0	A4 - U				-
	e of rights			1. None 2 1. Narrow		Medium		- l- l- · · ·	4 140 /	
(3) Indis	pensabilit				2, Rather lo		3. Considera onsiderably high			
	tion to the		cts.	20W 2.	1 10th 10	w 3. U(moluerably Ni	311 4.INC	dispensable	
(4) Over	all judgme			1. Less imp	ortant (eir	nale) 2	Normal (doub	10) 3 1	mportant (t-:-1	
	wontion			1		·9·0/ 2.	ranima (anař	7 10) 3.11	mportant (triple	e)

4. Significant (quadruple)

16

Evaluation by Intellectual Property Dept: $((1)+(2)+(3))\times(4)=$ Total of the evaluation values by the

requesting side and Intellectual Property Dept.*7

Enter the evaluation values into the formula.

Overall evaluation 84 or more -> S: Significant 64 to 83 -> A: Important 28 to 63 -> B: Normal 27 or lower -> C: Not apply

Evaluation Evaluation
Approver Approver
Seal Seal

*8 Place a circle on the appropriate item of the evaluation level.

4.6.		
Regular application		Patent firm
2. Domestic priority Original	inal application No :	- acremin
3. Division	mar application 140	
4. Change		
g the patent application	1. Will be offered 2 N/A (reason:	
	Z. Tyr (reason.	
	3. Division4. Change	 Domestic priority Original application No.: Division Change

IPW-001 (Rev. 1.5)

Should you have any comment on the evaluation, contact us within two weeks.

- A porous material having optional porosity and pore diameter to be placed between an electrode and a substrate.
- 2. The porous material is resin, ceramic, or metal or a compound of them, including woven or non-woven fabrics.
- 3. The porous material allows a liquid to flow through it onto the substrate surface (continuous pores).
- 4. The porous material can retain the liquid in the pores.
- 5. The porous material is 1-mm to 20-mm thick.
- 6. One or more pieces of the porous material can be placed between the electrode and the substrate (multiple pieces of the material can be used).
- 7. The porous material allows the liquid to move from the electrode side to the substrate side or vice verse (continuous pores).
- 8. The porous material can be wholly or partly coated, sintered, or reformed/surface-treated such as sealing.
- 9. A counter-electrode is located on the farthest circumference of the substrate.
- 10. The electrode can apply positive or negative voltage to the substrate surface anytime.
- 11. The porous material is partly in contact with the substrate through a medium of a liquid film.
- 12. The liquid film is 0-mm to 1-mm thick.
- 13. Thickness of the liquid film can be freely changed during substrate processing (having an appropriate method).
- 14. The electrode and the porous material are cased in a same space.
- 15. The case can be freely moved between the substrate processing position and the nonprocessing position (having an appropriate method).
- 16. The porous material can be conditioned (replacement of liquid, cleaning, and electroprocessing) on the non-processing position.
- 17. The porous material partly contains non-porous resin, ceramic, and metal.
- 18. The contact pressure between the porous material and the substrate can be freely changed in a range from 0 to 200 g/cm2 (an appropriate means required).
- 19. The case has a tilt mechanism for the substrate.

20.

発明部門メニューへ事業本部特許部メニューへ

社外秘

一時保存したものに追記する場合、または、承認/否認する場合、上部の「編集」リンクをクリックしてください。 **発明等届出**書

届出日:2003/11/12

知的財産部受付番号:K1030635 受付日:2003/11/20

|依頼元担当一記入欄||▼依頼元上長一記入欄||▼事業本部特許部一記入欄||▼ワークフロー情報|

★は必須入力項目です。

▼依頼元担当一記入欄

①【依頼元情報】

会社★	01 荏原製作所 部門 V370二プロ設計課							
整理番号(Doc.No.)	EB3216P							
担当者	会社区分十社員番号:0121105	氏名:國澤 淳	次 TEL:9488					
本部名★	PP 精密·電子							

②【基本情報】

国内/外国★	国内					
四法★	特許					
発明の名称★	電解処理装置及びその方法					
キーワード	めっき エッチング CMP 電解					
関連する製品名	めっき装置 エッチング装置 CMP装置					
関連する業務コード	その1 78配線めっき装置 その2					
研番	L-03D520					
研番依頼元	部署名 V370ニプロ設計課					
職務発明について★	1.職務発明である					

AY

)【荏原製作所/荏原総合研究所/荏原電産の発明者】

	会社	社員番号/氏名 (会社区分+社員番号)	内線NO/ポストNO/E-mail		発明者 の持分 (%)		代表発 明者 ★
1	EK0001/ 荏原製作 所	0120307 牧野 夏木	内線NO : 9057 ポストNO : 718 E-mail : makino natsuki@ebara.com	V370二プロ 設計課	Ε		Check
2	EK0001/ 荏原製作 所	0121105 國澤 淳次	内線NO : 9488 ポストNO : 718 E-mail : kunisawa junji@ebara.com	V370二プロ 設計課	E		
該当無しおよび予定発明者							

【荏原総合研究所・荏原電産以外の関連会社/社外の発明者】

<u>L</u>	会社コード/	名称	氏名	TEL/E	-mail	所属	部門また	は住所 米	国在住
1		•		TEL: E-mail:					•
該当	当無しおよび予	定発明者					·		
						·			
【出》		(mb Th.)	1/4 =				1000-001	7	
	コード/名称((哈奇利)	住所連絡先な	· ·			権利持 分(%)	費用負 担(%)	手続担 当 ★
1	EK0001 荏原製作所		本社住所: 連絡先住所: ⁻ 部署: 担当: TEL: FAX: E-MAIL:	T		·	E ·	E	担当
該当	無しおよび予	定出願人	<u></u>						<u> </u>
一	7								_ <u>·</u> ·
7					•				
	[緩急] · · · · · · · · · · · · · · · · · · ·	7	出願希望日	- 1	· <u> </u>				2
	1938. ICA	1	理由			発表先:			
	•					発表日:その他:	•		
<u></u>						てい他:			
	関係】	1/2		7				o E	
关利	書有無★	無	•	種類 その他			•		
相手	 先	1	Ţ.		•				
	,	2		. ·					
		3			•				• •
·	• • •	4	<u> </u>	_	•		•• :	•	
j .		5 その他					•		
契約	<u> </u>	COTIS)]-		• • •				•
共同!	出願契約書作	不要	<u> </u>	作成担当					
成★	`			相手先		7		, .	
<u> </u>		<u> </u>			その他]			
		•			• 0				
調査	実施状況】		•						
	犬況★	未調査					·		
調査の			検索資料						
競合メ	メーカー	Nutool	ノベラス セミツ						
					·				
	出願公知例】 D関連出願公第		· · · · · · · · · · · · · · · · · · ·			·	·		
				無					

(8)

<i>ま</i> t	: :は文献名:		· 		11		11	
2 号.	は文献名:		ファイル					
3 号		_	ファイル	<u> </u>]			
また 4 号	:は文献名 : 			<u> </u>	1			
	は文献名:	·	ファイル					
5 号 また	は文献名:	•	ファイル			•		
				<u> </u>	J	<u> </u>		
	関連出願公知例★		無					
1 号 また	は文献名:		ファイル					
2 号 また	は文献名:		ファイル					
3 号	は文献名:		ファイル					
4 号			ファイル					•
また 5 号	ま文献名:	<u> </u>	ファイル				•	
	は文献名:		ファイル					• .
ر ايكا					•			
【特記事項				· ·	· ·		·	
特記事項	先に出願済(国内(付済。	愛先)のもの	かに請求項	を追加し	ょした。明	細案は別途	月田知財	部篠塚様宛て送
<u> </u>								
明細書	明書(明細書素案)】	السعد		· ·	· · · · · · · · · · · · · · · · · · ·		· ·	
が参与		図面				その他	!	
添付者:	 	】 添付者:		<u>:</u>		E		
添付日:		添付日:	·	· ~		添付者: 添付日:		· ·
							•	
▲佐頼元	<u>世当一記入欄</u> 依頼元上長	_ = 1 Hm]	₩	10#± 3# #1	7 27 3 188		444	
- 1×130.70	三当 配入桶 成模儿工及	む人根	▼●朱平は	P14 51 B	2一記人懶	▼ -7-77L	一管報	
▼依頼元	上長一記入欄					•	•	•
【発明部門	浮価】				•			
発明の性質		. B:新	事業製品・	技術の	発明	<u> </u>		
①先行技術	に対する技術的優位性 、コスト削減、省エネ効果:	3. 排	当優位					
②課題・手		ラノ 3. 重	要	· · · · · ·		•		
③独創性 (発明の性質がCのときのみ必須) O. 未評価								
④本発明が (開発、販売	対象とする製品の開発計画	3. 開	発計画の中	中間段階	きである			
	製品に占める重要度(割合)) 4. 大	きい					
⑥依頼元総		3. 重						
評価点		39点						

Ż

出願要否	要(理由:)
外国出願要否	要
特記事項	本件国内優先出願のため、至急手続きお願い致します。

▲依頼元担当一記入欄 ▲依頼元上長一記入欄 事業本部特許部一記入欄 ▼ワークフロー情報

▼事業本部特許部一記入欄

0

部長記入欄	担当	坂口さん
	コメント・・	原稿が知財部篠塚さん宛送付されているそうです。原稿確認してください。
担当者記入欄	コメント	クレーム追加のための国内優先出願なのでOKとします。
	添付文書	
	作業終了サイン	坂口:終了

.

▲依頼元担当一記入欄 ▲依頼元上長一記入欄 ▲事業本部特許部一記入欄 ワークフロー情報

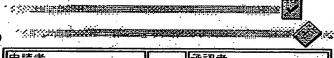
▼ワークフロー情報

現在のユーザ: seimitsu zzchizai/e/ebara_jp

現在の承認者:

要求 ID NTNN-5T89BU

ステータス: 完了



申請者		承認者
junji kunisawa/e/ebara_jp	•	akihiko tashiro/e/ebara_jp yukio fukunaga/e/ebara_jp seimitsu zzchizai/e/ebara_jp masamichi nakashiba/e/ebara_jp

承認者情報

(S)

申請者名	申請日	CCメール
junji kunisawa/e/ebara_jp	2003/11/12	natsuki makino/e/ebara_jp

او	承認者役職	承認者名	承認期限	ステータ ス	承認日	CCメール
	発明者上司	(承認不要)				
	リエソン	akihiko	2003/11/19	承認	2003/11/12	

	tashiro/e/ebara_jp	ì			
部長	yukio fukunaga/e/ebara_jp	2003/11/19	承認	2003/11/12	
事業部側特許部 門	seimitsu zzchizai/e/ebara_jp	2003/11/19	承認	2003/11/19	
	masamichi nakashiba/e/ebara_jp	2003/11/26	代理承認	2003/11/20	

プコメント

CN=akihiko tashiro/OU=e/O=ebara_jp CN=yukio fukumaga/OU=e/O=ebara_jp CN=seimitsu zzchizai/OU=e/O=ebara_jp CN=masaaki miyazaki/OU=e/O=ebara_jp 含宮崎代理受入2003.11.20

本件、承認いたします。 承認します 承認 承認 2003/11/12 17:37:47 2003/11/12 20:16:43

承認 2003/11/19 20:02:43

承認します。 中柴B打ち合わせ中につ 代理承認 2003/11/20 14:02:53

To the mean, for the dent	af tha income a - (a)	To the menu for Patent Dept. of the Grou	
TO The ment for the deni	of the inventorist	i to the mentitor Palent Lebt, of the Gro	ıın
TO GIO INCIIG IOI GIO GOPE		i to the inche for i atom bept. of the are	up

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: November 12, 2003

Intellectual Property Dept's receipt No.: K1030635 Date of receipt: November 20, 2003

For the responsible	▼ For the boss of the	▼ For Patent Dept. of	▼ Workflow information
person in the requesting	requesting side	the Group	
side			

Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

T [morniagori of the requeeting elec]					
Company name	01	Dept.	V370 Design Department Process		
	Ebara Corporation		Development Office 2 Development Center 1		
Reference No. (Doc.No.)	EB3216P				
Responsible person	Company category + Employee No.: 0121105				
	Name: Junji Kunisawa TEL: 9488				
Group name★	PP Precision Machinery				

2 [Basic information]

Domestic/foreign ★	Domestic				
IP category ★	Patent				
Title of the invention	Electrochemical processing apparatus and its method				
Keyword	Plating, etching, CMP, and electrochemical processing				
Names of related products	Plating apparatus, etching apparatus, and CMP apparatus				
Related job code	No. 1 7B Wire plating apparatus No. 2				
Job No.	L-03D520				
Requesting dept.	Dept. name V370 Design Department Process Development Offic Development Center 1				
About service invention *	1. Yes				

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

Company Employee No./name (Company category + employee No.) 1 EK0001/ 0120307 Extension No./E-mail address Corporation Extension No.: 9057 Post No.: 718 E-mail: makino.natsuki@ebar	V370 Design Department Process	Share of the rights (%) E	Living in U.S.	Representative inventor ★ Check
employee No.) 1 EK0001/ 0120307 Extension No.: 9057 Ebara Natsuki Makino Post No.: 718 Corporation E-mail:	V370 Design Department	(%)	in U.S.	
1 EK0001/ 0120307 Extension No.: 9057 Ebara Natsuki Makino Post No.: 718 Corporation E-mail:	Design Department			Check
Ebara Natsuki Makino Post No.: 718 Corporation E-mail:	Design Department	E		Check
Corporation E-mail:	Department			,
makino natsuki@ehar	Process	l .		·
i inamionialouniae cour				
a.com	Developme			1
	nt Office 2			
	Developme			
·	nt Center 1		1	
2 EK0001/ 0121105 Extension No.: 9488	V370	E	1 .	
Ebara Junji Kunisawa Post No.: 718	Design	1 .	1	
Corporation E-mail:	Department			· ·
kunisawa.junji@ebara	. Process	*		
com	Developme		•	
	nt Office 2			
	Developme		Į.	
	nt Center 1	l .	1	
N/A and potential inventor(s)				

4 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltl and external inventors]

	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.
1			TEL:	E	
L	·		E-mail:		
N	A and potential inventor	(s)			

5 [Appli	cant]							5	upport Documen
Code/na		Conta	ct address,	etc.	Share	of the ri	ghts	Share of the	Prosecution
(abbrevi	ation)				(%)		`	costs (%)	by: ★
EK0001	_		uarter add		E			E	Responsible
Ebara C	orporation		ct address:	-					person
		Dept.:		sible:			i		
		TEL:	FAX:				1		
NI/A and		E-mail			<u> </u>				
N/A and	potential inv	/entor(s	<u> </u>		<u> </u>			·	<u> </u>
6 [Urger	ncy of applic	ation fil	inal						•
Urgency			eferred data	of filing					·
) - igo.i.o,			ason	a Or ming		Polos	sed to	<u> </u>	
		'''				1	sed o		
	1					Other		1.	•
						1 - 1.101	•		
	ed contract]								
Written co	ontract ★			N/A			Туре		
L							Other		
Partner				1					
[2					
				3					
				4					
,				5					
Contract			•	Other					
	on of contra	ct docu	ments for	Not require			Drane		_
ioint appli	cation filing	*		Not require	eu _.		Prepa Partne	red by:	
,	.						rarine	;1	Other
	•								Outer
	rt search]	_							
Prior-art s			Not done	-			,		,
Search de	etails				Search				
C					Material				
Competito	or	· · · · · · · · · · · · · · · · · · ·	Nutool, No	ovellus, Ser	nitool, an	d A-MA	<u> </u>		
Related	d application	and n	rior orti						17
Ours: 🛨		i and p	norary	· · · · · · · · · · · · · · · · · · ·	 	A1/A			
1	No.					N/A	<u> </u>		
•	or docume	ent title:	-	• • •		File			
2	No.	orit dae.				File	· · · · · · · · · · · · · · · · · · · ·		
	or docume	ent title:			•	riie			
3	No.				•	File			
	or docume	ent title:	•	•		' ""			
4	No.				•	File		 .	
	or docume	ent title:							
5	No.	·				File			
	or docume	ent title:			·				
O411 A									
Others': 🖈		· · ·		•		N/A			
1	No.	4. 4241			·	File			
2	or docume No.	nt title:							
_	or docume	nt title:				File		·	
3	No.	nt due:			·		2	·	
·	or docume	nt title:	·		•	File			
4	No.	ute.				File			·
	or docume	nt title:				Lile		-]	
5	No. or docume		· · · · · · · · · · · · · · · · · · ·	·		File		_	.

10 [Special r	notel						Support Document	
Special note	Claims I	have been a ation draft h separately.	dded to the ap as been sent to	pplication a o Mr. Shind	lread ozuka	y filed (don of Intellect	nestic priority). The rual Property Dept. at	
11 [Description	nn of inver	ntion (enacifi	cation draft)]			-		
Specification	11 01 111401	Draw			Oth	oro T		
	<u> </u>	- Didw	1193		Out	ers		
Attached by:		Attac	hed by:		Atta	ched by:		
Attached on:			hed on:			ched by:		
		1			Auca	ched on.	-	
▲ For the resperson in the requesting	ne		e boss of the esting side	▼For P the G		Dept. of	▼ Workflow information	
▼For the boss 12 [Evaluation	of the req	uesting side	ventor(s)]					
Nature of the invention						B Inventi	on for new	
						1	technologies	
(1) Technical superiority over prior art			urt			3. Consid		
(Quality improvement, cost reduction, energy saving, etc.) (2) Severity of challenge/means					.)	0.11:-1		
(3) Originality (Enter data if the nature of the invention is C.						3. High 0. Null		
(4) Project for products based on the invention (development,				<u> </u>	3. In the intermediate stage			
sales, etc)	(Enter dat	ta if the natu	re of the inver	ntion is A o	, r B.)	5. In the intermediate stage		
(5) Importance	e of the inv	ention to the	e products	•		4. High		
(6) Overall jud	gment by	the requesti	ng side			3. Importa	int	
Rating of evalu			39 points					
Filing of the pa						Required	(reason:)	
Foreign filing o Special note	i ine patei	nt application	n is:			Required		
		·			•	immediate	cation should be filed as by as possible because a priority application will be	
▲ For the resp	oneible	A For the	boss of the	F O .				
person in the	j Originie	requesti			ent De Grou	ept. of the	▼Workflow information	
requesting s		roqueou			Giou	þ		
3 ▼ For Pater	nt Dept. of	the Group				,		
General	Respons		Mr. Sakaguc	hi .	•			
manager:	Commen				t to M	fr Shinozu	ka of Intellectual Property	
		•	Dept. Chec	k the draft.		ii. Omnozu	ka of intellectual Property	
Responsible	Commen	t	I approve the	request b	ecaus	se this is a	domestic priority	
person:		·	application for	r adding a	clain	n	and production	
	Attachme		,					
	Sign of c	ompletion	Sakaguchi: C	ompleted				
A Can the		. =						
For the responder for the person in the			boss of the	▲ For Pa		Dept. of	Workflow information	
requesting sign		requestir	ıy sıae	the Gro	oup			
				ı			.1	

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp Current approver: Request ID NTNN-5T89BU

Status: completed

14

Requested by:	Approved by:
junji kunisawa/e/ebara_jp	akihiko tashiro/e/ebara ip
	yukio fukunaga/e/ebara jp
·	seimitsu zzchizai/e/ebara jp
	masamichi nakashiba/e/ebara jp

▼Approver information

15

junji kunisawa/e/ebara_jp November 11, 2003	natsuki makino/e/ebara jp

16

Position of the	Name of the	Deadline of the	Status	Date of approval	CC mail
approver	approver	approval			
Boss of the	(Approval not				
inventor	required)				ļ
Liaison	akihiko tashiro/e/ebara_jp	November 19, 2003	Approved	November 12, 2003	
General manager	yukio fukunaga/e/ebara jp	November 19, 2003	Approved	November 12, 2003	
Patent Dept. of the Group	seimitsu zzchizai/e/ebara jp	November 19, 2003	Approved	November 19, 2003	
General manager of Intellectual	masamichi nakashiba/e/ebara_jp	November 26, 2003	Approved by a proxy	November 20, 2003	
Property Dept.	•		• •		[

▼Comment

CN=akihiko tashiro/0U=e/0=ebara_jp Approved November 12, 2003 17:37:47 I approve the request. CN=yukio fukunaga/0U=e/0=ebara_jp Approved November 12, 2003 20:16:43 OK. CN=seimitsu zzchizai/0U=e/0=ebara_jp Approved November 19, 2003 20:02:43 OK. CN=masaaki miyazaki/0U=e/0=ebara_jp Approved by a proxy November 20, 2003 14:02:53 Mr. Nakashiba is in a meeting; so Miyazaki, or his proxy, approves the request. November 20, 2003

発明部門メニューへ	事業本部特許部メニューへ

社外秘

一時保存したものに追記する場合、または、記入/承認/否認する場合、上部の「編集」リンクをクリックしてくださ

外国出願依賴書

発信日:2003/05/31

依頼元担当一記入欄▼依頼元上長一記入欄▼事業本部特許部一記入欄▼ワークフロー情報

★は必須入力項目です。

▼依頼元担当一記入欄

②【依頼元情報】

会社	01荏原製作所	部門	V370∨第二プ設計
整理番号			
担当者	社員番号:0120307	氏名:牧野 夏木	TEL:9320

②【基本情報】

外国出願対象の出願	知的財産部受付番号:K1020686 四法区分:特許 出願番号:2002-350529 出願日:2002/12/02 過数へ 発明の名称:電解処理装置及びその方法
出願国★	アメリカ
出願理由★	平坦化めっきの重要発明であるため

り【上記対象出願とまとめて外国出願したい案件】 ※当該発明も1行目に記載されています

	国	四法区分	出願番号	出願日
2				
3				
4				
5	:			
6				
\Box				
8				
9				
10				

補足事項			
11伸走争坞 1			
	 •	•	-
			

)【荏原製作所/荏原総合研究所/荏原電産の発明者】

所属部門コード/名 | 持分 | 米国在 | 代表発

										·		
				員番号	·			称	·		住	明者
		1 EKO 製作)01/荏原 所	012030 牧野 3	夏木	内線NO:E ポストNO: E-mail:V3	荏原製作所	V370\	/第二プ設言	† E%		
		2 EKOC 製作	01/荏原 所	012110 國澤 2	享次	内線NO:EI ポストNO:7 E-mail:V37	生原製作所	V370V	/第二プ設計	f E%		
		AV			: :							
(<u>]</u>	在原総合	研究所·	荏原電	差以外の	関連会社/	社外の発明者】	÷		•		•
			コード/				TEL/E-mail		所属部門	または住所	र् ग	米国在 住
			· · · · · ·			711	TEL: E-Mail:				·	
) [[
_	عا	ركي			•		٠	•				•
4	13 C	出願人】										
		(略称		/名称	住所連絡					権利 持分	費用 負担	手続担当
	1	EK000 荏原\$			本社住所連絡先位	斤:東京都大 計: 東京都大	田区羽田旭町1 -8510東京都	1番1号	An Maria	E%	E%	担当
					郡署:知	的財産部 担	2当:依田 正稔		旭町11—	¹		.
		<u> </u>			TEL:03	3743628	9 FAX:03374	55745				
		V		_								
9	【先	行技術	と献】		-		•					•
		見出し別)		01 自社	関連先行					添付者:		
		内容(3	(献名)	特願平	11-36775	4				添付日:		
۸.	-	該当箇	所									
		関連性	の説明									
		備考								·	; 	
	2	見出し(別)	文献種	02 他社	関連先行	文献				添付者:		
		内容(文	献名)	特開200	0-23207	3				添付日:		.
		該当箇	听									:
		関連性	の説明						· <u></u>			
1		備考										
	3	見出し(別)	文献種	01 自社	関連先行	文献			·			
		内容(文	献名)	特願200	3-015236)	1			委付日:		
		該当箇所	F			· .						
		関連性の	D説明		-			<u> </u>		•		
		備考										
li	4	見出し(文献種	02 他社	J連先行	 対 対			——————————————————————————————————————			
		別)					· .		13	及付者:		
Ш		内容(文	献名)	USP6413	403					委付日:		- 11

@

2

USP6413403

1	談当箇所	11	
	関連性の説明	1	
	備考		
5	見出し(文献種 別)	02 他社関連先行文献	添付者:
	内容(文献名)	USP6413388	添付日:
	該当箇所		
	関連性の説明		
11	備考		
6	見出し(文献種 別)	02 他社関連先行文献	添付者:
	内容(文献名)	USP6409904	添付日:
	該当箇所		
	関連性の説明		
	備考		
7	見出し(文献種 別)	02 他社関連先行文献	添付者:
	<u> </u>	USP6402925	添付日:
	該当箇所		
	関連性の説明		
	備考		
	見出し(文献種 別)		添付者:
- 13	内容(文献名)		添付日:
15	該当箇所		
Į.	関連性の説明		
	備考	<u> </u>	
	見出し(文献種別)		添付者: 添付日:
(=	内容(文献名) 該当箇所		
11	関連性の説明		
-	備考		
TI,	見出し(文献種 別)		
≀≌	内容(文献名)		
- 1 -	为各(又献名) 该当箇所	· · ·	
- 15	関連性の説明		
71	横考	==i	
<u> </u>			
	等説明書 (明細書	· 豪家)】	
細		図面	1 Z D 4h 11 1
, (- ISIM	その他
付	者:	添付者:	添付者:
付日	日:	添付日:	添付日:

3

▲依頼元担当一記入欄|依頼元上長一記入欄|▼事業本部特許部一記入欄|▼ワークフロー情報|

▼依頼元上長一記入欄

9

特記事項 銅配線の平坦化めっきに必要な装置構成、特にアノードヘッドの構造に関する発明であり、協業先 に装置を納めています。(US)

|▲依頼元担当一記入欄||▲依頼元上長一記入欄||事業本部特許部一記入欄||▼ワークフロー情報|

▼事業本部特許部一記入欄

▲依頼元担当一記入欄
▲依頼元上長一記入欄
▲事業本部特許部一記入欄
ワークフロー情報

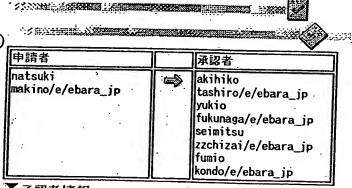
マワークフロー情報

現在のユーザ: seimitsu zzchizai/e/ebara_jp

) 現在の承認者:

要求 ID NTNN-5LNM4B

ステータス: 完了



▼承認者情報

<u>)</u>

申請者名 申請日 ||CCメール natsuki makino/e/ebara_jp 2003/05/31 junji kunisawa/e/ebara_jp

, حق						
	承認者役職	承認者名	承認期限	ステータ ス	承認日	CCメール
	発明者上司	(承認不要)			<u> </u>	
	リエソン	akihiko tashiro/e/ebara_jp	2003/06/07	承認	2003/06/03	
		Tukunaga/e/ebara_jp	2003/06/10	承認	2003/06/03	
	事業部側特許部 門長	seimitsu zzchizai/e/ebara_jp	2003/06/10	承認	2003/06/11	
_			<u> </u>			

゚゙コメント

CN=akihiko tashiro/OU=e/O=ebara_jp CN=yukio fukumaga/OU=e/O=ebara_jp CN=seimitsu zzchizai/OU=e/O=ebara_jp

承認 承認

2003/06/03 13:49:32 2003/06/03 20:44:10 2003/06/11 20:15:14

承認

本申請を承認します 承認します 外国出願承認します。

					• .			Suppo	ort Document
To th	ne menu for the de	ept. of the inve	entor(s)	To the	menu fo	r Patent Dep	ot. of the G	roup	
									Confidentia
To ad	d data to the temp	orarily saved	form or to	appro	ove/refus	e the form, o	click the [E	dit] link	above.
			Requ	est of	foreign fil	ling			
									May 31, 200
Fo	or the responsible	▼ For the	boss of t	he	▼ For F	Patent Dept.	of ▼ V	Vorkflow	information
pers	on in the requestir	ng reques	ting side		the G	iroup	İ		
	side								
Neve	r fail to fill * mark	ed columns.	_	•	-				
▼ For	the responsible in	the requestir	na side						
	nformation of the re	•	_			•	•		
	pany	01	1	Dept.	V370	Design De	partment F	rocess	
	,	Ebara Corpo	ration			elopment Off			t Center 1
Refe	rence No.								
	onsible person	Employee No	o.: 012030	07 Na	ame: Nat	suki Makino	TEL: 93	20	
									
2 IB	asic information]								
	uest for foreign	Intellectual	Property	Dept's	receipt i	No.: K10206	86 IP ca	tegory:	Patent
	cation filing		Application No. 2002-350529 Filing date: December 2, 2002						
1	.	To File Wra							
				: Electi	rochemic	al processin	ıg apparatı	us and if	ts method
Cou	ntry of filing ★		United States of America						
	son for filing ★	Important in	mportant invention for plating and electropolishing						
3 [A	pplication(s) that s	hould be fore	ign-filed to	ogethe	r with the	e described	above]		•
*The	invention in questi	on is listed in							
	Country	•	IP categ	ory	Appli	ication No.	Filing da	ite	
1									
2.							<u> </u>		
3									
4		·				·	<u> </u>		
5						•			
6	*								
7									
Ω					`.				

Supplement

4 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	to involvere in Ebara Corporatory Ebara Hoodarony Ebara Berban Etc.							
	Company	Employee No./name (company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.A.	Representative inventor	
1	EK0001/ Ebara Corporation	0120307 Natsuki Makino	Extension No.: EK0001 Post No.: Ebara Corporation E-mail: V370	V370 Design Department Process Development Office 2 Development Center 1	E%			
2	EK0001/ Ebara Corporation	0121105 Junji Kunisawa	Extension No.: EK0001 Post No.: Ebara Corporation E-mail: V370	V370 Design Department Process Development Office 2 Development Center 1	E%			

5 [For inventors in affiliates other than Ebara Research/Ebara Densan Ltd. and external inventors]

	With the William Control and Para Troopar of Para Delibar Eta. and external myentors						
Ŀ	Company code/name	Name	TEL/E-mail	Dept./contact address	Living in U.S.		
1			TEL:				
			E-mail:		Č		

6 [Applicant]

	Applicant code/name (abbreviation)	Contact address, etc.	Share of the rights	Share of the costs (%)	Prosecution by:
1	EK0001 Ebara Corporation	Headquarter address: 11-1 Asahi-machi, Haneda, Ohta-ku, Tokyo Contact address: 11-1 Asashi-machi, Haneda, Ohta-ku, Tokyo 144-8501 Dept.: Intellectual Property Dept. Responsible: Masatoshi Yoda TEL: 0337436289 FAX: 0337455745	E%	E%	Responsible person

7 [Documents of related prior art]

<u> </u>	ocuments of related price		,
1	Index (document category)	01 Our related prior art	Attached by: Attached on:
	Detail (title)	Application No. Heisei 11-367754	, accorded on
	Corresponding part	Application No. Heiser 11-307734	┥ .
	Relativeness		-
	Remarks		
2	Index (document	02 Others' related prior art	Attachadlan
2		02 Others' related prior art	Attached by: Attached on:
	category)	Dublichter No. 0000 000070	Allached on:
1	Detail (title)	Publication No. 2000-232078	
	Corresponding part		
	Relativeness		<u>.</u>
	Remarks		
3	Index (document	01 Our related prior art	Attached by:
	category)		Attached on:
	Detail (title)	Application No. 2003-015236	
	Corresponding part		
	Relativeness		
	Remarks	-	
4	Index (document	02 Others' prior art	Attached by:
	category)		Attached on:
	Detail (title)	USP6413403	
	Corresponding part		
	Relativeness	·	·
	Remarks		· ·
5	Index (document	02 Others' prior art	Attached by:
	category)		Attached on:
	Detail (title)	USP6413388	
	Corresponding part		
	Relativeness		
	Remarks		
6	Index (document	02 Others' prior art	Attached by:
	category)		Attached on:
	Detail (title)	USP6409904	
	Corresponding part		
	Relativeness		7
	Remarks		7
7	Index (document	02 Others' prior art	Attached by:
	category)	· · · · · · · · · · · · · · · · · · ·	Attached on:
	Detail (title)	USP6402925	–
	Corresponding part		-
	Relativeness		-
	Remarks		₸ .
8	Index (document		Attached by:
•	category)		Attached on:
	Detail (title)		Attached on.
	Corresponding part		 .
	Relativeness		-
	Remarks		-
9			<u> </u>
9 .	Index (document		Attached by:
•	category)		Attached on:
	Detail (title)	<u> </u>	Attached by:
	Corresponding part	· ·	Attached on:
	Relativeness		<u> </u>
	Remarks		<u> </u>
10	Index (document		Attached by:
	category)		Attached on:
	Detail (title)	·	
	Corresponding part		7
•	Relativeness		· ·
	1 —		╡

8 [Description of invention (specification draft)]

Specification	Drawings	Others	
Attached by: Attached on:	Attached by: Attached on:	Attached by: Attached on:	

▲ For the responsible	For the boss of the	▼For Patent Dept. of	▼ Workflow information
person in the	requesting side	the Group	
requesting side			

9 ▼For the boss of the requesting side

This invention relates to an apparatus configuration required for plating and electropolishing of Cu wiring, more particularly its anode head structure. We have				
 delivered the apparatus to the collaboration partner (U.S.).				

▲ For the responsible	▲ For the boss of the	For Patent Dept. of the	▼ Workflow information
person in the	requesting side	Group	
requesting side		•	

10 ▼For Patent Dept. of the Group

General	Responsible	Mr. Sakaguchi
manager:	Comment	Please.
Responsible person:	Comment	I think foreign filing of the application is required because it has been determined to be important.
	Attachment .	Attached by: Attached on:
	Sign of completion	Sakaguchi: Completed

▲ For the responsible in	▲ For the boss of the	▲ For Patent Dept. of	Workflow information
the requesting side	requesting side	the Group	

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver:

Request ID NTNN-5LNM4B

Status: completed

4	-
7	7

Requested by:	Approved by:
natsuki makino/e/ebara_jp	akihiko tashiro/e/ebara jp
	yukio fukunaga/e/ebara_jp
	seimitsu zzchizai/e/ebara_jp
	fumio kondo/e/ebara_jp

▼Approver information

12

Requested by:	Requested on:	CC mail
natsuki makino/e/ebara jp	May 31, 2003	junji kunisawa/e/ebara_jp

Position of the	Name of the	Deadline of the	Status	Date of approval	CC mail
approver	approver	approval		' ''	
Boss of the	(Approval not				
inventor	required)				
Liaison	akihiko tashiro/e/ebara_jp	June 7, 2003	Approved	June 3, 2003	·
General manager	yukio fukunaga/e/ebara jp	June 10, 2003	Approved	June 3, 2003	
Patent Dept. of the Group	seimitsu zzchizai/e/ebara jp	June 10, 2003	Approved	June 11, 2003	

▼Comment

CN=akihiko tashiro/0U=e/0=ebara_jp Approved June 3, 2003 13:49:32 I approve the request. CN=yukio fukunaga/0U=e/0=ebara_jp Approved June 3, 2003 20:44:10 OK. CN=seimitsu zzchizai/0U=e/0=ebara_jp Approved June 11, 2003 20:15:14 I approve the foreign filing.

♦Action

·
_
-
w.
7
4
_
=
O
\mathbf{c}
_
_
Ø
1
=
Ø
EP.

Ebara Natent Applications (applications later than Aug

	F 0 180		Not Filed					>juo			Not Filed	3	up	≥	Do	cus.	nen	it (5
February 6, 2004		E A STATE OF THE S	5 Ebara No		•	•	······································	Ebara US			Ebara. Not			bara PCT		*		·,	vara US only	
Febru	1 0 1 0 1 0 1 0		2 8			. •	•	2 9.E		· · ·	7		-	12 Ebara	 :	· · · · · · · · · · · · · · · · · · ·	·		24 Ebara	•
	ant Castric		0	· · ·	•	•		-		· ·		•	· 	-	·			•	0	
	HE FEE	a a a a a a a a a a a a a a a a a a a		· · ·	<u></u>	•	•		· ·	·:		·	~ .		 	. ·		<u>.</u>	<u>-</u> ,	·
ions later than Auge 2002)		te/ an electrical contact to a telectrical contact to a telectrical contact to a telectrode facing the substrate, a control element of the electrode and the substrate, the element having almost the a substrate and/ a drive mechanism for relative parallel movement																		
2002)	Electrofysis apparatus, comprains / e substance	periphery of a substrate/ an electrode facing the substrate/ a <u>gentrical</u> contact to a <u>electrical field between the electrode and the substrate</u> , the element having almost the same diameter with the substrate and/a drive mechanism for relative parallel movements of the substrate and the substrate and a drive mechanism for relative parallel movements.	מופחת סמפי			redacted		The form of the second	redacted			redacted				redacted			redacted	
		periphery of a substrated adaptive in 22-Aug-02 Electrolitic processing apparatus of the substrate and a					Apparatus and method for 02-Dec-02 electrolytic processing			Plating method and apparatus			23-Jan-03 apparatus					Apparatus for electrolytic 31-Jan-03 processing	16-Apr-03 semiconductor substrate	4
No. Abolication Ap		1 2002-242728					2 2002-350529			3 2003-015235			4 2003-015238					5 2003-025159	6 2003-111327	

- 15
<u> </u>
. <u>ഇ</u>
$\ddot{\sigma}$
_
Œ
0
\mathcal{C}
_
Œ
<u>. </u>
$\boldsymbol{\sigma}$
Ω
ш.

latent Applications (applications later than Aus

2003-138521 16-May-03 destroylog processing reducted reducted 2003-138521 16-May-03 destroylog processing method for reducted 2003-145017 22-May-03 reducted 2003-145017 22-May-03 reducted 2003-145018 26-May-03 reducted 2003-161236 05-Uur-03 reducted 2003-161237	Method Apparatus Potal	B Ebara Prepari	Under Preparation Preparation Preparation Preparation
Apparatus and method for Apparatus for supplying, recovering, measuring and 22-May-03 and apparatus Substrate processing method 27-May-03 and apparatus and plating Plating apparatus and plating 05-Jun-03 method Plating apparatus and plating 05-Jun-03 electrolyte retaining method	8 0		aration aration aration aration aration
Apparatus and method for 16-May-03 electrolytic processing Apparatus for supplying, recovering, measuring and recovering, measuring and Substrate processing method 26-May-03 and apparatus and plating 27-May-03 method Plating apparatus and plating 05-Jun-03 method Plating apparatus and plating 05-Jun-03 electrolyte retaining method	m 0		aration aration aration
Apparatus for supplying, recovering, measuring and recovering, measuring and Substrate processing method 26-May-03 and apparatus Plating apparatus and plating 05-Jun-03 method Plating apparatus and plating Plating apparatus and plating	m 0		aration aration aration
Substrate processing method Substrate processing method and apparatus 27-May-03 and apparatus and plating 05-Jun-03 method Plating apparatus and 05-Jun-03 electrolyte retaining method	0		aration aration
Substrate processing method 26-May-03 and apparatus Plating apparatus and plating 05-Jun-03 method Plating apparatus and Plating apparatus and Plating apparatus and 05-Jun-03 electrolyte retaining method			aration
Plating apparatus and plating Plating apparatus and plating Diating apparatus and Plating apparatus and Plating apparatus and Diating apparatus and Diating apparatus and			aration
Plating apparatus and plating Plating apparatus and plating Diating apparatus and Plating apparatus and Diating apparatus and Diating apparatus and Diating apparatus and	2 1 14		
Plating apparatus and plating Plating apparatus and plating Dis-Jun-03 method Plating apparatus and Plating apparatus and Plating apparatus and Plating apparatus and			
Plating apparatus and plating 05-Jun-03 method Plating apparatus and 05-Jun-03 electrolyte retaining method			
Plating apparatus and plating 05-Jun-03 method Plating apparatus and 05-Jun-03 electrolyte retaining method	1 1 24	24 Ebara PCT, T	¥
05-Jun-03 method Plating apparatus and 05-Jun-03 electrolyte retaining method			
Plating apparatus and 05-Jun-03 electrolyte retaining method		·.	
So can be electrolyte retaining method	1 18	16 Ebara PCT, T	À.
	0 1 5	Ebara PCT	<u>¥</u>
redacted			
2003-169791 13-Jun-03 method		-	•

ā
-
_
=
Φ
$\boldsymbol{\sigma}$
Œ
*
_
ō
Ö
$\mathbf{\circ}$
æ
T.
Ö
유
111
<u> </u>

February 6, 2004

Ebar atent Applications (applications later than AU 2002)

No Apolication N	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1					
			Abstract	Wethod Apparatus	Total Durie	70982
	· · · · · · · · · · · · · · · · · · ·				<u> </u>	
	*		redacted			
<u>-</u>						
14 2003-195406	Plating apparatus and plating			-		٠ <u>ډ</u>
				2 2	14 Ebara	Not Decided
					·	
			redacted		-)(-	:
15 2003-202515	Plating apparatus and plating.				i	
				1	Ebara/ 8 redacted	Not
			hanepa			
16 2003-310355	02-Sep-03 Apparatus for plating substrate			0		ž Z d
17 2002-2-2000			redacted		B.ROJ O	7 e c i de c
	04-Sep-03/Apparatus for plating substrate	1.00 A	A CASE			Z ot
18 2003-314755	Method and apparatus for 05-Sep-03 controlling electrolyte		redacted		LOBIA	Decided
				2 2	20 Ebara	Decided
				• •		
7.						
19 2003-319055	Plating apparatus and plating 10-Sep-03 method					
				- '	Į.	Not

Ebara Confidential

Not Decided Not Decided February 6, 2004 -Not Decided redac' ted/Ebar Not 14 Ebara 15 Ebara S III 198 Ebar Applications (applications later than August 2002) redacted redacted Plating apparatus and plating Apparatus and method for Plating apparatus and plating Apparatus and method for 30-Oct-03 processing substrate 28-Nov-03 electrolytic processing 31-Oct-03 method 01-Dec-03 method 20 2003-371159 21 2003-373391 2003-399443 3 2003-402008 2

20/Ebara

Ebara atent Applications (applications later than AU

10 Ebara Decided	-	fedacted	Plating apparatus and plating method of substrate
		redacted	Plating apparatus and plating
1 14 a Decided			
redao	•		Plating method and plating 25-Dec-03 apparatus
		redacted	
TOGETHE TO OVICE TO SEE	Method Apparent		

27

28

Meeting Minutes - The 2nd esse /EBARA JDA Workshop

Date; February 5 & 6, 2004

Place;

redacted

Attendees;

redacted.

Ebara – Manabu Tsujimura, Jay Horiuchi, Yukie Fukunaga, Koji Mishima, Norio Kimura, Ray Fang Keisuke Namiki, Keiichi Kurashina, Isao Nambu, Dan Connell, Kenichi Sasabe, Katsuyuki Musaka

Redacted

Redacted

Redacted

P List Exchange (redacted /Kenichi Sasabe)

There exist patent for additive distribution control for wide feature leveling by Ebara's competitor, which may interfere with current development activities on pad plating. (Ebara)

The patent explains superfill mechanism, which is different from flat overburden (redac)

ted 's disclosure on pad plating ready for Ebara's review (redac)

Ebara filed original Japanese patent application on touch down plang with "porous element" in 1999.

Will review possible addition of claim and/or coinventor (Ebara)

Still possible to file US patent application with redac as coinventor (redac)

redacted 's disclosure for e-CMP chemistries to be filed as redac redac's invention, while e-CMP apparatus with the method (chemistries) to be filed as redac /Ebara coinvention (redac)

Ebara's Japanese patent application items#2, 4, 10, 11, 12, 14, 22, 23, 24 to be reviewed in regards to redac's disclosure for possible addition of redac as coinventor (redac)

Ebara's Japanese patent application items#2, 4, 10, 11, 12, 14, 22, 23, 24 to be reviewed in regards to redac's disclosure for possible addition of redac as coinventor (redac)

Ebara's Japanese patent application item#16 to be Ebara invention (redac)

Ebara's disclosure item#26 and 28 to be filed as redac /Ebara coinvention (redac)

Ebara's disclosure item#26 and 28 to be filed as redac /Ebara coinvention (redac)

Ebara's disclosure item#20 can be the same content as redac /s disclosure (redac)

Ebara's disclosure item#20 can be the same content as redac /s disclosure (redac)

Will submit abstract translation of the draft application (Ebara)

Action Plan
Action Item

<u>Owner</u>

Due

Redacted

16. Abstract translation of Ebara's Japanese patent application	K. Sasabe	~Feb'04
(Item#2, 4, 10, 11, 12, 14, 22, 23, 24)		~reb 04
17. Abstract translation of Ebara's Japanese patent application of	draft K. Sasabe	~Feb'04
(Item#26, 28, 29)	It. Dasaoc	~160 04

Musaka, Katsuyuki, 午前 06:53 04/03/09 -0800, EBARA Patent Application Translations

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
To: " redacted (E-mail)" < redacted com>
Co: "Fukunaga. Yukio (E-mail)" <fukunaga.yukio@ebara.com>, "Sasabe Kenichi (E-mail)"

<sasabe.kenichi@ebara.com>

Subject: EBARA Patent Application Translations

Date: Tue, 9 Mar 2004 06:53:01 -0800

X-Mailer: Internet Mail Service (5.5.2653.19)

redacted -san,

Thank you for your time and valuable inputs in our meeting yesterday although your busy schedule.

Please find attached summary of Ebara's patent application status. There are some corrections in the one I handed to you a hard copy yesterday (highlighted in red).

<<EBARA Applications_030904.xls>>

Attached below are translations of Ebara's Japanese patent applications which hard copies I handed to you today.

<<2003-015236(#4).doc>> <<2003-149827(#10).doc>> <<2003-161236(#11).doc>> <<2003-161237(#12).doc>> <<2003-195406(#14).doc>>

<<2003-431211(#24).doc>> <<2004-022178(#26).doc>> <<2004-023256(#28).doc>> <<K1040028(#29).doc>>

Also, attached below is the Ebara's US patent application. As I explained to you yesterday, the #2 which was filed in Japan on 12/2/02 was abandoned. then re-filed as #22 in Japan on 11/28/03, within 1 year from the original(#2) filing date. The US patent applications for #2 as well as #22 were also filed about the same time, 12/1/03, to obtain the priority of #2, within 1 year from its original(#2) filing date in Japan.

<<GEB1998US(#22).pdf>> <<GEB1998US Image(#22).tif>> Please review and advise us which you want us to amend for co-invention with redacted

Best Regards. K.Musaka

P.S. I'm still waiting for a translation of #23. I'll e-mail it to you as soon as I receive it.



EBARA Applications 030904.xls



2003-015236(#4).doc



003-149827(#10).doc



2003-161236(#11).doc

Musaka, Katsuyuki, 午前 06:53 04/03/09 -0800, EBARA Patent Application Translations



2003-161237(#12).doc



2003-195406(#14).doc



2003-431211(#24).doc



2004-022178(#26).doc



2004-023256(#28).doc



K1040028(#29).doc



GER1998US(#22) ndf



GEB1998US Image(#22).tif

Musaka, Katsuyuki, 午後 08:47 04/05/07 +0900, S1 Project 特許の件

To: "Musaka, Katsuyuki" <kmusaka@ebaratech.com> From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: S1 Project 特許の件

Cc: 笹部憲一 〈sasabe.kenichi@ebara.com〉,mishima.koji@ebara.com

Bcc: fukunaga.yukio@ebara.com

Attached:

六平 様

昨日TELCONにて打ち合わせた標記の件で、#4、#10、#12、#14、#24の対処の方向に関して、現在辻村役員に打診をしております。

役員は本日不在でまだ内諾が得られておりませんので、大変恐縮ですが5月7日の F-t-F meetingでは「共願」を匂わさずに、「ECにて検討中」という表現に留めて 頂くようお願い致します。 内諾頂き次第ご連絡致します。

なお#26に関しては、内容が理解できる程度の翻訳資料を笹部さんに依頼をしています。時間との関係でどこまでできるかまだ分かりませんが、クレームだけでIBMに判断を仰いでも、ラチがあかないと考えています。

以上、取り急ぎお願いのみ致します。

福永(由)

Musaka, katsuyuki, PM 08:47 04/05/07 +09000, Regarding the SI Project patent

To: "Musaka, Katsuyuki" <kmusaka@ebaratech.com> From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: Regarding the S1 Project patent

Cc: Kenichi Sasabe <sasabe.kenichi@ebara.com>,mishima.koji@ebara.com

Bcc: fukunaga.yukio@ebara.com

Attached:

Dear Mr. Musaka.

Regarding the above subject we discussed at TELCON yesterday, I have contacted Mr. Tsujimura about how we think about our approach to #4, #10, #12, #14 and #24.

He is out today and I have not yet obtained hisinformal consent; therefore, I kindly request you to describe the matter in the F-t-F on May 7 only as "being reviewed at EC," instead of implying "joint application."

As soon as I obtained the informal consent, I will inform that to you.

Regarding #26, I have requested Mr. Sasabe to supply me with the documents translated enough to understand their contents. Due to the time limitation, I am not sure how much we can do. However, I believe asking [redacted: the US company] opinions only by supplying it with those claims does not help.

Here, I quickly note my request as above.

Y. Fukunaga

由, 11:25 04/05/21 +0900, Fwd: Export License に関する打合せ

To: 福永(由)室長殿, 三島部長殿, 国澤課長殿, 牧野殿, 赤井部長殿, 篠塚担当部長殿, 坂 口担当部長殿

From: 笹部憲一〈sasabe.kenichi@ebara.com〉 Subject: Fwd: Export License に関する打合せ

Cc: 鈴木室長殿

Bcc: Attached:

各位

Export Licenseに関する打合せを下記にて行いますので、ご出席お願い致します。

5月27日(木曜日) 9:00-12:00 藤沢 V2棟 第5会議室

特願2002-350529 特願2003-399443

の原稿作成、出願依頼、出願、国内優先の計画、国内優先の原稿作成、出願依頼、出願、 外国出願依頼、外国出願など、この出願の発明から出願に到る過程の資料を調査の上、コ ピーをお持ちください。

出願打合せのノート、メモ、弁理士との相談のノート、これら出願に関する記載のある社内の報告書、e-mailなど、関連すると思われる全ての資料のコピーが必要です。 よろしくお願いします。

Date: Tue, 18 May 2004 18:06:53 +0900

To: 福永(由)室長殿, 三島部長殿, 国澤課長殿, 牧野殿, 赤井部長殿, 篠塚担当部長殿, 坂 口担当部長殿

From: 笹部憲一〈sasabe.kenichi@ebara.com〉 Subject: Export License に関する打合せ

各位

redacted の情報が入った出願を日本で米国より先に出願した件に関して、Export Licenseを取 ろうとしています。

redacted

又このときに、各判断の記録や証拠があるか確認して行く必要があります。 牧野さん、国沢さんを含めて、どのような議論が為されてどのような判断をしたか、事実確 認とストーリーの明確化を行いたいと思います。

ご都合の良いところで打合せしたいと思います。 今週は赤井さんが海外出張ですので、来週やりたいと思います。 火曜日(25日)、水曜日(26日)、木曜日(27日)で都合の悪い時間をご連絡ください。 打合せは藤沢で行う予定です。

発明から日本出願までに発生した事柄

Ebaraが「ted にEBRのめっき槽地に付いて説明した。 2002. 6 2002. 8

redacted がEBRにJDPで実施したいことを説明した。

Presentationの資料をEBRは入手。
redacted とEBR(誰)が「redacted とEBR(証)」に関与する装置について相談。 2002. 8

この間、何があったのかな?

2002. 12. 2

EBRが日本出願

Y, 11:25 04/05/21 +0900, Fwd: Meeting regarding Export License

To: General Manager Y. Fukunaga, General Manager Mishima, Manager Kunisawa, Makino,

General Manager Akai, manager Shinozuka, Manager Sakaguchi

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Meeting regarding Export License

Cc: General Manager Suzuki

Bcc:

Attached:

To all concerned,

This message requests all concerned to attend the meeting aboutExport License as below.

Thursday May 27. From 9:00 a.m. to 12:00 a.m.

Meeting room 5 Building V2, Fujisawa Plant

Application No. 2002-350529

Application No. 2003-399443

The attendants are requested to check all data of processes from invention to filing of the two patents above, including patent drafting, request for filing, filing, scheduling for claming the domestic priority, drafting for claming the domestic priority, request for filing, filing, request for foreign filing, foreign filing, and bring the copies of them.

You must bring the copies of any kind of data if they seems to be related, including, but not limited to, notes taken in meetings for filing, memos, notes taken in consultation with our attorney, in-house reports containing articles relating to the filing, e-mails, and so on. I call for your cooperation.

Date: Tue, 18 May 2004 18:06:53 +0900

To: General Manager Y. Fukunaga, General Manager Mishima, Manager Kunisawa, Makino,

General Manager Akai, Manager Shinozuka, Manager Sakaguchi

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Meeting regarding Export License

To all concerned,

Regarding the issue that we filed the patent applications including information of [redacted: the US company] in Japan prior to filing in the U.S.A., we are going to apply for the Export License.

[redacted]

As we summarize, we need to check records or evidences of each decision made upon each event.

With Mr. Makino and Mr. Kunisawa, I will check the facts and clarify the story, that is, what were discussed and what were decided through the sequences.

I'd like to hold the meeting when all of you are available.

Mr. Akai is on an oversea business trip this week; thus, the meeting will be held next week. Inform me when you are not available: on Tuesday (25th), Wednesday (26th), or Thursday (27th). The meeting will be held in Fujisawa.

Events occurred from invention to domestic filing

2002. 6 Ebara explained [redacted: the US company] of the plating apparatus of EBR.

2002. 8 [redacted: the US company] explained EBR that they wanted to reduce the invention to practice in the JDP.

EBR obtained the presentation data.

2002. 8 [redacted: the US company] and EBR (who) discussed the apparatus to be lent to [redacted: the US company].

I wonder what happened during this period?

2002. 12. 2

EBR filed the patent applications in Japan Patent Office.

EBR -> [redacted: the US company] Explanation about the apparatus. 2002.6

[redacted: the US company]-> EBR Presentation about what they want to do.

[redacted: the US company]/EBR Meeting regarding the apparatus specifications. Minute.

The pad attached to the impregnant. Combination of plating, etching, and the down force.

Meeting regarding prosecution process of impregnation application at Watanabe Office

The 1st meeting regarding filing. Kondo, Shinozuka, Kunisawa, Watanabe. Impregnation. Planarization with plating. ntellectual Property Dept. -> Kunisawa. Advised to file. 10/2 Manager Kubota. Instruction. 2002.10.1

Kubo -> Shinozuka. Responsible staff changed. 11/20? Request for drafting 11.19 Kubo, Kunisawa, Kosugi

2002.12.2 Domestic filing 2002-350429

2002. Beginning of Oct. Design startd

2003. Beginning of Apr. Delivery

Request for foreign filing through the workflow 2003.7

Request for consideration of new matters

Etching <- Mr. Ogata attached his memos for preparing against Nutool to the request for approval 10.1

10.23 Request for addition

Domestic priority 2003.11.28

Filing in USA 2003.12.1

(1) Did not know that an invention achieved in the U.S.A. should be filed in USA first.

(2) Did not realize the content of this invention includes an invention made by [redacted: the US company]

Makino:(1) +(2)

Kunisawa: (1)

Fukunaga (1)

From: "Musaka, Katsuyuki" (kmusaka@ebaratech.com)

To: "'M Tsujimura'" \(\strujimura.manabu@ebara.com\), ogata.akira@ebara.com, "Kobayashi, Fumio (E-mail)" (kobayashi.fumio@ebara.com),fukunaga.akira@ebara.com.

fukunaga.yukio@ebara.com,tokushige.katsuhiko@ebara.com.

hodai.masao@ebara.com,mishima.koji@ebara.com, asami.masao@ebara.com, "Sasabe Kenichi (Email)" <sasabe.kenichi@ebara.com>,Kimura Norio <kimura.norio@ebara.com>,"Nambu, Isao"

<inambu@ebaratech.com>, "O'Connell, Dan" <doconnell@ebaratech.com>

Cc: horiuchi.takao@ebara.com, yago.natsunosuke@ebara.com

Subject: Meeting with Mr. redacted

Date: Thu. 10 Jun 2004 23:04:21 -0700

X-Mailer: Internet Mail Service (5.5.2653.19)

Great thanks to everybody participated in the quite intensive discussion in last week while my stay in Japan. I believe our meeting today with Mr. reducted was truly successful and satisfactory.

Dan, Nambu-san, Kimura-san and myself visited Mr. redacted today for the discussion on IP issue in JDA. (redac san also participated by phone.) The discussion was initiated by Dan explaining historical background of this matter, "Ebara had been working on planer plating technology prior to the engagement with _ted for the JDA, and filed patents before the contract, but after initial technical information exchange with redaction on this matter. Ebara should have informed redac the background IPs in time to avoid any confusion and conflict on the IP ownership. After internal discussion at Ebara, Ebara agreed to modify those patent applications as co-invention with redain recognizing its impact on the program and redac!s business."

Mr. reducted stated "iredac could not understand why Ebara did not submit the background IPs at the 1st workshop in Sept'03 accordingly to the JDA contract". I replied "Ebara understood the contract, and actually submitted the IP list at the workshop. However, the list was too brief to discuss the details, and re-submitted the list with abstracts in the workshop in Feb'04, which caused some delay in our initial discussion on this matter with redac Since then, we've been working with redac technical coordinator for identification of IP ownership, and redaction of total 8 Ebara's Japanese patent applications into co-invention with redac applying for export license for corresponding US patent applications. "redac san also backed us up stating "Those were the same understanding as hers".

I also explained "In order to avoid any confusion in patent application process in the future, Ebara propose to submit whole translation of IP disclosure to redac before filing patent application for ted services and determining the co-ownership. "redac san stated "1-page summary or abstract of US patent application should be sufficient." Dan stated "This process change requires redac's strong support in timely corresponding redac's decision to Ebara since Ebara rely on redac 's reply for filing the patent application."

Finally, I apologized the confusion and promised the compliance to the contract, and Mr. reducted replied "I'm fine, now."

I also talked with redaction after the meeting by phone, and she said "The meeting was quite satisfactory."

I understand it was difficult time for everybody to re-evaluate the contract and determine the countermeasure. Now, I believe, we have better understanding of the contract and how it impacts Ebara's business. We have no choice than succeeding the JDA with redain

Once again, thank you very much for your understanding and continuous support on this matter.

Best Regards.

K.Musaka

Mr. Musaka, 19:28 04/02/03 +0900, Ebara Patent List

To: Mr. Musaka

From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Ebara Patent List

Mr. Y. Fukunaga, Mr. K. Mishima Cc: 福永(由)室長殿, 三島部長殿

Attached: D:¥My Dcuments¥-redac用EBR特許リスト¥EBR Applications 02.2.6.xls;

Dear Mr. Musaka,

Please find attached Ebara patent application list.

Mr. Y. Fukunaga, Mr. Mishima and I selected the possible related Japanease patent

applications filed later than August 2002.

We believe the owner of the applications filed before August 2003, when the PaP Project Contract was agreed, is Ebara alone, because before the contract there was no exchange

of confidential information between redac and Ebara.

Applications filed after August 2003 must be checked by the technology covered by the application. The owner in the list is our idea for the discussion in the meeting. Last four applications are under preparation for application and not filed yet. I think it is difficult for them to understand the contents of the each application after short exlanation at the meeting. I think we had better to discuss about few applications which might be joint applications.

Best regards

February 6, 2004 🛌

	ion filling to the second seco	971	Electrolysis abbaratus	Method Assert	Camo	URIONA
1 2002-242728		processing apparatus	periphery of a substrate/ an electrode facing the substrate/ a control a substrate/ a control element of same diameter with the substrate and the substrate, the element having almost the substrate and a drive mechanism for relative parallel movement			
				0	1 5 Ebara	a Not Filed
:						
				• :		
			redacted		•	
2 2002-356529	02-Dec-02	Apparatus and method for		· ·	•	:
		a de la composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della composition della comp		. —	2 1 1 1 1 1 1 1 1	<u>.</u>
			redacted			•
3 2003-015235	Piating metho 23-Jan-03 therefor	Plating method and apparatus therefor		· -		
-				-	1 Ebara	Not Filed
4 2003-015238	Plating method and plating 23-Jan-03 apparatus	od and plating	priorita i	· · · · · · · · · · · · · · · · · · ·	· ·	
					1 12 Ebara	PCT, TW
				<u>.</u>		
					٠.	
-			redacted			· · · · · · · · · · · · · · · · · · ·
						
5 2003-025159	Apparatus for electrolytic	r electrolytic		•		
6 2003-111327	16-Apr-03 semiconductor	d for		0	4 24 Ebara	SO SO
		i substrate	redacted		į į	} .
	· · .				/ Zolebara	Preparation

		π	7
•	•	Ξ	•
	7	-	:
		==	•
	•	U	,
	٦		ı
į	Ğ	_	•
	7		;
•			٠
	•	J	
4	Г	7	
	_	_	
	C	a	
	i	Ξ	•
	ā		
=	÷	j	
۱	1	J.	

Ebara Confidential	Ebar atent Applications (applications later than Aries 2000)		6 3 1	
			repruary o, 2004 .	, 400
Title		Main Clarins	Clamo	in Foreign
		Method Apparatus	Total Gwer	(Angellearin
			•	
7 2003-138571 18-M Apparatus and method for	redacted			
gual and a second place of the second place of			· i	Under
Apparatus for supplying, recovering, measuring and	redacted	7	y Ebara	Preparation
and an analysis of a section of a		3 0	· 8 Ebara	Under
 	redacted			
2003-148326 26-May-03		-	17.7	Under
		1	14 CDara	Preparation
	redacted		·.	
10 2003-149827 27-May-03 method				
		-	· 24 Ebara	PCT, TW
	redacted		· · · · · · · · · · · · · · · · · · ·	
Plating apparatus and plating 05-Jun-03 method				
		-	16 Ebara	PĊT, TW
12 2003-161237 05-Jun-03 electrolyte retaining method	redacted			
		0	S Ebara	PCT, TW
		-		-
	redacted			· .
13 2003-169791 13-Jun-03 method				
ŀ			· -	Not

10
∵≔
_ ⊆
<u></u>
Ō
u=
=
7
-=
O
e O
E.
ara C
bara (
Ebara (
Ebara (

Ebara	Ebara Confidential	Ebare atent Applications (applications later than Augus)		February 6 2004	2004
NOT ADDICATION	alora your lefting Date		Wantiplans		UKerca
			Mathed Asparant	Total Owner	Application
					
		redacted	·		
14 2003-195408	Plating apparatus and plating 10-Jul-03 method		· .		
			2 2	14 Ebara	Decided
· · · · · · · · · · · · · · · · · · ·					
		redacted	· .		:
15 2003-202515	Plating apparatus and plating 28-Jul-03 method			Ebara/	•
			1	8 redacted	Decided
16 2003-310355	02-Sep-03 Apparatus for ploting and the sep-	redacted ;		•	
	ensura ginera di nana		0	10 Ebara	Not Decided
17 2003-313307	04-Sep-03 Apparatus for plating substrate	redacted	· .		50 22
. 00	Method and apparatus for		0	13 Ebara	Decided
	U3-Sep-03 controlling electrolyte	יפתפרונה	2 2	20 Ebara	Not Decided
		redacted	•		
÷					
19 2003-319055	Plating apparatus and plating 10-Sep-03 method		-		Not

. <u> </u>
4
~
ਡ
a
O
1
-
_
\overline{a}
•
\boldsymbol{C}
$\overline{}$
œ
1
æ
"
Ω
ш
ш

Ebara Confidential	Ebar Apart Aparilla	. •	
	2002)	L.	February 6, 2004
	A BELEEK TO THE TOTAL THE	Mathod America	ns Trough
Apparatus and method for 30-Oct-03 processing substrate	nethod for trate		Market Market Market 197
			Not 14 Ebara Decided
		•	
	redacted		
21 2003-373391 31-Oct-03 method	s and plating		
		-	15 Ebara Decided
			-
Apparatus and method for 22 2003-399448 28-Nov-03 electrolytic and method for	thod for		
SEBOOLD ON A CONTROL OF THE CONTROL	Buss	3	redac Ebar Not
	redacted		
23 2003-402008 01-Dec-03 method	and plating		
			-

reducted reducted reducted reducted reducted reducted	ettori W. Full Ende
	•
	Plating method and plating
10 Ebara	٠,
10 Ebara	•
10 Ebara	
1 10 Ebara	
redacted	٠.
redacted	
redacted	
	•

Ebera Confidential Ebera Confidential Ebera Start Applications (applications (applic	2004.	d (Control	· ·	Not Decided		Not Decided	· :	No t
Ebera Confidential Ebera Stein Applications (applications later than Aug. 2002) Substrate processing apparatus Substrate processing apparatus Plating apparatus and plating Plating apparatus and plating Plating apparatus and plating	February 6,		·	43 Ebara		13 Ebara		
Ebara Confidential Ebara Salent Applications (applications later than All 2002) Substrate processing apparatus Retiring apparatus and plating Plating apparatus and plating Plating apparatus and plating Plating apparatus and plating Plating apparatus and plating Plating apparatus and plating				6				
Ebara Confidential Ebara and plating Ebara Applications (applications later than Autorities and plating method of substrates and plating method of substrates and plating method of substrates and plating method of substrates and plating method of substrates				0		3		•
Substrate processing apparatus Plating apparatus and plating method of substrate Plating apparatus and plating method of substrate method of substrate								
Substrate processing apparatus Plating apparatus and plating method of substrate Plating apparatus and plating method of substrate method of substrate	olications (applications late		refacted		redacted		redacted	
Ebara Confidenti	Ebara atent App				72. 74. 74.		. •	
Ebara Confiden	tial			Substrate processing apparatus	Plating apparatus and plating method of substrate			Plating apparatus and plating method of substrate
	Confidential Confi		.:					
FORMANDA (4)	Ebara			7:	8			

Meeting Minutes - The 2nd Sec /EBARA JDA Workshop

Date; Februar

February 5 & 6, 2004

Place;

redacted

Attendees;

redacted

Ebara – Manabu Tsujimura, Jay Horiuchi, Yukio Fukunaga, Koji Mishima, Norio Kimura, Ray Fang Keisuke Namiki, Keiichi Kurashina, Isao Nambu, Dan CConnell, Kenichi Sasabe, Katsuyuki Musaka

Redacted

Redacted

Redacted

IP List Exchange (redacted /Kenichi Sasabe) There exist patent for additive distribution control for wide feature leveling by Ebara's competitor, which may interfere with currentdevelopment activities on pad plating. (Ebara) The patent explains superfill mechanism, which is different from flat overburden (redac) 's disclosure on pad plating ready for Ebards review (redac)

Ebara filed original Japanese patent application on touch down plaing with "porous element" in 1999 Will review possible addition of claim and/or coinventor (Ebara)

- Still possible to file US patent application with redar as coinventor (redar)

redacted 's disclosure fore-CMP chemistries to be filed as redard sinvention, while e-CMP apparatus with the method (chemistries) to be filed as redard (Ebara coinvention)

Ebara's Japanese patent application items#2, 4, 10, 11, 12, 14, 22, 23, 24 to be reviewed in regards to redar's disclosure for possible addition of redard as coinventor (redard)

Will submit abstract translation on above items (Ebara) • Ebara's Japanese patent application item#16 to be Ebara invention (redac)
• Ebara's disclosure item#26 and 28 to be filed as ted /Ebara coinvention (redac)

-ted Will submit abstract translation of thedraft applications (Ebara)
 Ebara's disclosure item#20 can be the same content as redac's disclosure (redac)

Will submit abstract translation of the draft application (Ebara)

Action Plan
Action Item

<u>Owner</u>

<u>Due</u>

Redacted

16.	Abstract translation of Ebara's Japanese patent application		K. Sasabe	~Feb'04
17.	(Item#2, 4, 10, 11, 12, 14, 22, 23, 24)	•		2000
. 17:	Abstract translation of Ebara's Japanese patent application draft (Item#26, 28, 29)		K. Sasabe	~Feb'04



Fax +81-3-3745-5745 (Japan)

2004.2.8.

知財部 近藤副部長殿 | 転送お願いしする 特許部 坂口担当部長殿 1/1

redacted Lo 調整結果報告と依賴 708 笹部

確認 la facts.

- 1. 2002.8月の meeting において reducted から合浸材に padを付けることが説明まれている。
- 他社と共同用発として 含温材 z. Ebara 🖈 🐪 を用いため,さを削発し、1999年12月以降日本に 特許出願いいる.
- 3. 日本の他社による合環材を用いためのきの出願かつ 1999年2月に有る.

行動計画

- 1. 2002,8月以前に、共同用発にあいて、padを用いて め,きの特許出願が無かれか確認する.
- 2. redacted として11件の出願が共同出願の可能性がある~ 考えてかり、それらり出願り 要約、請求項回、供り 説明 9英訳 4 图 & Ebara が作り、redacted IT 送付 する。今下記出願の上記部分の英訳お願いします。約2週間。
- 3 redacted と共願が必要となった場合には展明者の追加と

出願人の追加を行う。 英記がいった役れな 4. 共顧9可能性9あ3出願は 特願 2002.350529 (图内優先)報) US出願有 PCT出胸有. Œ) 2003-015236 PCT出解有 **②** 2003-149827

PCT出願有 0 2003 - 161236 PCT出廊有 (Z) 2003-161237 Œ 2003 - 195406 日本のみ

2003 - 399 443 (2002-3505299 国内展先) 日本のみ 42

W 日本クツ、 2003 - 43/211

K 1030466 Ø K1040012 (28) K1040028

(P)

5、redacted から3件の出願が示され、2件は共同、1件はredacted単類。





Fax +81-3-3745-5745 (Japan)

2004.2.8

To: Deputy General Manager Kondo in Intellectual Property Dept.

To: Manager Sakaguchi in Patent Dept.



Please forward.

1/1

Report of Coordination with [redacted: the US company] and Request

708 Sasabe

Confirmed facts

- 1. In the meeting held in August 2002, [redacted: the US company] explained pads would be attached to impregnants.
- 2. Ebara developed a plating technique jointly with a company and filed patent applications in Japan after December 1999.
- 3. A Japanese company filed patent applications for a plating technique using impregnants in February 1999.

Schedule of actions

- 1. Check if any patent application for such plating technique using pads invented in the joint development was filed before August 2002.
- 2. [redacted: the US company] regards that 11 applications are possible to be joint applications. Ebara is responsible for preparing English-translated <u>abstracts, claims, brief descriptions of the drawings, explanations of symbols</u> and drawings of these applications, and sending them to [redacted: the US company]. => Please translate the above-mentioned parts the applications listed below in about two weeks.
- 3. When such applications are decided to be the joint applications with [redacted: the US company], add the inventors and applicants.
- 4. Listed below are possible joint applications.

If the English-translated text can be used as they are, its OK.

	•		•	
App. No.	2002-350529	(Original application of the domestic priority)	Filed in the U.S. A.	(2)
	2003-015236		Filed through PCT.	(4)
	2003-149827		Filed through PCT.	(10)
	2003-161236		Filed through PCT.	(1,1)
_	2003-161237	·	Filed through PCT.	(12)
	2003-195406	•	Filed in Japan only.	(14)
	2003-399443	(Domestic-priority-claimed application of 2002-350529)	Filed in Japan only.	(22)
	2003-431211		Filed in Japan only.	(24)
•	K1030446			(26)
	K1040012	·		(28)
	K1040028	·		(29)

^{5. [}redacted: the US company] disclosed three applications: two will be the joint applications while the rest ([redacted: technical field]) will be sole application of them.

Mr. Hiroyuki Hagiwara, 18:25 04/02/28 +0900, 米国における発明者追加について

To: Mr. Hiroyuki Hagiwara

From: 笹部憲一 〈sasabe.kenichi@ebara.com〉 Subject: 米国における発明者追加について

Cc: Bcc: Attached:

Fish & Neave 萩原弁護士殿

いつもお世話になり有難うございます。 Portlandにて口頭でお伺いしましたが、下記の点に関してアドバイスいただきたくお願い致します。

Redacted

Redacted

恐縮ですが、来週(3月第1週)末までにアドバイスいただければ助かります。

笹部 憲一

This information is intended for the use of the addressee and may contain information that is privileged and confidential. If you are not the intended recipient you are hereby notified that the unauthorized dissemination of this communication is strictly prohibited. If you have received this communication in error, please notify us immediately.

Mr. Hiroyuki Hagiwara, 18:25 04/02/28 +0900, Regarding addition of inventors in US

To: Mr. Hiroyuki Hagiwara

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Regarding addition of inventors in US

Cc:

Bcc:

Attached:

Fish & Neave

Dear Attorney Hagiwara,

We always appreciate your advice and support for the patent issues.

As I orally mentioned in Portland, I'd like to ask for your advice again regarding the following points.

[REDACTED]

[REDACTED]

We'd appreciate if you could give us your advice till the end of next week (1st week of March).

Kenichi Sasabe

[Below to the end is originally English text.]

This information is intended for the use of the addressee and may contain information that is privileged and confidential. If you are not the intended recipient you are hereby notified that the unauthorized dissemination of this communication is strictly prohibited. If you have received this communication in error, please notify us immediately.

To: "Kenichi Sasabe (E-mail)" \sasabe@fuj.ebara.co.jp>

Cc: "Hagiwara, Hiroyuki" <HHagiwara@fishneave.com>, "Toh, Kaede" <KToh@fishneave.com>

Subject: Response to your question regarding U.S.-Japan joint development situation

Original Message-

> From: Zamot, Lucila

> Sent: Wednesday, March 03, 2004 5:30 PM

> To: Jackson, Robert R.

> Subject Sasabe letter >

> <<Sasabe ltr.PDF>>

FOF L

Sasabe ltr.PDF



Herbart F. Schwartz Eric C. Woglam Robert C. Morgan Kenneth B. Herman Robert R. Jackson Jesse J. Jenner W. Edward Bishy Patricia A. Martone Roderick R. McKehie James F. Holly, Jr. Richard M. Barnes Laurero S. Roges Vincent N. Palladino

Robert I. Goldman'
Thomas I. Sacrest
Doniel M. Genti
Norman H. Bearno'
Kevin I. Colligan
Glern A. Outserbout
Susan Projeti
Margaret A. Pierri
Doughas I. Gibert
Denise I. Loring
Jeffuny H. Ingerman
Mark H. Bournburg
Jane A. Massaro

Duane-Ozeki Hough
Nazik D. Rowland*
Edward J. DeFrance*
Eric R. Hubbard
William J. McCabe
John M. Hintz
Richard A. Inz
Frances M. Lynch
Christopher J. Hument
A. Joy Amold
Steven Cherny
Jeanne G. Curtis
Jeanne C. Curtis

Gerald J. Fathmann, M.
Kevia P. B. Admracon
Robert W. Morris
Mynash S. Lete
Jaire T. Gurnston
Richard L. Rainey
Pablo D. Hender
Pablo D. Hender
Robert B. Wison
Robert B. Wison
Robert B. Wison
Robert B. Wison
Robert B. Wison
Robert B. Wison
Robert B. Wison
Robert B. Wison
Robert B. Wison
Robert B. Wison
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert
Robert B. Robert B. Robert
Robert B. Robert B. Robert
Robert B. Robert B. Robert
Robert B. Robert B. Robert
Robert B. Robert B. Robert
Robert B. Robert B. Robert
Robert B. Robert B. Robert
Robert B. Robert B. Rob

Frederick P. Fish 1855-1930 Charles Neave 1867-1937

"Calibratis and New York Hars "Calibratio Box Only "OC Bar Only

ROBERT R. JACKSON
DIRECT DIAL 212.596.9022
E-MAIL RIACKSONGFISHMEAVE.COM

March 3, 2004

VIA E-MAIL

Mr. Kenichi Sasabe General Manager Ebara Corporation Patent Department New Product Development Division Precision Machinery Group 42-1 Honfujisawa Fujisawa-shi 251-8502 Japan

> Hypothetical Questions Regarding U.S.-Japan Joint Development Situation Our File: 1184.001

Dear Mr. Sasabe:

Thank you for your inquiry.

The following is my attempt to at least partly answer your questions.

Please make sure that what I say does not reflect some factual misunderstanding by me. If you detect any such misunderstanding, please accept my apology, and please correct me

1251 AVENUE OF THE AMERICAS, NEW YORK, NY 10020 TEL 212.596.9000 FAX 212.596.9090 525 UNIVERSITY AVENUE, PALO ALTO. CA 94301 TEL 650.617.4000 FAX 650.617.4090 1825 I STREET, NW. SUITE 400. WASHINGTON DC 20006 TEL 202.857.5222 FAX 202.857.5237

Mr. Kenichi Sasabe March 3, 2004 Page 2

Mr. Kenichi Sasabe March 3, 2004 Page 3

Mr. Kenichi Sasabe March 3, 2004 Page 4

Mr. Kenichi Sasabe March 3, 2004 Page 5

redacted

Feedback from you regarding the foregoing would now be helpful to me.

Sincerely yours,

Whent P. Jackson
Robert R. Jackson

RRJ:lz

Mr. Pedersen, 17:04 04/05/11 +0900, Export license for Japanese application

To: Mr. Pedersen

From: 笹部憲一〈sasabe.kenichi@ebara.com〉 Subject: Export license for Japanese application

Cc. Mr. Akai

Bcc:

Attached: D:¥My Dcuments¥; redac PaP project¥Mr.Pedersen.doc;

Dear Mr. Pedersen,

Please give us your advise on the issue described in the attached document by the end of this week.

If you need more information please let me know by e-mail.

I will have a telephone conference with redac attorney on this matter next week.

Best regards,

Kenichi Sasabe Patent Department Ebara Corporation

Mr. Pedersen, 15:17 04/05/15 +0900, Export License

To: Mr. Pedersen

From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Export License

Cc: Mr. Akai, Mr. Saito, Mr. Y.Fukunaga

Bcc:

Attached: D:¥My Dcuments¥ redac PaP project¥Export License.doc;

Dear Mr. Pedersen

I have studied your letter and the article by Mr. Helfgott but I really cannot understand how far or how precise we must describe the situations and reason of the error. I drafted a draft attached to this e-mail.

Please give me your comment.

Please point out any comments, for example what to say ,what not to say, etc. I think this kind of document submitted to USPTO may be a part of the file wrapper of the related US application. I want to say as little as possible to get the export license.

redacted

I appreciate if you can give me your comment by 10:00pm on May 18 in Japantime (9:00am May 18 EST)

Best regards, Kenichi Sasabe

Mr. Pedersen, 12:49 04/05/18 +0900, Export license

To: Mr. Pedersen

From: 笹部憲一 〈sasabe.kenichi@ebara.com〉

Subject: Export license

Cc: Mr. Akai, Mr. Shinozuka, Mr. Saito

Bcc:

Attached:

Dear Mr. Pedersen

redacted

Please give us your brief advice for the question (1) by May 19, 9:00pm Japan time (May 19, 8:00am EST)

I am sorry we don't have enough time to consider.

Best regards, Kenichi Sasabe

Mr. Musaka, 11:45 04/05/19 +0900, Fwd: Export license

To: Mr. Musaka

From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Fwd: Export license

Cc: Bcc:

Attached:

六平様

下記のメールはEBRの米国出願を担当している弁護士とのやり取りですが、多くの出願に関してライセンスを取ることに対する弁護士からのアドバイスです。#2、#22に関してライセンスを取ることと、関連する7件に関して取ることで、決定的に難しくなることは無さそうです。 ご参考までにお送りいたします。

Date: Wed, 19 May 2004 08:44:35 +0900

To: Mr. Y.Fukunaga, Mr. Mishima

From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Fwd: Export license

福永様、三島様

Pedersen弁護士から回答がきました。 昨日Pedersenに送ったメールは以下の物です。

Dear Mr. Pedersen

Please give us your brief advice for the question (1) by May 19, 9:00pm Japan time (May 19, 8:00am EST) I am sorry we don't have enough time to consider.

Best regards, Kenichi Sasabe

Subject: Export license

Date: Tue, 18 May 2004 17:28:41 -0400

Thread-Topic: Export license

Thread-Index: AcQ9Hxce2SSOqX65QCiKZ2e3wEljxA=
From: "Nils E. Pedersen" <npedersen@wenderoth.com>
To: "????" <sasabe.kenichi@ebara.com>

Dear Mr. Sasabe,

redacted

Please let me know what further questions you may have.

Sincerely,

Nils E. Pedersen

for

WENDEROTH, LIND & PONACK, L.L.P.

Attomeys and Counselors at Law

Patents, Trademarks, and Copyrights

2033 K Street, N.W., Suite 800

Washington, DC 20006 U.S.A.

Confidentiality Notice:

This e-mail message and any attachments are confidential, may be privileged, and may contain proprietary information. This email is intended exclusively for the individual or entity to which it is addressed. If you are not the intended recipient, please notify Wenderoth, Lind & Ponack, L.LP. immediately by replying to this message or by

sending an e-mail to wlp@wenderoth.com, and destroy all copies of this message and any attachments. Thank you. If you are not the intended recipient, you are not authorized to read, print, copy, retain, or disseminate this email or any information included in this email.

For more information about Wenderoth, Lind & Ponack, L.L.P., please visit us on the web at www.wenderoth.com

Mr. Musaka, 11:45 04/05/19 +0900, Fwd: Export license

To: Mr. Musaka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Export license

Cc:

Bcc:

Attached:

Dear Mr. Musaka,

I'd like to forward the communication with the attorney for EBR responsible for filing in the U.S.A. as a reference. He offers us some advices regarding obtaining licenses for many patent applications. Briefly to say, if we obtain licenses for #2 and #22 and seven related applications, filing in the U.S.A. will not be critically hard.

Date: Wed, 19 May 2004 08:44:35 +0900

To: Mr. Y.Fukunaga, Mr. Mishima

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Export license

Mr. Fukunaga, Mr. Mishima

Our Attorney, Mr. Pedersen gave me his reply.

The message below is the mail I sent to Mr. Pedersen yesterday.

[Below to the end is originally English text.]

由, 10:42 04/05/24 +0900, Fwd: Petition and Statement Your Ref: GEB1988

To: 福永(由)室長殿

From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Fwd: Petition and Statement Your Ref: GEB1988

Cc: 赤井部長殿, 篠塚担当部長殿

Bcc:

Attached: C:\footnote{C:\footnote{PROGRAM} FILES\footnote{EUDORA\footnote{FILES\footnote{EUDORA\footnote{Fales}} PaP project\footnote{EUDORA\footnote{Fales}} PaP project\footnote{Fales} PaP project\footnote

福永様

Pedersenさんのメールは文字化けしていますが、ブランクなどが変な文字に置き換わっているだけのようですので、添付のWord文書のようになると思います。

このような内容で直接の関係者それぞれのpetition(請願)を作っていく必要があります。

Statementの方は笹部の名前になっていますが、私は後で調べて分かった部分が多いので、直接の知識のある方にお願いすることになると思います。

Pedersenさんにはまだ相談していませんが、このプロジェクトに関する包括ライセンスを取っておく必要があると思います。

Subject: Petition and Statement Your Ref. GEB1988

Date: Sat, 22 May 2004 10:52:08 -0400

X-MS-Has-Attach: yes

Thread-Topic: Petition and Statement Your Ref: GEB1988 Thread-Index: AcRADFtJFJ/QEyZ6R6mRalz1DYNCMQ==From: "Nils E. Pedersen" <npedersen@wenderoth.com>

To: <sasabe.kenichi@ebara.com>

May 24, 2004

Ebara Corporation

Patent Department

11â€'1 Asahiâ€'cho, Haneda, Ohtaâ€'ku

Tokyo 144‑8510, Â JAPAN

Attn: Â Mr. Kenichi Sasabe

Dear Mr. Sasabe:

redacted

redacted

Sincerely,

Nils E. Pedersen

for

WENDEROTH, LIND & PONACK, L.L.P.
Attorneys and Counselors at Law
Patents, Trademarks, and Copyrights
2033 K Street, N.W., Suite 800

Washington, DC 20006 U.S.A.

Confidentiality Notice:

This e-mail message and any attachments are confidential, may be privileged, and may contain proprietary information. This email is intended exclusively for the individual or entity to which it is addressed. If you are not the intended recipient, please notify Wenderoth, Lind & Ponack, L.L.P. immediately by replying to this message or by sending an e-mail to wlp@wenderoth.com, and destroy all copies of this message and any attachments. Thank you. If you are not the intended recipient, you are not authorized to read, print, copy, retain, or disseminate this email or any information included in this email.

For more information about Wenderoth, Lind & Ponack, L.L.P., please visit us on the web at www.wenderoth.com

Y, 10:42 04/05/27 +0900, Fwd: Petition and Statement Your Ref GEB1988

To: General Manager Y. Fukunaga

From Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Petition and Statement Your Ref: GEB1988

Cc: General Manager Akai, Manager Shinozuka

Bcc:

Attached: C:\text{C:YPROGRAM FILESYEUDORA\text{\text{*}}attach\text{*}petition.doc;C\text{*}PROGRAM FILES\text{*}EUDORA\text{*}attach\text{*}verified statement.doc;D\text{*}My Documents\text{*}[redacted: the US company]PaP project\text{*}Letter from pedersen04.05.24.doc;

Dear Mr. Fukunaga,

The message sent by Mr. Pedersen was garbled; though, the garbled characters are blanks only. You can read his message in the attached Word file.

Referring the statement as Mr. Pedersen prepared, we need to prepare petitions for each person directly responsible for the issues.

His example statement is to be signed by me, Sasabe; however, I will request people who directly know about the issues because I learned many things later after studying.

Although I have not asked Mr. Pedersen for his opinion yet, I think we should obtain the open general license on this project.

[Below to the end is originally English text including garbled characters.]

kmusaka@ebaratech.com, 19:48 04/03/06 +0900, Fwd: S1プロジェクトPat Listの件

To: kmusaka@ebaratech.com

From: 笹部憲一 〈sasabe.kenichi@ebara.com〉 Subject: Fwd: S1プロジェクトPat Listの件

Cc: fukunaga.yukio@ebara.com, mishima@shi.ebara.co.ip

Attached: D:¥My Dcuments¥ redac PaP project¥English translation of Ebara applications for redac ¥2003-015236.doc; D:¥My Dcuments¥ redac PaP project¥English translation of Ebara applications for redac ¥2003-149827.doc; D:¥My Dcuments¥redac PaP project¥English translation of Ebara applications for redac ¥2003-161236.doc; D:¥My Dcuments¥redac PaP project¥English translation of Ebara applications for redac ¥2003-161237.doc;

Dear Musaka-san

Please find attached translation of Ebara's Japanese applications. We prepared the English translation of the following applications

Analiantian Na
Application No.
2003-015236
2003-149827
2003-161236
2003-161237
2003-195406
2003-431211
2004-022178
2004-023256
K1040028

At the meeting I explained that the item No.26-28 was under preparation for application. But 26-28 was already filed by the end of January 2004. Item No.29 is not filed yet.

Item No. 22 is a domestic priority application (国内優先) of the original application No.2. The original application (Item No. 2) is abandoned and amended application No. 22 is alive. I explained that item No.2 was filed in US and item No.22 was not filed in US. But I found the US application included the amended claims and this US application is the application of item #22 instead of item #2.

I will send the US application on Monday because I don't have e-data of this application.

Item #23 is not prepared yet. Because I did not notice item #23 was included in the applications to be reviewed until I received the Meeting Minutes. Please give us some more time for this application.

I will send the English translations listed above in 2 separated mails.

Best regards Kenichi Sasabe

X-Sender: yf08594@pop.ebara.co.jp

X-Mailer. QUALCOMM Windows Eudora Version 4.3.2-J

Date: Fri, 05 Mar 2004 13:03:37 +0900

To: sasabe.kenichi@ebara.com

From: Yukio Fukunaga \fukunaga.yukio@ebara.com>

Subject: S1プロジェクトPat Listの件

Cc: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>, mishima.koji@ebara.com

特許部

笹部 様

標記の件大変恐縮ですが、翻訳結果を ETI 六平さんに~3/9(US)までに電子データにて送付をお願い致したく。 (六平さんがその後一週間半出張で留守になるため、出張前にに説明しておきたいとのことです)

ご多忙中申し訳ございませんが、よろしくお願い致します。

福永(由)

To: kmusaka@ebaratech.com

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Regarding S1 Project Pat List

Cc: fukunaga.yukio@ebara.com, mishima@shi.ebara.co.jp

Bcc:

Attached: D:\text{My Documents}\text{[redacted: the US company] PaP project\text{English translation} of Ebara applications for [redacted: the US company]\text{\text{Pa003-015236.doc; D:\text{\text{My}}} Documents\text{\text{[redacted: the US company]\text{\text{Pa003-149827.doc; D:\text{\text{\text{My}}}} Documents\text{\text{[redacted: the US company]\text{\text{\text{Pa003-149827.doc; D:\text{\text{\text{\text{My}}}} Documents\text{\text{[redacted: the US company]\text{\text{\text{Pa003-161236.doc; D:\text{\text{\text{\text{\text{My}}}}} Documents\text{\text{\text{[redacted: the US company]\text{\text{\text{Pa003-161236.doc; D:\text{\text{\text{\text{\text{My}}}}} } }

Documents*[redacted: the US company] PaP project*English translation of Ebara applications for [redacted: the US company]*2003-161237.doc

[Below to the beginning of the next message is originally English text excluding the bold characters.]

Dear Musaka-san

Please find attached translation of Ebara's Japanese applications.

We prepared the English translation of the following applications

ltem No.	Application No.
4	2003-015236
10	2003-149827
11	2003-161236
12	2003-161237
14	2003-195406
24	2003-431211
26	2004-022178
28	2004-023256
29	K1040028

At the meeting I explained that the item No.26-28 was under preparation for application. But 26-28 was already filed by the end of January 2004. Item No.29 is not filed yet.

Item No. 22 is a domestic priority application (domestic priority application) of the original application No.2. The original application (Item No. 2) is abandoned and amended application No. 22 is alive.

I explained that item No.2 was filed in US and item No.22 was not filed in US. But I found the US application included the amended claims and this US application is the application of item #22 instead of item #2.

I will send the US application on Monday because I don't have e-data of this application.

Item #23 is not prepared yet. Because I did not notice item #23 was included in the applications to be reviewed until I received the Meeting Minutes. Please give us some more time for this application.

I will send the English translations listed above in 2 separated mails.

Best regards Kenichi Sasabe

X-Sender: yf08594@pop.ebara.co.jp

X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J

Date: Fri, 05 Mar 2004 13:03:37 +0900

To: sasabe.kenichi@ebara.com

From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: Regarding S1 Project Pat List

Cc: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>, mishima.koji@ebara.com

Patent Dept.

Dear Mr. Sasabe,

I would like to ask you to send the translation result regarding the Pat list to Mr.Musaka of ETI by 9 April (US) via e-mail.

(Mr. Musaka will leave the office for the business trip for about one and a half week after that date. He says he wants to explain to [edacted: the US company] before making his trip.)

I realize you are very busy; though, I would appreciate your cooperation.

Y. Fukunaga

kmusaka@ebaratech.com, 23:12 04/03/09 +0900, S1 project patent

To: kmusaka@ebaratech.com

From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: S1 project patent

Cc: fukunaga.yukio@ebara.com, mishima.koji@ebara.com

Attached: D:¥My Dcuments¥-ted 用EBR特許リスト¥Ebara Patent Applications Mar0904.xls;

六平様

ご指摘のありましたリストのitem # 2と#22の外国出願欄を修正しました。添付します。

Item #2と#22の関係について説明します。

それぞれの出願日は

出願番号

出願日

Item #2

2002-350529

2002.12.2

#2の国内優先出願 2003-399443 Item #2のUS出願

未入手

2003.11.28 2003.12.1

です。

日本で国内優先を行って、親出願と国内優先出願とを優先権主張して外国出願を行う 事が多いのすが、国内での国内優先出願が手間取りますと、国内優先より前に外国 出願することになります。この場合には、優先権主張は親出願だけとなり、親出願に 開示されていない事項は外国出願日が出願日となります。 今回は11月29日が土曜日ですので、実質1稼動日の違いで国内優先の方が早かった ことになりますが、米国出願は進めていた手続きに従って12月1日に出されています。 このため、US出願には優先権として2002-350529のみが記されています。 (親出願の優先権を生かすためには12月2日までにUS出願が必要で、優先権証明を 取ったりしているよりUS出願した方が早いためこのように処理しています。)

お送りしたUS出願原稿で#22で追加になっている部分は以下の部分です。

p.7 line 13-line 21

p.8 line 14-p.10 line 11

p.11 line 4-p.13 line 8

p.14 Fig.15, 17の説明

p.15 Fig.18-21の説明

p.36 line 5- p.37 line 6

p.38 line 5- p.45 line 2(最後)

Claim 17-21, 24-27

内容としては、複数の電極ヘッドを用いた複数段の処理、複数の処理液を用いた複数 段の処理がitem #2に追加されています。

US出願は12月1日に出願されていますが、米国の代理人事務所から日本の弁理士事 務所にまだApplication Noの連絡が入っておらず、現時点では分かりません。分かり次 第連絡いたします。

以上、よろしくお願い致します。 笹部

Kmusaka@ebaratech.com, 23:12 04/03/09+0900, S1 project patent

To: kmusaka@ebaratech.com

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: S1 project patent

Cc: fukunaga.yukio@ebara.com, mishima.koji@ebara.com

Bcc:

Attached: D:\(\frac{1}{2}\)My Documents\(\frac{1}{2}\)EBR Pat list for [redacted: the US company]\(\frac{1}{2}\)Ebara Patent Applications Mar0904.xls;

Mr. Musaka,

For the list items #2 and #22 you pointed out, I've corrected the descriptions in the column for foreign application filing. The corrected one is attached to this email.

The relation between Items #2 and #22 is as described below.

Their application Nos. and filing dates are:

Application No. Filing date

Item #2 2002-350529 December 2, 2002

Domestic priority application for #2 2003-399443 November 28, 2003

U.S. application of Item #2 N/A December 1, 2003

Usually, we first file an original patent application and its domestic priority application in Japan, and then file its foreign application with a claim of priority for the original and domestic priority applications. In cases where it takes long time to file domestic priority applications, we file relevant foreign applications in advance of the domestic priority applications. In these cases, priority is claimed for their original applications only; for items not disclosed in the original applications, the foreign application filing date becomes the filing date.

For Items #2 and #22, the domestic priority application was filed one operating day earlier than the U.S. application (because November 29 is Saturday), which was filed on December 1 in the ongoing process.

As a result, the U.S. application claims priority for 2002-350529 only.

(To make priority for the original application effective, the U.S. application must have been filed on or before December 2. These steps have been taken because filing the U.S. application is more time-effective than obtaining priority certificates.)

The following items have been added to #22 in the submitted U.S. application draft.

- p.7 line 13 to line 21
- p.8 line 14 to line 11 in p.10.
- p.11 line 4 to line 8 in p.13
- p.14 Description of Figs.15 and 17
- p.15 Description of Figs.18 to 21
- p.36 line 5 to line 6 in p.37
- p.38 line 5 to line 2 in p.45 (end)

Claims 17 to 21 and 24 to 27

Descriptions on a multi-stage process using multiple electrode heads and a multi-stage process using multiple processing liquids have been added to Item #2.

Regarding to the U.S. application filed on December 1, our attorney frm in Japan is not informed of the application No. from the attorney firm in the United States. I will let you know as soon as I figure out the No.

Sincerely,

Sasabe

中柴部長殿, 赤井副部長殿, 近藤副部長殿, 篠塚担当部長殿, 23:51 04/03/17 +0900, ted 関連出

To: 中柴部長殿, 赤井副部長殿, 近藤副部長殿, 篠塚担当部長殿

From: 笹部憲一〈sasabe kenichi@ebara.com〉

Subject: redac 関連出願の出願方法

Cc. 福永(由)室長殿, 三島部長殿, 坂口担当部長殿

Bcc:

Attached:

知財部各位

redac 関連の新規出願については、今後下記のようにしたいと考えますので、問題点のご検討 をお願いします。 大きな問題点がなければ、この案をベースに進めたいと考えます。

redac -tedとは共同開発契約の中で、

- 1. このプロジェクトにかかわる発明は、発明後30日以内に相手側のTechnical Coordinator に書類で連絡する
- 2. 連絡を受けた側はその案件が共願に該当するか検討し回答する
- 3. 特許出願後2ヶ月以内に、出願のコピーを相手側に渡す。

ことになっています。なお、Technical Coordinatorは、redac redac to EBR: 六平さんです。

このため、今後は社関連出願は

- このため、うちには関連に関係できた。 1. 発明等届出書の段階で、ted 関連となる可能性について検討する。(特許部→福永由紀
- 夫室長) 2. redac 関連の可能性のあるものは、発明の要約の英訳を作成し、Excel sheetに記入して六平さんに送付する。
- 3. 六平さんは「社に連絡し、検討を依頼する。
- 4. 上記2、3と並行して、弁理士に依頼して出願書類を作成する。

5. redac からの回答が、共願希望の場合には、redac の発明者を加えて、英訳し、米国第1国出願とする。

- 6. 出願から2ヶ月以内に、出願現行のコピーを六平さんを通して「ted に渡す。
- 7. redac の回答が、共願不要であれば、在原の発明者のみで日本国内に出願する。 / .-ted の回台か、共願不安での行いる、任原の光明日のかで日本国内に正願する。 8. クレームと要約との英訳を作成し、出願から2ヶ月以内にコピーを六平さんを通してtedに 渡す。

対象となる出願は、接触、擦りを伴う含浸めっき、及び電解加工、電解CMPです。

今後、新規の出願に関しては上記の方法によることと致したく、問題点のご検討お願いしま 特に、共願の場合は将来の問題を防止する意味で米国第1国出願としますので、ご注意お 願いします。 万一、redac 関連と思われる出願がチェックなしに知財部に回っていると思われる場合には、恐縮ですが、ご連絡お願いします。

米国第1国出願とした場合には、6ヶ月以上1年以内経過した後、米国から外国出願しま

なお、共同開発が継続しますので、エキスポートライセンスは取得しておいた方がよいと考え ます。 昨年のEBR関連会社の問題のその後、及び現在ライセンスを取得する上での問題につい て、SSDに確認してください。

General Manager Nakashiba, Deputy General Manager Akai, Deputy General Manager Kondo, Manager Shinozuka, 23:51 04/03/17+0900, How to file [redacted: the US company]-involved applications

To: General Manager Nakashiba, Deputy General Manager Akai, Deputy General Manager Kondo, Manager Shinozuka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: How to file [redacted: the US company]- involved applications

Cc: General Manager U. Fukunaga, General Manager Mishima, Manager Sakaguchi

Bcc:

Attached:

To all concerned in Intellectual Property Dept.

I propose that new [redacted: the US company]- involved applications will be filed in the procedure described below. Your check and review would be very appreciated. If everything is OK, I will go ahead based on this proposal.

According to the joint development contract with [redacted: the US company].

- 1. Any invention linked to this project shall be reported to Technical Coordinator of the other side with a written notification within 30 days of the invention
- 2. The side receiving the report shall consider and reply whether the invention is subject to a joint patent application or not, and;
- 3. Copies of the application documents shall be delivered to the other side within two months of the patent application filing.

Technical Coordinator of [redacted: the US company] is [redacted: personal name] and of EBR is Mr. Musaka.

Considering this contract, follow the procedure described below for filing [redacted: the US company]- involved applications:

- 1. Consider the possibility that an invention may be related to [redacted: the US company] upon preparation of "Notification of Invention" (Patent Dept. -> General Manager Yukio Fukunaga).
- 2. For an invention that may be related to [redacted: the US company], translate the abstract of the invention into English. Then, fill out the Excel form and submit it to Mr. Musaka.
- 3. Mr. Musaka will contact [redacted: the US company] and ask for its review.

- 4. Along with Steps 2 and 3, ask appropriate attorneys to prepare documents for application filing.
- 5. When [redacted: the US company] replies that the patent application of the invention should be a joint application, add an inventor or inventors in [redacted: the US company] to the documents and translate them into English. Then, file the first application in the United States.
- 6. Deliver a copy of the application draft through Mr. Musaka to [redacted: the US company] within two months of the application filing.
- 7. When [redacted: the US company] replies that the joint patent application of the invention is not required, file the application in Japan under name(s) of the inventor(s) in Ebara only.
- 8. Translate the claims and the abstract of the invention into English and submit copies of the translations through Mr. Musaka to [redacted: the US company] within two months of the application filing.

Applications related to impregnation plating, electro-chemical process, and electro-chemical mechanical polishing that involve contact and rubbing are subject to the procedure above.

I propose that new applications will filed according to the procedure above in the future, and your check and review would be greatly appreciated.

Take particular note of joint applications that would be filed first in the United States to prevent future trouble.

If any [redacted: the US company]-involved application appears to have been sent to Intellectual Property Dept. with no check done, I would be very grateful for reporting me about it.

To file the first patent application of an invention in the United States, the application will be filed in the United States as a foreign application in six months or more and within one year.

Appropriate export licenses should be obtained because the joint development continues. For the troubles occurred after the issues caused by an affiliate of EBR last year and current issues related to obtaining the licenses, consult SSD.

Mr. Musaka, 三島部長殿, 14:43 04/04/29 +0900, -ted /EBR 出願

To: Mr. Musaka, 三島部長殿 From: 笹部憲一〈sasabe.kenichi@ebara.com〉 Subject: -ted /EBR 出願 Cc: 福永(由)室長殿

Bcc:

4月24日にお話しましたEBRの主張をお送りします。 referenceはお持ちと思いますが、念のためお送りします。 referenceのvolが大きいため、何度かに分けてお送りします。 荏原の出願が荏原の権利であることを -ted に説明するための資料です。

#4について

4 月 24 日にお話しましたが、本日資料を見直していて、redac の 2002 年 8 月の資料の"Tool Design / Process Development Plan"の表に Design Modification として "Provide adjustable wafer/pad distance coupled to applied Volt." と言う言葉を見つけました。

24 日には redacted からはパッドとウエハの押付け力 (Down force) は常に+なので、パッドとウエハは接触していると考えていましたが、これでは差が言えなくなりました。このため、電流が逆転しないことを理由にしました。電流の大きさを変えることは redacted からは開示されていませんので、上記 Design Modification にある applied Volt.も電流の polarity の変化と考えました。

このため、クレーム 1、2、6.8の voluntary amendment も applied voltage を applied plating voltage に変更する程度としたいと思います。

redacted に出している英文は、日本出願の翻訳でほぼ正確な翻訳ですが、英文のクレーム として検討した物ではありませんので、実際に外国出願する場合には翻訳は変わると思 います。

この場合にも、電圧が基板側がカソード電圧又はゼロになるような範囲に限定した翻訳 にします。

三島さんは redac から示されたのはヘッドにパッドをつけた図と、めっきとエッチングを繰り返すプロセスの図だけだとのことですが、8/23/02の日付の Tool Modification for 200mm Plating & Electropolishing Modules という議事録(jointly agreed between Ebara and redac that ・・・)という文書があり、control z-motion、 control down force by distance and calibrate distance vs force などが合意されていますので、三島さんが記憶している 2 枚の図よりはもう少し具体的な議論がされていたかもしれません。

#10 について

Ebara の単願としたい。このためクレーム 13 は取り下げる。

#12、14、24 について

全て Ebara の単願と考える。

Mr. Musaka, General Manager Mishima 14:43 04/04/29 +0900, [redacted: the US company]/EBR application

To: Mr. Musaka, General Manager Mishima

From: Kenichi Sasabe <sasabe.kenichi@ebara.com> Subject: [redacted: the US company]/EBR application

Cc: General Manager U. Fukunaga

Bcc:

Attached: D:\text{MyDocuments} \text{Iredacted: the US company} \text{PaP project} \text{Comments on documents sent by Mr. Musaka.doc; D:\text{MyDocuments} \text{Ownership of patent applications 04.04.29.xls; D:\text{MyDocuments} \text{Iredacted: the US company} \text{PaP project} \text{Mr. Mishima} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{PresentationRubbingJuly.01.ppt; D:\text{MyDocuments} \text{Iredacted: the US company} \text{Predacted: a Japanese company} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument} \text{Iredacted: a Japanese company} \text{Jocument}

I send you the Ebara's point of view that I have talked on April 24.
I think you have the reference, but I send it, just in case.
Because the volume of reference is huge, I will divide it into several mails.

Dear Mr. Musaka,

This is a document to explain [redacted: the US company] the applications filed by Ebara in Japan should belong to Ebara

Regarding #4

As I have informed on April 24, I found words, "Provide adjustable wafer/pad distance coupled to applied Volt." as Design Modification in the table "Tool Design / Process Development Plan" in the documents of August 2002 by [redacted: the US company] when I was reviewing the document today.

On 24th, I had been thinking that the pad and the wafer was always in contact because of the pressing force of the pad and the wafer (down force) was always + based on the presentation by [redacted: the US company]. However, because of it, we can no longer say the difference.

Therefore, I used a point that the current does not invert for that reason. Changing the current intensity is not disclosed by [redacted: the US company]; therefore, I interpreted the applied Volt. in the above Design Modification as change of current polarity.

Therefore, I would like to make changes to voluntary amendment in the claims 1, 2, 6, 8 to the degree, from applied voltage to applied plating voltage.

Although the English translation submitted to [redacted: the US company] is the translation of the Japanese patent application and is almost exact translation. However, this is not discussed for using as the claims in English, the translation will be changed when actually filing it for a foreign application.

In this case, too, the translation is going to be a range limited such that the voltage on the substrate side becomes either the cathode voltage or zero.

Mr. Mishima says what [redacted: the US company] presented were only a drawing of a head having a pad and a drawing of a process repeating plating and etching. However, the minutes, Tool Modification for 200mm Plating & Electropolishing Modules, dated on 8/23/02, contains a sentence (jointly agreed between Ebara and [redacted: the US company] that ...), and matters including control z motion, control down force by distance and calibrate distance vs force have been agreed. Therefore, more in depth discussions might have been taken place than what Mr. Mishima remembers about two drawings.

Regarding #10

We desire to file it as the Ebara solo application. Therefore, we drop the claim 13.

Regarding #12, 14, 24

We see all of them for the Ebara solo application.

Attachment Preliminary amendments



由, 08:55 04/05/06 +0900, Fwd: FW: Ebara Patent Applications and subject of telecon 5/06/

To: 福永(由)室長殿

From: 笹部憲一 〈sasabe.kenichi@ebara.com〉

Subject: Fwd: FW: Ebara Patent Applications and subject of telecon 5/06/04 at 5:00 pm

Cc:

Bcc:

福永様 金曜日6:00AMの電話会議、笹部は対応可能です。他の方が対応可能でしたら、六平さんに OK回答していただきたくお願いします。 三島さんにも出席いただいたほうが良いと思います。 私は今日は10時半ごろから羽田に行かなければならないので、恐縮ですが、お願い致しま

す。

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com> To: "Fukunaga. Yukio (E-mail)" <fukunaga.yukio@ebara.com>,"Sasabe Kenichi (E-mail)" <sasabe.kenichi@ebara.com>,"Nambu, Isao" <inambu@ebaratech.com> Cc: "Kimura, Norio" <nkimura@ebaratech.com> Subject: FW: Ebara Patent Applications and subject of telecon 5/06/04 at 5:00 pm Date: Tue, 4 May 2004 23:43:53 -0700 Importance: high X-Mailer. Internet Mail Service (5.5.2653.19)

Folks,

Please find attached IP list on which ted san added summary of our discussion today in the last column.

Understanding each company's position on those patent applications at this time, we'd like to propose a telephone conference as follows,

5/6(Thu) 5:00pm(EDT), 5/7(Fri) 6:00am(JST) Date & Time: TBD (Will send you separate e-mail once

Call-In: notified by redac.) redacted Attorneys Attendees:

redaci redaci ted -ted-san, redacted Attorneys EC/ETI - Sasabe-san, Fukunaga-san, Nambu-san, Musaka

(Please add appropriate person(s) if necessary.)

I understand it's very early in the moming. However, that's only time reducted attorneys are available. Also, originally, reduction was proposing sometime in next week, but all the sudden, she is in a hurry to conclude the discussion, and wants to hold the meeting in this week.

I really appreciate for your generous understanding and strong support on this matter.

Best Regards, K.Musaka

Original Message

redacted

redacted

Y, 08:55 04/05/06 +0900, Fwd: FW: Ebara Patent Applications and subject of telecon 5/06/

To: General Manager Y. Fukunaga

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: FW: Ebara Patent Applications and subject of telecon 5/06/04 at 5:00 pm

Cc:

Bcc:

Attached: C:\(\frac{1}{2}\)PROGRAM FILES\(\frac{1}{2}\)EUDORA\(\frac{1}{2}\)attach\(\frac{1}{2}\)EBARA

Applications_030904__[redacted: the US company]_invent_05_04_04_Musaka.xls;

Mr. Fukunaga,

I can attend the telephone conference to be held from 6:00 am on Friday. If the other members can attend the conference, please replay to Mr. Musaka that we are ready. I think Mr. Mishima should also attend the conference.

Today I will leave for Haneda around 10:30, so I cannot handle the matter. Your arrangement would be greatly helpful.

[Below to the end is originally English text.]

Yukio Fukunaga, 14:14 04/05/07 +0900, Re: S1 Project 特許の件

To: Yukio Fukunaga \(\frac{fukunaga.yukio@ebara.com \rangle}{} From: 笹部憲一 〈sasabe.kenichi@ebara.com〉 Subject: Re: S1 Project 特許の件

Cc: Bcc:

Attached:

福永様

共願6件は #2、#22、#26、#28、#29、#30のことですね。 #26は三島さんのコメントはありましたが、共願として良いですか? 他の点については、これで良いと思います。

At 13:55 04/05/07 +0900, you wrote: 笹部様

下記のメール案を作成してみましたので、内容をご検討頂きたくお願いします。 (本日中の回答希望にしましょうか?) (あるいは六平さんにECにて検討中ということにして、時間をもらいましょうか?)

福永(由)

辻村 役員殿

標記の件、現状報告と懸案事項のご相談を申し上げます。

【現状】

2月のWorkshop後、笹部さんセンターで特許の帰属について、下記のように「ted と調整中 です。

検討案件: 30件

・荏原単願: 19件

IBM·荏原共願: 6件

5件(内4件はJDP契約前出願、内3件PCT出願済み)

【懸案事項】

荏原としては極力単願での調整を進めてきましたが、上記調整中の5件は、荏原が単願 を主張 するものの、折り合いが付いておりません。

(今朝方の先方Attomyを含めたテレコンでも、平行線を辿ったままです)

内容が所謂擦りめっきの方法と装置であるため、当方は2001年頃実施していた「擦り めっき」の

資料(日付はなし)を提示して理解を求めましたが、redac の主張はJDPに入る前に荏原の バック

グランド技術を開示すべきだったのに、今になって開示するのは手続きとしておかしい、と ッフンにまた。 いう具合です。 また「redac として、S1プロジェクトの成果としての期待(メンツ?)もあるようにも感じます。

【対処案】

上記調整中5件に関し、両社ギリギリの線で受容できそうな下記の案を提案したいと考 えます。

日本出願およびPCT出願(USは除く)は、荏原単独のまま(ただし一部クレーム補正

必要)

- ・US出願は共願 (ただしworkshop時に提案受けた「tedacの発明を新たに組み込むこと)
- ●本対処方法に関し、アドバイス頂ければ幸いです。 対処案でOKであれば、笹部さんの方で作業を進めて頂く予定です。

福永(由)

Yukio Fukunaga, 14:14 04/05/07 +0900, Re: Regarding S1 project patent

To: Yukio Fukunaga <fukunaga.yukio@ebara.com>

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Re: Regarding S1 project patent

Cc:

Bcc:

Attached:

Mr. Fukunaga,

You mean the six joint applications are #2, #22, #26, #28, #29, and #30.

Mr. Mishima has commented on #26. Is it OK that #26 will be a joint application?

For the rest, I think the draft is OK.

At 13:55 04/05/07 +0900, you wrote:

Mr. Sasabe,

I've prepared a draft of an e-mail as shown below. Please check and review its details. (Should we request a response to the e-mail within today?)

(Or, should I make a report to Mr. Musaka that the matter is under consideration atEC to gain some time?)

Y. Fukunaga

Member of the Board, Mr. Tsujimura,

Regarding to the subject matter, I will report the current situation and present related concerns.

[Current situation]

After the workshop in February, we are in coordination with [redacted: the US company] for application filing, led by Mr. Sasabe, as described below.

- Under discussion: 30 applications
- Sole application by Ebara: 19 applications
- Joint application by [redacted: the US company] and Ebara: 6 applications
- Under coordination: 5 applications (four of which have been filed before conclusion of the JDP contract and three of which have been also filed as PCT applications.)

[Related concern]

Ebara has made best efforts so that the applications can be filed as sole applications; however, no agreement is reached for the five applications under coordination that Ebara insists should be filed as sole applications.

(The telephone conference, held this morning with the inclusion of the other side's attorney ended up without any progress.)

Those applications are related to the method and apparatus for "rubbing & plating," so we presented documents (without date) on studies about "rubbing & plating" implemented around 2001. With these materials, we asked for their understanding. [redacted: the US company], however, maintained as follows: Ebara should have disclosed the background technique before implementation of the JDP. Disclosing the technique at this late date is an unjustifiable action.

[redacted: the US company] has probably placed expectations on (and had pride about) potential results of the S1 project.

[Proposed action]

For the five applications under coordination, we would like to make a proposal below that may be at least accepted by both the companies:

- · Sole application by Ebara for Japanese and PCT applications (excluding U.S. applications) (Correction of some claims is required.)
- · Joint application for U.S. applications (Incorporation of the invention by [redacted: the US company] proposed at the workshop is required.)

Your advice on this proposal would be appreciated.

If the proposal described above is OK, I will ask Mr. Sasabe to go forward

Y. Fukunaga

redacted

11:17 04/05/08 +0900, Re: Disclosures Number 2 and 22 first filed in Japan

To: redacted

< redacted .com>

From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Re: Disclosures Number 2 and 22 first filed in Japan

Cc: Mr. Y.Fukunaga, Mr. Mishima, Mr. Musaka, Mr. Akai

Bcc:

Attached:

Dear redac -san

Thank you for your e-mail.

I think the Ebara inventors made their invention in Japan. But I will confirm them on Monday.

I will discuss with Mishima-san and Fukunaga-san about the facts and the reasons of the error, and I will send you our story.

Thank you very much for your help.

Best regards, Kenichi Sasabe

At 17:39 04/05/07 -0400, you wrote:

redacted

redacted

PREPARED BY redac ATTORNEY / PRIVILEDGED AND CONFIDENTIAL

三島部長殿, 13:58 04/05/29 +0900, 米港特許庁にExport Licenseを申請するに当たっての

To: 三島部長殿

From: 笹部憲一 〈sasabe.kenichi@ebara.com〉

Subject: 米港特許庁にExport Licenseを申請するに当たっての資料の件

Cc:

Bcc:

Attached:

S1プロジェクトに関する出願に関連する資料のコピーをお出しください。

Export Licenseを申請するには、直接関与した人の請願書と証拠資料の提出が必要です。

す。

現在ペンディングになっている物も含めて、#2, 4, 10, 11, 12, 13, 14, 16, 20, 22, 24, 26, 28, 29合計14件に関する資料(発明に関する資料、発明者への指示、出願依頼、弁理士との相談、知財部との相談、木村さん、六平さん、IBMとのコレポン、ノート、email など)のコピーをご提出ください。 福永さん、知財部、牧野さん、国沢さんには27日に依頼しました。

;)

笹部憲一〈sasabe,kenichi@ebara.com〉の印刷

General Manager Mishima 13:58 04/05/29 +0900, Regarding documents for Export License application to USPTO

To: General Manager Mishima

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Regarding documents for Export License application to USPTO

Cc:

Bcc:

Attached:

Submit copies of documents on the application fling linked to the S1 project.

Upon export license application, application forms filled by those directly involved and evidence documents must be submitted.

Submit copies of documents on the 14 applications in total, including the pending ones: #2, 4, 10, 11, 12, 13, 14, 16, 20, 22, 24, 26, 28, and 29 (documents related to the invention, instructions to the inventors, request of application filing, consultation with the patent agent and Intellectual Property Dept., correspondence between Mr. Kimura and Musaka and [redacted: the US company], related notebooks and e-mails, etc.).

I already asked Mr. Fukunaga, Intellectual Property Dept., Mr. Makino, and Mr. Kunisawa on May 27 to submit the documents.

倉科殿, 並木殿, 中田課長殿, 三島部長殿, 神田課長殿, 長井殿, 山, 21:59 04/06/08 +0900, reducted

To: 倉科殿, 並木殿, 中田課長殿, 三島部長殿, 神田課長殿, 長井殿, 山本殿716, 森沢殿, 井 出殿753, 鈴木秀直殿, 君塚リーダー殿, 国澤課長殿

From: 笹部憲一 〈sasabe.kenichi@ebara.com〉

Subject: redac米国発明の外国出願に関する協力依頼の件 Cc: 牧野殿, 赤井部長殿, 坂口担当部長殿

Attached: D:¥My Dcuments¥redac PaP project¥調査協力依頼040609.doc; D:¥My Dcuments¥redac PaP project¥Pedersen依頼¥Retroactive Foreign Filing License Statement2.xls; D:¥My Dcuments¥-red PaP project¥発明者質問状.doc;

redacted と実施しているS1(PaP)プロジェクトにおいて、EBRが日本で単独出願していた出願に対し、「redac から共願にするよう要求があり、調整しておりますが、現在13件が共願の検討対象となっています。

redacted と共願にする場合には、fedac の発明者を追加することになり、米国で為した発明は米国に 最初に出願しなければならない規定に違反します。このため、米国特許庁及び商務省に Retroactive Foreign Filing Licenseを請願する必要があります。 これに関しまして、添付依頼書に基づき、質問書へのご回答を戴きたくお願い致します。

なお、6月21日に-tedと打合せが予定されており、それまでに対応する必要がありますので、 恐縮ですが6月11日までにご回答いただきたく、ご協力お願い致します。

		作成日 DATE	2004. 6. 9.	Р. 1
宛 先 FOR	下記各位	DOC.No.	708-A460901	
題目	米国発明の海外出願に		全 TOTAL	. 枚 SHEETS
関する協力依頼の件	作成目的 PURPOSE	調査協力依頼		
プロジェクト名 PROJECT	\$1	用 途 SERVICE	Export License	
JOB No.		在原製番 EBARA SER.No		
ITEM No.		機名/装置名 MODEL/EQUIP	·.	台数 SET

redac と実施している S1 (PaP) プロジェクトにおいて、EBR が日本で単独出願していた出願に対し、redac から共願にするよう要求があり、調整しておりますが、現在 13 件が共願の検討対象となっています。

redac と共願にする場合には、redac の発明者を追加することになり、米国で為した発明は米国に最初に出願しなければならない規定に違反します。このため、米国特許庁及び商務省に Retroactive Foreign Filing License を請願する必要があります。

既に共願にすることが決まっている牧野さん、国沢さんには既にお話を伺いましたが、他の方にも添付資料にご記入の上特許部宛て返送お願いします。(国澤殿:表の#28 分割アノードについてご回答ください。)請願が認められるためには、違反に気づいた後、速やかに手続きを行うことが必要ですので、恐縮ですが、至急 6月 11 日までにご回答お願いします。

該当する出願は添付の EBR/redac共願検討出願の表に記載の物です。

発明内容の簡単なメモをつけてありますが、出願原稿をご覧になりたい方は特許部笹部(8550)又は坂口 (9020)までご連絡ください。

質問用紙は質問書Aと質問書Bに分かれています。

質問書 A は発明者の S1(PaP)プロジェクトとの関連に関する質問です。発明者毎に1回お答えください。 質問書 B は各出願に関する質問です。出願1件ごとにご回答ください。複数の出願の発明者になっている方は、恐縮ですが質問書 B をコピーしてご使用ください。

e-mail でもお送りしておきますので、必要な場合はプリントアウトして戴いても結構です。

依頼先

716 倉科殿、 716 並木殿、 716 中田殿、716 三島殿、753 神田殿、753 長井殿、716 山本殿、756 森澤殿、

753 井出殿、716 鈴木殿、EU 君塚殿

cc 760 国澤殿、760 牧野殿

	発 行	承 認	係	. 負 .
ACTION NECESSARY	ISSUED BY	APPROVED BY	CHECKED -	BY
B·関連部署 CONTENTS ESSENTIAL	精密・特許部		笹部	
C・参考まで			,	





Kurashina, Namiki, Manager Nakada, General Manager Mishima, Manager Kanda, Nagai, Yama, 21:59 06/06/08 +0900, [redacted: the US company]

To: Kurashina, Namiki, Manager Nakada, General Manager Mishima, Manager Kanda, Nagai, Yamamoto716, Morisawa, Ide753, Hidenao Suzuki, General Manager Kimizuka, Manager Kunisawa

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Regarding request of your cooperation about foreign filing of inventions with

[redacted: the US company] in USA

Cc: Makino, General Manager Akai, Manager Sakaguchi

Attached: D:\text{My Documents}\text{[redacted: the US company] Pap project\text{Call for cooperation for investigation 040609.doc; D\text{YMy Documents}\text{[redacted: the US company] Pap project\text{\text{Pedersen Request\text{\text{Retroactive Foreign Filing License Statement2.xls; D\text{\text{YMy Documents}\text{\text{[redacted: the US company] Pap project\text{\text{Questionnaire to inventors.doc;}}

Regarding the S1 (PaP) project operated with [redacted: the US company], [redacted: the US company] has requested us to change the sole applications filed by EBR in Japan to the joint applications. We have worked on this issue and identified 13 applications are subject to discussion for joint application.

If they are filed as the joint applications with [redacted: the US company], inventors of [redacted: the US company] will be added. This violates the regulation providing any invention achieved in the U.S.A. shall be filed in the U.S.A. first. To solve this problem, we need to get up a petition for Retroactive Foreign Filing License to Department of Commerce and the United States Patent and Trademark Office

I attached a document regarding this issue. Id like to request all of you to respond the questionnaire.

Please note that a meeting will be held on 21 June with [redacted: the US company]. We need to prepare till that date. I realize all of you are very busy; though, please return your answer by 11 June. I call for your cooperation.

					Support Document AE		
		作成日 DATE	2004.	6.	9.		P. 1
宛 先 FOR	All concerned	DOC.No.	708-A4	6090	1		
題目	Request for your cooperation					全	枚·
TITLE	regarding foreign filing of inventions in the U.S.A.	作成目的 PURPOSE	Rec	quest	for inve		SHEETS
プロジェクト名 PROJECT	\$1	.用 途 SERVICE	Exp	ort L	icense		
JOB No.	·	在原製番 EBARA SER.N	lo				
ITEM No.		機名/装置名					台数

MODEL / EQUIP.

Regarding the S1 (PaP) project operated with [redacted: the US company], [redacted: the US company] has requested us to change the sole applications filed by EBR in Japan to the joint applications. We have worked on this issue and identified 13 applications are subject to discussion for joint application.

If they are filed as the joint applications with [redacted: the US company], inventors of [redacted: the US company] will be added. This violates the regulation providing any invention achieved in the U.S.A. shall be filed in the U.S.A. first. To solve this problem, we need to get up a petition for Retroactive Foreign Filing License to Department of Commerce and the United States Patent and Trademark Office.

Though I already requested Mr. Makino and Mr. Kunisawa, whose inventions have already determined to be joint applications, I'd like to request other members to answer the questionnaire, an attached file. When you complete, please return to Patent Dept. (To Mr. Kunisawa: Please answer Item #28 in the list about divided anode).

To make our petitions granted, quick action must be taken as soon as we realized violation. I understand all If you are very busy; though, please return your answer immediately by 11 June. The applications in question are listed on an atached file regarding the filing of EBR/[redacted: the US company] joint applications.

I gave brief comments about the inventions; though, please contact Sasabe (8550) or Sakaguchi (9020) in Patent Dept. if you wish to refer drafts of the applications.

The questionnaire is divided into Form A and B.

Form A lists questions about relations between the inventor and the S1 (PaP) project. All inventors are requested to answer.

Form B lists questions about each application. All inventors are requested to answerper application. If multiple inventors achieve the invention, please make a copy of Form B and answer. I send the same document via e-mail as well. You can print out if necessary.

	Porcon who are required at a grown the grown the	:	
布 勒 均 元	Person who are requested to answer the questionnaire		
- KK 187	716 Kurashina, 716 Namiki, 716 Nakada, 716 Mishima, 753 Kanda, 753 Nagai, 716, Y	'amamoto. '	756
O SET ACT	Morisawa, 753 Ide, 716 Suzuki, Kimizuka of EU		
	cc: 760 Kunisawa, 760 Makino		

			·	
	A・実施または手配 ACTION NECESSARY	免 行 ISSUED BY	承 認 APPROVED BY	係 貝 CHECKED BY
	B··関連部署 CONTENTS ESSENTIAL	Patent Dept.		Sasabe
- 控	C・・参 考 ま で INFORMATION ONLY	Precision Machinery Group	·	Sasabe



SET

赤井部長殿, 篠塚担当部長殿, 16:11 04/06/11 +0900, Fwd: Meeting with Mr. reducted

To: 赤井部長殿, 篠塚担当部長殿

From: 笹部憲一 〈sasabe.kenichi@ebara.com〉

Subject: Fwd: Meeting with Mr. redacted

Cc: 坂口担当部長殿

Bcc: Attached:

赤井様、篠塚様

いろいろとお手数をかけていますではつの特許の件ですが、下記のように解決の方向に向かうことになりました。
6月10日にではつででではのProject ManagerであるMr. reducted と荏原のProject Managerである木村さん、ETIのDan O'connell、南部さんとで会談し、特許出願の件で、契約違反等の問題になりかけていた件をとりあえず解決してくれました。今後の出願は、明確にではと関連しないものは荏原単願の日本出願でよいですが、でははが、関係する可能性のあるものは基本的に米国出願とすることとし、出願前に英文原稿をではは、見せることにします。辻村さんにもこの方向で了解をもらっています。こうすると、米国出願の件数が増えること(日本出願を何件かまとめて米国出願できなくなる)、出願までの日数が増えること、原稿作成が日本の弁理士、ではは、米国弁護士それぞれで変更、修正される可能性があり、新たな問題が出てくる可能性が有ることなど、いくつか問題が考えられますが、このではいかり、新たな問題が出てくる可能性が有ることなど、いくつか問題が考えられますが、このではいの件に関しては特別扱いとすることとします。

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>
To: "'M Tsujimura'" <tsujimura.manabu@ebara.com>, ogata.akira@ebara.com, "Kobayashi, Fumio (E-mail)" <kobayashi.fumio@ebara.com>,fukunaga.akira@ebara.com, fukunaga.yukio@ebara.com,tokushige.katsuhiko@ebara.com, hodai.masao@ebara.com,mishima.koji@ebara.com, asami.masao@ebara.com, "Sasabe Kenichi (E-mail)" <sasabe.kenichi@ebara.com>,Kimura Norio <kimura.norio@ebara.com>,"Nambu, Isao" <inambu@ebaratech.com>,"O'Connell, Dan" <doconnell@ebaratech.com>
Co: horiuchi.takao@ebara.com, yago.natsunosuke@ebara.com
Subject: Meeting with Mr. redacted Date: Thu, 10 Jun 2004 23:04:21 -0700
X-Mailer: Internet Mail Service (5.5.2653.19)

Great thanks to everybody participated in the quite intensive discussion in last week while my stay in Japan. I believe our meeting today with Mr. reducted was truly successful and satisfactory.

Dan, Nambu-san, Kimura-san and myself visited Mr. redacted today for the discussion on IP issue in JDA. (redacted san also participated by phone.) The discussion was initiated by Dan explaining historical background of this matter, "Ebara had been working on planer plating technology prior to the engagement with redacted for the JDA, and filed patents before the contract, but after initial technical information exchange with reducted on this matter. Ebara should have informed redacted the background IPs in time to avoid any confusion and conflict on the IP ownership. After internal discussion at Ebara, Ebara agreed to modify those patent applications as co-invention with reducted recognizing its impact on the program and redacted so business."

Mr. redacted stated "redac could not understand why Ebara did not submit the

background IPs at the 1st workshop in Sept'03 accordingly to the JDA contract". I replied "Ebara understood the contract, and actually submitted the IP list at the workshop. However, the list was too brief to discuss the details, and re-submitted the list with abstracts in the workshop in Feb'04, which caused some delay in our initial discussion on this matter with redaction of IP ownership, and redacted technical coordinator for identification of IP ownership, and redacted attorneys for modification of total 8 Ebara's Japanese patent applications into co-invention with redacted applying for export license for corresponding US patent applications. reddacted also backed us up stating "Those were the same understanding as hers".

I also explained "In order to avoid any confusion in patent application process in the future, Ebara propose to submit whole translation of IP disclosure to redac before filing patent application for redac's review and determining the co-ownership. "redac-san stated "1-page summary or abstract of US patent application should be sufficient." Dan stated "This process change requires redac's strong support in timely corresponding redac's decision to Ebara since Ebara rely on redac's reply for filing the

patent application."

Finally, I apologized the confusion and promised the compliance to the contract,

and Mr. redacted replied "I'm fine, now."

I also talked with redaction sand after the meeting by phone, and she said "The meeting was quite satisfactory."

I understand it was difficult time for everybody to re-evaluate the contract and determine the countermeasure. Now, I believe, we have better understanding of the contract and how it impacts Ebara's business. We have no choice than succeeding the JDA with $\frac{redac}{-ted}$.

Once again, thank you very much for your understanding and continuous support on this matter.

Best Regards, K.Musaka General Manager Akai, Manager Shinozuka, 16:11 04/06/11 +0900, Fwd: Meeting with Mr. [redacted: personal name]

To: General Manager Akai, Manager Shinozuka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: Meeting with Mr. [redacted: personal name]

Cc: Manager Sakaguchi

Dear Mr. Akai, Mr. Shinozauka,

Regarding the issue related to [redacted: the US company] that we have worked on, I have a news that it will be solved as shown below.

In the meeting held on June 10 in [redacted: the US company], Mr. [redacted: personal name], Project Manager of [redacted: the US company], Mr. Kimura, Project Manager of Ebara, and Mr. Dan O'connell and Mr. Nanbu of ETI discussed the patent filing issue and finally managed to solve the point that might cause breach of contract.

In future, inventions clearly irrelevant to [redacted: the US company] can be sole applications of Ebara, however, if they are possibly relevant to [redacted: the US company], basically, they will be joint applications. English drafts will be shown to [redacted: the US company] before filing. Mr. Tsujimura has already agreed with this direction. This procedure may cause other problems, such as, that the number of filing in the U.S.A will be increased (combining a batch of applications filed in Japan to one US application will not be allowed); that days taken for preparing for filing patent application will be increased; or that drafts may be changed or corrected by Japanese patent attorney, [redacted: the US company], patent attorneys in the U.S.A; however, regarding the issue that [redacted: the US company] is involved is exceptional.

On the way to solve the problem, we may cause more inconveniences to Intellectual Property Dept.; though, I appreciate your understanding and cooperation.

[Below to the end is originally English text.]

治之及 61'7 30

③34 计法共序 装置 田民库府

A) API SAR

Apply reducted of tillings 12/4.

0.00日日日日十年11日1日日

Nain 1: 2001, 9 graduated 7 608 9 41 721, 511 2" 60尺9条件工作器

既出所られがはは三島なる湖でておけかり 一年パッドの利からは入れてるBRのアイデア

同様対水をシルは外により回めの Claim 1 A # 4 9 claim 8 x 181 # 18

Claim 2 of 2 Mil (rate Hour)

18th EBR onlyind.

四全部在顾便一部以明新了与的知识

あるをたったい 神が一部に

成在一〇〇 电路2.77分分

4 Ph 73 Di redocted & 78 13

在初生作了中国3

①等達(クレームをい)は明治にする

rediscred ずず、とななすに見っている。 さっかけのないなないある

plating iz falis ON/OFF 静智大存在以 EBR Onighal.

claim 6 EBR 217" reducted of Down force Higher + Claim 3, 4.5 it discussion (21) Aus.

claim / FBR

8.9.10,11,12 件 79 1 花属

Claim 13 叶柏对里加线通光的Kidra 14 1 13 9 1 L. B. dein 1.2 中共和日本を得ないが成立をいう

年午中のClain一下は、文個大が自己、それ、ことが、 本、文文、公安の方"中"、并中、Chaim 14同7年 388 74年7世3872 dain 「静山北北北北海图「·野洲路打

Claim 12 BBK ONginal 路向抗棒 #50 to 28R idea. 13.14 179 经属

東福(字おかて上下は 5BR original

护在隐围技和各机、GBR Oniginal C/ain 1 >- 10 2 21/1 18.

BQ1四门 酒產計想我梅人 reducted 學打

押在してめってはなが、浄代なし? EBR original Clar. 11

19へとな なっていまではほほのない。

Claim 2~

8. P.10.11 air bag 38horiquel FUT RY EBR Original ainhey EBR original 孫原中公和

所当科特 成住 BBRONY、2d EBR onjuit 看核杜梅 04.4.19

Specification

Amplitude of plating voltage Pressing and Detaching [redacted: the US company] disclosure

include electro-etching voltage As the inventions of [redacted: the US company] have not been filed, ask [redacted: the US company] if they want to file their inventions. Ebara don't want to make the whole application a joint application.,

1. Facts should be made clear for each claim.

This invention is different from the technology that [redacted: the US company] presented. Some points of their presentation gave us a chance to consider. Plating technology with the current repeating ON and OFF and with a pad repeating touching and detaching the substrate is Ebara's original technology. EBR original applications 3, 4, 7, 9, 10, 11, 12 will be divided and made Ebara sole application. Others will be joint application,

Or, method claims will be jointed, and apparatus claims will be Ebara sole.

က

Y,Fukunaga Mishima

Sakaguchi

Sasabe

Make all applications joint applications. Give us some

rights for their patents useful for Ebara in return.

Patent Dept. ightharpoonup List up patents of [redacted: the US company] useful for Ebara.

Summarize 1, 2 and 3 above, and will send to Mr. Musaka. Inventors' names of [redacted: the US company] General Manager Mishima → Patent Dept.

#12

Claim 1: Ebara will claim that the invention is Ebara original based on a small Mr. Mishima will search Ebara's applications regarding a pad for plating filed diameter polishing pad presented to [redacted: company name] in 2001.7 so far and inform Patent Dept.

Supplying solution between two layers of a pad is Ebara's idea.

#14

The phrase "to water tightly seal the edge part" should be deleted. domestic priority application

Claim 1 of this application has the same invention with claim 8 of #4.

Claim 2 is joint filing. (rotation)

Other claims are Ebara original.

#14(continue)

Claim 3, 4, 5 were not discussed.

Claim 6 is Ebara idea. [redacted: the US company] presented down force was always +.

Claim 7: EBR

Claim 8, 9, 10, 11 and 12 are dependent claims of claim 7. Claim 13: applying current after relative motion is Ebara idea Claim 14 is a dependent claim of claim 13.

Claim 1 and 2 may be joint applications, but may be difficult to be patented.

#24

Claim 1: the phrase carrying current "in a state that the conductor layer is static to the porous product", " ----" part should be deleted.

In this claim 1, plating solution compositions were added to Claim 1 of #4 application. Plating solution is publicly known. We will claim this claim is Ebara idea like claim 1 of application #4.

Claim 12 : Ebara original. A pressing and separating mechanism.

13, 14 Dependent claims of claim 12.

14: Vibration is Ebara idea.

Vertical movement of the substrate holding part is Ebara original idea.

#10

Claim 1: Seal should be deleted

A pressing and separating mechanism is Ebara original idea.

Claim 13: Temperature adjust mechanism is on the tool requirement list of

[redacted: the US company] → joint application

Claim 16: pressing and plating is publicly known. No patentability?

17 : Ebara original

18 : Ebara original

19-24 : not related to plating

Claim 2

4 : torque sensor for detecting running torque is Ebara original idea.

5, 6 : air bag is Ebara original idea.

7 : multilayer structure of the porous product may be publicly known.

8, 9, 10 and 11: air bag is Ebara original idea

12 : Dependent claim of claim 11.

14 : pressurize the backside of the substrate with fluid is Ebara original idea.

15 : Ebara original, Vibrating mechanism is Ebara original idea.

Mr. Musaka, Mr. Y.Fukunaga, Mr. Mishima, 00:48 04/05/20 +0900, Fwd: S1出願

To: Mr. Musaka, Mr. Y.Fukunaga, Mr. Mishima From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Fwd: S1出願

Cc: Bcc:

Attached: D:¥My Dcuments¥-redac PaP project¥各出願の要点.xls;

各位

電話打合せに基づき、クレームにパッド(またはそれに類する物)の記述のある出願を確認 しました。 添付の表のようになります。

三島さんとは相談しましたが、福永さんとは相談できていません。 電話会議で下記#13, 16を話すことにするか、明朝福永さんと相談します。 この情報は参考としておいてください。

福永さん、三島さんに先程お送りした物を若干修正しています。

含浸材(高抵抗体)にパッドをつけたものを対象と考えます。("アノードの表面にパッド"まで含めると、含浸めっきや、TSBの特許まで入ってしまいます。)

#11:六平さんとの議論に出ましたが、パッドの記述はありません。日本出願はEBR単願、外国出願(PCT)は#4、10、12とまとめて1件になっていますので共願としたいと思います。

#13:フェースダウンのめっきです。含浸材の上に基板接触体が有り、基板と接触します。この出願はクレームの英訳を作っていません。基板接触体は従属項で出てくるので、Excel sheetの英訳には基板接触体が書かれていませんでした。 "a substrate contact element disposed on the resistive porous element "をexcel sheetの記述に追加する必要があります。フェースダウンなので、S1とは無関係と出来ますでしょうか。共願も止むなしと思います。

#15:金属イオンを透過させない隔膜を基板表面に接触させ、金属イオンの供給を制限する物です。クレームでは含浸材又は高抵抗体は記述されていませんので、含浸材+パッドという構成とは異なり、無関係と考えます。図では全て高抵抗体の表面に隔膜が配置されています。パッドで擦って添加剤を除去するのとは考えが異なります。これはクレームの英訳を作っていません。

#16:分割含浸材+多孔質体。含浸材の分割を主な発明とするものですが、多孔質体の均一な接触を目的としており、IBMが興味があるなら共願でしょうか。これはクレームの英訳を作っていません。

#21:アノードと被めっき面の間にイオン交換膜を配置する物です。クレームには含浸材や高抵抗体はなく、イオン交換体だけがあると解釈できますので、無関係としたいと思います。図3(メインの実施例)では含浸剤の変わりにイオン交換体が置かれています。他の実施例では、含浸材の上にイオン交換膜が配置されています。クレームでは含浸材の上にイオン交換膜という構成ではありませんので、無関係とします。

検討対象の

#4、#10、#12は多孔質接触体と含浸材、又は多層の多孔質材をクレームしています。(これはPCT出願していますので、#11も含めて、対象国全てに関するExport Licenseを取ることになります。多分通常のerrorの理由説明の他に、対象国名を並べて書くだけで済むと思います。)

Mr. Musaka, Mr. Y.Fukunaga, Mr. Mishima, 00:48 04/05/20 +0900, Fwd: S1出願

#14、#24はパッドのクレームはありませんが、接触なじませの出願です。

#26, 28, 29, 30はパッドのクレームはありません。

クレームの英訳を作った物は #4, 10, 11, 12, 14, 22, 24, 26, 28, 29だと思います。上記13, 15, 16, 21は英訳がありません。

ここに書いていない物も全てクレームをチェックしましたが、他にはパッドの記述はありません。

Mr. Musaka, Mr. Fukunaga, Mr. Mishima, 00:48 04/05/20 +0900, Fwd: S1 application

To: Mr. Musaka, Mr. Y.Fukunaga, Mr. Mishima

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Fwd: S1 application

Cc: Bcc:

Attached: D:\text{My Documents}{\text{[redacted: the US company]}PaP project}{\text{points of each}}

application.xls;

To all concerned,

Based on the telephone conference, I have identified patents that contain descriptions of a pad (or a means equivalent to it) in their claims.

They are as listed in the attachment.

I have discussed the matter with Mr. Mishima, but not with Mr. Fukunaga yet.

I will either discuss #13 and 16 below in the telephone conference or talk with Mr. Fukunaga tomorrow morning.

Regard this information is only for your reference.

I have slightly made corrections on what I sent to Mr. Fukunaga and Mr. Mishima earlier.

We regard impregnants (highly resistive element) with a pad fall into the category. (If we extend to cover "a pad on an anode surface," impregnation plating and [redacted: a Japanese company]) patents are also going to be included.)

#11: As mentioned during the discussion with Mr. Musaka, there is no pad description. For the Japanese patent application, we would like to file it as Ebaras solo application. But for the international application (PCT), as it is a bundle of #4, 10, and 12, we would like to file it as a joint application.

#13: It is a facedown-type plating. On the impregnant, a substrate contact element exists and this contacts with the substrate. We have not translated the claims into English. The substrate contact element is described in the dependent claims; therefore, it was not written in the translation in the Excel form. A sentence "a substrate contact element disposed on the resistive porous element" needs to be added to the description in the Excel form. Since this is the facedown-type, I wonder if it can be deemed to have no relation with S1. I think its joint application is unavoidable.

#15: This application restricts metal ion supply by contacting abarrier membrane that impermeates metal ions with a substrate surface. The claims do not describe neither the impregnant nor the highly resistive element. Therefore, we assume it is different from a construction of an impregnant + a pad, thus, has no relation. In the drawing, the barrier membranes are arranged on all surfaces of the highly resistive element. Its approach is different from additive removal by scrubbing with a pad. We have not translated the claims into English.

#16: Segmented impregnant + porous material. Although this application holds segmentation of the impregnant as the primary invention, the segmentation is for uniform contact of the porous material. If [redacted: the US company] is interested in this, this may be filed as the joint application.

We have not translated the claims into English.

#21: This application has an ion exchange membrane between an anode and a plating target. The claims do not describe the impregnant or the highly resistive element, and the method is interpreted as having the ion exchanger only; thus, I want to conclude this has no relation. In Fig. 3 (main preferred embodiment), an ion exchanger is mounted instead of an impregnant. In other preferred embodiments, an ion exchange membrane is placed on an impregnant. The claims do not describe a structure having an ion exchange membrane on an impregnant; we shall conclude this has no relation.

The applications under review, #4, #10 and #12, claim a porous material contactelement and an impregnant or a multi-layered porous material. (Since this is filed for PCT, we will have to obtain the Export License, including #11, for all target countries. Most likely, just listing the names of the target countries in addition to ordinal explanations for error, I tlink.)

Although #14 and #24 do not claim on a pad, they are applications related to better contact.

The applications #26, 28, 29, and 30 do not claim on a pad.

Claims have been translated into English for #4, 10, 11, 12, 14, 22, 24, 26, 28, and 29, think. The applications 13, 15, 16, and 21 above do not have English translations.

I have checked all claims even not written here, and those other than mentioned here do not describe a pad.

Mr. Musaka, 19:09 04/05/18 +0900, Fwd: Re: #26出願(2004-022178)

To: Mr. Musaka

From: 笹部憲一〈sasabe.kenichi@ebara.com〉 Subject: Fwd: Re: #26出願(2004-022178)

Cc: Mr. Y.Fukunaga, Mr. Mishima

Bcc:

Attached: D:¥My Dcuments¥ redac PaP project¥EBR application English translation¥特願 2004-022178¥2004-022178specification.doc; D:¥My Dcuments¥ redac PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p1.lzh; D:¥My Dcuments¥ redac PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p2.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p3.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p4.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p5.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p6.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p7.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p8.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p8.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p8.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p8.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p8.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p8.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p8.lzh; D:¥My Dcuments¥ redacted PaP project¥EBR application English translation¥特願2004-022178¥Drawing圧縮¥Draw p9.lzh;

六平様

いっかっている。 が回の電話会議で三島さんから説明した#26の明細書の英訳です。 クレームだけでは、redac の権利が含まれているかどうか分からないので、明細書の訳を作りました。 全 但し、時間もあまりなかったので、明細書の放文ではなく、前半だけの英訳です。 後半は、知財部がつけた部分で、装置としてベベルエッチやリンス、無電解キャップめっきなどが書かれています。後半部分は、JDPとは関係のない内容で、クレームもされていませんので、翻訳は省略させていただきました。 図は圧縮してありますが、解凍できなければご連絡ください。(自動解凍ではありません) 三島さんにコメントしてもらう予定でしたが、本日出張ですので、明日三島さんに依頼します。 大平さんの判断も必要と考えますと、福永さんがコメントされています。 前回の電話会議と、それ以降のredacとの打合せ状況を考えて、コメントいただければありがたく存じます。

X-Sender: yf08594@pop.ebara.co.jp X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J Date: Tue, 18 May 2004 18:46:44 +0900 To: 笹部憲一 <sasabe.kenichi@ebara.com>,mishima.koji@ebara.com From: Yukio Fukunaga <fukunaga.yukio@ebara.com> Subject: Re: #26出願(2004-022178)

笹部 様

翻訳有り難うございました。

六平さんにコメントを付けて、送って頂けますでしょうか。 (出来れば「何故荏原単願と判断しているか」のコメントもあった方がよいのですが、 本日三島さんが外回りのため、コメントできるとしても明日になります)

まずは六平さんに送って、目を通して頂くのがよいと考えます。 (redac にはまだ提出せずに、六平さんの判断も必要と考えます)

福永(由)

Mr. Musaka, 19:09 04/05/18 +0900, Fwd: Re: #26 application (2004022178)

To: Mr. Musaka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com> Subject: Fwd: Re: #26 application (2004-022178)

Cc: Mr. Y.Fukunaga, Mr. Mishima

Bcc:

Attached: D:YMyDocumentsY[redacted: the US company]PaP projectYEBR application English translation\Patent application 2004-022178\parallel{2004-022178} English translation\Patent application 2004-022178\parallel{2004-022178} D:\text{MyDocuments}{\text{[redacted: the US company]PaP project}}EBR application English translation\(\frac{1}{2}\) Patent application 2004-022178\(\frac{1}{2}\)Compressed Drawings\(\frac{1}{2}\)Draw p1.lzh; D:\footnote{MyDocuments}{redacted: the US company}PaP project\footnote{EBR application English translation*Patent application 2004-022178*Compressed Drawings*Draw p2.lzh; D:\forall MyDocuments\forall redacted: the US company PaP project\forall EBR application English translation*Patent application 2004-022178*Compressed Drawings*Draw p3.lzh; D:\text{MyDocuments}\text{fredacted: the US companyPaP project}\text{EBR application English} translation¥Patent application 2004-022178¥Compressed Drawings¥Draw p4.lzh; D:\text{MyDocuments}{\text{[redacted: the US company]PaP project}\text{EBR application English} translation*Patent application 2004-022178*Compressed Drawings*Draw p5.lzh: D:\text{D:\text{YMyDocuments} application English} Pap project\text{\text{EBR application English}} translation*Patent application 2004-022178*Compressed Drawings*Draw p6.lzh; D:\text{MyDocuments}{redacted: the US company}PaP project\text{YEBR application English} translation*Patent application 2004-022178*Compressed Drawings*Draw p7.lzh: D:\text{MyDocuments} [redacted: the US company]PaP project\text{YEBR application English} translation*Patent application 2004-022178*Compressed Drawings*Draw p8.lzh; D:\text{D:YMyDocuments} [redacted: the US company]PaP project\text{YEBR application English} translation\(\frac{4}{2}\) Patent application 2004-022178\(\frac{4}{2}\)Compressed Drawings\(\frac{4}{2}\)Draw p9.lzh;

Dear Mr. Musaka,

This is the English translation of the #26 specification, which was explained by Mr. Mishima in the previous telephone conference.

Since our US partner will not be able to determine whether the rights of [redacted: the US company] are included or not only by checking the claims, we translated the specification. However, we did not have enough time, and we only translated the first half, not the entire specification.

The latter half is the section added by Intellectual Property Dept., describing bevel etching, rinsing, and electroless cap plating as the apparatus. The latter portion has no contents relating to JDP and no claims are made; therefore, we skipped translating the section. The drawings are compressed, and contact me if you cannot uncompress them. (They do not automatically decompress.)

I was planning to have comments from Mr. Mishima today. However, since he is out today, I will request that to Mr. Mishima tomorrow.

Mr. Fukunaga has commented me that he thinks Mr. Musaka's decision is also necessary. I appreciate your comments on this matter based on the discussions in the previous telephone conference and the perceptions acquired from the subsequent meetings.

X-Sender: yf08594@pop.ebara.co.jp

X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J

Date: Tue, 18 May 2004 18:46:44 +0900

To: Kenichi Sasabe <sasabe.kenichi@ebara.com>, mishima.koji@ebara.com

From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: Re: #26 application (2004-022178)

Dear Mr. Sasabe,

Thank you for sending me the translation.

I appreciate if you send it to Mr. Musaka with the comment. (If possible, I think it is better to have his comment on "why he has determined it for Ebara's sole application." Since Mr. Mishima is out today, it will be tomorrow if he can comment on it.)

I think it is good to first send it to Mr. Musaka and have him read it. (I think we should not yet submit it to [redacted: the US company], and Mr. Musaka also needs to make decision about it.)

Y. Fukunaga

Mr. Pedersen, 09:43 04/06/02 +0900, Export License

To: Mr. Pedersen From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Export License

Cc: Bcc:

Attached:

Dear Mr. Pedersen

redacted

Please give us your advise.

Best regards, Kenichi Sasabe

Mr. Musaka, 15:37 04/06/08 +0900, Fwd: 英文翻訳の件

To: Mr. Musaka

From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Fwd: 英文翻訳の件

Cc: Mr. Y.Fukunaga, Mr. Shinozuka, Mr. Sakaguchi

Bcc:

Attached: C:\PROGRAM FILES\EUDORA\attach\attach\hat\hattach\hat\hattach\hat\hattach\hat\hattach\hat\hattach\hat\hattach\hat\hattach\h

六平様

#14(2003-195406)の英訳をお送りします。 日本出願の優先日を確保するため、日本出願のそのままの英訳となっていますが、外国出願用に若干の構成の修正があります。 前回クレームのみ英訳してもらった事務所とは別の事務所で外国出願用に英訳していますので、クレームの部分も英訳しなおしています。

redacted でチェックする際、クレームの変更は問題ありませんが、明細書の内容を変更する場合には、それに関連する部分は、外国出願日が出願日となりますので、ご注意願います。 修正する場合には、出来るだけ元の明細書をそのまま残し、修正部分を追加するようにしてください。

宜しくお願いします。

To: 笹部憲一 〈sasabe.kenichi@ebara.com〉

Subject: 英文翻訳の件

X-Mailer. Lotus Notes Release 5.0.8 June 18, 2001

From: shinozuka.shuhei@ebara.com

Date: Mon, 7 Jun 2004 14:14:11 +0900

X-MIMETrack: S/MIME Sign by Notes Client on shuhei shinozuka/e/ebara_jp(Release 5.0.8 |June18, 2001) at 2004/06/07 14:14:14, Serialize by Notes Client on shuhei shinozuka/e/ebara_jp(Release 5.0.8 |June18, 2001) at 2004/06/07 14:14:14, Serialize complete at 2004/06/07 14:14:14, S/MIME Sign failed at 2004/06/07 14:14:14: 暗号キーが見つかりません。, Serialize by Router on ntnhan22m/e/ebara_jp(Release 5.0.12 |February 13, 2003) at 2004/06/07 02:14:17 PM

笹部部長殿

特願2003-195406の英文翻訳をお送り致します。

篠塚 脩平

(株) 荏原製作所 知的財産室

〒144-8510 東京都大田区羽田旭町11-1 TEL:03-3743-6872

FAX:03-3743-5745

E-mail:shinozuka.shuhei@ebara.com

Mr. Musaka, 15:37 04/06/08 +0900, Fwd: Regarding the English translation

To: Mr. Musaka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com> Subject: Fwd: Regarding the English translation Cc: Mr. Y.Fukunaga, Mr. Shinozuka, Mr. Sakaguchi

Bcc:

Attached: C:\(\frac{1}{2}\)PROGRAM FILES\(\frac{1}{2}\)EUDORA\(\frac{1}{2}\)attach\(\frac{1}{2}\)Patent Application No. 2003-195406

translation.doc;

Dear Mr. Musaka,

I send you the English translation of #14 (2003195406).

To assure the priority date of the Japanese patent application, it is the direct translation of the Japanese application. However, it was given some layout corrections for foreign filing. This English translation is done by an office different from one, which translated only claims into English last time. Therefore, the claims section is again translated into English.

When checking it at [redacted: the US company], although changes in the claims is no problem, be careful that changes in the contents of the specification will regard its filing date as the filing date of the foreign application for those parts relating to the changes. When making corrections, it is best to leave the specification as is and add the corrections.

Thank you for your cooperation.

To: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Regarding the English translation

X-Mailer: Lotus Notes Release 5.0.8 June 18, 2001

From: shinozuka.shuhei@ebara.com Date: Mon, 7 Jun 2004 14:14:11 +0900

X-MIMETrack: S/MIME Sign by Notes Client on shuhei shinozuka/e/ebara_jp(Release 5.0.8

June 18, 2001) at 2004/06/07 14:14:14. Serialize by Notes Client on shuhei shinozuka/e/ebara_jp(Release 5.0.8 |June18, 2001) at 2004/06/07 14:14:14,Serialize complete at 2004/06/07 14:14:14,S/MIME Sign failed at 2004/06/07 14:14:14: cryptography key not found, Serialize by Router on ntnhan22m/e/ebara jp(Release 5.0.12 | February 13.

2003) at2004/06/07 02:14:17 PM

Dear General Manager Sasabe,

I send you the English translation of the patent application.

Shuhei Shinozuka Intellectual Property Dept. **Ebara Corporation** 11-1 Asahicho Haneda Ota-ku 〒144-8510 Tokyo

> TEL: 03-3743-6872 FAX: 03-3743-5745

E-mail: shinozuka.shuhei@ebara.com

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>

To: "kurashina.keiichi@ebara.com" (kurashina.keiichi@ebara.com), "hodai.masao@ebara.com" (hodai.masao@ebara.com),"'mishima.koji@ebara.com'" (mishima.koji@ebara.com),"Wada. Yutaka (E-mail)" <wada.yutaka@ebara.com>,"'fukunaga.yukio@ebara.com'"

<fukunaga.yukio@ebara.com>,"'nambu.isao@ebara.com'" <nambu.isao@ebara.com>,"Fang, Rui" <rfang@ebaratech.com>,"Kumekawa, Masayuki"

<mkumekawa@ebaratech.com>,"'namiki.keisuke@ebara.com'"

<namiki.keisuke@ebara.com>,"'kimura.norio@ebara.com'"

<kimura.norio@ebara.com>,"'asami.masao@ebara.com'" <asami.masao@ebara.com>,"'Manabu Tsujimura'" \(\tsujimura.manabu@ebara.com\)

Cc: "Yamamoto, Satoru (E-mail)" \(\symmamoto.satoru@ebara.com\),"'kanda.hiroyuki@ebara.com'" <kanda.hiroyuki@ebara.com>,"'nakada.tsutomu@ebara.com'"

<nakada.tsutomu@ebara.com>,"'Owatari Akira (E-mail)'" <owatari.akira@ebara.com>,"'Nanjo.

Takahiro (E-mail)" <nanjo.takahiro@ebara.com>,"Maekawa, Fumio (E-mail)"

<maekawa.fumio@ebara.com>."'makino.natsuki@ebara.com'

<makino.natsuki@ebara.com>,"'Morisawa. Shinya (E-mail)'"

(morisawa.shinya@ebara.com)."'Kunisawa. Junji (E-mail)'"

\(\text{kunisawa,junji@ebara.com}\), "\(\text{katsuoka.seiji@ebara.com}\)" \(\text{katsuoka.seiji@ebara.com}\), "\(\text{Tokusige}\)

Katsuhiko (E-mail)'" <tokushige.katsuhiko@ebara.com>, "Sasabe Kenichi (E-mail)"

⟨sasabe.kenichi@ebara.com⟩,"'jthoriuchi@aol.com'" ⟨jthoriuchi@aol.com⟩,"'Kozo Nakao'"

<nakao.kozo@ebara.com>,"'Fumio Kobayashi'" <kobayashi.fumio@ebara.com>,"'Akira Ogata'" <ogata.akira@ebara.com>,"'Fukunaga Akira (E-mail)'" <fukunaga.akira@ebara.com>,"'Natsunosuke

Yago'" <yago.natsunosuke@ebara.com>

Subject: Revised - 3rd redac JDP Workshop (6/21/04) Agenda

Date: Wed. 16 Jun 2004 21:45:22 -0700

Importance: high

X-Mailer: Internet Mail Service (5.5.2653.19)

Folks,

Please find attached 3rd ted JDP Workshop agenda which was revised based on discussion with tedac san of ted today.

Please note that the meeting location has been changed from redact to . redacted

Please review and provide any inputs.

Best Regards, K.Musaka



3^{rdredac}-EBARA JDA Workshop Meeting Agenda

Date & Time: June 21, 2004 (Mon) 9:00am-5:30pm

Place:

ETI -

redacted

Phone: redacted

Agenda:

June 21, 2004(Mon)

redacted

* IP - IP List Update K.Sasabe

* Wrap-Up with Action Plan Review K.Musaka 5:00pm-5:20pm

* Closing Remarks redacted 5:20pm-5:30pm

------- Dinner (Location TBD) -------

Mr. Musaka, 18:51 04/06/18 +0900, S1 IP list

To: Mr. Musaka

From: 笹部憲一 〈sasabe.kenichi@ebara.com〉

Subject: S1 IP list

Cc: Mr. Y.Fukunaga, Mr. Mishima

Bcc:

Attached: D:¥My Dcuments¥-red PaP project¥#3Workshop 04.06.21¥EBR_red 04.06.21.ppt; D:¥My Dcuments¥-red 用EBR特許リスト¥Ebara Patent Applications June15,2004.xls; D:¥My Dcuments¥-red PaP project¥#3Workshop 04.06.21¥Translation of claims of #13 Facedown plating .doc; D:¥My Dcuments¥-red PaP project¥#3Workshop 04.06.21¥Translation of claims of #16 Apparatus for plating substrate.doc;

六平様

#3 workshop のIPの資料をお送りします。

パワーポイント Excel sheet #13のクレームの英訳 #16のクレームの英訳

です。

パワーポイントは会議で使用するものです。1.5Hrですので、かなり省略してやります。

Excel sheet/1

#30,31,32が追加されています。全て共願です。 2,4,10,11,12,14,22,24,26,28,29は共願としました。

#13は従属項にパッドがあることを追記しました。

#13のクレーム及び#16のクレームの英訳は#13,#16のownershipの検討のための物です。 この帰属がもめることが無ければ、出す必要はないと思います。

Mr. Musaka, 18:51 04/06/18 +0900, S1 IP list.

To: Mr. Musaka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: S1 IP list

Cc: Mr. Y.Fukunaga, Mr. Mishima

Bcc:

Attached: D:\text{My Dcuments}\text{IBM PaP project}\text{#3Workshop 04.06.21}\text{EBR_[redacted: the US company] 04.06.21.ppt; D:\text{My Dcuments}\text{EBR patent list for [redacted: the US company] \text{\text{Ebara Patent Applications June15,2004.xls; D:\text{\text{My Dcuments}\text{\text{[redacted: the US company]} PaP project}\text{#3Workshop 04.06.21}\text{\text{Translation of claims of #13 Facedown plating .doc; D:\text{\text{My Dcuments}\text{\text{[redacted: the US company]} PaP project}\text{#3Workshop 04.06.21}\text{\text{Translation of claims of #16 Apparatus for plating substrate.doc;}}

Dear Mr. Musaka

I send IP document for #3 workshop.

The document is consist of

PowerPoint

Excel sheet

English translation of #13 application

English translation of #16 application.

PowerPoint document is for the meeting. As I have only 1.5hours, I will omit considerably. In Excel sheet

#30, 31 and 32 are added. Alljoint applications.

#2, 4, 10, 11, 12, 14, 22, 24, 26, 28 and 29 are changed to joint applications.

Description of a pad in a dependent claim is added in abstract of #13.

English translations of applications #13 and 16 are for study of ownership of these applications.

If the ownership of these applications will not be a concern, I will not use these documents.

Support Document AN

Nils E. Pedersen, 16:18 04/06/23 -0400, Petitions for retroactive foreign filing licer... Page 1 of 1

Subject: Petitions for retroactive foreign filing license

Date: Wed, 23 Jun 2004 16:18:24 -0400

X-MS-Has-Attach: ves

Thread-Topic: Petitions for retroactive foreign filing license Thread-Index: AcRZXzyE2tZKas7ERrC1q9TDC9IGAw=

To: "????" <sasabe.kenichi@ebara.com>

Dear Mr. Sasabe,

It was nice to see you again this afternoon. I hope you have an uneventful trip back to Japan.

redacted

Sincerely,

Nils E. Pedersen

for

WENDEROTH, LIND & PONACK, L.L.P. Attorneys and Counselors at Law Patents, Trademarks, and Copyrights 2033 K Street, N.W., Suite 800 Washington, DC 20006 U.S.A.

Confidentiality Notice:

This e-mail message and any attachments are confidential, may be privileged, and may contain proprietary information This email is intended exclusively for the individual or entity to which it is addressed. If you are not the intended recipient, please notify Wenderoth, Lind & Ponack, L.L.P. immediately by replying to this message or by sending an e mail to wlp@wenderoth.com, and destroy all copies of this message and any attachments. Thank you. If you are not th intended recipient, you are not authorized to read, print, copy, retain, or disseminate this email or any information included in this email.

For more information about Wenderoth, Lind & Ponack, L.L.P., please visit us on the web atwww.wenderoth.com



20040738 Fukunaga Statement - revision 1.rtf



20040738 Fukunaga Statement - revision 2.rtf

Support Document AO
Page 1 of 1

Sasabe, 02:19 04/06/26 +0900, Fw: Export License

From: "Sasabe" <2233754801@jcom.home.ne.jp>

To: <sasabe.kenichi@ebara.com> Subject: Fw: Export License

Date: Sat, 26 Jun 2004 02:19:51 +0900

X-Mailer: Microsoft Outlook Express 5.50.4133.2400

---- Original Message ----

From: Sasabe

To: npedersen@wenderoth.com
Cc: akai.yuichi@ebara.com

Sent: Thursday, June 24, 2004 7:52 PM

Subject Export License

Dear Mr. Pedersen

Thank you for the meeting on June 23.

redacted

Thank you for your cooperation. Best regards Kenichi Sasabe

Mr. Musaka, 10:15 04/06/29 +0900, #3 Workshop Meeting IP presentation

To: Mr. Musaka

From: 笹部憲一〈sasabe.kenichi@ebara.com〉 Subject: #3 Workshop Meeting IP presentation

Cc: Mr. Y.Fukunaga

Bcc:

六平様

先日は有難うございました。 会議で使用した資料をお送りいたします。

なお、荏原の米国出願を担当しているPedersen redacted

Mr. Musaka, 10:15 04/06/29 +0900,#3 Workshop Meeting IP presentation

To: Mr. Musaka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: #3 Workshop Meeting IP presentation

Cc: Mr. Y.Fukunaga

Bcc:

Attached: F.\(\frac{1}{2}\)2004.6 [redacted: the US company]\(\frac{1}{2}\)FEBR_[redacted: the US company]\(\frac{1}{2}\)2004.6 [redacted: the US company]\(\frac{1}{2}\)FEBR_ are Patent Applications June18,2004.xls; F.\(\frac{1}{2}\)2004.6 [redacted: the US company]\(\frac{1}{2}\)Translation of claims of \(\frac{1}{2}\)13 Facedown plating .doc; F.\(\frac{1}{2}\)2004.6 [redacted: the US company]\(\frac{1}{2}\)Translation of claims of \(\frac{1}{2}\)16 Apparatus for plating substrate.doc;

Dear Mr. Musaka

Thank you very much at the meeting.

I send the documents I used for presentation at the meeting.

I talked with an attorney, Mr. Pedersen, who is representing Ebara in US filing. Based his advice reducted

Mr. Musaka, Mr. Y.Fukunaga, 12:40 04/06/30 +0900, #28 English translation

To: Mr. Musaka, Mr. Y.Fukunaga

From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: #28 English translation

Cc: Mr. Shinozuka

Bcc: Attached:

Dear Mr. Musaka

Please find attached English translation of #28 (2004-23256). Claim 1 is modified from Japanese original claim to eliminate a limitation of peripheral seal.

Best regards, Kenichi Sasabe

Mr. Musaka, 21:09 04/07/09 +0900, Ebara Applications #13 and #16

To: Mr. Musaka

From: 笹部憲一〈sasabe,kenichi@ebara.com〉 Subject: Ebara Applications #13 and #16

Cc: Mr. Y.Fukunaga

Bcc: Attached:

Dear Mr. Musaka

At the workshop meeting on June 22, we asked $\frac{redac}{-ted}$ to reconsider the ownership of applications #13 and #16.

Is there any response from the on this matter?

Please confirm how they consider.

We are preparing for filing petition for foreign filing license also for these applications. If it is not necessary we will delete these numbers from the draft of the petition.

Matsuo, Kontechs, 13:15 04/07/13 +0900, Re: 翻訳データについて確認させてください

To: "Matsuo, Kontechs" <saiko.matsuo@kontecs.com>
From: 笹部憲一 <sasabe.kenichi@ebara.com>
Subject: Re: 翻訳データについて確認させてください
Cc:
Bcc:
Attached:

At 11:25 04/07/13 +0900, you wrote: 笹部様

コンテックスの松尾です。 今朝の打ち合わせの際はありがとうございました。 原稿を拝見いたしました。そこで、いくつか確認させてください。

●電子データをご用意くださっているところではないかと思いますが、 電子データでいただけるものは、なるべく電子データでお願いいたします。 A'、V'の2枚目、Z"の2枚目も電子データがあれば大変助かります。 また、EおよびE2はウェブサイトの画面かと思いますが、 これもデータで落としたものをいただけると、大変助かります。

出来るだけ電子データをそろえてお送りします。

- ●社名にマーキングがないページがいくつかありました(V、V、V"、Z)。 マーキングされているものとして、翻訳してよろしいですか? チェックを十分出来ていないため、抜けがあると思います。気が付かれた場合には、 お願いします。
- ●S'''に人名(英語)があります。この方のお名前はどのように扱ったらよろしいですか? Pedersenは残してください。
- ●Z'''にも人名(英語)がありますが、この方はETIの方なので、そのままでよろしいですね?

Dan O'connellは残してください。

以上です。どうぞよろしくお願い申し上げます。

Matsuo, Kontechs, 13:15 04/07/13 +0900, Re: Questions about data for translation

To: "Matsuo, Kontechs" <saiko, matsuo@kontechs.com>

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Re: Questions about data for translation

Cc:

Bcc:

Attached:

At 11:25 04/-7/13 +0900, you write:

Dear Mr. Sasabe

This is Matsuo of Kontechs.

Thank you for the meeting this morning.

I looked through the document. I have some question.

 I suppose you are preparing electronic data of the document. Please supply electric data as much as possible.

If you can supply electronic data of A', second page of V', second page of Z''', it will be helpful for us.

I think document E and E2 are hard copies ofwebsite. If you can download it and supply it to us, it is also a great help for us.

I will try to supply electronic data as much as I can.

 On some pages (V, V', V"', Z) company names are not masked. May we treat these names as masked?

As I could not check enough, there may be some errors. If you find such a error, please as it is masked.

There is a human name on S". How should we treat it?

Please leave "Pedersen" not masked.

There is a human name on Z". This gentleman is from ETI. I will leave it not masked.

Please leave "Dan O'connel" not masked.

That is all my question.
I look for your response.

***** Kontechs became a joint-stock company from July 1, 2004 *****

Saiko Matsuo

Kontechs Corp. Translation Service Dept.

3-1-21 Fukuda, Yamato-shi, Kanagawa-ken 242-0024

Tel/Fax: 0466-81-7759 (Ebara Research 7706)

In-house mail: ER out-sourcing section

e-mail: saiko.matsuo@kontechs.com



To: 篠塚担当部長殿 From: 笹部憲一〈sasabe.kenichi@ebara.com〉

Subject: Export License

Cc: 赤井部長殿

Bcc: Attached:

次の国内受付番号の発明届出書のコピーをお送りください。 同時に、出願時の事業部の部長が福永由紀夫さんか、三島さんのどちらかを教えてくださ

事業部部長

出願番号	国内受付番号
2002-242726	K1020505
2003-015235	K1020693
2003-015236	K1030031
2003-025159	K1030036
2003-111327	K1030262
2003-149827	K1030250
2003-161236	K1030263
2003-161237	K1030264
2003-169791	K1030261

Manager Shinozuka, 20:16 04/07/16 +0900, Export License

To: Manager Shinozuka

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Export License Cc: General Manager Akai

Bcc:

Attached:

Please send me copies of "Notification of Invention"s of the following domestic receipt numbers.

i -	•	
Application Number	Domestic Receipt Number	General Manager of Development
2002-242726	K1020505	
2003-015235	K1020693	
2003-015236	K1030031	•
2003-025159	K1030036	
2003-111327	K1030262	·
2003-149827	K1030250	
2003-161236	K1030263	•
2003-161237	K1030264	
2003-169791	K1030261	

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>

To: '笹部憲一' <sasabe.kenichi@ebara.com>

Cc: fukunaga.yukio@ebara.com

Subject: RE: Ebara Applications #13 and #16

Date: Sun, 18 Jul 2004 18:52:59 -0700

X-Mailer: Internet Mail Service (5.5.2653.19)

Sasabe-san,

Sorry for the long delay in my response, but redaction has not been back from her vacation yet and I do not expect any feedback from redaction on this matter until she comes back to work on next Thu, 7/22.

Can you hold the petition application till then?

Regards, K.Musaka

----Original Message-

From: 笹部憲一 [mailto:sasabe.kenichi@ebara.com]

Sent: Friday, July 09, 2004 8:09 AM

To: kmusaka@ebaratech.com Cc: fukunaga.yukio@ebara.com

Subject: Ebara Applications #13 and #16

Dear Mr. Musaka

At the workshop meeting on June 22, we asked redacto reconsider the ownership of applications #13 and #16. Is there any responce from redaction on this matter? Please confirm how they consider.

We are preparing for filing petition for foreign filing license also for these applications. If it is not necessary we will delete these numbers from the draft of the petition. Subject: RE: Export License

Date: Tue, 20 Jul 2004 16:59:41 -0400

X-MS-Has-Attach: yes

Thread-Topic: Export License

Thread-Index: AcRo0q+o22ngJmXHQRuswmPN/FU93QFrh65A

From: "Nils E. Pedersen" <npedersen@wenderoth.com>

To: "????" <sasabe.kenichi@ebara.com>

Cc: "Joseph Gorski" <jgorski@wenderoth.com>

Dear Mr. Sasabe,

Thank you for your email of last week. I am sorry that it took so long to get back to you.

redacted

Unfortunately I will be out of the office until August 2, 2004. I have discussed the present matter with Joe Gorski, so please send/copy any correspondence in the meantime to Joe as well, and he can assist you in my absence.

Sincerely,

Nils E. Pedersen

for

WENDEROTH, LIND & PONACK, LLP. Attorneys and Counselors at Law Patents, Trademarks, and Copyrights 2033 K Street, N.W., Suite 800

Washington, DC 20006 U.S.A.

Confidentiality Notice:

This e-mail message and any attachments are confidential, may be privileged, and may contain proprietary information. This email is intended exclusively for the individual or entity to which it is addressed. If you are not the intended recipient, please notify Wenderoth, Lind & Ponack, LL.P. immediately by replying to this message or by sending an e-mail to wlp@wenderoth.com, and destroy all copies of this message and any attachments. Thank you. If you are not the intended recipient, you are not authorized to read, print, copy, retain, or disseminate this email or any information included in this email.

For more information about Wenderoth, Lind & Ponack, LLP., please visit us on the web at www.wenderoth.com

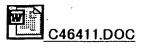
-----Original Message-

From: sasabe.kenichi@ebara.com [mailto:sasabe.kenichi@ebara.com]

Sent: Tuesday, July 13, 2004 8:12 AM

To: Nils E. Pedersen Co: akai.yuichi@ebara.com Subject: Export License

Dear Mr. Pedersen



コンテックス松尾様, 21:10 04/07/22 +0900, 納品受領の件

To: コンテックス松尾様 From: 笹部憲一〈sasabe.kenichi@ebara.com〉 Subject: 納品受領の件

Cc: Bcc: Attached:

松尾様

翻訳を受領いたしました。 請求書をお送りください。 有難うございました。

Matsuo, Kontechs, 21:10 04/07/22+0900, Receiving the delivered translation

To: Ms. Matsuo, Kontechs

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Receiving the delivered translation

Cc:

Bcc:

Attached:

I have received the translation.

Please send the bill to me.

Thank you very much.

ukio Fukunaga, 19:56 04/07/06 +0900 redac 発明者ご連絡頂きたく(至急)

X-Sender: yf08594@pop.ebara.co.jp

X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J

Date: Tue, 06 Jul 2004 19:56:12 +0900

To: "Musaka, Katsuyuki" <kmusaka@ebaratech.com> From: Yukio Fukunaga \(\frac{fukunaga.yukio@ebara.com} \)

Subject: redac 発明者ご連絡頂きたく(至急)

Cc: shinozuka.shuhei@ebara.com, sasabe.kenichi@ebara.com

六平 様

標記の件、<u>S1 Pat List #14(特願2003-195406)のUS出願手続きのため、redac 発明者を至急ご連絡頂きたく</u>、お願い致します。

なお優先日が7月10日で押し迫っています。 恐縮ですが、日本時間7月7日(水)朝一番までに篠塚さん(本社知財部)および 笹部さんにE-mailにてご連絡願います。

ところでredacの正式名称は、下記でよいでしょうか? redacted

(本件、笹部さん外回りのため、小職より連絡させて頂いています)

福永(由)

Yukio Fukunaga, 19:56 04/07/06 +0900, Please inform us of the names of inventors of [redacted: the US company] (Urgent)

X-Sender: yf08594@pop.ebara.co.jp

X-Mailer: QUALCOMM Windows Eudora Version 4.3.2-J

Date: Tue, 06 Jul 2004 19:56:12 +0900

To: "Musaka, Katsuyuki" <kmusaka@ebaratech.com> From: Yukio Fukunaga <fukunaga.yukio@ebara.com>

Subject: Please inform us name of inventors of [redacted: the US company] (Urgent)

Cc: shinozuka.shuhei@ebara.com, sasabe.kenichi@ebara.com

Dear Mr. Musaka

For the US filing of the application S1 Pat. List #14(2003-195406), please promptly inform us of the names of the inventors of [redacted: the US company].

The priority limit is coming close, July 10.

Please e-mail to Mr. Shinozuka (IP department) and Mr. Sasabe by the early morning of July

Is the full name of [redacted: the US company] as follows? [redacted: the US company]

(As Mr. Sasabe is out of the office today, I report to you for him)

Y. Fukunaga

04.3.31 Y.Fukunaga, Mishima, Kurashina, Sasabe

- #4: This invention was what Ebara presented to [redacted: the US company].
- #14: Ebara reported [redacted: the US company] about pad in January 2003.

 This invention belongs to Ebara.
- #24: Tha same process with #14. Plating solution was also Ebara's solution.

 There is a report on this development.

#12:

Support Document AY

				:											ļ	
 theme					٠.					• .	•			L	 ر_	
 	_	F	•	 		-	 -	 	 •	•				•	 	_

redacted

04 3 31	福和(10) 三島 倉科 符许部仓衡在
	#4: GBR D' redacted 10 presentation (E & 2
	#/6 pad + 2003 1 w redacted w \$ 1 m
	EBR 187
	サンチ、オノリレ同じプロセス、めっきをも日
	報告書あり
	#12 i

Support Document AZ

nakashiba.masamichi@ebara.com, 赤井副部長殿, 09:05 04/03/24 +0900, Re: [社関連出願の出願

To: nakashiba.masamichi@ebara.com, 赤井副部長殿

From: 笹部憲一〈sasabe.kenichi@ebara.com〉 Subject: Rented 関連出願の出願方法

Cc: Bcc:

Attached:

中柴様、赤井様

まず教えていただきたいことがあります。

このプロジェクトのプレーヤーは3名いて、redac、EC、ETIです。

EBR側の登録メンバーは

Project Manager: N. Kimura (ETI/EC) Technical Coordinator: K. Musaka (ETI) ETI Tech Team: K. Namiki, R. Fang (ETI) EC Project Team Leader: Y. Fukunaga (EC)

Patent/IP Leader: K. Sasabe (EC)

となっています。

redac にEBRの装置があり、その装置を使ってredacとETIと時によってECとが実験や解析、打合 せなどを行っています こういう中で、出願案件が主としてECから出され、しかしted、ETIの寄与もあるとして考えた場合 ("ted が主として発明した物は"ted が中心となって出願するはずです)、ECがライセンスを取ればよいのでしょうか。それとも、ETI、ted もうイセンスが必要なのでしょうか。

EC又はETIがライセンスを取ればよいのなら、以前から話を進めてもらっているSSDのライセ ンスの話しに追加してしまえばよいように思います。
「redain も含めて、プロジェクトとして何らかのまとまった申請が必要なら、「社に相談する必要があると思いますし、その場合には「redain いらここを使いたいとの要求が出るかもしれません。

誰が、どのような範囲に関してライセンスを取る必要があるのかを、まず明確にしたいと思い ます。 誰に依頼するかはその上で決めればよいと思います。

At 10:48 04/03/23 +0900, you wrote:

笹部様 どう考えますか

Forwarded by masamichi nakashiba/e/ebara_jp on

2004/03/23

10:47 -

yuichi akai 2004/03/22 17:25

To: masamichi nakashiba/e/ebara_jp@ebara_jp

cc: sasabe.kenichi@ebara.com, fumio kondo/e/ebara_jp@ebara_jp, shuhei shinozuka/e/ebara_jp@ebara_jp, fukunaga.yukio@ebara.com, mishima.koji@ebara.com, sakaguchi.yoshiharu@ebara.com

Subject: Reired 関連出願の出願方法 (Document link: masamichi nakashiba)

nakashiba.masamichi@ebara.com, Deputy General Manager Akai, 09:05 04/03/24, Re: Filing procedure of applications related to [redacted: the US company]

To: nakashiba.masamichi@ebara.com, Deputy General Manager Akai

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: Re: Filing procedure of applications related to [redacted: the US company]

Cc:

Bcc:

Attached:

Dear Mr. Nakashiba and Mr. Akai

First of all I have something that I would like you to teach me.

There are three players in this project, i.e. [redacted: the US company], Ebara Corp. and ETI.

The registered members of Ebara side are:

Project Manager: N. Kimura (ETI/EC)

Technical Coordinator: K. Musaka (ETI)

ETI Tech Team: K. Namiki, R. Fang (ETI)

EC Project Team Leader: Y. Fukunaga (EC)

Patent/IP Leader: K. Sasabe (EC)

There is a processing tool made by Ebara in [redacted: the US company] facility. [redacted: the US company] and ETI, and in some cases Ebara Corp., are conducting experiments, analysis and meeting together.

In this situation if ideas for applications are made mainly by EC, and ETI and [redacted: the US company] also contributing the ideas (if [redacted: the US company] mainly made the idea, [redacted: the US company] will lead the filing), is filing the petition for export license only by EC enough, or ETI and [redacted: the US company] also should file the petition?

If export license only by EC or ETI is necessary, I think this filing can be integrated in the filing of the export license that IP department has been proceeding with SSD.

If a filing for a comprehensive export license for this project including [redacted: the US company] is necessary, [redacted: the US company] may propose a firm they want to use for this filing.

I would like to clarify who, and for what area, should file the export license. Whom we ask to represent us can be decided later.

At 10:48 04/03/23 +0900, y	ou write:	
Dear Mr. Sasabe		
How do you think?	•	
	Forwarded by masamich	ni nakashiba/e/ebara_jp on
2004/03/23		
10:47		

yuichi akai 2004/03/22 17:25

To: masamichi nakashiba/e/ebara_jp@ebara_jp

cc: sasabe.kenichi@ebara.com, fumio kondo/e/ebara_jp@ebara_jp, shuhei shinozuka/e/ebara_jp@ebara_jp, fukunaga.yukio@ebara.com, mishima.kqii@ebara.com, sakaguchi.yoshiharu@ebara.com

Subject: Re: Filing procedure of applications related to [redacted: the US company] (Document link: masamichi nakashiba)

赤井副部長殿, 11:18 04/03/25 +0900, Fwd: JDP Patent Applications

To: 赤井副部長殿

From: 笹部憲一 〈sasabe.kenichi@ebara.com〉

Subject: Fwd: JDP Patent Applications

Cc: 篠塚担当部長殿, 近藤副部長殿, 中柴部長殿, 福永(由)室長殿

Attached: D:¥My Dcuments¥-red 用EBR特許リスト¥Ebara Patent Applications Mar0904.xls;

赤井様

先週六平さん、福永(由)さんと「ted 関係の出願について打合せを行い、その結果に基づいて六平さんが「ted の「ted さんと打ち合わせた結果だそうです。輸出ライセンスを取って日本出願を生かしたいもの、USで出願したので日本出願 (2004.1頃)を取り下げたいものなどがあります。 対応について検討して回答する必要があります。 めっきが中心ですので現在は近藤さんの範囲ですが、フライイングで赤井さんに協力お願いします。赤井さんが藤沢に来られる時に、福永さんを含めて相談したいと 思います。 Item番号の分かるリストは篠塚さんが持っていると思いますが、念のため貼付して おきます。(ブル―の部分は2004.3.9の変更分です。)

redac の件は今後の出願に関しても相談しておいた方がよいと思います。

From: "Musaka, Katsuyuki" <kmusaka@ebaratech.com>

To: "Sasabe Kenichi (E-mail)" \sasabe.kenichi@ebara.com\,"Fukunaga. Yukio (E-mail)"

<fukunaga.yukio@ebara.com>

Cc: "Nambu, Isao (E-mail)" <isao.nambu@nifty.ne.jp>,"Kimura. Norio (E-mail)"

<kimura.norio@ebara.com>,"Hodai. Masao (E-mail)" <hodai.masao@ebara.com>,"Mishima.

Koji (E-mail)" <mishima.koji@ebara.com>

Subject: JDP Patent Applications

Date: Wed, 24 Mar 2004 17:29:06 -0800

Importance: high

X-Mailer, Internet Mail Service (5.5.2653.19)

Sasabe-san, Fukunaga-san,

I had a meeting with redac-san on last Monday regarding patent applications through the JDP.

Followings basically explain how she wants us to handle this matter.

Item#2(USP) and Item#22(JP) - Add " redacted " and " redacted redacted " as co-inventor. (So, EC/redacted have to apply for export license.)

Item#4(JP), #10(JP), #12(JP), #14(JP), #24(JP) - redac -san believes redac s posses rights as co-inventors. However, she generously understood complexity of the correction process, and will discuss with patent attorney to decide which of the following 3 options they want to pursue.

Opt.1 - Withdraw. Then, re-submit as redac /Ebara co-invention.

Opt.2 – Add redac as co-applicants.
Opt.3 – Add redac as co-inventors. (Apply for export license)

Item#11(JP) - redac - san does not believe redac owns any rights as co-inventor. So, it's OK as it is now, Ebara's own invention.

Item#26(JP), #28(JP), #29(JP) – Abandon all JPs since Philippe already submitted disclosure covers #26 and #28, and so as #29 by $^{\rm redac}_{\rm ted}$. So, those are being filed as USP under $^{\rm redac}_{\rm ted}$ /Ebara co-inventions.

redacted 's disclosure which hard copy we reviewed in last week will be also filed as USP under redacted /Ebara co-invention.

Please re-discuss with folks in Japan if those are acceptable, and let me know any issues/concems.

Thank you for your understanding and strong support on this matter.

Best Regards, K.Musaka

Deputy General Manager Akai, 11:18 04/03/25 +0900, Fwd: JDP Patent Applications

To: Deputy General Manager Akai

From: Kenichi Sasabe <sasabe.kenichi@ebara.com>

Subject: JDP Patent Applications

Cc: Manager Shinozuka, Deputy General Manager Kondo, General Manager Nakashiba,

General Manager Y. Fukunaga

Bcc:

Attached: D:\footnote{My Documents\footnote{Ebara patent list for [redacted: the US company]\footnote{Eabara Patent Applications Mar0904.xls:

Dear Mr. Akai

I discussed with Messrs. Musaka and Fukunaga last week about applications related to [redacted: the US company]. This is a result of a talk between Mr. Musaka and [redacted: personal name] of [redacted: the US company].

There were some applications for which we will have an export license and use the Japanese applications as they are, some applications for which the Japanese applications (filed around January, 2004) shall be dismissed as US applications containing similar inventions have been filed in US, and so on.

We must consider how to treat these applications and reply to him.

As plating is the main technology, which is covered by Mr. Kondo, I would like to ask Mr. Akai's cooperation though you are not in charge of this technology yet. When Mr. Akai comes to Fujisawa, I would like to have a discussion including Mr. Fukunaga

Mr. Shinozuka should have the list of the applications by which you know the item numbers I attach the list to this mail just in case. (portions colored blue were modified on March 9, 2004.)

We had better discuss also about future filing related to [redacted: the US company].

[Below to the end is originally English text.]

```
Musaka, Katsuyuki, 09:05 04/03/12 -0800, RE: EBARA Patent Application Translati.. Page 1 of 2

From: "Musaka, Katsuyuki" <a href="mailto:kmusaka@ebaratech.com">kmusaka@ebaratech.com</a>
To: "' redacted (E-mail)'" < redacted >
Cc: "Fukunaga. Yukio (E-mail)'" <fukunaga.yukio@ebara.com</a>, "'Sasabe Kenichi (E-mail)'" <sasabe.kenichi@ebara.com</a>>
Subject: RE: EBARA Patent Application Translations
Date: Fri, 12 Mar 2004 09:05:57 -0800
X-Mailer: Internet Mail Service (5.5.2653.19)
```

fredac -san,

Please find attached translation of Ebara's Japanese patent application item#23.

<<2003-402006(#23).doc>>

I believe that's the last item we agreed to prepare the translations, and have not been submitted.

Please review and advise how you want us to handle the matter.

Best Regards, K.Musaka

```
-Original Message-
 > From:
               Musaka, Katsuyuki
 > Sent: Tuesday, March 09, 2004 9:53 AM
 > To:
         redacted
                      (E-mail)
 Cc: Fukunaga. Yukio (E-mail); Sasabe Kenichi (E-mail)
               EBARA Patent Application Translations
 > Subject:
 >redac
 Thank you for your time and valuable inputs in our meeting yesterday
 > although your busy schedule.
> Please find attached summary of Ebara's patent application status. There
 > are some corrections in the one I handed to you a hard copy yesterday
 > (highlighted in red).
> << File: EBARA Applications_030904.xls >>
> Attached below are translations of Ebara's Japanese patent applications
> which hard copies I handed to you today.
> << File: 2003-015236(#4).doc >> << File: 2003-149827(#10).doc >> <<
> File: 2003-161236(#11).doc >> << File: 2003-161237(#12).doc >> << File:
> 2003-195406(#14).doc >> << File: 2003-431211(#24).doc >> << File:
> 2004-022178(#26).doc >> << File: 2004-023256(#28).doc >> << File:
> K1040028(#29).doc >>
> Also, attached below is the Ebara's US patent application. As I explained
> to you yesterday, the #2 which was filed in Japan on 12/2/02 was
> abandoned, then re-filed as #22 in Japan on 11/28/03, within 1 year from
> the original(#2) filing date. The US patent applications for #2 as well as
> #22 were also filed about the same time, 12/1/03, to obtain the priority
> of #2, within 1 year from its original(#2) filing date in Japan.
```

```
> << File: GEB1998US(#22).pdf >> << File: GEB1998US_Image(#22).tif >> > Please review and advise us which you want us to amend for co-invention > with redacted >> > Best Regards, > K.Musaka >> P.S. I'm still waiting for a translation of #23. I'll e-mail it to you as > soon as I receive it.
```



2003-402006(#23).doc

理由:a. 社外発表(右欄記入)

社内・社外発明者や EBR 以外の出願人名義について、本用紙に書ききれないときは発明等届出掛補足書に記入し本用紙に添付する。

b. 当社先願公開期限

c. 国内優先権主張期限

願 緩

急

至急(/ 月 2 | 日まで)

発表先:

21

	9)													
↑	契	契約関係※7	共同	可研究等基	契約書	1.	有(相手	:) ②無		
発明			共同	司出願契約	約書	1/2/	要(作成 不要	担当:	a. 当初	. b.	相手先	())
者記		共同出願、他社会	名義の	出願とする	根拠として	て契約	書がある場合	3、契約	静の写しを	添付する	•		··		
										52069	-			,	
標)調査済み		出願内容	に最も近り	,		: \	2. 無		22,50	()			,
í		(右欄記入)	公知例を る。	2 部添作	すす	他社のもの	D (D. 有(特開 2	2000 – 2	320	78)
V	2	未調査		າ. -					2. 無				•		·
<u></u>	<u> </u>														
T	Ě		発明	の性質	発明の	件質	こより A.	B.	Cのうち.	一列をご	建択 (記:	号を()) して評(ж	
	評	萨価項目					・技術の発		B.新事業				C.先行ア		7発明
	1)先行技術に対	する	技術的	1.	司等			若干優位		3. 相当		·	断然優	
	L	優位性													
)他社侵害確認			<u> </u>		困難		かなり困	難	3. やや			容易	
	-	課題・手段の			1. 7		- 445		普通		3. 重要		(4)	最重要	ਦ ਜੁ
	1)他社における 回避困難度	4発	明の・	1. 容易	Ź	2. やや困	팷	(3) mt	でり困難	4.	不可			
		実施関係			1. 不明	 }		j	1. 未定						
依							小規模		2. 試作	予定				•	
頼	1				3. 国内			ĺ	3. 試作	中又はを	筝				
产		LL CELL STORY		4	多 国内	1と外	国で実施		4. 採用	决定					
依頼元上長記	6	技術的実現性		ļ		•				. —			1. 不明		困難
入欄	1	独創性				 -							3. 容易		検討済
禰		TYANT		.								ı	1. 不明 3. 中	2. 4.	小.
.	8	群評価※9			· · · · · · · · · · · · · · · · · · ·	1	. 普通(1	 . 倍)	2.	重要(2	(倍)	(3/	最重要(3		
	×8	他社が本発明等を	侵害し	しているか	否かの判別							~			اد بر بر بر
	 *9	本発明及び他の関				•	•	99 A M	Λ Σ \$ 00 1 ~ ₩.	-t-7 taki		e on this bu	-		
0	/	価計算式		3 H 91 C 101				/3}						0 1	
		列,B列発明	*	· · · · · · · · · · · · · · · · · · ·	依頼元評価ランク ^{※10} 出願要否 (1) 要 2. 公開技報で 45 以上 →S/ 3. 不要(理由:						なでよ	7			
)+②+③+④+€))×(B=5×7.	3. 不要 (建田: 30~44 →A 外国出願 ① 要 (国名: 未国										
	C 3	列発明	·	 .	20~29 →B 2. 不要 3. 未定										
	(D)+②+③+⑥+⑦))×(8	3)=	19以	下 →	C								
	4)				×10 該当	の評価	ーーー ランクに〇マ	を付け	る。		.•			. 4	
Ψ -	¥——	記事項 / (3	. ,	(0)	De for	H)	1+7+6	h++ :	******	29 -	75.5.		~ ~~	\neg 7	
		1.03	. /:	.70 . 1	1371-117	主上	公2743	<i>)</i>) ()	H9.0	现	があで	<u> </u>	19.		
10	3	•				•				•				•	
	発	知財部評価点	Ħ			知則	才部評価ラン	ク*11	,	総	S:最重	要			
	明	①特許性:_		مر		(1)	+2+3+4))×(§	= 16		A: 重要		1 /2	(伊)	1
-	an	②権利の広さ	*****	### = -	36 以上 →S 評 B 通常						113	1.28	3/2 t		
知	評価	③他社侵害研 ④本発明の回				1	~35 →A			一価十	で : 公開 D: 見合		承認:	E A	担当者
財	1,222	⑤群評価:	<u> </u>				~23 →B 以下 →C			12	D . 兄 c E : 会社		印		節
記	<u>س</u>				×11 av.		記入し、該当	4 M 3 V 6	ボランクにC				」 <u></u> 評価ランクに	~ ∩*#	14.7
知財部記入欄	出	A). 通常出願	<u> </u>		- ur	<i></i>		コマノのナル	ルノノンに し	フで りり な				○ 조 切	, a.
1641	願	2.国内優先		張	基礎出願 者	野号 ·		•				44.0	许事務所		
4	形	3. 分割		<u>u</u>		⊸ , y •	•					-	<u> </u>	,	ł
	態	4. 変更										1		/	
	出願	質した方	と給す	⁻ る	2. 支	給した	ない(理由	:)

ie inventor should till the colditins form 2 to 11.

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS)

Industrial Cleaning Co.,Ltd. (EICC),	or E	bara	Heingeration Equ	ipment &	Systems Co.,	Lia. (EHS).			
The column below is			Dept.	Post	Employee	Name	Share	Seal for	Living
applicable only to inventors				Tel	No. (five		of the	confirming	in U.S. ⁵
in EBR.		١.		İ	digits)		rights	the transfer	0.8.
Regarding to the service	1								
invention described above, I		1	Process	716	21155	Keiichi	60%	Kurashin	
(inventor, deviser, or creator)	 _	İ	Development			Kurashina		a	
acknowledge that any and	17	1	Office 2	·	1				
all rights to the invention in	ತ	1	Development						
Japan and other countries	n-house	1	Center 1						
have been transferred to the	į	1	·]	
Company (Ebara	6								
Corporation) upon invention.	entor								
The column below is									
applicable only to inventors	Total:	2	Process	715	08320	Keisuke	20%	Namiki	
in ER, EB, EICC, and ERS.	<u>a</u>		Development			Namiki			
]		Office 1					·	
Regarding to the service	⊉.		Development						
invention described above, l	è	L	Center 1				×		
(inventor, deviser, or creator)	inventor(s))"2	3	Process	716	20248	Tsutomu	10%	Nakada	
acknowledge that any and	(S)		Development			Nakada			
all rights to the invention in	23	[;	Office 2						
Japan and other countries			Development						
have been transferred to the			Center 1						
Company ()	1	4	Same as	716	13010	Koji	10%	Mishima	
upon invention.			above			Mlshima			
i		5							
			*						

³ Put a checkmark if the investor is living in U.S.

<u>ک</u>		
Application type	1. Sole application by EBR 2. Joint application by EBR and acompany other than EBR	
	3. Sole application by a company other than EBR 4. Other	
L		

•	6 ¹⁴ The "Applicant other than E	EBR" column is for inv	ventors in EB, EICC, and ERS; for	inventors in ER, see the inst	ructions on the form.		
	Patent prosecution by:	(1.) EBR 2. Othe	r than EBR (.)			
Expense is: 1. Paid by EBR 2. Equally shared 3. Paid otherwise							
	Applicant other than EBR*4	Company/ personal name	Contact (address, Tel, and responsible in Intellectual	Share of the rights	Share of the cost		
	(Total: applicant(s))		Property Dept.				
-[%	%		
				%	. %		

*The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor	Company	Name	Address	Share of the interest
(Total: inventor(s))*5				%
1		•		%
	•			

If descriptions of in-house//external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

Urgency of	1. Normal	Released on: 2003/1/24
application filing	2. High (by January 21.)	Released to: Cooperative
	Reason: a. External release (Fill the right column.)	company in US
	b. Deadline for publication of our prior	
	application	
•	c. Deadline for claiming domestic priority	
	Collaboration contract	

IPW-001 (Rev. 1.3)

Related Written contract/for joint research 1. Available (partner:) 2. N/A (current) Contract Written contract for joint filing of patent 1. Required (Prepared by: a. Us b. Partner ())	9			
, , , , , , , , , , , , , , , , , , ,		Written contract for joint research	1. Available (partner:) 2. N/A (current)	_
onnlications 2 Not required	contract*6	Written contract for joint filing of patent	1. Required (Prepared by: a. Us b. Partner ())	
2. Not required)	applications	2. Not required	

When there is a written contract that justifies the joint filing or filing under other name, attach a copy of it to this form.

Prior-art search	Related application and	Ours	1. Available (K1020693) 2. N/A
). Done (Fill the right column.) 2. Not done	prior art: Attach two items of prior art related to the application.	Others'	1. Available (Publication No. 2000-232078) 2. N/A

11								
Nature of invention	Choose A, B, or C (enclose	with a circle), considering t	he nature of the invention.					
	A. Invention for current	B. Invention for new	C. Invention of new ideas					
Evaluation item	products/technologies	products/technologies						
(1) Technical superiority over	1. None 2. A little 3. Cor	1. None 2. A little 3. Considerable 4 Very large						
prior art		•						
(2) Difficulty to find infringement **	1.Very difficult 2.Consider	ably difficult 3.A little difficu	ult 4.Easy					
(3) Severity of challenge/means	1. Unknown 2. Normal 3. High 4. Very high							
(4) Difficulty of design around	1.Easy 2.A little difficult 4.Impossible							
(3) Applicability to production	1.Unknown	1.Not decided						
	2.Domestic small scale	2.Planed to trial prod.						
	3.Domestic large scale	3.Under or finished trial						
	4.Domestic and abroad	production	·					
(O) T 1 : 1 : 1 : 1:	·	4.Decided to adopt						
(6) Technical realizability			1.Unknown					
·			2.Difficult					
			3.Easy 4.Study finished					
(7) Originality			1.Unknown 2. Low					
(1) Originality			3. Medium 4. High					
(8) Group judgement ^{*9}	1. Normal (single) 2. Impo	rtant (double) 3. Most imp	1					
	1. Normal (single) 2. impo	rant (double) 0. Wost imp	oliani (inple)					

⁸ Difficulty to judge if other company infringes this invention

Judge of importance of this invention to other inventions in an invention group comprising this invention and other re lated inventions

13

12		· ·				
()alc	ulation for	rating	Rating by requesting department			
((1)+ = 57 For i	nventions (2)+(3)+(4 nventions (2)+(3)+(6)+(5))×(8) of C	45 or higher → S 30-44 → A 20-29 → B Less than 19 → C			

13	• •
Filing of the patent application is:	Required Not required; it should be published on Journal of Technical Disclosure. Not required (reason:
Foreign filing is:	1.Required (country name: 2.Not required 3.Not dicided

14	
Special note	2003.1.10 Discussed with patent agent Ono. Please proceed urgent.

Boss's seal of approval: Wishima

15

	15			
		Evaluation by Intellectual Property Dept	Rating by Intellectual Property Dept*11	Overall evaluation*12
	Evaluation	(1) Patentability: 2	((1)+(2)+(3)+(4))×(5)=16 36 or higher → S 24-35 → A 16-23 → B Less than 15 → C	S: Most important A: Important B: Normal C: Journal of Technical Disclosure. D: No filing
L			, , , , , , , , , , , , , , , , , , ,	E: By company circumstance

-	
Evaluation	Evaluation
Approver	Approver
Seal:Kubo	Seal:
03.1.28	Shinozuka

Enter the evaluation values and circle the appropriate rank. *12 Place a circle on the appropriate item of the evaluation level.

Application	1. Regular application	Patent firm
category	2. Domestic(pr)ority Original application No.:	Ono
i	3. Division	
	4. Change	
Award for fili	ng the patent application 1. Will be offered 2. N/A (reason:)
Remarks		

Should you have any comment on the evaluation, contact us within two weeks.

IPW-001 (Rev. 1.3)

v	発明等届出	書(1/2)	4	、特別	F) 2. 墓屋	、3.そ	の他) **	(補足	斯 1.有·	2.無)	社外秘
	· · · · · · · · · · · · · · · · · · ·		**	KUP	ELTHINIT TO	الله الله	新案で出頭したい	場合は、「3.その [er coent	川内川南部と川	版する.
١	Post (7:5)			Post		1623	COLUMN THE			30250 5 投付日/	No.
(第1·2·19		AN L		一個新鄉門		A A	(1025·10	<i>3)</i> -	i	K10302±
		に技紀人機の協印機もお客	snus	mixun.	Fan.	0h# 1/版	>	類日(西暦)	2005	8年、2	E 10 C
1 (2	太枠内をご記入	下さい。		_	7.7.77	03.4.	·	賴丘(四個) 賴元 Doc.N			月 19日
	依 (部門コ-ド)	(V512)	Z DŽŪ	が管理	6. H1\$	14'- 関	8. 住	京総合研究所
ĺ	瀬 部門名	技術統括 第一プロセス開発		発セ.	ンター 第一 3	分一方	自母 情報·通信		·電子 係		原ポイラ 原工業洗浄
	部 書類送付先			<u>^</u>			営業 環境エンジ・エアリ	.w.	会社		原冷熱システム
	門担当者	個人コード		•	-		風水力 -	,	1.0	(טולי (
ĺ		(Post: 715	7	Геl: 9	9244)				·		
3	発明等の名称	パルスめっき機	Łtk							/ 飯	3
		異方性、多孔質		k.	パルフ委に知り	·n	·		PPO	1-6	16)
	関連する製品又に)U				079	194
	製品の性格 (1)				2. 重点拡販	機種で	ない。研	番成果	开 No. L ー	02D547	09.
Ø									· · · · · · · · · · · · · · · · · · ·		
	\sim	職務発明である							下の社内発明		
	***********	職務発明ではな	*****		****************			292	度渡確認印格 印刷)	1に採印し	. < < < < < < < < < < < < < < < < < < <
•		職務発明ではな その譲渡につい				- 19 3074	低利につざ、	```	-1-12/		
		→右欄に捺印して	知的	財産部	Bに送付してくださ		D社内発明者記	己入欄の			
ı	× 2				捺印しないで下さ					 	•
3	※2「社内発明者」欄には荏原 下楣は EBR の発明者等		f究所(E		原ポイラ(EB)、崔原工第 所属部門名	Post		ERS)の発明者等の 氏名	み記入する。	権利譲	要 米国 ^{※ 3}
·	上記の職務発明等に関	関し、私(発明者・	法		///PANN PL	Tel	(5桁)				部在住
	考案者・創作者)は発 て日本及び外国にお		社内発明者		第一開発センター	1	13010	三島 浩二		10	3
	会社(株式会社在原		者	-	第二プロス開発室	9427	<u> </u>			%' \	3/
<u>*</u>	たことを確認します。 下個はEREBEICC ERSの	の発明を含みたけに済用す	部	1)	第一開発センタ - 第二プロス開発室	716 8566	20248	中田勉		10 6	
	3.))U)HHYICI)ICENIY	4	1	第一開発センター		21155	倉科 敬一		40	
	上記の職務発明等に関		_		第二プロス開発室	8556				%° \	
ì	考案者・創作者) は発見 て日本及び外国におり		多	1 1	第一開発センター第一	715	08320	並木計介			监
'	会社(たことを確認します。)に譲渡し	** 2	5	プロス開発室	9244				% ×	15
	·					 					
O.								*	³ 米国に在住し	ている場合は	レ印を付ける。
					EBR 以外の者			BR 以外の		4. そ	の他
? Оr	4 在原ポイラ(EB)、在原工業						入する。荏原総合	研究所(ER)は紀入	要領を参照のこ	Ŀ.	
1		1) EBR 1) EBR 負担			BR 以外の者 匀等負担 3		\	·)		
ŀ		会社名又は氏名			力等負担 S 先(住所、Tel	41財		夕玺)		権利持分	· 費用負担
- 1	出願人名義 ^{※4}	A II-U X (6 IV-L	'		Ju . CILL///C Tel	· M1961	nbi 115 3 16	1147		%	
- 1	(計 名)										
ı		·							•	%	%
יֶּל רופּ	⁽⁵ 「社外発明者」 脚には 在原製	作所(EBR)、在原総合研	究所(EI	R)、荏原	(ポイラ(EB)、荏原工業	先浄(EiCC)	,在原冷然システム(I	ERS)以外の発明者	等を記入する。		
ூட	社 会社名			无 名			住 所				権利持分
	外計			•							%
	発 ———	•									%
	者 5 ———										%
L								- · · · · · · · · · · · · · · · · · · ·	•	<u>.</u>	
	社内·社外発明者やEBR 以外 IPW - 001(Rev. 1.		本川紙	に掛きも	きれないときは発明等症	出海杨定县	に起入し本用紙に	番付する。			

7 - 7 -							
出願緩急	登念 (3月 竹) E	まで) 理由:a. 社外発表(右欄 ・	利 期限				
契約関係	系*8 共同研究等	契約書 1. 有(相手:) 2. 無				
	共同出願契						
		② 不要	, , , , , , , , , , , , , , , , , , , ,				
※6 共同川崎.	他社名義の出願とする根拠として	契約責がある場合、契約責の写しを孫付する。					
調査実施	並状況 関連出	頭・公知例 当社のもの 1. 有	(
1. 調査	* 0 mm	に近い公知例 2. 無					
(2). 未認		他在のもの 1. 有 ・)				
(c). A (d)	明 且	2. 無					
_	mag - U se	There are the second					
評価項目	発明の性質	発明の性質によりA, B, Cのうな (A)現在製品・技術の発明 B.新事	6一列を選択(記号を○)して評価 業製品·技術の発明 『C.先行アイデア発明				
I	術に対する技術的	1. 同等 2. 若干優位					
優位性	<u> </u>						
②課題· ③独創性	手段の重要性	1. 不明 2. 普通	3. 重要 4 最重要				
			1. 不明 2. 小 3. 中 4)大				
	が対象とする製品	1. 開発計画はない					
の開発	計画	2. 開発計画の終了段階である ③ 開発計画の中間段階である	_				
		4. 開発計画の初期段階である					
⑤本発明 要度	が製品に占める重	1. 小さい 2. やや小さ	い 3. やや大きい ④ 大きい				
⑥依頼元	総合評価	1. 軽度(1倍) 2. 通常(2倍	3. 重要 (3倍) (4) 最重要 (4倍)				
ET A DIA	5 20° III						
評 A 列0 価 B 列0		+⑤)×⑥= 60° 出願要否	(1) 要 2. 公開技報でよい 3. 不要(理由:)				
計区列の		+⑤)×⑥= 外国出願	(1) 要(国名:木闰				
算	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,		2. 不要 3. 未定				
		9					
特記事項	小野先生たみ	Benneced	(E長印)				
	2.773						
_	許性	1. なし ② 小	3. 中 4. 大				
	利の広さ	1. 狭い ② やや狭い	3. やや広い 4. 広い				
	発明の回避困難度	1. 容易 (4) やや困難	3. かなり困難 4. 不可				
	許的総合評価	1. 軽度(1倍) ②, 通常(2倍	f) 3. 重要(3 倍) 4. 最重要(4 倍)				
知財部評価	西点:(①+②+③)×()= 12 , 総合評価 ^{※8} 84以	上 → S:重点				
>4X1 HP41 II	*7	* 45-61	33 → A): 重要				
依賴元評值	依頼元評価点 + 知財部評価点 = 72.						
	※7」評価	※8 該当の評価ラ	シクに〇を付ける。				
	通常出願		特許事務所				
形 3.5	· 割	5					
態 4. 変	至更						
出願賞	1. 支給する	2. 支給しない(理由:)				
備考	1	•	— — ·				

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara

Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS).									
The column below is			Dept.	Post	Employee	Name	Share	Seal for	Living
applicable only to inventors				Tel	No. (five		of the	confirming	in
in EBR.	1			1	digits)		rights	the transfer	U.S.*3
Regarding to the service		1.		1					
invention described above, I		1	Process	716	13010	Koji	10%	Mishima	
(inventor, deviser, or creator)	-		Development	9427		Mishima			
acknowledge that any and		1	Office 2		1				
all rights to the invention in	5	1	Development	l	[
Japan and other countries	눍		Center 1						
have been transferred to the	In-hous			İ				· ·	
Company (Ebara	Œ.			l				·	
Corporation) upon invention.	inventor								
The column below is	19								
applicable only to inventors	윽	2	Process	716	20248	Tsutomu	10%	Nakada	
in ER, EB, EICC, and ERS.			Development	8566		Nakada			
	(Total:		Office 2						
Regarding to the service			Development]	
Invention described above, I			Center 1						·
(inventor, deviser, or creator)	inventor(s))	3	Process	716	21155	Keiichi	40%	Kurashin	
acknowledge that any and	lă.		Development	8556		Kurashina		a	
all rights to the invention in	19		Office 2				, .		
Japan and other countries	<u>(s)</u>		Development			•		ĺ	
have been transferred to the	13		Center 1						
Company ()		4	Process	715	08320	Keisuke	40%	Namiki	
upon invention.			Development	9244		Namiki	·	·	
			Office 1					- G.	. ,
			Development		n 35				
		_	Center 1						
	M. U	5			u ii				
							300		

Put a checkmark if the investor is living in U.S.

1. Sole application by EBR 2. Joint application by EBR and acompany other than EBR Application type 3. Sole application by a company other than EBR 4. Other

7 The "Applicant other than 8	EBR" column is for inv	ventors in EB, EICC, and ERS; for	inventors in ER, see the in	structions on the form.
Patent prosecution by:	1. EBR 2. Othe	er than EBR () \	
Expense is:	1. Paid by EBR	2. Equally shared 3. Paid	otherwise	
Applicant other than EBR*4	Company/ personal name	Contact (address, Tel, and responsible in Intellectual	Share of the rights	Share of the cost
(Total: applicant(s))		Property Dept.		
			%	%
			%	%

	<u>umn is for inventors o</u>	utside of EBR, ER, EB, El	CC, and ERS.	<u> </u>
External inventor	Company	Name	Address	Share of the interest
(Total: inventor(s))*5				%
		·	·	%

If descriptions of in-house//external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

IPW-001 (Rev. 1.5)

Notification of Invention (2/2) Confidential								Confidential		
Urgency of application filing			nal (by Middle of March) n: a. External release (Fill the right column.) b. Deadline for publication of our prior application c. Deadline for claiming domestic priority Collaboration contract					eased on: YYYY/MM/DD eased to:		
10										
Related	Written co	ontract)f	or joint research		1. Avail	able (partn	er:) 2. N/A (current)		
contract ^{*6}	Written co		for joint filing of patent	t		Required (Prepared by: a. Us b. Partner ()) Not required				
⁶ When there is a			justifies the joint filing or	filing und			copy of it	to this form.		
11		 		T						
Prior-art searc	:h		Related application and	Ours	Ours 1. Available (2. N/A)		
Done (Fill the right column.) Not done			prior art: Attach two items of prior art related to the application.	Others	1. Availa 2. N/A	1. Available (2. N/A)		
12					•					
Na Evaluation iter	ture of inv	rention	Choose A, B, or C (enclose with a circle), consider A. Invention for current products/technologies products/technologies					C. Invention of new ideas		
(1) Technical : prior art	superiority	over	1. None 2. A little 3. Considerable 4 Very large							
(2) Severity of challenge/			1. Unknown 2. Normal 3. High 4. Very high							
(3) Originality								Low 3. Medium 4. High		
()4) Developme products b invention			N/A In the final stage In the intermediate stage In the early stage				·			
(5) Importance invention to		ucts	1. Low 2. Rather lo	ow 3.0	Considerat	oly high 4	. High			
(6) Overall jud requesting	•	the	Less important (s Significant (quadr		2. Moderat	te (double)	3. lm	nportant (triple)		
13	H •	:								
Galculation for rating of the evaluation	of ation inventions of A or B For inventions ((1)+(2)+(3)+(5))×(6) =			paten applic Forei	patent 2 application is:		I. Required I. Not required; it should be published on Journal of Technical Disclosure. I. Not required (reason:) I. Required (country name: U.S)			
14	of C				applic	cation is:		ot required ot determined		
Special note	Places	ck Pata	ent agent One			•		Boss's seal of		
		38 F 711P	311 AUGUST 11 1 / 1 K)					I DOSS'S SPALOT		

15

approval; Mlshima

(1) Patentability
(2) Scope of rights 1. None 2. Low 3. Medium 4. High Narrow 2. Rather narrow 3. Considerably wide 4. Wide
 Low 2. Rather low 3. Considerably high 4. Indispensable Evaluation (3) Indispensability of the invention to the products Overall judgment on patenting 1. Less important (single) 2. Normal (double) 3. Important (triple) 4. Significant (quadruple) the invention

16

Evaluation by Intellectual Property

Dept.: ((1)+(2)+(3))×(4)= *7 12

Votal of the evaluation values by the requesting side and Intellectual

Property Dept.*7 = 72

Overall evaluation '8 84 or more -> S: Significant 64 to 83 -> A: Important 28 to 63 -> B: Normal 27 or lower -> C: Not apply

Evaluation
Approver
Seal:
Kondo
Seal:
Shinozua
03.4.10

Enter the evaluation values into the formula.

*8 Place a circle on the appropriate item of the evaluation level.

Application	1. Regular application Patent	firm
category	2. Domestic priority Original application No.:	
	3. Division	
	4. Change	
Award for filit	ing the patent application 1. Will be offered 2. N/A (reason:	
Remarks		

IPW-001 (Rev. 1.5)

Should you have any comment on the evaluation, contact us within two weeks.

急 c. 国内優先権主張期限

社内・社外発明者や EBR 以外の出願人名義について、本用紙に書ききれないときは発明等届出書補足書に記入し本用紙に添付する。

理由: a. 社外発表(右欄記入)

b. 当社先願公開期限 ·

発表日:

発表先:

日

月

1. 普通 2. 至急(

願

緩

月

日まで)

ש ווואפוונתו פווחחות וווו מופ כתוחווופ ווחווו ל וח ו ו

4 *2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co.,Ltd. (EB), Ebara Industrial Cleaning Co.,Ltd. (FICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS)

Industrial Cleaning Co., Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS).									
The column below is			Dept.	Post	Employee	Name	Share	Seal for	Living
applicable only to inventors	1			Tel	No. (five		of the	confirming	in
in EBR.]		,		digits)]	rights	the transfer	".S.Ü
Regarding to the service						İ			٠.
invention described above, I	1	1	Process	716	20248	Tsutomu	20%	Nakada	
(inventor, deviser, or creator)	_		Development			Nakada			
acknowledge that any and	그		Office 2						
all rights to the invention in	n-house		Development						
Japan and other countries	9SI		Center 1	·					
have been transferred to the	3						ļ		
Company (Ebara	<u>ō</u>								
Corporation) upon invention.	ento								
The column below is	3							·	
applicable only to inventors	Total:	2	Process	715	08320	Keisuke	30%	Namiki	1
in ER, EB, EICO, and ERS.			Development			Namiki			
			Office 1		-				1
Regarding to the service	inventor(s))*2		Development					·]	1
invention described above, I	en	3	Center 1 Process	716	01155	l/-ii-bi	000/	16	
(inventor, deviser, or creator)	Ö	3	Development	716	21155	Keiichi	30%	Kurashin	
acknowledge that any and all-rights to the invention in	(s))		Office 2			Kurashina		a	[
ا المعاملة المعاملة المعاملة المعاملة المعاملة المعاملة المعاملة المعاملة المعاملة المعاملة المعاملة المعاملة ا	7.5		Development]	
have been transferred to the			Center 1		i				
Company (4	Same as	716	13010	Koji	20%	Mishima	
upon invention.			above			Mishima	_0/0		• •
		5		 					
			·						
		· · · · ·							

³ Put a checkmark if the investor is living in U.S.

	·
Application type	1. Sole application by EBR 2. Joint application by EBR and acompany other than EBR
•	3. Sole application by a company other than EBR 4. Other
<u> </u>	

The "Applicant other than EBR" column is for inventors in EB, EICC, and ERS; for inventors in ER, see the instructions on the form.

Patent prosecution by:	1. EBR 2. Othe	er than EBR ()	· · · · · · · · · · · · · · · · · · ·
Expense is:	1. Paid by EBR	2. Equally shared 3. Paid of	otherwise	· vý
Applicant other than EBR*4 (Total: applicant(s))	Company/ personal name	Contact (address, Tel, and responsible in Intellectual Property Dept.	Share of the rights	Share of the cost
			%	%
			%	%

*The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor	Company	Name	Address .	Share of the interest
(Total: inventor(s))*5				%
,				%

If descriptions of in-house//external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

Urgency of application filing	1. Normal 2. High (by January 21.)	Released on: Released to:	
application imig	Reason: a. External release (Fill the right column.)	rieleased to.	
·	b. Deadline for publication of our prior		•
	application	`	
•	c. Deadline for claiming domestic priority	•	
	Collaboration contract		

IPW-001 (Rev. 1.3)

approval: Mishima

Notification of Invention (2/2)

9									
Related	\M/ritton oo	ntract	for joint research			1 Availe	h1- /	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \	
contract 6 Written contract applications							ble (partner:) 2. N/A (current)	
			t for joint filing of patent			2. Not re		y: a. Us b. Partner ())	
When there is a written contract that			t justifies the joint filing of	r filin	a und	er other nam	equired	ia a abili d	
10		naci ina		1 19416	ig und	ei other nam	e, allach a copy of	it to this form.	
Prior-art sear	ch		Related Ours			1. Availa	ble (Heisei 11-36	67754)	
			application and			2. N/A		•	
1. Done (Fill t	he right col	lumn.)			thers	1. Available (Publication No. 2000-248397)			
2. Not done			Attach two items of prior art related to the application.			2. N/A			
	•								
11		******	таррисации.	<u>.</u>					
Na Na	ature of inv	ention	Choose A, B, or C	(end	close	with a circl	e), considering ti	he nature of the invention.	
		\bigcirc	A. Invention for cur	rent	t	B. Invention	n for new	C. Invention of new ideas	
Evaluation ite			products/technolog				echnologies		
(1) Technical	superiority	over	1. None 2. A little	3.	. Con	siderable	4 Very large		
prior art (2) Difficulty to	o find		1 Vanddifficult 2 C		oid or c	الماء والظنورياء	O A 1:41 - 1:45	IA 4 =	
infringeme			1.Very difficult 2.0	JOH:	sidera	ably allicult	3.A little amict	uit 4.Easy	
(3) Severity o			(Unknown 2. Normal 3. High 4. Very high						
challenge,		_	· ·						
(4) Difficulty of	f design ar	eun)d	1.Easy 2.A little difficult 3.Considerably difficult -						
/E) Applicabili	te to produ	-tion	4.Impossible						
(5) Applicabili	ty to produ	cuon				1.Not deci		-	
)			3.Domestic large scale				o trial prod. r finished trial		
							production		
	•					4.Decided		·	
(6) Technical	realizability	,					1.Unknown		
			·					2.Difficult	
•								3.Easy	
(7) Originality								4.Study finished	
(7) Originality								1.Unknown 2. Low	
(9) Group jude	· · · · · · · · · · · · · · · · · · ·	-	4 Name (1 (Ain ata)	6 1				3. Medium 4. High	
(8) Group judg			1. Normal (single) fringes this invention	2. 1	mpon	ant (double	e) 3. Most impo	ortant (triple)	
				inv	ention	amun comp	rioina thia incontian	and other related inventions	
2		·	i to other inventions in al	1 11 10	CHUOH	13	iising this invention	and other related inventions	
Galculation for rating Rating by requesting					Filing of the		1. Required		
		rtment			nt	2. Not required; it should be published on			
For inventions	of A or B	higher → S	· · · · · · · · · · · · · · · · · · ·		cation is: Journal of Technical Disclosure				
((1)+(2)+(3)+(4)	+(5))×(8)		ı → A			•	3. Not required	l (reason: `)	
= 51		9 → B		Foreign filing		1.Required (country name: US, CN, KR,			
For inventions of C		than 19 → C		is:		TW, EU)			
$((1)+(2)+(3)+(6)+(7))\times(8)$				•	2.Not required				
= .							3.Not dicided		
4	•								
Special note		•						Boss's seal of	

15

13		··	•
	Evaluation by Intellectual Property Dept	Rating by Intellectual Property Dept ¹¹	Overall evaluation*12
Evaluation	(1) (Patentability: 2 (2) Scope of rights: 2 (3) Difficulty to find infringement: 2 (4) Difficulty of design around: 2 (5) Group judgement: 2	$((1)+(2)+(3)+(4))\times(5)=16$ 36 or higher \rightarrow S 24-35 \rightarrow A 16-23 \rightarrow B Less than 15 \rightarrow C	S: Most important A: Important B: Normal C: Journal of Technical Disclosure. D: No filing E: By company circumstance



Evaluation Evaluation
Approver Approver
Seal: Seal:
Shinozuka
03.4.15

*11 Enter the evaluation values and circle the appropriate rank. *12 Place a circle on the appropriate item of the evaluation level.

Application	1. Regular application			Patent firm			
category	2. Domestic(pr)ority Ori	ginal application No.	•	Watanabe · Hotta			
	3. Division						
	4. Change	•					
Award for fili	ng the patent application	1. Will be offered	2. N/A (reason:)			
Remarks		·					

Should you have any comment on the evaluation, contact us within two weeks.

IPW-001 (Rev. 1.3)

_	$\overline{}$	١.
_	1.	
	1/	
	4	
١.		_

	発明等届出	出書(1/2)	1.特	許 2.意	3.そ	の他)		(補足	計 1.有	・2.無)	1	上外秘
\bigcirc	Post (716)			Uとしておお出版 Post (クロを	とする。例し、火川) Post (52)	新案で出版 知道は経済	したいりかり	は、「3.その何	K/0 K/0	知的財産部と 30264	州以する.	
	中田 中田 1823275 182 3.7 20248 20248				部 印	R	D4689	担当者印	MILK	部 受付日	No. 16	
2	太枠内をご記	•	LIA Z PERKI	ندر: (۱) المراجعة		X 10-3	以利	日(西曆) 元 Doc.N		3年 3	月 25 I	3
	依 (部門コード) 瀬 部門名 一書類送付: 部 担当者 門) (V350 第一開発センタ, 第	1		期発一部	(本 3.4.	管情風が落	:アリンク	御 (1964)	1 6 · 花 7 · 花	主原総和 主原ボイ 主原工業	'ラ 【
3)-	発明等の名称	基板のめっき装置	異なって	カーき七辻						/41	FI	
L									PP,		4.15	
	キーワード	めっき、平坦性、								10	7994	
	関連する製品又 製品の性格	1. 重点拡販機種			<i>、</i> ンプめっき 拡販機種で		研番店	対果 イ	开 No. L	-02D54	7.	
(4)	^{※ 2} 「社内発明者」欄	には荏原製作所(EBR)、	在原総	合研究所(ER)、荏原ポイラ	ŒB)、荏	原工業洗	浄(EICC)	の発明者等	のみ記入す		
	下欄はEBRの発明者 上記の職務発明		社	所属部門	名 Post Tel	個人	1-'}'	氏 名		権利 持分	認印	米国※4
	(発明者·考案 明等の時点にお	者·創作者)は発 いて日本及び外 切の権利を会社	社内発明者	第一開発第二プロ	センタ 716	2 1	1 5 5	倉科 敬		40%	富	THE STATE OF THE S
1	国におりる (株式会社荏原 したことを確認	『製作所)に譲渡』		第一開発第一プロ	センタ 715	0 8	3 2 0	並木言	介	40%	葉	
	下側はER,EB,EICCの列 上記の職務発明	初者等だけに適用する。]*3等に関し、私	4 3	第一開発第二プロ	1	2 0	2 4 8	中田 勉		10%	(3	
	(発明者·考案: 明等の時点にも	者·創作者)は発 さいて日本及び外 切の権利を会社	名 4	第一開発第二プロ	センタ 716	1 3	0 1 0	三島 浩	_	10%		
1	したことを確認 したことを確認)に譲渡』	2 5			-				%)	
ন *	^{《3} 届出発明が職務	発明でないと考える場合	合は認印	欄に押印せす	*に送付する。		*4 *	く国に在住	している場	場合はレ印る	を付ける。	
	出願形式 1	. EBR 単独 2.	EBR	と EBR 以	外の者との	共同 3	3. EB	R以外の	者の単独	虫 4. 3	その他	
) <u>-</u>	Harrier (de A.El			- N.M	and the state of			 	<u> </u>	<u> </u>		
	出願手続会社 費用負担	1. EBR 1. EBR 負担		EBR 以外の 均等負担	<u>7</u> 百(3. その	(th		,	·	•		
	EBR 以外の	会社名又は氏名			Tel、知財語		4者名等	<u> </u>		権利抗	寺分 費	用負担
	出願人名義 ^{× 5} (計 名)					<u> </u>					%	%
											%	%
ን እ	⁵ 荏原ポイラ(EB)、	在原工業洗浄(EICC)	は上記「I	EBR 以外の出	「願人名義」の概	に記入す	る。荏原	京総合研究	所(ER)はi	己入要領を	参照のこ	٤.
7	会社名		氏	名		住 所				-	権利	付持分
タ発	計							<u> </u>				%
り者	会社名 会社名		-							· · · · · · · · · · · · · · · · · · ·		%
_												
8) <u> </u>	出 1. 普通	には荏原製作所(EBR)、	在原総	合研究所(ER)、荏原ポイラ(EB)、在J	原工業洗	浄(EICC) 発表日		者等を記入 F	、する。 月	·B
	願 2. 至急 緩 急	(月日音	まで)	b	. 社外発表 . 当社先願名 . 国内優先相	公開期阻	3	発表先	:			

社内・社外発明者や EBR 以外の出願人名義について、本用紙に書ききれないときは発明等届出書補足書に記入し本用紙に添付する。

		明等届品	出書(2/2	2)								· 2	土外 秘
V.		約與係*7	共同研究等基	辺約部 1	1. 有(相手	<u> </u>) 2	2. 無		
		אואוניו	共同出願契約		1. 要(作成		a. 当社	b.	相手先())
発明			7 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1		2. 不要								
者記	1873	共同出願、他社	名義の出願とする	根拠としてタ	別的ながある場	合、契約	対数の写しを記	忝付する	•				
入欄		查実施状況		願・公知例	当社のも	の (1)有(出	时间包	2000-13.	2015)
11#1	1.	. 調査済み	43 Ave 201 va	に最も近い E 2 部添付す	- //////		2. 無	44.88 0				***************************************	
	2	(右棚記) . 未調査	3.		他社のも	1	1. 有(2. 無	特朋2	2000-24839	7)
<u>\</u>		- Manage					2. All						
V	=		発明の性質	発明の性	質によりA	R	Cのうち-	- 別をも	発択 (記号)	<u>(۶۵) ا</u>	て評価		***
	評	価項目)L910)ILA	K	品・技術の発				技術の発明		行アイラ	ア発明	月
		先行技術に対 優位性	付する技術的	1. 同等	Ţ	2.	若干優位	(3) 相当優	经位	4. 断然	《優位	
	_		図の難易度※8	()	かて困難		かなり困難	Œ	(3.)やや団	難	4. 容易		
		課題・手段の		1. 不明	月 2. やや		普通	n cer##	3. 重要		4. 最重	要	
1	[[他社における 回避困難度) 本	1. 容易	2. 7575 	四難	(3.*)かな	リ四類	4. 不	P)			
依	(3)	実施関係	•	1. 不明 2. 国内 <i>0</i>	りみ小規模		1. 未定 2. 試作予	产定·	•			•	
依頼元上長記				3. 国内の	Dみ大規模		3. 試作中	中又は	斉				
上	6	支術的実現性		4.)国内と	と外国で実施	<u>5</u>	4. 採用法	定		1. 7	KRH (2. 困難	æ.
記	W.	文例的关税的	-		-			_		3. 4		4. 検診	
入脚	7									1. 7	不明 2	2. 小	
	(O)#	洋評価 ^{※9}			1 th '36	(2. (\$2.)		重要(2) (†)	3. 「	<u>₽ 4</u> .要(3 倍	4. 大	*****
			を侵害しているか	まなの料即 す	1. 普通	(1 10)	\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	主女 (A	2 10/	3. 双里	安(3 旧	/	
_	_ × 9 _		関連する発明で形			発用のは	カの茶畑にかっ	ナス切み	めた重要度の	4₹/ #			
0	<u></u>	西計算式	対理する光明(ル		平価ランク ^{※10}	(3)	り発明に対	1. 3			開技報で	₹- } - ¿ .}	
		刊,B 列発明		45 以上		┨╏		3. 7	下要(理由	:	אר אנותו	. O. V -)
			(3)×(8= <u><i>3</i>0</u>	30~44	-(A) .	9	国出願	(1) 3	要(国名:) 下要	化国)
7		可発明 +②+③+⑥++	(7))×(8)=	20~29		<u> </u>		2. /	卜要	3. 未	疋		
]						(_6	(a)
V @	4	ਹਵਾਨ		―――――	評価ランクに	しを何り	ి .					7 7 8	
	行声	記事項											
_ 				<u> </u>								_	,
	発	知財部評価			知財部評価			総	S:最重要	į	•		,
	明	O			(D+2+3+		0=16	合	A: 重要	į	مشتنع	•	
1	の神	②権利の広 ③他社母宝	さ: <u></u> 確認の難易度		36 以上 → S 24~35 → A			評価	B). 通常 C: 公開表	5報 【			
EII	価		回避困難度:_		16~23 - €			*	D:見合t	<u>+</u>	一部89	大 担当	,
田材部記入		⑤群評価:	<u>Z.</u>		15 以下 →(12	E:会社都	哈	4-11-	fl)	
元 €	3			※11 評価	i点を記入し、i	該当の評	価ランクに〇	つを付け	る。 ^{※12} 該		ンクに〇を	と付ける。	•
閉	出	① 通常出		甘琳山路平	무·					特許事務	<u> </u>		
1	願	2. 国内優 3. 分割	元催土次 2	基礎出願番	' ' ' ' ' ' ' ' ' '					淹	工· 北	i A	
	態	4. 変更		-						/1 2 C		~~	
	出願備表		支給する	2. 支統	としない(理	由:)
	111017	-, I											

140	uncauon or myc	maon (1/2) (I Falein	2. UC	esign 3. U	ther) (Supplement, 1.	Maci	19d 2. N/A) Confidential	
			Use this form	i for p	atent appik	cation filing. For utility mod	del ap	plication, enclose "3. Other" with a	
1			Circle and Cons	SUIL W	Aln intellect	ual Property Dept.			
Pos	1-(718)				- De	est () Post (EQ) Intelle		December 1, December 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1,	
_	his form Manage	2	Patent Gene	-7	Related				
1 /	illed by: Nakad		iaison: manag		dept.:	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \		Responsible Date of receipt person: by IP Dept./No.	
	Nakada 03.3.2	. / ! }	Nagai / Mishin		Sasabe		ido)	2003.04.16	
	09.3.25		13.3.31		934.8			\2000.07.10	
				ne "Er		of the requesting dept." co	himn	on 2/2	
_			, - p			or the requesting Lopi. Go			
			1	/Saka	aguch)	Date of reques	et (Cl	nristian year): 2003/4/1	
	•		Ţ	103	.4.08	Requesting de	or (O)	1115tian year). 2003/4/1	
2				100	.4.00)	nequesting de	pι. υ	OC.NO 716-	
_	in within heavy-lin	o framo	.						
 					,		,		
合	(Dept. code)	(V350)		0	1. Corp	orate		6. Ebara Research	
Requesting dept.	Dept. name		s Development	Category		egic Information and		7. Ebara Boiler Co.,Ltd.	
E			2 Development	9		munication Systems	₽	8. Ebara Industrial Cleaning	
Š		Center	1	<u> </u>		Machinery & Systems		Co.,Ltd.	
[₹	Person	Name:	Tsutomu			neering	(Affiliate)	·	
a	responsible for	Nakad	a .	(Group)	_	•	e)		
18	the documents	Employ	ee No.: 20248	<u> </u>	J. Flec	ision Machinery			
-			716 Tel: 8566)	10	1			141	
3									
Ťit	le of the invention		Plating Method	and	annaratu	e of substrato		pp,01 (limura)	
	wword	-	Plating, planarit						
	elated product or te	oobpolo						03.4.16	
					griauon pi	ating, Bump plating		111111100000	
	aracter of the pro	uuci	1. Sales-focuse			Result of:		Job No. L-02D547	
	2. Not sales-focused								

4

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co., Ltd. (EB), Ebara Industrial Cleaning Co., Ltd. (EBC), or Ebara Politicaration Equipment & Systems Co., Ltd. (EBC)

The second second second	Ť	1	Refrigeration Equ					T	
The column below is			Dept.	Post	Employee	Name	Share	Seal for	Living
applicable only to inventors	1	1	Í	Tel	No. (five		of the	confirming the transfer	in U.S.*3
in EBR.	_			1	digits)	·	rights	ule dansier	0.3.
Regarding to the service							Í		
invention described above, I		1	Process	716	21155	Keiichi	40%	Kurashin	
(inventor, deviser, or creator)	1_	1	Development			Kurashina		a	
acknowledge that any and	17		Office 2	ļ					
all rights to the invention in	١ĕ	ı	Development			,			,
Japan and other countries	In-house		Center 1		•			(
have been transferred to the	įν	1		1					
Company (Ebara	100	l			,	·			
Corporation) upon invention.									
The column below is	1_				1				
applicable only to inventors	12	2	Process	715	08320	Keisuke	40%	Namiki	
in ER, EB, EICC, and ERS.	(Total:		Development			Namiki			
	1		Office 1						
Regarding to the service			Development			l l	a .		
invention described above, I	 ₹		Center 1						
(inventor, deviser, or creator)	inventor(s))*2	3	Process	716	20248	Tsutomu	10%	Nakada	
acknowledge that any and	چا		Development			Nakada			
all rights to the invention in	₩.		Office 2						
Japan and other countries	20	i	Development						
have been transferred to the	1		Center 1						
Company ()		4	Same as	716	13010	Koji	10%	MIshima	
upon izvention.			above			Mishima	•		
		5							
~									

Application type 1. Sole application by EBR 2. Joint application by EBR and acompany other than EBR 3. Sole application by a company other than EBR 4. Other

The "Applicant other than EBR" column is for inventors in EB, EICC, and ERS; for inventors in ER, see the instructions on the form.

Patent prosecution by:	1. EBR 2. Othe	r than EBR (}	
Expense is:	1. Paid by EBR	2. Equally shared 3. Paid	othewise	
Applicant other than EBR*4 (Total: applicant(s))	Company/ personal name	Contact (address, Tel, and responsible in Intellectual Property Dept.	Share of the rights	Share of the cost
			%	%
<u> </u>	· · · · · · · · · · · · · · · · · · ·		%	%

7
"5The "External inventor" column is for inventors outside of EBR, ER, EB, EICC, and ERS.

External inventor	Company	Name	Address	Share of the interest
(Total: inventor(s))*5			•	%
		·		%
				·

If descriptions of in-house//external inventors or applicants other than EBR cannot be contained in this form, write the descriptions in the Supplement and attach it to this form.

Urgency of	1. Normal	Released on:
application filing	2. High (by	Released to:
	Reason: a. External release (Fill the right column.)	
	b. Deadline for publication of our prior	
	application	
	c. Deadline for claiming domestic priority	
	Collaboration contract	· ·

IPW-001 (Rev. 1.3)

Notification of Invention (2/2)

9										
Related	Written co	ntract	for joint research		1. Availa	able (partner:) 2. N/A			
contract 6	Written co application		for joint filing of paten	it		ired (Prepared b	y: a. Us b. Partner ())			
6 When there is			t justifies the joint filing or	filing u	nder other nam	ne, attach a copy of	it to this form.			
Prior-art sear	ch		Related	Ours	1. Availa	1. Available (Application 2000-132015)				
1. Done (Fill t	ho right col	ump)	application and prior art:	Othe	2. N/A	-LI- /D- LI: -:				
2. Not done	ine ngrit coi	umm.)	Attach two items of	Other	2. N/A	able (Publication	No. 2000-248397)			
			prior art related to the	İ	2.19/					
			application.	<u> </u>		····				
11	-A£:	A2	10							
No.	ature of Inve	noon (A) Invention for curr	enclos	e with a circ	le), considering t	he nature of the invention.			
Evaluation ite	m	_ '	products/technologi			on for new echnologies	C. Invention of new ideas			
(1) Technical		over	1. None 2. A little							
prior art						, ,				
(2) Difficulty to infringement			1.Very difficult 2.C	onside	rably difficul	t 3.A little diffici	ult 4.Easy			
(3) Severity o	र्ग		1. Unknown 2. No	rmal	3. High 4. \	Very high	•			
challenge,			<u> </u>							
(4) Difficulty of design around			1.Easy 2.A little di 4.Impossible	fficult	3.Considera	ably difficult	-			
(5) Applicabili	ty to produc	ction	1.Unknown		1.Not dec		· -			
			2.Domestic small so			to trial prod.	•			
		4	3.Domestic large sc	Domestic large scale 3.Under or finished trial production						
		. 9	9.Domestic and abre	oau		4.Decided to adopt				
(6) Technical	realizability				7.Bedided	to adopt	1.Unknown			
	•			-			2.Difficult			
							3.Easy			
(7) Originality					-		4.Study finished			
(7) Originally	•						1.Unknown 2. Low 3. Medium 4. High			
(8) Group jude	remen 9		1. Normal (single)	2 Impo	ortant (doubl	e) 3. Most impo				
		pany in	fringes this invention	<u> </u>	·· (dodb)	ej o. Most impt	rtait (triple)			
⁹ Judge of import	ance of this in	vention	to other inventions in an	inventio	on group comp	rising this invention	and other related inventions			
12			<u> </u>	13						
Salculation for	rating		g by requesting		ng of the	1. Required				
	-64		rtment		ent		d; it should be published on			
For inventions			higher → S	ap	olication is:	Journal of 16 3. Not required	echnical Disclosure.			
$((1)+(2)+(3)+(4)+(5))\times(8)$ 30-44 = 30					•	3. Not required	r (reason:)			
For inventions	of C) → B		reign filing		untry name: US)			
((1)+(2)+(3)+(6)	6)+(7))×(8)	Less	than 19 → C	is:		2.Not required 3.Not dicided	·			
=				1.		3.Not dicided	· .			
14										
Special note			•				Boss's seal of			
• •			•		•		approval:			
					· · · · · · · · · · · · · · · · · · · 					

15	·		
	Evaluation by Intellectual Property Dept	Rating by Intellectual Property Dept***	Overall evaluation*12
\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\\	(1) (Patentability: 2 (2) Scope of rights: 2	((1)+(2)+(3)+(4))×(5)=16 36 or higher → S	S: Most important A: Important
luation	(3) Difficulty to find infringement: 2 (4) Difficulty of design around: 2		B: Normal C: Journal of Technical
Š	(5) Group judgement: 2	Less than 15 → C	Disclosure. D: No filing
			E: By company circumstance

Evaluation Evaluation Approver Approver Seal: Seal: Kondo

Enter the evaluation values and circle the appropriate rank. *12 Place a circle on the appropriate item of the evaluation level.

Application	1. Regular application		Patent firm		
category	2. Domestic priority Or	iginal application No.:	Watanabe · Hotta		
	3. Division				
•	4. Change				
Award for fili	ng the patent application	1. Will be offered 2. N/A (reason:)		
Remarks					

Should you have any comment on the evaluation, contact us within two weeks.

IPW-001 (Rev. 1.3)

		7
	(-	א א
Э.	/	_

				. ~		e ochei	10 104		
•	発明等届出書(1/2)	1.特許	2.意匠		他).**		1.有・2.無)		社外秘
0	Post (716)			但し、実用新案 ost (52)_知的		は、「3.その他」に(つを付し知的財産部 1030261	と相談する。	
(WAR MAN	部長		近途者15 第649	知財部 受付日 2003. 64. 16		30281
10	2/2の仮有元上長紀入間の傾印間もお忘れ	れなく領点印下さい	63.4.08) 102)	依頼 佐頼	日(西暦) 元 Doc.No.7		3月2	5日
	依 (部門コ・ド) (V350 類 部門名 第一開発センタ・第 元 書類送付先 氏名:神田 名 部 担当者 個人コード:第 (Post:716	灸之●	発室,開発-)	一部 区分(本部)	3. 風水 4. エンジ	・通信・制御 カ ニアリング・ ・電子		荏原総存	
ම) 発明等の名称 基板のめっき装	男ながみ。	キーセット				2		$\widetilde{}$
	光明等の名称 基板ののつき装	直及ひめつ?	2万伝			P	1,0/	Ti.	_
	キーワードめっき、平坦性、			., .			-03	4.15	
	関連する製品又は技術 DMI 製品の性格 1. 重点拡販機種		き、パンプ。 . 重点拡販		\	et en la company	- I -00D5	47-	· ·
	設品の任格 1. 里点仏販機種 ** ² 「社内発明者」 欄には荏原製作所(EBR)						o. L -02D5。 理者等のみ記入		
5	下欄は EBR の発明者等だけに適用する。		属部門名	-,-	因人3-1。	氏名	権利	認印	米国^{※ 4}
	上記の職務発明*3等に関し、私			Tel			持分		在住
	(発明者・考案者・創作者) は発 明等の時点において日本及び外		一開発センタ 二プロセス	716 2	1 5 5 9	神田 裕之・	110	(A)	2)
	国における一切の権利を会社 (株式会社荏原製作所)に譲渡	1919年	/ □C^ 開発センタ	716 2	0 8 0 4	長井 瑞樹	40,	一个	₹—
	したことを確認します。	計	一プ ロセス				70,	(3)	
ŀ	下標はER,EB,EICCの新路等だけに適用する。 上記の職務発明※3等に関し、私		一開発センタ 二プロセス	716 2	2 1 6 3 0	山本 暁	Zo, %	1 (2)	<u>5</u>)
	(発明者・考案者・創作者) は発 明等の時点において日本及び外		一開発センタ	716 1	3 0 1 0	三島 浩二	20.%	1/=	=\
	国における一切の権利を会社	※ 第	二プ・吐ス			·			<u> </u>
	()に譲渡したことを確認します。	5 5					%	5	
L S	※ ³ 届出発明が職務発明でないと考える場	合は認印樹に打	甲印せずに送付	けする。	×4;	 	いる場合はレ印	」 を付ける	
1	出願形式 (1). EBR 単独 2.	EBR & E	BR以外の記	皆との共同	3. EB	R以外の者の)単独 4.	その他	
<u>(</u>									
	出願手続会社 ① EBR		以外の者()		
	要用負担 (T) EBR 負担 EBR 以外の 会社名又は氏名	2. 均等	<u>負担 3 </u> 住所、Tel、	その他	田少女友	<u>*) </u>	権利	持 公 [1	 費用負担
	出願人名義*5) 建和元(生///、Tei、	和照 即 .	担当有石号	チ ノ	TETT	%	%
ı	(計 名)								
								%	%
?) ?)	^{※ 5} 荏原ポイラ(EB)、荏原工業洗浄(EICC)	は上記「EBRリ	以外の出願人名	議」の欄に翻	己入する。荏原	原総合研究所(E	R)は記入要領を	参照のこ	
~~	→ 全社名	氏 名		住	所			権	利持分
	外計								%
E	発 明					•		- -	%
1	社() 会社名 外発明								%i
L			· · · · · · · · · · · · · · · · · · ·			·			
3	^{※6} 「社外発明者」 欄には荏原製作所(EBR)、	在原総合研究	的(ER)、在原	ボイラ(EB)	、荏原工業洗	净(EICC)以外の	D発明者等を記	入する。	
3	出 (1). 普通 願 2. 至急 (月 日3	まで) 理由	3:a. 社夕	、発表(左	棚記なり	発表日: 発表先:	年	月	E
	1 m 1 m m 1 m 1 m 1 m 1 m 1 m 1 m 1 m 1	~ < / /== U	u. LL/	17421 141	いまけんへく	162016 .			, 1

社内・社外発明者や EBR 以外の出願人名義について、本用紙に掛ききれないときは発明等届出書補足事に記入し本用紙に添付する。

b. 当社先願公朋期限

国内優先権主張期限

緩

急

C				·										
Λ	契約関係	ž.** 7	共同研究	记等契約書	1. 有(相	手:)	2. 魚	Ħ.	
- 発明者			共同出願	顛契約書	1. 要(作 2. 不要	成担当	: a. 当社	b.	相手	先())
者記	※7共同出際	承、他社名	義の出願と	する根拠とし	て契約書がある	場合、契約	約書の写しを添	付する						
入欄	調査実施			連出願・公知		もの	1. 有()
	1. 調達		1 / 4	i内容に最も近] 例 を 2 部 添	<u> </u>		2. 無					*****		
	2. 未訓	i欄記入 調査	る.		・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・・	€00	1.有(2.無 [·])
-V	<u></u>					<u>-</u> -								
1			発明の性	質 発明の	D性質により	A. B.	Cのうちー	列をi	発択	(記号)	۶(۱)	して評	価	
	評価項目		NA NA STE		E製品·技術の		B新事業類					. 先行ア		ア発明
	①先行技		する技術	的 1.	同等	3)	若干優位			相当堡			断然值	
			の難易度	*8 1.	極めて困難	2.	かなり困難		(3.)	やや困	難	4.	容易	
	③課題・				不明		普通			重要		4.	最重要	Ę
	回避困	難度	本発明の			神田雄	3. かなり	2困難	É :	4. 不	可			
<i>H</i> -	⑤実施関	係		1. 不		t	十二 未定	, e. e.					_	
1X 頼			•		内のみ小規模 内のみ大規模		2. 試作予 3. 試作中		本					
元上					内と外国で実		4. 採用決		7					
依頼元上長記入欄	⑥技術的	実現性)1	. 不明 . 容易		困難 検討済
欄	⑦独創性										51	不明中		小大
1:	⑧群評価	※ 9			(1,) 普通	(1倍)	重(及)	要(2 倍)		3. 最	重要((3 倍)	
	×8 他社が4	発明等を	侵害してい	るか否かの判	別の程度のこと	•						~		
Œ	× ⁹ 本発明及	び他の関	連する発明	で形成する発	明群における、	本発明の何	也の発明に対す	る相対	的な	重要度の	評価。			•
	評価計算	式		依頼	元評価ランク*ュ		L願要否 【	10	更		2.	公開技	報でよ	(1)
	A列,B列			1	L上 →S	7 L				(理由	:)
))×®= <u>2</u>		44 →A			-		国名:			•)
	C 列発明 (①+②+②))×®=_		29 / B) (下 →C			2	下安		30	未定		
Ve				×10 該	当の評価ランク	── に○を付り	する。					•		(A)
V.	特記事項													
<u> </u>				 										
10	発知財	部評価点	<u> </u>		知財部評	価ランク×11		総	S:	最重要		\neg		
		許性:			(1)+2+3			合		重要	•			
			z: <u>z</u> .		36以上 -	→S	 	評		通常			2	
4 n	評③他			易度: 3	24~35 -			価 **		公開技		TE.	郊	山地 超当都
知財部記入	価 ④本 ⑤群	発明のE 評価:		度:_2_	16~23 -			12		見合せ 会社都		1		21849
	9			×11	呼価点を記入し		評価ランクに〇	を付け	る。	×12 該	当の評価	—」 西ランク(ー に○を作	けける。
闡	出(1).	通常出願	Ą							• 1		事務所		
	願 2.	国内優先	尼権主張	基礎出願	預番号:					Ī				
	形 3.										2	' て		
	据 4. 3 出願賞		友給する	2 5	支給しない(四中・)
1 1			~17H J W		~11H ~ 10 4 7 (- AL LA								/ /

Notification of Invention (1/2) (1 Patent 2. Design 3. Other) (Supplement: 1. Attached 2. N/A) Confidential "Use this form for patent application filing. For utility model application, enclose "3. Other" with a Confidential circle and consult with Intellectual Property Dept. Post (718) Post (52) Intellectual Property Dept. K1030264 This form Patent Manager General Related General Manager Responsible Date of receipt filled by: Kanda liaison: manager. dept.: manager. person: y IP Dept./No Kondo Kanda Nagai Mishima. Sasabe Nakashiba Yamaji 2003.04.16 03.4.8 Q3.4.15 Be sure to affix the seal in the appropriate space of the "For the boss of the requesting dept." column on 2/2. Sakaguch Date of request (Christian year): 2003/3/25 03,4,08 Requesting dept. Doc.No.: 716-Fill in within heavy-line frames. (Dept. code) (V350) Ebara Research 6. Corporate 1. Dept. name **Process Development** Ebara Boiler Co., Ltd. Requesting Cate Strategic Information and 2. (Affiliate) Office 2 Development Ebara Industrial Cleaning Communication Systems Co.,Ltd. Center 1 3. Fluid Machinery & Systems Name: Hiroyuki Kanda Person 4. **Engineering** responsible for Employee No.: 21559 **Precision Machinery** (Post: 716 Tel: 7247) the documents Title of the invention Plating Method and apparatus of substrate pp,01 limura Keyword -Plating, planarity, uniformity, filling ability 03.4.15 Related product or technology DMP, Impregnation plating, Bump plating 1. Sales-focused Character of the product Result of: Job No. L-02D547 2. Not sales-focused

*2 The "In-house inventor" column is for inventors in Ebara Corporation (EBR), Ebara Research (ER), Ebara Boiler Co.,Ltd. (EB), Ebara Industrial Cleaning Co.,Ltd. (EICC), or Ebara Refrigeration Equipment & Systems Co., Ltd. (ERS).

Industrial Cleaning Co., Ltd. (EICC),	OI E	Dala	,						
The column below is	1		Dept.	Post	Employee	Name	Share	Seal for	Living
applicable only to inventors	1	1		Tel	No. (five		of the	confirming	in U.S. ^{*3}
in EBR.	_	1			digits)	İ	rights	the transfer	0.8.
Regarding to the service]				}		1		
invention described above, I		1	Process	716	21159	Hiroyuki	40%	Kanda	
(inventor, deviser, or creator)	_		Development			Kanda			
acknowledge that any and	7		Office 2				1		
all rights to the invention in	S	Į.	Development						
Japan and other countries	n-house	1	Center 1	:			l		
have been transferred to the	Ş.						1		
Company (Ebara	8						1		
Corporation) upon invention.	ento								
The column below is	ニ								
applicable only to inventors	Total:	2	Process	716	20894	Mizuki	20%	Nagai	
in ER, EB, EICC, and ERS.	<u>a</u>		Development			Nagai			
			Office 2					·)
Regarding to the service	15.		Development				1		
invention described above, I	é		Center 1	•					
(inventor, deviser, or creator)	inventor(s))*2	3	Process	716	21630	Satoru	20%	Yamamot	
acknowledge that any and	T S		Development			Yamamot		0 .	
all rights to the invention in			Office 2			0			
لوapan and other countries	"		Development		•				
have been transferred to the			Center 1						
(Comparhy (4	Same as	716	13010	Koji	10%	Mishima	
upon invention.	.		above			Mishima			
		5							
				·					
						3		imeastar is lisi	

³ Put a checkmark if the investor is living in U.S.

Released on:

Released to:

<u> </u>		<u> </u>					· · · · · · · · · · · · · · · · · · ·
Application type				2. Joint application by npany other than EBR		oth	er than EBR
6	1			.parry sais. arair 2011	1. 04101		
*4 The RA - 15 - 4 - 41							
i ne "Applicant otner	than t	BH" column is for inv	entors	in EB, EICC, and ERS; for	inventors in ER, see the	insti	ructions on the form.
Ratent prosecution	n by:	1 EBR 2. Othe	r tha	n EBR (`.		•
Expense is:		1. Paid by EBR	2. E	qually shared 3. Paid	otherwise		
Applicant other tha	an	Company/	Con	tact (address, Tel, and	Share of the rights		Share of the cost
EBR*4		personal name	rest	onsible in Intellectual			
(Total: applican	t(s))	•	· •	perty Dept.			
	•					%	%
						%	%
7 *SThe "External inventor	or" colu	umn is for inventors o	utside	of EBR, ER, EB, EICC, and	IERS.		
External inventor		Company		Name	Address	T	Share of the interest
(Total: inventor)	(s))* ⁵				\$		%
• .				·		9	%
If descriptions of in-hor	use//ex	dernal inventors or at	policar	ts other than FBB cannot b	e contained in this form	write	the descriptions in the

Reason: a. External release (Fill the right column.) b. Deadline for publication of our prior

Collaboration contract

c. Deadline for claiming domestic priority

application

IPW-001 (Rev. 1.3)

application filing

Urgency of

Supplement and attach it to this form.

1. Normal

2. High (by

1104,,,004,,00		(-,-)	•				Confidential
9							
Related	Written co	ntract	for joint research		1. Availa	able (partner:) 2. N/A
contract*6			for joint filing of paten	t			by: a. Us b. Partner ())
	application				2. Not re	eguired	
When there is a	a written cont	ract tha	t justifies the joint filing or	filing und	ler other nam	ne, attach a copy of	it to this form.
10			Ta				
Prior-art searc	cn		Related application and	Ours	1. Availa 2. N/A	able ()
1. Done (Fill the	he right col	umn.)	prior art:	Others		able (, , , , , , , , , , , , , , , , , , , ,
2. Not done	_	•	Attach two items of		2. N/A	•	
·			prior art related to the			•	
11	· · · · · · · · · · · · · · · · · · ·		application.	<u> </u>			
	ture of inve	ontion	Chance A. P. or C. (onologo	with a siral	la) assaidariss	M
110			A. Invention for curr	enciose	B. Invention		the nature of the invention. C. Invention of new ideas
Evaluation iter	m	\sim	products/technologi			echnologies	C. Invention of new ideas
(1) Technical:	superiority	over	1. None 2. A little				<u> </u>
prior art						. vory large	
(2) Difficulty to	o find		1.Very difficult 2.C	onsider	ably difficul	t 3.A little diffic	ult 4.Easy
infringeme							
(3) Severity of			1. Unknown 2. No	rmal 3	. High 4. \	Very high	
challenge/			4 5 0 4 1201 12	76: 10			
(4) Difficulty of	r design ar	ouna	1.Easy 2.A little dif 4.Impossible	micult :	3.Considera	ably difficult	<u> </u>
(5) Applicabilit	v to produ	ction	1.Unknown		1.Not dec	ided	
(-) . 45	., p. caa.	01.011	2.Domestic small sc	ale		to trial prod.	_
			3.Domestic large sca			r finished trial	·
			4.Domestic and abro		production		•
(2) = 1					4.Decided	to adopt	
(6) Technical r	realizability						1.Unknown
				-		, I	2.Difficult
		•					3.Easy 4.Study finished
(7) Originality							1.Unknown 2. Low
			20.00				3. Medium 4. High
(8) Group judg	jement ^{*9}		1) Normal (single)	2. Impor	tant (double	e) 3. Most imp	ortant (triple)
			fringes this invention	:			*
	ance of this ir	rvention	n to other inventions in an	invention	n group comp	rising this invention	n and other related inventions
12				13			
Galculation for	rating		g by requesting		g of the	1. Required	•
For inventions	-4 A D	<u> </u>	rtment	pate		2. Not require	d; it should be published on
For inventions			higher → S	app	lication is:	3. Not require	echnical Disclosure.
((1)+(2)+(3)+(4) = 20)+(3)) × (6)		1 → A	<u> </u>	•		
For inventions	of C) → B		eign filing	1.Required (co	ountry name:)
((1)+(2)+(3)+(6)		Less	than 19 → C	is:		2.Not required	
=						3.Not dicided	
14				<u> </u>			
Special note							Boss's seal of
							approval:
							Mishima /

15

15			•
	Evaluation by Intellectual Property Dept	Rating by Intellectual Property Dept***	Overall evaluation*12
Evaluation	 (1) (Patentability: 2 (2) Scope of rights: 2 (3) Difficulty to find infringement: 3 (4) Difficulty of design around: 2 (5) Group judgement: 2 	((1)+(2)+(3)+(4))×(5)=18 36 or higher → S 24-35 → A 16-23 → B Less than 15 → C	S: Most important A: Important B: Normal C: Journal of Technical Disclosure. D: No filing E: By company circumstance



Evaluation	Evaluation
Approver	Approver
Seal:	Seal:
Kondo	Yamaji
	03.4.17

Enter the evaluation values and circle the appropriate rank. *12 Place a circle on the appropriate item of the evaluation level.

	1. Regular application		Patent firm			
category		riginal application No	Kuma			
	3. Division		•			
	4. Change	·				
Award for fili	ng the patent application	1. Will be offered	2. N/A (reason:)		
Remarks						

IPW-001 (Rev. 1.3)

Should you have any comment on the evaluation, contact us within two weeks.

発明部門メニューへ 事業本部特許部メニュー

社外秘

ー時保存したものに追記する場合、または、承認/否認する場合、上部の「編集」リンクをクリックしてください。 **発明等届出書**

届出日:2003/06/27

知的財産部受付番号:K1030415 受付日:2003/07/03

依頼元担当一記入 ▼依頼元上長一記入 ▼事業本部特許部一記入 ▼ワークフロー情

★は必須入力項目です。

▼依頼元担当一記入欄



②【依頼元情報】



会社★	01 荏原製作所	部門	V350二プロ開発一	
整理番号(Doc.No.)	716-L36271			
担当者	会社区分+社員番号:0121155	氏名:	倉科 敬一 TEL:8556	
本部名★	PP 精密·電子			

②【基本情報】

国内/外国★	国内	
四法★	特許	
発明の名称★	基板のめっき装置及びめっき方法	
キーワード	めっき、平坦性、均一性、埋設性	
関連する製品名	DMP、含浸めっき、バンプめっき	
関連する業務コード	その1 7B配線めっき装置 その2 7Cバンプめっき装置	
研番	L-03D51306	
研番依頼元	部署名 V350二プロ開発ー	
職務発明について★	1.職務発明である	



③ 【荏原製作所/荏原総合研究所/荏原電産の発明者】

		社員番号/氏 名 (会社区分+社 員番号)				米国在 住	代表発明 者 ★
1	EK0001/ 荏原製作 所	0121155 倉科 敬一	内線NO : 9293 ポストNO : 716 E-mail : kurashina.keiichi@ebara.com	V350二プロ 開発一	25		Check
	EK0001/ 荏原製作 所	0120894 長井 瑞樹	内線NO:9293 ポストNO:716 E-mail:nagai.mizuki@ebara.com	V350二プロ 開発一	25		
	EK0001/ 荏原製作 所	0121630 山本 暁	内線NO : 9293 ポストNO : 716 E-mail : yamamoto.satoru@ebara.com	V350ニプロ 開発ー	25		
	EK0001/ 荏原製作 所	0121559 神田 裕之	内線NO: 7247 ポストNO: 716-2 E-mail: kanda.hiroyuki@ebara.com	V350二プロ 開発ー	15		,

		•						
5 EK0001/ 01 在原製作 三 所	113010 島 浩二	内線NO:9427 ポストNO:716 E-mail:mishim	a.koji@ebara	ı.com	V350二プ 開発ー	□ 10		
該当無しおよび予	定発明者					<u></u>		
	 			•				
【荏原総合研究所・	荏原電産以タ	トの関連会社/	社外の発明	者】				
会社コードノネ	各称	氏名	TEL/E-	mail	所属部門	引または住	所米国	在住
1			TEL: E-mail:					
該当無しおよび予算	完整服务		L man.		<u> </u>	·		
EX 3 # C 63 & C 1 7	E.F.91			•		- 1		
【出願人】				·				
コード/名称(略称)	住所連絡先など				利持 費 担	(%)	手続担 当 ★
1 EK0001 在原製作所	·	本社住所: 連絡先住所:〒 部署: 担当: 「EL: FAX: E-MAIL:			E	E		担当
<u>し」</u> 該当無しおよび予算		TO COLOR	· · · · · · · · · · · · · · · · · · ·					
	CIMINA	<u></u>						
					-			
出願緩急】)(Note that the second		12.2				
出願緩急	至急	出願希望日理由	2003/07/		発表先:		<u>-</u>	
		上 一	拉尔光教		光表元: 発表日:200 その他:		. :	
【契約関係】				* . •		**		100
契約書有無★	無		種類その他					•
相手先	1							
	2			•			•	
	3			•		•	•	
	5							
	その他			t v		•		
契約書				•				
共同出願契約書作	不要		作成担当					
成★		·	相手先	その他]]			
								
AV	•							
▲▼ 調査実施状況】					•			

調査状況★	未調査			
調査内容		検索式:		
		資料:		
競合メーカー	ノベラス、ニ	ューツール、アプライドマテ	Jアル、AMCリサーチ	

② 【関連出願公知例】

当	社の関連出願公知例★	有
1	特願2003-15236号 または文献名:	ファイル
2	号 または文献名:	ファイル
3	号 または文献名:	ファイル
4	号 または文献名:	ファイル
5	号 または文献名:	ファイル

他	社の関連出願公知例★	無
1	号 または文献名:	ファイル
2	号 または文献名:	ファイル
3	号 または文献名:	ファイル
4	号 または文献名 :	ファイル
5	号 または文献名 :	ファイル

li	<u> </u>	
Ш		
Ш	=1	

(特記事項) 特記事項

②【発明等説明書(明細書素案)】

明細書	図面	その他
<u>- なじませ条件3521.doc</u> サイズ: 196608バイト	_ なじませ条件3521.TIF サイズ: 356976バイト	
添付者:keiichi kurashina/e/ebara_jp 添付日:2003/06/27	添付者:keiichi kurashina/e/ebara_jp 添付日:2003/06/27	添付者: 添付日:

▲从杨二担业 台 1	AL 45 - 1 - 5 - 7 7		
	依賴元上長一記入		▼ワークフロー格
	10x4870-1-1x 10-7x	【▼中米个即行町中 配入	Y J J J H 18 .

▼依頼元上長一記入欄

② 【発明部門評価】

		<u> </u>
発明の性質	14.19大制日 サギの200	:
光明の注負	A:現在製品・技術の発明	

①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)		3. 相当優位
②課題・手段の重要	性	4. 最重要
③独創性 (発明の性質がCのと	きのみ必須)	0. 未評価
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)		4. 開発計画の初期段階である
⑤本発明が製品に占	める重要度(割合)	4. 大きい
⑥依賴元総合評価		4. 最重要
評価点		60点
出願要否	要(理由:)	
外国出願要否	要	
特記事項	関連特許をまとめ、全	〒内海外出願が必須。

▲依頼元上長一記入 ▲依頼元担当一記入 事業本部特許部一記入

事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	お願いします。
担当者記入欄	コメント	CL1に記載の構成は、特開2000-232078(東芝)に開示されているが、CL2 の含浸体と基板の被めっき面が接触と非接触を繰り返す振動である点の記 載はありません。よって、出願することはOKと考えます。
	添付文書	
	作業終了サイン	坂口:終了

<u>▲依頼元担当一記入</u>	▲依頼元上長一記入	▲事業本部特許部一記入	ワークフロー情



現在のユーザ: kenichi sasabe/e/ebara_jp 現在の承認者: 要求 ID NTNN-5NW6L3

ステータス: 完了



\mathfrak{G}

申請者
keiichi kurashina/e/ebara_jp

sasabe/e/ebara_jp masamichi nakashiba/e/ebara_jp

承認者情報

(3)

申請者名	申請日	CCメール
keiichi kurashina/e/ebara_jp	2003/06/27	akira fukunaga/e/ebara_jp

0

Ł		•	•			
	承認者役職	承認者名	承認期限	ステー タス	承認日	CCメール
	発明者上司	hiroyuki kanda/e/ebara_jp	2003/07/04	承認	2003/06/30	
	リエゾン	tsutomu nakada/e/ebara_jp	2003/07/07	承認	2003/06/30	·
	部長	koji mishima/e/ebara_jp	2003/07/07	承認		hiroyuki kanda/e/ebara_jp katsuhiko tokushige/e/ebara_jp hidenao suzuki/e/ebara_jp hidekazu nagano/e/ebara_jp
		kenichi sasabe/e/ebara_jp	2003/07/07	承認	2003/07/02	
Ĺ	知的財産部 部長	masamichi nakashiba/e/ebara_jp	2003/07/09	承認	2003/07/03	·

▼コメント

CN=hiroyuki kanda/0U=e/0=ebara_jp 承認 2003/06/30 14:10:56 特になし CN=tsutomu nakada/0U=e/0=ebara_jp 承認 2003/06/30 14:53:34 承認しました。 CN=koji mishima/0U=e/0=ebara_jp 承認 2003/06/30 15:15:30 第一クレームのドライシール規定を外せるのならば外すこと。AMATはシールレスのため。 CN=kenichi sasabe/0U=e/0=ebara_jp 承認 2003/07/02 23:50:33 承認します。 CN=masamichi nakashiba/0U=e/0=ebara_jp 承認 2003/07/03 10:51:41

▲アカション

To the menu for the dept. of the inventor(s) To the menu for Patent Dept. of the Group

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/06/27

Intellectual Property Dept's receipt No.: K1030415 Date of receipt: 2003/07/03

For the responsible person in the requesting	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
side			

Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

Company name *	01	Dept.	V350 Development Department 1, Process				
	Ebara Corporation		Development Office 2				
Reference No. (Doc.No.)	716-L36271						
Responsible person	Company category + Employee No.: 0121155 Name: Keiichi Kurashina TEL: 8556						
Group name★	PP Precision Machinery						

2 [Basic information]

Domestic/foreign ★	Domestic							
IP category ★	Patent							
Title of the invention	Plating apparatus and method of substrate							
Keyword	Plating, planarity, uniformity, filling ability							
Names of related products	DMP, Impregnation plating apparatus, Bump plating apparatus							
Related job code	No. 1 78 Wire plating apparatus No. 2 Bump plating apparatus							
Job No.	L-03D51306							
Requesting dept.	Dept. name V350 Development Department 1, Process Development Office 2							
About service invention ★	1. Yes							

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor
1	EK0001/	0121155	Extension No.: 9293	V350	25		Check
	Ebara	Keiichi Kurashina	Post No.: 716	Developme		Ċ	
	Corporation		E-mail:	nt		·	
			kurashina.keiichi@eba	Department		. '	- '
	-		ra.com	1, Process		İ	•
				Developme			· ·
				nt Office 2	`		
2	EK0001/	0120894	Extension No.: 9293	V350	25		
	Ebara	Mizuki Nagai	Post No.: 716	Developme		ľ	
	Corporation		E-mail:	nt			
	•		nagai.mizuki@ebara.c	Department			•
		1	om	1, Process	ł		
				Developme	· ·	·	
				nt Office 2			
3	EK0001/	0121630	Extension No.: 9293	V350	25		
	Ebara	Satoru Yamamoto	Post No.: 716	Developme			
	Corporation -		E-mail:	nt			•
		!	yamamoto.satoru@eb	Department			
		İ	ara.com	1, Process			
		į ·	· ·	Developme			
				nt Office 2			
4	EK0001/	0121559	Extension No.: 7247	V350	15		
	Ebara	Hiroyuki Kanda	Post No.: 716-2	Developme			
	Corporation		E-mail:	nt			•
			kanda.hiroyuki@ebara	Department			
8-			.com	1, Process			
				Developme			
		ĺ	130	nt Office 2		l	

5	EK0001 Ebara Corpora	tion	0113010 Koji Mis	himà		Post N E-mail:	o.: 71	o.: 9427 6 @ebara.	.c D	t)epa , Pr)eve	elopme artment ocess elopme	10			
N/A	A and pot	ential in	ventor(s)	-		·							· · · · · · · · · · · · · · · · · · ·		
4	[For inve	entors	in affilia	ites ot	ner th	nan Ebara				De	nsan L	td and	i externa	l invento	rs].
	Compa	ny cod	de/name	e Na	me		TE	L/E-ma	ail		Dept./d	contac	t addres		g in
1							TE	L:		\dashv				U.S.	
	A J	- 4 4° -	1:	(-)			E-r	mail:		_		· · ·			
[IN/	A and p	otentia	ınvenu	or(s)					•	i_	·····				
	[Applica														
	de/nam		Co	ntact a	ıddre	ss, etc.		1	e of th	he i	rights ·		e of the	Prosec	ution
	obreviati	on)				.1.1		(%) E				costs	(%)	by: ★	a:bla
	(0001 ara Cor	noratio		adqua ntact a		ddress:		=				E		Respor person	ISIDIE
==	ara Cor	porauc	De			ss. T onsible:		1						person	
			TE		FAX:			Ī							
	·			nail:				_						<u> </u>	
N//	A and po	otentia	linvent	or(s)											
6	[Urgenc	y of ap	plicatio	n filing	1										•
Ur	gency					data of fili	ng	2003/		9	·				
				Reas	on			Outsi					o: [redact		
								prese	entatio	on	Other		n:2003.0	17.10	•
L											, <u>Garo</u> ,	<u> </u>	- · · · · · · · · · · · · · · · · · · ·		····
7	[Related	contr	act]												
Wr	itten cor	ntract	*		1	N/A			Туре		· · · ·	4			•
_		· · · · · ·			-				Othe	er	· · · · · · · · · · · · · · · · · · ·	┙.			
Pa	rtner				2						•				
			٠,		. 3										
						4				•	٠	•			
					5										
	<u> </u>				<u> </u>	Other			·					•	
	ntract		ntroot.		-	let require			Dron		ad by a	٦.		•	
	eparation cuments			ication		ot require	eu.		Parti		ed by:	+	·		
	ng ★	, 101 10	т арр		ŀ		ļ r					Oth	er	\exists	
					·					.,,		1		•	
	Prior-ar			11	Not d	<u> </u>		•					·		
	or-art se		<u>×</u>	 '	voi u	one		Soar	ch for	mu	da:	:			
Search details					•	Mate									
Со	mpetito				Vove	llus, Nuto	ol, Ap			als,	AMC F	Resea	rch		
9	[Related	I annlic	ration o	nd pri	nr arti	<i>,</i> ·		•							•
	rs: ★	applic	auon a	nu pn	n arı					N	/A				
1		Appli	cation N	lo. 20	03-15	236		<u>-</u> -	·		ile	•			
Ľ			cument												
2		No.						9	•	Fi	ile				-
-		or do No.	cument	title:				•	•	-	ile				
3			cument	title:							ii C				
4		No.								Fi	ile		•		
or document title:							1_								

	·								
1	No.								
0	r documen	t title:							
O411A	-				1.				
Others': ★	_					/A			
1	o. r document	ı bialı.	•		F	ile			
2 N		i ude.				ile	_		
1 1	o. r document	t title:				lie			
3 N		title.				ile			
1	document	title:		' '	ne ·	· .			
	No.					le	┥		
	document	title:		1					
5 N	0.			Fi	le	-			
or	document	title:							
	,		•						
10 [Special n	ote]				•				
Special note	<u> </u>								
44 (17)		. ,							
	on of invent	,,	cation draft)]			<u>_</u> .			
Specification Adaptation Co	nditio-	Drawi			Othe	ers			
3521.doc	ondition	3521.	ation Condition	ן יו					
Size: 196608	hite .		356976 bite						
Attached by: h			ned by: Keiichi		Atta	ached by:			
	1					ched by: ched on:			
Attached on: 2003/06/27 Attached on: 2003/06/27					, ma	oned on.			
									
▲ For the resp		For the	boss of the	▼For Pa	atent	Dept. of	▼ Workflow information		
person in th		reque	sting side	the Gr					
requesting s	<u>side</u>					·			
Toutha have	_£ 4l								
▼For the boss									
12 [Evaluation Nature of the intermediate o		pt. of the inv	rentor(s)]			I & 1			
ivalure of the i	nvention	•					on for Current		
(1) Technical s	superiority	over prior a	<u> </u>			products/technologies 3. Considerable			
			ction, energy sa	avina etc	`	3. Conside			
(2) Severity of	challenge	means	odon, chergy de	Aving, etc.		4. Highest			
			e of the invent	ion is C.)	-	0. Null			
(4) Project for	products b	ased on the	invention (dev	elopment		4. In the in	itial stage		
sales, etc)	(Enter data	a if the natu	re of the invent						
(5) Importance	of the inv	ention to the	products			4. High			
(6) Overall judgment by the requesting side						4. Most Important			
Rating of evalu	ıation					60 points			
Filing of the patent application is:						Required (reason:)			
Foreign filing of the patent application is:						Required			
Special note						Combining related applications and			
						file foreign	application in this year		
					1				
▲ For the resp		▲ For the I	ooss of the	For Pate	ent De	ept. of the	▼ Workflow information		
person in the	person in the requesting side Gro								
requesting s	ide					•			
			·						
3 ▼For Pater	nt Dept. of	the Group							
General	Responsi		Mr. Sakaguch						
manager:	Commen	t ·	Please check						
	The state of the s								

manager: Comment Please check the draft.

Responsible person: The construction of CL1 is disclosed in Publication 2000232078 (Toshiba), but the repetitive movement of CL2 of the impregnation element and plating surface of the substrate to touch and separate to each other is not disclosed.

Filing of this application is OK.

Attachment	
Sign of completion	Sakaguchi: Completed

▲ For the responsible person in the	▲ For the boss of the requesting side	▲ For Patent Dept. of the Group	Workflow information
requesting side			

▼Workflow information

Current user: seimitsu zzchizai/e/ebara jp

Current approver:

Request ID NTNN-5NW6L3

Status: completed

14 .

Requested by:	Approved by:
Keiichi kurashina/e/ebara_jp	hiroyuki kanda/e/ebara jp
	tsutomu nakada/e/ebara jp
	koji mishima/e/ebara jp
	keniichi sasabe/e/ebara ip
	masamichi nakashiba/e/ebara ip

▼Approver information

15

Requested by:	Requested on:	CC mail
Keiichi kurashina/e/ebara_jp	2003/06/27	akira fukunaga/e/ebara ip
10		

16 .				•	
Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	hiroyuki kanda/e/ebara jp	2003/07/04	Approved	2003/06/30	
Liaison	tsutomu nahada/e/ebara_jp	2003/07/07	Approved	2003/06/30	
General manager	koji mishima/e/ebara_jp	2003/07/07	Approved	2003/06/30	hiroyuki kanda/e/ebara_jp katsuhiko
	u .				tokushige/e/ebara_jp hidenao suzuki/e/ebara_jp hidekazu nagano/e/ebara_jp
Patent Dept. of the Group	kenichi sasabe/e/ebara jp	2003/07/07	Approved	2003/07/02	
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2003/07/09	Approved	2003/07/03	

▼Comment

CN=hiroyuki kanda/0U=e/0=ebara_jp Approved 2003/06/30 14:10:56 nothing special.

CN=tsutomu nahada /0U=e/0=ebara_jp Approved 2003/06/30 14:53:34 I approved

CN=koji mishima /0U=e/0=ebara_jp Approved 2003/06/30 15:15:30 if dry seal limitation in the first claim can be dismissed, please dismiss it. AMAT is seal-less.

CN=kenichi sasabe /0U=e/0=ebara_jp Approved 2003/07/02 23:50:33 I approved

CN=masamichi nakashiba /0U=e/0=ebara_jp Approved 2003/07/03 10:51:41

発明部門メニューへ 事業本部特許部メニュー

社外秘

一時保存したものに追記する場合、または、承認/否認する場合、上部の「編集」リンクをクリックしてください。 **発明等届出書**

届出日:2003/07/15

知的財産部受付番号:K1030448 受付日:2003/07/18

依頼元担当一記入		●主要大型件社和	
11亿明元和当一記人	I V 1/4 98 37 F 45 57 A		ルマワー・10つ コー・1巻
放樹ルたコール人			N Y / T / / H T 18 1
	The state of the s		

★は必須入力項目です。

▼依頼元担当一記入欄

☑【依頼元情報】



会社★	01 荏原製作所	部門 V350ニブロ	口開発一
整理番号(Doc.No.)	716-L37152		
担当者	会社区分+社員番号:0121155	氏名:倉科 敬一	TEL:8556
本部名★	PP 精密·電子		

②【基本情報】

国内/外国★	国内					
四法★	特許					
発明の名称★	基板の	めっき装置		,		
キーワード	めっき、	めっき、平坦性、均一性、埋設性				
関連する製品名	DMP.	DMP、含浸めっき、バンプめっき				
関連する業務コード	その1	7B配線めっき装置	その2	7Cバンプめっき装置		
研番	L-03D5	1306				
研番依頼元	部署名	部署名 V350二プロ開発ー				
職務発明について★	1.職務务	き明である				



【荏原製作所/荏原総合研究所/荏原電産の発明者】

	会社	社員番号/氏 名 (会社区分+社 員番号)	内線NO/ポストNO/E-mail			米国在 住	代表発明 者 ★
1	EK0001/ 荏原製作 所	0121155 倉科 敬一	内線NO : 9293 ポストNO : 716 E-mail : kurashina.keiichi@ebara.com	V350ニプロ 開発ー	30		Check
	EK0001/ 荏原製作 所	0120894 長井 瑞樹	内線NO : 9293 ポストNO : 716 E-mail : nagai.mizuki@ebara.com	V350ニプロ 開発ー	20	•.	
	EK0001/ 荏原製作 所	0121630 山本 暁	内線NO∶9293 ポストNO∶716 E−mail∶yamamoto.satoru@ebara.com	V350ニプロ 開発ー	20		
4	EK0001/ 荏原製作 所	0121559 神田 裕之	内線NO : 7247 ポストNO : 716−2 E−mail : kanda.hiroyuki@ebara.com	V350ニプロ 開発ー	20		

		•							
		113010	内線NO:942	7			ニプロ 10	-	
		三島 浩二	ポストNO:710 E-mail:mishir		ra.com	開発-	T.		
	該当無しおよび予	定発明者				<u> </u>			<u>-</u> -
	EX 1/1/C032CO 7	たんり 日	_=						
				•					•
(\mathcal{G})	【荏原総合研究所・								
	会社コードノニ	各杯	氏名	TEL/E	-mail	所屬	属部門また!	は住所 米	国在住
		•		TEL: E-mail:		ŀ			
	該当無しおよび予	定発明者							
		2,0,7,1					· · · · · · · · · · · · · · · · · · ·		
								•	
(3)	【出願人】								
	コードノ名称(略称)	住所連絡先なと				権利持	費用負	手続担
-			•	•			分(%)	担(%)	当
	1 EK0001		本社住所:				II] <u> </u>]E	*
	在原製作所	#	連絡先住所: 〒			•	 -		担当
			部署: 担当: TEL: FAX:						
			E-MAIL:						
	該当無しおよび予算	定出願人						<u> </u>	
					•	· · · · · · · · · · · · · · · · · · ·			
<u> </u>					•	•			
Ø ₁	【出願緩急】 出願緩急	至急	出願希望日	2003/08	/0F			 	
	山解板板心	土心	理由	その他		発表先			
				(0)		発表日	:		
.				1 ::		その他	:次世代配 あり、早急	線めっき装に性味も田	置の基本
•						有り。写	めり、平息 ければ早	いほど良い	のの必安
7	7 ŧπ ψ5 88 Æ ¶					-			
	【契約関係】 契約書有無★	無		種類	1	• .		····	
.				その他	·]				:
.	相手先	1		1	J				
		2.		1					
	•	3		֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓֓	•				
		4		j					
		5		j					•
		その他							
15	契約書		·		*				j
	共同出願契約書作 成★	不要		作成担当				•	•
	灰莱			相手先		_]			1
· <u> </u>		<u> </u>	·	<u> </u>	その他				

(8)	「 章国	査実	施士	₽ :'₽
(0)	LAM	且太	#E12	ヘルレ

調査状況★	未調査	
調査内容	検索式:	
	資料:	
競合メーカー	ノベラス、アプライドマテリアル、ニューツール	

② 【関連出願公知例】

当	社の関連出願公知例★	有					
1	特願2003-15236号 または文献名:	ファイル					
2	号 または文献名:	ファイル					
3	号 または文献名:	ファイル					
4	号 または文献名:	ファイル					
5	号 または文献名:	ファイル					

他	せの関連出願公知例★	無	
1	号 または文献名:	ファイル	
2	号 または文献名:	ファイル	•
3	号 または文献名:	ファイル	
4	号 または文献名:	ファイル	
н —	号 または文献名:	ファイル	

и		
ы	A 1	•
14	-	
н		1 .

②【特記事項】

特記事項

() 【発明等説明書(明細書素案)】

明細書	図面	その他	
<u>- 分割含浸材3714.doc</u> サイズ: 64512パイト			
添付者:keiichi kurashina/e/ebara_jp 添付日:2003/07/15	添付者: 添付日:	 添付者: 添付日:	

▲依頼元担当一記入	依頼元上長一記入	▼事業本部特許部一記入	▼ワークフロー情

▼依頼元上長一記入欄

② 【発明部門評価】

発明の性質	A. 現左制見 开货办公司
元劳砂住員	A: 現在製品・技術の発明

①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)	3. 相当優位	
②課題・手段の重要性	3. 重要	
③独創性 (発明の性質がCのときのみ必須)	0. 未評価	
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)	4. 開発計画の初期段階である	
⑤本発明が製品に占める重要度(割合)	3. やや大きい	
⑥依頼元総合評価	4. 最重要	
評価点	52点	
出願要否 要(理由:)	要(理由:)	
外国出願要否要		
特記事項関連特許をまとめ、	年内海外出願が必須	

▲依頼元担当一記入 ▲依頼元上長一記入 事業本部特許部一記入

▼事業本部特許部一記入欄

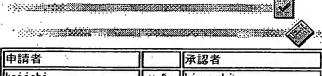
部長記入欄	担当	坂口さん
	コメント	お願いします。非分割パッドの1件と纏めても良いと思います。
担当者記入欄	コメント	本発明に関連出願である親水性パッドの発明を含めることは可能と考えま す。
	添付文書	
	作業終了サイン	坂口:終了

▲依頼元担当一記入
▲依頼元上長一記入 ▲事業本部特許部一記入

現在のユーザ: kenichi sasabe/e/ebara_jp 現在の承認者:

要求 ID NTNN-5PG6JH

ステータス: 完了



申請者
eiichi urashina/e/ebara_jp

L	•	masamichi nakashiba/e/ebara_jp
_		

承認者情報

(5)

申請者名	申請日	C C メール
keiichi kurashina/e/ebara_jp	2003/07/15	akira fukunaga/e/ebara_jp

(16

承認者役職	承認者名	承認期限	ステー タス	承認日	CCメール
発明者上司	hiroyuki kanda/e/ebara_jp	2003/07/22	承認	2003/07/15	
リエゾン	tsutomu nakada/e/ebara_jp	2003/07/22	承認	2003/07/15	
部長	koji mishima/e/ebara_jp	2003/07/22	承認		hidenao suzuki/e/ebara_jp kunihito ide/e/ebara_jp kazufumi nomura/e/ebara_jp
事業部側特 許部門長	kenichi sasabe/e/ebara_jp	2003/07/22	承認	2003/07/18	·
知的財産部 部長	masamichi nakashiba/e/ebara_jp	2003/07/25	代理承認	2003/07/18	

▽コメント

CN=hiroyuki kanda/0U=e/0=ebara_jp 2003/07/15 13:59:21 2003/07/15 14:57:15 承認 特になし CN=tsutomu nakada/OU=e/O=ebara_jp 承認 承認いたしました。 CN=koji mishima/OU=e/O=ebara_jp 2003/07/15 15:32:11 第一クレームがface-downも含むように 承認 留意。アノードの記載内容が含浸face-upを限定している。 CN=kenichi sasabe/OU=e/O=ebara_jp 承認 2003/07/18 15:19:30 承認します。 32 中柴Bの委任により宮崎代 CN=masaaki miyazaki/OU=e/0=ebara_jp 代理承認 2003/07/18 17:12:32 理受入2003.7.18

◆アクション

To the menu for the dept. of the inventor(s) To the menu for Patent Dept. of the Group

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/07/15

Intellectual Property Dept's receipt No.: K1030448 Date of receipt: 2003/07/18

For the responsible	▼ For the boss of the	▼ For Patent Dept. of	▼ Workflow information
person in the requesting	requesting side	the Group	
side			·

Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

A	104	D	MOSO Devisioner and Demonstrated A. Dunas and
Company name	01	Dept.	V350 Development Department 1, Process
	Ebara Corporation		Development Office 2
Reference No. (Doc.No.)	716-L37152		
Responsible person	Company category + Employee No.: 0121155		
	Name: Keiichi Kuras	hina T	EL: 8556
Group name★	PP Precision Machine	ery	

2 [Basic information]

Domestic/foreign ★	Domestic
IP category ★	Patent
Title of the invention	Plating apparatus of substrate
Keyword	Plating, planarity, uniformity, filling ability
Names of related products	DMP, Impregnation plating apparatus, Bump plating apparatus
Related job code	No. 1 7B Wire plating apparatus No. 2 Bump plating apparatus
Job No.	L-03D51306
Requesting dept.	Dept. name V350 Development Department 1, Process Development Office 2
About service invention ★	1. Yes

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor
1	EK0001/	0121155	Extension No.: 9293	V350	30	 	Check
1	Ebara	Keiichi Kurashina	Post No.: 716	Developme	•	٠	O.L.O.K
Ι.	Corporation		E-mail:	nt		1	
1	, ,		kurashina.keiichi@eba	Department			
1			ra.com	1, Process		. •	
1		·		Developme].	•
1	• •			nt Office 2		Ì	
2	EK0001/	0120894	Extension No.: 9293	V350	20		
	Ebara	Mizuki Nagai	Post No.: 716	Developme			
	Corporation		E-mail:	nt			
١.			nagai.mizuki@ebara.c	Department	l ' '	l	**
			om	1, Process			
	·		1	Developme	ļ		
I .	7	,		nt Office 2			
3	EK0001/	0121630	Extension No.: 9293	V350	20]	
	Ebara	Satoru Yamamoto	Post No.: 716	Developme		1	
	Corporation		E-mail:	nt			
	•	i	yamamoto.satoru@eb	Department			
			ara.com	1, Process			
				Developme			
	-	•		nt Office 2			
4	EK0001/	0121559	Extension No.: 7247	V350	20		
	Ebara	Hiroyuki Kanda	Post No.: 716-2	Developme			•
	Corporation		E-mail:	nt			·
	·		kanda.hiroyuki@ebara	Department	•		·
	•		.com	1, Process	l.,		
		9		Developme			
			Ī	nt Office 2		l ·	

5	EK0001/ Ebara Corporat	ion	Koji	3010 Mishim	ia ,	Extensi Post No E-mail: mishima om	o.: 716		nt Dep 1, P Dev	output output	10			
	,			(-)	<u>-</u>									
4	[For inve	ntors	in af	filiates	other than	Ebara	Rese	arch/Eba	ra D	ensan L	td and	l externa	al inver	ntors]
	Compar	ny cod	de/na	ame	Name			/E-mail				t addres		ring in
1					• .	-	TEI							-
N/A	and po	tentia	d inve	entor(s	s)			iaii.						· · · · · ·
						<u> </u>								
	Applicar											·		
•	de/name breviatio		- 1	Conta	ct address,	etc.		Share of	f the	rights	1	e of the	1.	ecution
	0001	711)		Hoado	uarter addr	.000.		(%) E			costs	(%)	by: 7	
	ara Corp	oratio			ct address:			E , ,			_		perso	onsible on
	·		- 1	Dept.:	Respons	-								
				TEL:	FAX:									
NI/A	\ 	N		E-mail			-						· ·	
IN/P	and po	enua	ı inve	entorts)		!					•		
6 [Urgency	of ap	plica	tion fil	inal							•		
	ency	T			eferred data	of filin	g	2003/08/	05					1
				Re	ason			Outside		Relea	sed to	: .,		
			•					presenta	tion		sed o			
														tent for a
												tion wire t is nece		
			•			*	l					arding th		
				·						Soone	er the l	better.		
. ·	D - 1 - 41 -												*	
	Related of the contract of the					NI/A								
AAIIC	iten cont	ract	₹.			N/A	•			Type Othe				
Par	tner		 ,			1		1 (Other	·		•	
						2		<u> </u>	·.	1 .	· .			
						3]				
						4								
						5		-		J				1
Con	ntract					Other		-		•				
		of co	ntrac	t docu	ments for	Not re	quire	<u> </u>		Prop	arod by			
	applicat					140016	quire	·		Partn	ared by	/ ·		_
,			······9							1 000		Ot	her	-
	•													
	Prior-art									•				
	r-art sea		<u> </u>		Not done									
Sea	rch deta	ils					-	Search fo	ormu	ıla:				
Cor	petitor				Novellus	Applia -	100-	Material:	4n -1			•		
JUII	iheriroi	<u> </u>			Novellus,	Applied	iviat	enais, 'Nu	1001	<u> </u>				
	Related a	φplic	ation	and p	rior art]				•					
Ours	s: ★								N,	/A				·
1	1			No. 2	2003-15236	:			Fi	le				

File

No. or document title:

	T							
3	No. or documen	t title				F	file	
4	No. or documen					F	ile	_
5	No.	t title				F	ile	-
	or documen	t title	•					
Others': 🖈								
Orners: X	No.						I/A	<u> </u>
	or documen	t title:	: ·		•	-	ile	
2	No.					F	ile	·
	or documen	t title:	<i>'</i>				·	<u> </u>
3	No. or document	t titla:				F	ile	
4	No.	t title.	·		<u> </u>	F	ile	-
	or document	t title:				1''	iie	
5	No.					F	ile	
	or document	title:				<u>. </u>		
10 [Specia	l notel			•		·		
Special not		-						
11 [Description of the control of	otion of inven	tion (specification dra	ft)]				<u>.</u>
	impregnation	n	Drawings	•		Othe	ers	
element 37		•						;
Size: 64512								
Attached by	/: Keiichi		Attached by:				ched by:	
kurashina/e	/ebara_jp n: 2003/07/15		Attached on:			Atta	ched on:	
Allacried of	1. 2003/07/15)						<u> </u>
▲ For the re	esponsible	T	For the boss of t	he	▼ For P	atent	Dept. of	▼ Workflow information
person in	the	1	requesting side		the G		Бор.: О	v voimou incimation
requestin	g side	<u></u>			<u> </u>			
For the hor	ss of the requ	Lootin	ugʻaida					
			the inventor(s)]					
Nature of th	e invention		<u> </u>				A. Invention	on for Current
				.**			1	echnologies
	al superiority			.10			3. Conside	erable
(2) Severity	of challenge	t, cos	st reduction, ene	ergy s	aving, etc	.)	0.15-6	•
			e nature of the i	nveni	ion is C)		3. High 0. Null	
(4) Project f	or products b	ased	on the inventio	n (de	velopmen	<u></u>	4. In the in	itial stage
sales, et	c) (Enter dat	a if th	ne nature of the	inven				stage
(5) Importar	nce of the inv	<u>entio</u>	n to the product	s			3. A little h	
		he re	questing side				4. Most Im	portant
Rating of eva			•				52 points	
	patent applic of the paten				<u>. </u>		Required (reason:)
Special note		it app	ilication is.	•			Required	rolated applications and
	<u>. </u>			•.			file foreign	related applications and application in this year
				<u>·</u>				-Thursday III and Acti
▲ For the re			or the boss of th	e			ept. of the	▼ Workflow information
person in		re	equesting side			Grou	р	
requesting	y side	L			L			

13 ▼For Patent Dept. of the Group

General Responsible Mr. Sakaguchi
manager: Please check the draft. It may be possible to combine with a non segmented pad.

Responsible person:	Comment	It seems to be possible to combine with the hydrophilic pad application, which is related to this application.
person.	Attachment	application, which is related to this application.
	Sign of completion	Sakaguchi: Completed

▲ For the responsible	▲ For the boss of the	▲ For Patent Dept. of	Workflow information
person in the	requesting side	the Group	
requesting side			

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver:

Request ID NTNN-5PG6JH

Status: completed

14

Requested by:	Approved by:
Keiichi kurashina/e/ebara_jp	hiroyuki kanda/e/ebara jp
	tsutomu nakada/e/ebara jp
	koji mishima/e/ebara jp
·	keniichi sasabe/e/ebara ip
	masamichi nakashiba/e/ebara jp

▼Approver information

15

Requested by:	Requested on:	CC mail	
Keiichi kurashina/e/ebara_jp	2003/07/15	akira fukunaga/e/ebara jp	
16	•		

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	hiroyuki kanda/e/ebara jp	2003/07/22	Approved	2003/07/15	
Liaison	tsutomu nahada/e/ebara_jp	2003/07/22	Approved	2003/07/15	
General manager	koji mishima/e/ebara_jp	2003/07/22	Approved	2003/07/15	hidenao suzuki/e/ebara_jp kunihito ide/e/ebara_jp kazufumi nomura/e/ebara_jp
Patent Dept. of the Group	kenichi sasabe/e/ebara jp	2003/07/22	Approved	2003/07/18	
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2003/07/25	Approved by a proxy	2003/07/18	

▼Comment

CN=hiroyuki kanda/0U=e/0=ebara_jp Approved 2003/07/15 13:59:21 nothing special. CN=tsutomu nahada /0U=e/0=ebara_jp Approved 2003/07/15 14:57:15 I approve CN=koji mishima /0U=e/0=ebara_jp Approved 2003/07/15 15:32:11 pay attention so that the first claim include the face-down. The description of the anode limits to the face-up impregnation. CN=kenichi sasabe /0U=e/0=ebara_jp Approved 2003/07/18 15:19:30 I approve CN=masamichi nakashiba /0U=e/0=ebara_jp Approved 2003/07/18 17:12:32 Miyazaki, or his proxy, approves the request. 2003.7.18

発明部門メニューへ 事業本部特許部メニュー

社外秘

ー時保存したものに追記する場合、または、承認/否認する場合、上部の「編集」リンクをクリックしてください。 **発明等届出書**

届出日:2003/07/03

知的財産部受付番号:K1030456 受付日:2003/07/24

依頼元担当一記入 ▼依頼元上長一記入 ▼事業本部特許部一記入 ▼ワークフロー情

★は必須入力項目です。

▼依頼元担当一記入欄



❷【依頼元情報】

会社★	01 荏原製作所	部門	350二プロ開発ー	
整理番号(Doc.No.)	716-E37031			
担当者	会社区分十社員番号:0120894	氏名:長	井 瑞樹 TEL:9293	
本部名★	PP 精密·電子			

②【基本情報】

CORP. IN TAX	·					
国内/外国★	国内					
四法★	特許					
発明の名称★	めっき方法及びめっき装置					
キーワード	半導体基板、めっき、銅、多孔質材料、電解めっき					
関連する製品名	DMP、含浸めっき					
関連する業務コード	その1 7B配線めっき装置 その2					
研番	L-03D51306					
研番依頼元	部署名					
職務発明について★	1.職務発明である					



③【荏原製作所/荏原総合研究所/荏原電産の発明者】

	会社	社員番号/氏 名 (会社区分+社 員番号)	内線NO/ポストNO/E-mail		持分 (%)	米国在住	代表発明 者 ★
41	EK0001/ 荏原製作 所	長井 瑞樹	内線NO : 9293 ポストNO : 716 E-mail : nagai.mizuki@ebara.com	V350二プロ 開発一	70		Check
2	EK0001/ 荏原製作 所	神田 裕之	内線NO : 7247 ポストNO : 716-2 E-mail : kanda.hiroyuki@ebara.com	V350ニプロ 開発ー	10		
3	EK0001/ 荏原製作 所	倉科 敬一	内線NO : 8556 ポストNO : 716 E-mail : kurashina.keiichi@ebara.com	V350ニプロ 開発ー	10	.•	
4	EK0001/ 荏原製作 所	1	内線NO : 9293 ポストNO : 716 E-mail : yamamoto.satoru@ebara.com	V350ニプロ 開発ー	10		•

	該当無し	および予	定発明者						
4)	【荏原総合	含研究所∙∶	荏原電産 以	外の関連会社。	/社外の発明	月者】			
~		コードノネ		氏名	TEL/E-		所属部	門または住	米国在住
		0049荏原	1	君塚 亮一	TEL:81-		中央研	究所	
	-3	ンライト			E-mail: e	u- uka@nifty.ne.jp			
	該当無し	および予り	全租 经][· y o km · i z	ditae iii cy.nogp			
		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	C)C-97 E			· · · · · · · · · · · · · · · · · · ·			
		. •		·					·
③	【出願人】	·				•			
		・ /名称(略称)	住所連絡先など	<u> </u>		権分	利持 費用(%) 担(%)	
						····	77	(%))
	1 EKO 荏原	1001 京製作所		本社住所: 連絡先住所:〒			E	E	担当
				部署: 担当: TEL: FAX:				•	
				E-MAIL:					
	該当無し	および予算	2出願人		•				
						······································			
ு (ச	 【出願緩急	1	•						
_ [出願緩急		至急	出願希望日	2003/07	/25		W (**	
				理由	その他	,	発表先:	-25	
							発表日:	開発テーマの	基本特許の一
Ì	8	••.	1					かも同様技	術の開発を行
			<u> </u>				الدي درا	能压入。	
Ø,	契約関係]	16		76= 4=				
	契約書有	無★ .	無		種類			•	
·	相手先		1	jf ·	その他		٠		
			2		- ·	•		•	
			3		† .	•			
	i		4 .		1 .			•	
			5 ·		j				
	****		その他		٠.				
16	契約書	初处去儿	7 æ]	The section of	1			
- 1	共同出願: 成★	契約書作	个安		作成担当 相手先	<u></u>	· .		•
- 11			1	•					
		·			16-7-76	その他	1		
					11 7 7.0	その他	<u> </u>		
	▲▼	状況1				その他	<u> </u>		

調査状況★	調査済	
調査内容	機械検索	検索式:めっき×(研磨+化学機械研磨+化学的機械研磨+電解研磨) ×銅×平坦化
		資料:
競合メーカー	ノベラス、セミ	ソール、AMAT、Nutool、ACMリサーチ

② 【関連出願公知例】

当	社の関連出願公知例★	有
1	特願2003-15236号 または文献名:	ファイル
2	号 または文献名:	ファイル
3	号 または文献名:	ファイル
4	号 または文献名:	ファイル
5	号 または文献名:	ファイル

他	せの関連出願公知例★	有			
1	特願平11-33234号 または文献名:	ファイル			
2	号 または文献名:	ファイル			
3	号 または文献名:	ファイル			
4	号 または文献名:	ファイル			
5	号 または文献名:	ファイル			

г	į	
ı		3
И		
Ш		1

(特記事項) 特記事項

②【発明等説明書(明細書素案)】

明細書	図面	その他
一特許説明書(平坦化PO).doc		
サイズ:48640バイト		
添付者:mizuki nagai/e/ebara_jp 添付日:2003/07/03	添付者: 添付日:	添付者: 添付日:

	▼事業本部特許部一記入	

②▼依頼元上長一記入欄

【発明部門評価】

発明の性質		A: 現在製品・技術の発明
①先行技術に対する抗 (品質向上、コスト)	支術的優位性 削減、省エネ効果等)	2. 若干優位
②課題・手段の重要性	生	3. 重要
③独創性 (発明の性質がCのとき	きのみ必須)	0. 未評価
④本発明が対象とする(開発、販売など)(発明の性質がA又はB		4. 開発計画の初期段階である
⑤本発明が製品に占め	める重要度(割合)	3. やや大きい
⑥依頼元総合評価		3. 重要
評価点		36点
出願要否	要(理由:)	
外国出願要否	要	
特記事項		



▲依頼元担当一記入 ▲依頼元上長一記入 事業本部特許部一記入 ▼ワークフロー情

②▼事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	チェックして下さい。
担当者記入欄	コメント	出願要と判断いたします。なお、めっき液については、当社出願である公知例 (特開2000-345392)があります。
·	添付文書	
	作業終了サイン	坂口:終了

<u>▲依頼元担当一記入</u>	▲依頼元上長一記入	▲事業本部特許部一記入	ワークフロー情
			4 L



▼ワークフロー情報

現在のユーザ: kenichi sasabe/e/ebara_jp

現在の承認者:

要求 ID NTNN-5P49LK

ステータス: 完了



a

申請者	承認者
mizuki nagai/e/ebara_jp	hiroyuki kanda/e/ebara_jp tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp

sasabe/e/ebara_jp masamichi nakashiba/e/ebara_jp
--

承認者情報

Ø

申請者名	申請日	CCメール	
mizuki nagai/e/ebara_jp	2003/07/03	akira fukunaga/e <u>/</u> ebara_jp	

(

_			•			·
	承認者役職	承認者名	承認期限	ステー タス	承認日	CCメール
	発明者上司	hiroyuki kanda/e/ebara_jp	2003/07/10	承認	2003/07/03	
	リエゾン	tsutomu nakada/e/ebara_jp	2003/07/10	承認	2003/07/07	
	部長	koji mishima/e/ebara_jp	2003/07/14	承認		hidenao suzuki/e/ebara_jp kunihito ide/e/ebara_jp kazufumi nomura/e/ebara_jp
	事業部側特 許部門長	kenichi sasabe/e/ebara_jp	2003/07/15	承認	2003/07/23	
		masamichi nakashiba/e/ebara_jp	2003/07/30	代理承 認	2003/07/24	

▽コメント

CN=hiroyuki kanda/0U=e/0=ebara_jp 2003/07/03 17:08:33 否認 山本君の社員番号が違っていた CN=hiroyuki kanda/OU=e/0=ebara_jp 承認 2003/07/03 17:20:29

CN=tsutomu nakada/OU=e/0=ebara_jp 承認 2003/07/07 10:32:42 承認します

CN=koji mishima/OU=e/O=ebara_jp 承認 2003/07 で、組み替えが必要であり、知財部殿にご指導願いたい 2003/07/08 15:25:54 クレーム前半は既出願と同様なの

CN=kenichi sasabe/OU=e/O=ebara_jp 2003/07/23 18:13:13 承認 承認します。

CN=masaaki miyazaki/OU=e/O=ebara_jp 代理承認 2003/07/24 14:04:43 中柴B不在のため宮崎代理

受入2003.7.24

アクション

To the menu for the dept. of the inventor(s) To the menu for Patent Dept. of the Group

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/07/03

Intellectual Property Dept's receipt No.: K1030456 Date of receipt: 2003/07/24

For the responsible	▼ For the boss of the	▼ For Patent Dept. of	▼ Workflow information
person in the requesting	requesting side	the Group	
side			-

Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

T Innommaders of allo roda.	sourig ciacj				
Company name *	01	Dept.	V350 Development Department 1, Process		
	Ebara Corporation		Development Office 2		
Reference No. (Doc.No.)	716-L37031				
Responsible person	Company category +	- Employ	/ee No.: 0120894		
	Name: Mizuki Nagai TEL: 9293				
Group name★	PP Precision Machine	ry			

2 [Basic information]

Domestic/foreign ★	Domestic			
IP category ★	Patent			
Title of the invention	Plating method and plating apparatus			
Keyword	Semiconductor substrate, plating, copper, porous material, electrolytic plating			
Names of related products	DMP, Impregnation plating apparatus			
Related job code	No. 1 7B Wire plating apparatus No. 2			
Job No.	L-03D51306			
Requesting dept.	Dept. name			
About service invention ★	1. Yes			

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name (Company category + employee No.)	Extension No./post No./E-mail address	Dept. code/name	Share of the rights (%)	Living in U.S.	Representative inventor
1	EK0001/ Ebara Corporation	0120894 Mizuki Nagai	Extension No.: 9293 Post No.: 716 E-mail: nagai.mizuki@ebara.c om	V350 Developme nt Department 1, Process Developme nt Office 2	30		Check
2	EK0001/ Ebara Corporation	0121559 Hiroyuki Kanda	Extension No.: 7247 Post No.: 716-2 E-mail: kanda.hiroyuki@ebara .com	V350 Developme nt Department 1, Process Developme nt Office 2	20		
3	EK0001/ Ebara Corporation	0121155 Keiichi Kurashina	Extension No.: 9293 Post No.: 716 E-mail: kurashina.keiichi@eba ra.com	V350 Developme nt Department 1, Process Developme nt Office 2	20		
4	EK0001/ Ebara Corporation	0121630 Satoru Yamamoto	Extension No.: 9293 Post No.: 716 E-mail: yamamoto.satoru@eb ara.com	V350 Developme nt Department 1, Process Developme nt Office 2	20		
N/A	and potential in	ventor(s)					•

4	lFor inv	entors in	affiliate	s other than	Ebara	Rese	arch/Ebara	a De	nsan l	Ltd and	i exte	ernal i	nvento	orsì
		any code/		Name			/E-mail		_	contac			Livin	
1		EK0049 Ryoichi Ebara-Udylite Co. Ltd.			nizuka	TEL: 81-3855 E-mail: eu-ryo.kimizuka @nifty.ne.jp			Research & Development Center		iter			
N/	A and p	otential in	ventor	(s)										
5	[Applica	ıntl												
Co	de/nam	e	Conta	act address,	etc.	-	Share of t	he r	rights	Share	e of the	ne F	rosec	ution
	breviat	ion)			•		(%)			costs	(%)		y: ★	
	(0001	poration		quarter addr			Ε .			E			lespor	nsible
LD	aia Coi	porauon	Dept.	act address: ⁼ : Respons								P	erson	
ł			TEL:		ibic.									
<u> </u>			E-ma											
<u>N/</u>	A and p	otential in	ventor((s)	~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~~									<u> </u>
6 [Urgenc	y of applic	cation f	iling]										
	gency	Urger		referred data	a of filin	g	2003/07/2	5						
_			R	eason			Outside			ased to				
		ļ		-		- 1	presentation	on		ased or r: This i		o of b	ooio n	atonto
ŀ		}								is deve				
						i			comp	etitors	are p	ossib		eloping
L							·]	a sim	ilar tec	hnol	ogy.		
7 [Related	contract	1											•
		ntract ★			N/A				Туре)	$\overline{}$			
					ļ				Othe	r				.
Par	rtner			-	1				4					
			·	•	3		· ·		1					İ
					4		1		1					
					5		·]					.
<u>.</u>	-tt				Other		_							
	ntract paratio	n of contra	act doc	uments for	Not re	auire	ed .	· · ·	Pren	ared by	·		•	
		ation filing			''	,quii (, 4 ,		Partr		'-			7
		· · · · · · · · · · · · · · · · · · ·										Other		
8 [I	Prior-ar	t search]	•	•									٠	
		earch ★		Done										
Sea	arch det	ails		Compute	r searcl	h	Search for	mul	a: plat	ing x (p	olish	+ che	emical	
				1				al polish + chemical mechanical-polish +				olish +		
							electrolytic Material:	po	lish) x	copper	x pla	anariz	ation	
Competitor Novellus, Semitool, Ap				· erial:	s. Nut	ool. AC	M re	search	<u> </u>					
										,,,,,				
		application	on and	prior art]	•		 	T		·				·
	's: ★						·	N/		`				
1		Application or document		2003-15236				Fil	е					
2		No.	iiciii iili	<u>. </u>			·	Fil	е е					1
:		or docun	nent titl	e: ·										
3		No.						Fil	е					
4		or docum	nent titl	e:				Fil						
.T .		or docum	nent titl	e:				- 11						
								L						

1 1	10.		<u>, , , , , , , , , , , , , , , , , , , </u>		F	ile		
9	r documen	t title:	· .	·				
Others': ★					IN	I/A		
	Innlication I	H11-33234				ile	T	
	r documen				1	ne		
	No.			· · · · · · · · · · · · · · · · · · ·	F	ile	1	
	or document title:							
1	lo.		_		Fi	ile	7	
	r documen	t title:		<u>.</u>	1_		_	
1 1 1	lo. r document	t title.	•		F	ile		
	o.	i ille.	,	·	+-:	le	-	
	r document	titile:			15	ie		
	•							
10 [Special r	note]							
Special note	<u> </u>							
11 December	· · · · · · · · · · · · · · · · · · ·	· / · · · · · ·						
11 [Description Specification	on of Inven	uon (specific Drawi	cation draft)]		O#-	T		
Patent explan	nation	Diawi	ings		Othe	ers		
document (pla				ł				
PO).doc								
Size: 48640 b								
Attached by:			ned by:			ched by:		
nagai/e/ebara	_jp	Attach	ned on:		Atta	ched on:		
Attached on:	2003/07/03	<u> </u>				····		
▲ For the resp	nonsible	For the	boss of the	W For Po	tont	Dant of		
person in th			e boss of the µesting side			Dept. of	▼ Workflow information	
requesting		loque	oung oldo	une and	Jup		*	
▼For the boss								
12 [Evaluation	n by the de	pt. of the inv	/entor(s)]					
Nature of the i	invention						on for Current	
	· · ·		· · ·				echnologies	
(1) Technical						2. A little		
(2) Severity of	nprovemen Feballanda	t, cost reduc	ction, energy s	aving, etc.)	× .	0.15.3		
(3) Originality			re of the invent	tion is C)		3. High		
(4) Project for	products b	ased on the	invention (de	velopment		0. Null		
sales, etc)	(Enter data	a if the natu	re of the inven	tion is A or	B١	4. In the initial stage		
(5) Importance	e of the inv	ention to the	e products		<u> </u>	3. A little high		
(6) Overall jud	igment by t	he requesti	ng side	· · · · · · · · · · · · · · · · · · ·		3. Importa		
Rating of evalu						36 points		
Filing of the pa	atent applic	ation is:				Required (reason: \	
Foreign filing of	of the pater	t application	n is:			Required	reason.	
Special note						quii cu		
▲ For the resp		▲ For the l	boss of the	For Pate	nt D	ept. of the	▼ Workflow information	
person in the	е	requesti	ng side			•		
requesting s	ide	•				•		
·			-					
3 ▼For Pate			· .				<u> </u>	
General	Respons		Mr. Sakaguc			•		
manager:	Commen		Please check					
Responsible	Commen	t					ng solution, our	
person:			application (a					
	Attachme						· · · · · · · · · · · · · · · · · · ·	
	Sign of completion Sakaguchi: Completed							

ent Dept. of Workflow information

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver;

Request ID NTNN-5P49LK

Status: completed

14

Requested by:	Approved by:
mizuki nagai/e/ebara_jp	hiroyuki kanda/e/ebara jp
	tsutomu nakada/e/ebara jp
	koji mishima/e/ebara jp
	keniichi sasabe/e/ebara jp
	masamichi nakashiba/e/ebara jp

▼Approver information

15

Requested by:	Requested on:	CC mail
mizuki nagai/e/ebara jp	2003/07/15	akira fukunaga/e/ebara jp

10					
Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	hiroyuki kanda/e/ebara jp	2003/07/10	Approved	2003/07/03	
Liaison	tsutomu nahada/e/ebara_jp	2003/07/10	Approved	2003/07/03	
General manager	koji mishima/e/ebara_jp	2003/07/14	Approved	2003/07/08	hidenao suzuki/e/ebara_jp kunihito ide/e/ebara_jp kazufumi nomura/e/ebara_jp
Patent Dept. of the Group	kenichi sasabe/e/ebara_jp	2003/07/15	Approved	2003/07/23	, , , , , , , , , , , , , , , , , , ,
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2003/07/30	Approved by a proxy	2003/07/24	

▼Comment

CN=hiroyuki kanda/0U=e/0=ebara_jp Rejected 2003/07/03 17:08:33 Yamamoo's employee number is wrong.

CN=hiroyuki kanda/0U=e/0=ebara_jp Approved 2003/07/03 17:20:29

CN=tsutomu nahada /0U=e/0=ebara_jp Approved 2003/07/07 10:32:42 | approve

CN=koji mishima /0U=e/0=ebara_jp Approved 2003/07/08 15:25:54 front half of the claim is similar

to the previously filed application. IP department please lead us for the re-arrangement. CN=kenichi sasabe /0U=e/0=ebara_jp Approved 2003/07/23 18:13:13 I approve

CN=masaaki miyazaki /0U=e/0=ebara_jp Approved 2003/07/24 14:04:43 As Mr. Nakashiba is out of the office, Miyazaki, or his proxy, approves the request. 2003.7.24

発明部門メニューへ事業本部特許部メニュー

社外秘

ー時保存したものに追記する場合、または、承認/否認する場合、上部の「編集」リンクをクリックしてください。 **発明等届出書**

届出日:2003/07/16

知的財産部受付番号:K1030466 受付日:2003/07/24

依頼元担当一記入 ▼依頼元上長一記入 ▼事業本部特許部一記入 ▼ワークフロー情

★は必須入力項目です。

▼依頼元担当一記入欄



(7) 【依頼元情報】



会社★	01 荏原製作所	部門	V350ニプロ	開発一	
整理番号(Doc.No.)	716-L37161				
担当者	会社区分+社員番号:0121155	氏名:	倉科 敬一	TEL: 8556	
本部名★	PP 精密·電子				

②【基本情報】

Lem'T' (A TAZ)			
国内/外国★	国内		
四法★	特許		
発明の名称★	基板のめっき装置およびめっき方法		
キーワード	めっき、平坦性、均一性、埋設性		
関連する製品名	DMP、含浸めっき、バンプめっき		
関連する業務コード	その1 7B配線めっき装置 その2 7Cバンプめっき装置		
研番	L-03D51306		
研番依頼元	部署名 V350二プロ開発一		
職務発明について★	1.職務発明である		



③ 【荏原製作所/荏原総合研究所/荏原電産の発明者】

	会社	社員番号/氏名 (会社区分+社員番号)	内線NO/ポストNO/E-mail	所属部門コード/名称	持分 (%)	米国在 住	代表発明 者 ★
1	EK0001/ 荏原製作 所	0121155 倉科 敬一	内線NO : 9293 ポストNO : 716 E-mail : kurashina.keiichi@ebara.com	V350二プロ 開発ー	60		Check
2	EK0001/ 荏原製作 所		内線NO:9293 ポストNO:716 E-mail:nagai.mizuki@ebara.com	V350二プロ 開発ー	10		
	EK0001/ 荏原製作 所	山本 暁	内線NO : 9293 ポストNO : 716 E-mail : yamamoto.satoru@ebara.com	V350ニプロ 開発ー	10		. ,
	EK0001/ 荏原製作 所		内線NO: 7247 ポストNO: 716−2 E−mail: kanda.hiroyuki@ebara.com	V350ニプロ 開発ー	10		

	li- Harran e i la			_		l		
		13010 島 浩二	内線NO:942 ポストNO:71			V350ニプロ 開発ー	10	•
•		70—		ma.koji@ebara.co		,		
	該当無しおよび予算	定発明者					<u> </u>	
				<u>.</u>			· · · · · · · · · · · · · · · · · · ·	
			•					
\mathcal{Q}	【荏原総合研究所・	荏原電産以 外	外の関連会社	/社外の発明者】				
	会社コード/名	5称	氏名	TEL/E-ma	il	所属部門ま	たは住所	全国在住
	1		•	TEL:			•	
				E-mail:				
	該当無しおよび予算	足発明者			•			
		•			•			
3	【出願人】							
	コードノ名称(格称)	住所連絡先な。	<u> </u>		権利	寺 費用負	手続担
		i				分(%)	担(%)	
	L I Evocat						<u> </u>	*
	1 EK0001 荏原製作所		本社住所: 連絡先住所:〒	:		· E	E	担当
		· -	部署: 担当:	•				
			TEL: FAX: E-MAIL:					
			- WAIL:					إسسا
	該当無しおよび予算	E出願人						
				·				
6	【出願緩急】							
9	出願緩急	至急	出願希望E	2003/08/06				
-			理由	その他				
		·	-			発表日:		
	*					その他:次世代	弋配線めっき装 P急に特許を	長置の基本
			.		į	ひ要がある。5	とはいれば早い	国めてあり

(D)	【契約関係】						· ·	
j	契約書有無★	無	•	種類		•		. '
				その他		•		
;	相手先	1				•		
ļ		2 ·		_] .			•	
ļ		3]			•	
		4]				
		5						
.		その他		•			•	
.	契約書							
	共同出願契約書作	不要	 	作成担当		•		·
	成★			相手先				
		·		70	D他	*		

∕	【調		~ **	-1 L	4	r
()	£ = EB	4Y 3	Ξ Խλ	ж	•	
V))	LOW	ELZ		ᆪ	"	

調査状況★	未調査		
調査内容	検索式:		
	資料:		
競合メーカー	ノベラス、アプライドマテリア	アル、ニューツール	

② 【関連出願公知例】

当	社の関連出願公知例★	有
1	特願2003-15236号 または文献名:	ファイル
2	号 または文献名:	ファイル
3	号 または文献名:	ファイル
4	号 または文献名:	ファイル
5	号 または文献名:	ファイル

他社の関連出願公知例★		無					
1	号 または文献名:	ファイル					
2	号 または文献名:	ファイル					
3	号 または文献名:	ファイル		·			
4	号 または文献名 :	ファイル			. <u>.</u>		
5	号 または文献名:	ファイル					

	ļ	I
п		
ш		
H		
ш		

(特記事項) 特記事項

◎ 【発明等説明書(明細書素案)】

明細書	図面	その他
_ エント・オ・イント3714.doc サイズ:73216バイト		
添付者:keiichi kurashina/e/ebara_jp 添付日:2003/07/16	添付者: 添付日:	添付者: 添付日:

依頼元上長一記入 ▲依頼元担当一記入 ▼事業本部特許部-

▼依頼元上長-記入欄

②【発明部門評価】

FACARAL TO LIMIT		•
PORD ON HILES		
発明の性質	A:現在製品・技術の発明	
<u> </u>		

①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)	3. 相当優位
②課題・手段の重要性	3. 重要
③独創性 (発明の性質がCのときのみ必須)	O. 未評価
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)	4. 開発計画の初期段階である
⑤本発明が製品に占める重要度(割合)	4. 大きい
⑥依頼元総合評価	4. 最重要
評価点	56点
出願要否 要(理由:)	
外国出願要否要	
特記事項関連特許をまとめ、	年内海外特許出願は必須

▲依頼元担当一記入 ▲依頼元上長一記入 事業本部特許部一記入 ▼ワークフロー情

②▼事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	お願いします。
担当者記入欄	コメント	出願要と判断いたします。
	添付文書	
	作業終了サイン	坂口:終了

▲依頼元担当一記入 ▲依頼元上長一記入 ▲事業本部特許部一記入 ワークフロー情

▼ワークフロー情報

現在のユーザ: kenichi sasabe/e/ebara_jp

現在の承認者:

要求 ID NTNN-5PH77U

ステータス: 完了



nakashiba/e/ebara_jp

承認者情報

(3)

申請者名	申請日	CCメール:
keiichi kurashina/e/ebara_jp	2003/07/16	akira fukunaga/e/ebara_jp

6

承認者役職	承認者名	承認期限	ステー タス	承認日	CCメール
発明者上司	hiroyuki kanda/e/ebara_jp	2003/07/23	承認	2003/07/16	
リエゾン	tsutomu nakada/e/ebara_jp	2003/07/23	承認	2003/07/17	
部長	koji mishima/e/ebara_jp	2003/07/24	承認		hidenao suzuki/e/ebara_jp kunihito ide/e/ebara_jp kazufumi nomura/e/ebara_jp
事業部側特 許部門長	kenichi sasabe/e/ebara_jp	2003/07/25	承認	2003/07/23	
知的財産部 部長	masamichi nakashiba/e/ebara_jp	2003/07/30	代理承認	2003/07/24	

▽コメント

CN=hiroyuki kanda/0U=e/0=ebara_jp CN=tsutomu nakada/0U=e/0=ebara_jp CN=koji mishima/0U=e/0=ebara_jp しない)のも包含するクレームに修正のこと CN=kenichi sasabe/0U=e/0=ebara_jp CN=masaaki miyazaki/0U=e/0=ebara_jp 承認

2003/07/16 14:24:57 2003/07/17 17:42:05 2003/07/18 08:20:56 承認 承認

特になし 承認しました。 第一クレーム、face-down(アノードは移動

承認 2003/07/23 18:15:31

承認します。 58 中柴B不在のため宮崎代理 代理承認 2003/07/24 14:08:58

受入2003.7.24

To the menu for the dept. of the inventor(s) To the menu for Patent Dept. of the Group

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/07/16

Intellectual Property Dept's receipt No.: K1030466 Date of receipt: 2003/07/24

For the responsible	▼ For the boss of the	▼ For Patent Dept. of	▼ Workflow information
person in the requesting	requesting side	the Group	
side			

Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

Company name *	01 Ebara Corporation	Dept.	V350 Development Department 1, Process Development Office 2				
Reference No. (Doc.No.)	716-L37161						
Responsible person		Company category + Employee No.: 0121155 Name: Keiichi Kurashina TEL: 8556					
Group name★	PP Precision Machine	ry					

2 [Basic information]

Domestic/foreign ★	Domestic					
IP category ★	Patent					
Title of the invention	Plating apparatus and method of substrate					
Keyword	Plating, planarity, uniformity, filling ability					
Names of related products	DMP, Impregnation plating apparatus, Bump plating apparatus					
Related job code	No. 1 7B Wire plating apparatus No. 2 7C Bump plating apparatus					
Job No.	L-03D51306					
Requesting dept.	Dept. name V350 Development Department 1, Process Development Office 2					
About service invention ★	1. Yes					

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

~ _		in Luara Corporation	`				
i	Company	Employee No./name	Extension No./post	Dept.	Share of	Living	Representative
		(Company category +	No./E-mail address	code/name	the rights	in U.S.	inventor 🖈
		employee No.)		Υ.	(%)	ļ	
. 1	EK0001/	0121155	Extension No.: 9293	V350	60 .		Check
	Ebara	Keiichi Kurashina	Post No.: 716	Developme			:
	Corporation ,	•	E-mail:	nt			·
1	 		kurashina.keiichi@eba	Department			٠.
			ra.com	1, Process			-
	Į .	İ		Developme	ļ		·
		<u> </u>		nt Office 2			
.2	EK0001/	0120894	Extension No.: 9293	V350	10	,	•
	Ebara	Mizuki Nagai	Post No.: 716	Developme			
	Corporation	-	E-mail:	nt			
		·	nagai.mizuki@ebara.c	Department			
			om	1, Process			
				Developme		,	
				nt Office 2			
3	EK0001/	0121630	Extension No.: 9293	V350	10		
	Ebara	Satoru Yamamoto	Post No.: 716	Developme			
	Corporation		E-mail:	nt '			
1		••	yamamoto.satoru@eb	Department			
,		•	ara.com	1, Process			
1		·		Developme			·
				nt Office 2			•
4	EK0001/	0121559	Extension No.: 7247	V350	10		
ĺ	Ebara	Hiroyuki Kanda	Post No.: 716-2	Developme			
- 1	Corporation		E-mail:	nt	•		
- 1	•		kanda.hiroyuki@ebara	Department			
			.com	1, Process		. `	
				Developme			
- 1				nt Office 2		×	

5	EK000	1/	0113010	· ·	Extensi	on No	. 9427	V35	50	10			
	Ebara		Koji Misł		Post No				/elopme	'			
	Corpor	ation			E-mail:	. 14=#6) - b	nt					
					om	a.KOji@	ebara.c		artment Process				
								Dev	relopme				
N/	and no	tential in	ventor(s)					nt C	Office 2	<u> </u>			
14//	varia po	teritar iri	veritor(s)					L					
4	[For inv	entors	in affiliat	es other than	n Ebara	Rese	arch/Eba	ra D	ensan L	td and	d externa	l inv	entors]
	Compa	any cod	de/name	Name		TEL	/E-mail		Dept./	contac	ct addres		_iving in
1				<u> </u>		TEL							J.S.
1'1			•			E-m							
N/A	A and p	otentia	l invento	r(s)			<u> </u>				:		
		· · - · ·											
	Applica Applica			· · · · · · · · · · · · · · · · · · ·		·							
1	de/nam breviat		Con	tact address,	, etc.		Share of	t the	rights		e of the		secution
<u> </u>	0001	1011)	Hea	dquarter add	ross.		(%) E		· · · · · ·	E	s (%)		★ sponsible
	ara Coi	poratio		tact address:						_			sponsible
			Dep		sible:								
ĺ			TEL										
N/A	and n	otentia	E-m I invento						:			l	
	t and p	Ote: Ida	HIVEIILO	1(3)									
		y of ap	plication										·
Urg	gency	l		Preferred dat	a of filin		2003/08/	06	1 =				
		ł	. [Reason		1	others		1	ased to			-
							•					asic	patent for a
}		ł				1	•				ation wire		
											it is nece		
											arding th better.	ıs re	lation.
ш.		i							1 00011	er tile	better.		
	Related												
Wri	tten co	ntract	*		N/A	٠			Type				
Par	tner	··········		<u> </u>	1		1	•	Othe	<u>r </u>	بــــــ		100
	u.o.		• .		2	· ·			-				, , , , , , , , , , , , , , , , , , ,
					3]			•	
					4								
			. •		5 Other		<u> </u>		ك				
Cor	ntract		,		Julei	· · · · ·	┧ ・ 、		•				
		n of co	ntract do	cuments for	Not re	equire	ed		Prep	ared b	y:		
join	t applic	ation fi	ling ★	•			,		Partr				
	·							•	1		. 0	ther	0
8 [F	Prior-ar	t searc	h]										
	r-art se			Not done	9	· · · · · · · · · · · · · · · · · · ·	•	· ·					•
	rch det						Search fo	omu	ıla:		•	<u>·</u>	· · · · · · · · · · · · · · · · · · ·
Material:													
Con	npetitor			Novellus	, Applied	Mat	erials, Nu	itool					
ס יונ	Rolatod	annlic	ation on	d prior and					t		•		
	neialed s: ★	applic	auon an	d prior art]		· .	· · · · · · · · · · · · · · · · · · ·	N	/A	•	 -		
1		Applic	ation No	. 2003-1523	6	. -			ile				
		or doc	ument ti				•	''		ļ			
2	· 7	No.						Fi	ile				

or document title:

3	No. or document	t title:			Fi	le		
4 .	No. or document			<u> </u>	Fi	le	1	
5	No.				Fi	le		
	or document	title:				. –		
Others': *	-				N,			
1	No.							
•	or document title:					le		
2	No.	uue.			Fi	lo	-	
-	or document	title:	•		' '	16		
3	No.				Fi	le	-	
	or document	title:			' '	.0		
4	No.				Fi	le	1	
	or document	title:						
5	No.				Fi	le	7	
	or document	title:		•				
10 (0	14-7			•				
10 [Special not			·			-	•	
Special noi	te		<u> </u>	· · · · · · · · · · · · · · · · · · ·				
11 Descri	ntion of invent	ion (specification draft)]					
Specification			Drawings		Othe	ers		
Endpoint 3				· · · · · · · · · · · · · · · · · · ·	-			
Size: 7321		l						
Attached by			Attached by:		Attac	ched by:		
kurashina/e	e/ebara_jp				ched on:			
Attached or	n: 2003/07/16	5			<u> </u>			
A Caraba							1-14 10	
▲ For the reperson in		'	For the boss of the requesting side	▼For Patent Dept. of		Dept. of	▼Workflow information	
requestir			requesting side	the Group				
·	ig olde	1	,	I				
▼For the bo	ss of the requ	estin	a side		•			
			the inventor(s)]			•		
Nature of th						A. Invention	on for Current	
			<u> </u>	· ·			echnologies	
(1) Technic	al superiority	over	prior art			3. Conside	erable	
(Quality	/ improvement	t, cos	st reduction, energy sa	aving, etc	.)			
	of challenge			i		3. High		
(3) Originality (Enter data if the nature of the invention is C.)(4) Project for products based on the invention (development,						0. Null 4. In the initial stage		
						4. In the in	itiai stage	
sales, etc) (Enter data if the nature of the invention is A or B.) (5) Importance of the invention to the products 4. High								
(6) Overall judgment by the requesting side						4. Most Im	nortant	
Rating of evaluation						56 points	·	
		ation						
Filing of the patent application is: Foreign filing of the patent application is:						Required (reason:) Required		
Special note					Combining related applications and			
-F							application in this year	
	esponsible	▲ F	or the boss of the	For Pat	ent D	ept. of the	▼ Workflow information	
person in		re	equesting side		Grou			
requestin	g side		•					

13 ▼For Patent Dept. of the Group

General	Responsible	Mr. Sakaguchi
manager:	Comment	Please check the draft.
Responsible	Comment	Filing of this invention is necessary.
person:	Attachment	
	Sign of completion	Sakaguchi: Completed

▲ For the responsible	▲ For the boss of the	▲ For Patent Dept. of	Workflow information
person in the	requesting side	the Group	
requesting side		•	

▼Workflow information

Current user: kenichi sasabe/e/ebara jp

Current approver:

Request ID NTNN-5PH77U

Status: completed

14

Requested by:	Approved by:
keiichi kurashina/e/ebara_jp	hiroyuki kanda/e/ebara_jp tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp keniichi sasabe/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼Approver information

15

Requested by:	Requested on:	CC mail
keiichi kurashina/e/ebara jp	2003/07/16	akira fukunaga/e/ebara jp
16		

16	•	•			
Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	hiroyuki kanda/e/ebara jp	2003/07/23	Approved	2003/07/16	
Liaison	tsutomu nahada/e/ebara_jp	2003/07/23	Approved	2003/07/17	
General manager	koji mishima/e/ebara_jp	2003/07/24	Approved	2003/07/18	hidenao suzuki/e/ebara_jp kunihito ide/e/ebara_jp kazufumi nomura/e/ebara jp
Patent Dept. of the Group	kenichi sasabe/e/ebara_jp	2003/07/25	Approved	2003/07/23	
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2003/07/30	Approved by a proxy	2003/07/24	

▼Comment

CN=hiroyuki kanda/0U=e/0=ebara_jp Approved 2003/07/16 14:24:57 nothing special.

CN=tsutomu nakada /0U=e/0=ebara_jp Approved 2003/07/17 17:42:05 | approve.

CN=koji mishima /0U=e/0=ebara_jp Approved 2003/07/18 08:20:56 Modify the first claim to include face-down (anode does not move).

CN=kenichi sasabe /0U=e/0=ebara_jp Approved 2003/07/23 18:15:31 I approve.

CN=masaaki miyazaki/0U=e/0=ebara_jp Approved by a proxy 2003/07/24 14:08:58 Mr. Nakashiba is out of office; so Miyazaki, or his proxy, approves the request. 2003.7.24

発明部門メニューへ事業本部特許部メニュー

社外秘

一時保存したものに追記する場合、または、承認/否認する場合、上部の「編集」リンクをクリックしてください。 **発明等届出書**

届出日:2003/12/26

知的財産部受付番号:K1040012 受付日:2004/01/13

依頼元担当一記入 ▼依頼元上長一記入 ▼事業本部特許部一記入 ▼ワークフロー情

★は必須入力項目です。

▼依頼元担当一記入欄



②【依頼元情報】



会社★	01 荏原製作所	部門	V350ニプロ	開発一	\neg
整理番号(Doc.No.)					ョ
担当者	会社区分+社員番号:0121559	氏名:	神田 裕之	TEL: 7247	乛
本部名★	PP 精密·電子				ヿ

②【基本情報】

国内/外国★	国内
四法★	特許
発明の名称★	基板のめっき装置およびその方法
キーワード	
関連する製品名	
関連する業務コード	その1 その2
研番	L-
研番依頼元	部署名
職務発明について★	1.職務発明である



③ 【荏原製作所/荏原総合研究所/荏原電産の発明者】

	会社	社員番号/氏名 (会社区分+社員番号)	内線NO/ポストNO/E-mail			米国在 住	代表発明 者 ★
1	EK0001/ 荏原製作 所	0121559 神田 裕之	内線NO : 7247 ポストNO : 716−3 E−mail : kanda hiroyuki@ebara.com	V350ニプロ 開発ー	20		Check
2	EK0001/ 荏原製作 所	0113010 三島 浩二	内線NO : 9427 ポストNO : 716 E-mail : mishima.koji@ebara.com	V350二プロ 開発ー	20	·	
13.	EK0001/ 荏原製作 所	0120308 森澤 伸哉	内線NO : 9088 ポストNO : 717 E-mail : morisawa.shinya@ebara.com	V510ープロ 開発ー	20		
4	EK0001/ 荏原製作 所	0121105 國澤 淳次	内線NO : 9488 ポストNO : 718 E−mail : kunisawa.junji@ebara.com	V370二プロ 設計課	20		

				•	•					
	5		0121368	内線NO:9025				ニプロ 1	10	
		在原製作 所	井出 邦仁	ポストNO:716			開発-	-		
			0107400	E-mail:ide.kun	hito@ebara.	com	<u> </u>			
		EK0001/. 荏原製作	0107426 鈴木 秀直	内線NO:9025 ポストNO:716-	. 2		V3502 開発-	ニプロ 1	0	
		所	10000000000000000000000000000000000000	E-mail:suzuki.l		ara.com	111176			
	該	当無しおよび	予定発明者					<u></u>		
							· · · · · · · · · · · · · · · · · · ·			
<i>(</i>)			- +			 •				
(A)				外の関連会社/			7/	4		
	Ļ	会社コード。	/名称	氏名	TEL/E-	mail		部門また	は住所 米	国在住
	'				TEL: E-mail:				•	·
	<u></u>	」 当無しおよび	· 予定参明者		- 1114111				<u></u>	
	[BX =	当無しわよい	ア			 				
										·
A	7 11 5	—— 頼人】								
<u>ي</u>		類人』 コード/名和	左(四久子左)	住所連絡先など] [# ==1++	THE DA]
		コートノ 名を	小(四合个小)	仕所連絡尤なと	•			権利持分(%)	費用負担(%)	手続担当
										*
	1	EK0001		本社住所:			· · · · · · · · · · · · · · · · · · ·	E	Ε	担当
		在原製作R		連絡先住所:〒 部署: 担当:				1		
			·	TEL: FAX:			•	·		
	Ш			E-MAIL:			· · · · · · · · · · · · · · · · · · ·	JL		
	該当	当無しおよび・	予定出願人					•		
		Y		7	· .					
: יב	ты в	有經会 1	<i>:</i>							
		項緩急】 頁緩急		出願希望日			<u>·</u>			
. :	LLI M	只《妖·心		理由	4		数主件	• •	·	
):				-			発表先 発表日	.•		
	<u>. </u>						発表日 その他	: :	•	
ক। ক	غ刀幺	为関係 】								
_ ,		9書有無★	無	1	種類	•				
	, C. Tr.	/ = 17/11/15	" "		その他	•		•		
	相手		11	<u> </u>	(0) 1/2					
			2							·
		•	3				·			·
			4		÷					
			5				•			·
		•	その他		•					
	契約	1盘								
. 4		出願契約書	作。不声	<u> </u>	/cotton st		•			
	八尺尺)山殿天初 省 (11:17安	15	作成担当				•	
.					相手先	スの仏	=			
Į		=				その他	<u> </u>	·		
- 11										

(3)	[調:	本生	杜	44:	:00
\bullet	【 高樹 *	皆事	MD.	ЯX	`π `

調査状況★	未調査		· · · · · · · · · · · · · · · · · · ·	
調査内容		検索式:		
		資料:		
競合メーカー	·			

②【関連出願公知例】

当	社の関連出願公知例★	有
1	特開2002-129383号 または文献名:	ファイル
2	号 または文献名:	ファイル
	号 または文献名:	ファイル
4	号 または文献名:	ファイル
5	号 または文献名:	ファイル

他	社の関連出願公知例★	無
T	号 または文献名:	ファイル
2	号 または文献名:	ファイル
3	号 または文献名:	ファイル
4	号 または文献名:	ファイル
5	号 または文献名:	ファイル

•		_
ш		_
ш		,
н		
ш	******	

(特記事項) 特記事項

②【発明等説明書(明細書素案)】

明細書	図面	その他
<u>- 分割アノード+含浸材 特許.doc</u> サイズ: 35840バイト	- 分割アノード+含浸材 サイズ:44544バイト	.doc
添付者:hiroyuki kanda/e/ebara_jp 添付日:2003/12/26	添付者:hiroyuki kanda/e/eba 添付日:2003/12/26	ra_jp 添付者: 添付日:

依頼元上長一記入 ▲依頼元担当一記入 ▼事業本部特許部一記入

▼依賴元上長一記入欄

②【発明部門評価】

発明の性質		B:新事業製品・技術の発明
①先行技術に対する技術的優位性 (品質向上、コスト削減、省エネ効果等)		3. 相当優位
②課題・手段の重要性	生	4. 最重要
③独創性 (発明の性質がCのときのみ必須)		O. 未評価
④本発明が対象とする製品の開発計画 (開発、販売など) (発明の性質がA又はBのときのみ必須)		3. 開発計画の中間段階である
⑤本発明が製品に占め	かる重要度(割合)	4. 大きい
⑥依賴元総合評価		4. 最重要
評価点		56点
出願要否	要(理由:)	
外国出願要否	要	
特記事項		·



▲依頼元担当一記入 ▲依頼元上長 事業本部特許部一記入 一記入 ▼ワークフロー情

② ▼事業本部特許部一記入欄

f (L		坂口さん
	コメント	めっき膜の均一化のみを述べていますが、後工程に望ましい膜厚分布とする ことを含めておいてください。方法クレームもこの考えのものを追加しておいて ください。
担当者記入欄	コメント	<発明の効果>で述べているように例えば、後工程に望ましい膜厚分布とすることの具体例等を明細書に記載しておく方がよい。また、方法クレームには上記の具体的手法を追加した方がよいと思います。
	添付文書	
	作業終了サイン	坂口:終了

▲依頼元担当一記入 ▲依頼元上長一記入 ▲事業本部特許部



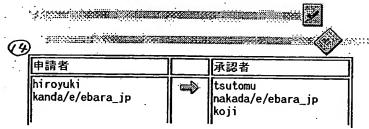
▼ワークフロー情報

現在のユーザ: seimitsu zzchizai/e/ebara jp

現在の承認者:

要求 ID NTNN-5UL5AZ

ステータス: 完了



mishima/e/ebara_jp seimitsu zzchizai/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼承認者情報

Ø.

申請者名	申請日	CCメール .	
hiroyuki kanda/e/ebara_jp	2003/12/26		

(

	·	· · · · · · · · · · · · · · · · · · ·			<u> </u>
承認者役職	承認者名	承認期限	ステー タス	承認日	CCメール
発明者上司	(承認不要)				
リエソン	tsutomu nakada/e/ebara_jp	2004/01/02	承認	2003/12/26	
部長	koji mishima/e/ebara_jp	2004/01/02	承認	2004/01/05	masao hodai/e/ebara_jp kunihito ide/e/ebara_jp hiroyuki kanda/e/ebara_jp satoru yamamoto01/e/ebara_jp seiji katsuoka/e/ebara_jp masaaki kimbara/e/ebara_jp masaji akahori/e/ebara_jp sota nakagawa/e/ebara_jp
事業部側特許部門	seimitsu zzchizai/e/ebara_jp	2004/01/12	承認	2004/01/13	
知的財産部-部長	masamichi nakashiba/e/ebara_jp	2004/01/20	受入	2004/01/13	

▼コメント

CN=tsutomu nakada/0U=e/0=ebara_jp 承認 2003/12/26 12:49:20 承認します CN=koji mishima/0U=e/0=ebara_jp 承認 2004/01/05 10:26:25 めっき限定ではなく電解装置を対象とすること、第一項からシールの限定は削除すること。 CN=seimitsu zzchizai/0U=e/0=ebara_jp 承認 2004/01/13 09:41:47 承認します。 CN=masamichi nakashiba/0U=e/0=ebara_jp 受入 2004/01/13 11:38:55

◆アクション

To the menu for the dept. of the inventor(s)

To the menu for Patent Dept. of the Group

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/12/26

Intellectual Property Dept's receipt No.: K1040012 Date of receipt: 2001/01/13

For the responsible person in the requesting	▼ For the boss of the requesting side	▼ For Patent Dept. of the Group	▼ Workflow information
side		-	

Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [In	formation	of the	requesting	sidel
-------	-----------	--------	------------	-------

Company name 🛨	01 Ebara Corporation	Dept.	V350 Development Department 1, Process Development Office 2			
Reference No. (Doc.No.)						
Responsible person	Company category + Employee No.: 0121559 Name: Hiroyuki Kanda TEL: 7247					
Group name★	PP Precision Machinery					

2 [Basic information]

Domestic/foreign ★	Domestic				
IP category ★	Patent '	, , , , , , , , , , , , , , , , , , , ,			
Title of the invention	Plating apparatus and method of substrate				
Keyword					
Names of related products					
Related job code	No. 1	No. 2			
Job No.	L-				
Requesting dept.	Dept. name	•			
About service invention ★	1. Yes	·			

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

	Company	Employee No./name	Extension No./post	Dept.	Share of	Living	Representative
		(Company category +	No./E-mail address	code/name	the rights	in U.S.	inventor *
		employee No.)		,	(%)	0.0.	
1	EK0001/	0121559	Extension No.: 7247	V350	20		Check
1	Ebara	Hiroyuki Kanda	Post No.: 716-2	Developme	i		
1	Corporation		E-mail:	nt		. ` .	
1			kanda.hiroyuki@ebara	Department		٠,	;
1	ļ		.com	1, Process			
i	·			Developme			•
				nt Office 2			
2	EK0001/	0113010	Extension No.: 9427	V350	20		
1	Ebara	Koji Mishima	Post No.: 716	Developme ·		•	į
	Corporation		E-mail:	nt .			
1			mishima.koji@ebara.c	Department			i
1	-	Y	om	1, Process	ì		
		·		Developme			1
				nt Office 2		1	
3	EK0001/	0120308	Extension No.: 9088	V510	20		
'	Ebara	Shinya Morisawa	Post No.: 717	Developme			
	Corporation		E-mail:	nt .			
		_	morisawa.shinya@eba	Department			
			ra.com .	1, Process			
				Developme			•
				nt Office 1	·		
4	EK0001/	012105	Extension No.: 9488	V370	20		
	Ebara	Junji Kunisawa	Post No.: 718	Design		•	_
1	Corporation		E-mail:	Department	·		.
			kunisawa.junji@ebara.	, Process			
			com	Developme			
Ш		L		nt Office 2			

5	EK0001 Ebara Corpora	ation	0121368 Kunihito I	de	Post No E-mail:	o.: 716	o.: 9025 6 9ebara.co	Developme nt Department Process Developme nt Office 2		10		
6	EK0001	/	0107426		Extensi			V35	0	10	7	
	Ebara	,ion	Hidenao	Suzuki	Post No	o.: 716	5-3		elopme			. (
	Corpora	111011			E-mail:	hiden	ao@ebar	nt Dep	artment			
					a.com			1, P	rocess		-	
									elopme ffice 2		1.	
N/	A and pot	ential in	ventor(s)					TIL O	nice 2	<u> </u>		·
<u> </u>			-					L	 . · · · · · · · · · · · · · · · · · · ·			· · · · · · · · · · · · · · · · · · ·
4	[For inve	entors	in affiliate	es other than	Ebara	Rese	earch/Eba	ra D				
	Compa	iny cod	de/name	Name		TE	/E-mail		Dept./	contact ac	dress	
1				<u> </u>								U.S
	A and po	otentia	l inventor	(s)		L						· · · · · · · · · · · · · · · · · · ·
,,.	<u></u>						· · · · · · · · · · · · · · · · · · ·	 ¹			•	
	[Applica											
	de/nam		Cont	act address,	etc.	٠	Share of	f the	rights	Share of		Prosecution
	breviati	on)					.(%)	•		costs (%)	by: ★
ŧ.	(0001 ara Cor	noratio		dquarter add act address:			Ε .			Е	İ	Responsible
	ara oon	porauc	Dept		-					•	ļ	person
		:	TEL:		oibio.						*	
			E-ma				<u></u>				ĺ	
N/A	and po	otentia	l inventor	(s)								
6	Lraone	v of an	plication	filinal	•							•
	gency	y or ap		referred dat	a of filin	n T						· · · · · · · · · · · · · · · · · · ·
'''	ردببدو			Reason	<u> </u>	9			Relea	sed to:		
		i	.			- 1				sed on:		
L									Other	•		
7 [Dalatad		41				•					
	Related tten con			· <u> </u>	N/A				Туре	·	- 1	· · · · · · · · · · · · · · · · · · ·
***	acii con	in act	^		1.47	. :	•		Othe	r		÷
Par	tner	-			1				1 0 4.0	•		
			•		2] ·			
					3							
			;	•	5	<u> </u>			4	•		
					Other		 		J			
Cor	ntract			,	·		-					
Pre	paration	of co	ntract do	cuments for	Not re	quire	ed		Prep	ared by:		
join	t applica	ation fi	ling 🛨			·	ě	,	Partr			
					<u> </u>						0	ther
B []	Prior-art	coerc	h]				_	•			•	
	or-art se			Not done						•	-;	· · · · · · · · · · · · · · · · · · ·
	arch det			. 101 00110		. 1	Search fo	ome	la:	· · · · · · · · · · · · · · · · · · ·	•	
							Material:		<u></u>			
Cor	npetitor									· .	-	. 1
		٠,							-			
		applic	ation and	prior art]	· 							
Our	s: ★	D. 1	4:	0000 155					<u>'A</u>			,
١.			ation No. Sument tit	. 2002-12938 le	5 3			Fi	le			

	1					•	<u>.</u>	
2	No. or document	title:			F	ile		
3	No.	uue.				ile	- '	
	or document	title:			-lie			
.4						ile	-	
L	or document	title:	1		- 1.			
5	No.				F	ile	1	
	or document	title:						
Others': *						I/A		
1	No.		•		F	ile		
	or document	title:				 ·		
2	No.	4:41		•	F	ile		
3	or document No.	uue.		 _		ile	-	
١	or document	title:	•		וו	ile		
4	No.	uuc.			+	ile	-	
	or document	title:			1.	ii.C		
5	No.				F	ile		
	or document	title:						
10 Specia							*	
Special not	ie							
11 Descri	ntion of inventi	ion (c	specification draft)]					
Specification		1011 (3	Drawings	· -	Oth	ore	X**	
Segmented			Segmented anode +		Out	eis		
impregnation		- 1	impregnation elemen	t.doc	1	•		
patent.doc	•	1	Size: 44544 bites					
Size: 35840								
Attached by	y: hiroyuki	1	Attached by: hiroyuk	i.		Attached by:		
kanda/e/eb	ara_jp n: 2003/12/26	- 1	kanda/e/ebara_jp	2/20	Atta	Attached on:		
Adached of	1. 2003/12/26	L	Attached on: 2003/12	2/26				
▲ For the re	esponsible	F	or the boss of the	▼For P	atent	Dept. of	▼ Workflow information	
person in			requesting side	the G		Dept. Of	• • • • • • • • • • • • • • • • • • •	
requestin	ıg side							
	ss of the requ			•		• • •		
2 Evalua	tion by the dep	ot. of	the inventor(s)]	<u> </u>	·: ·	· :		
Nature of th	e invention					B. Invention for New		
(1) Technical superiority over prior art							echnologies	
				ovina oto	,	3. high		
(Quality improvement, cost reduction, energy saving, etc.) (2) Severity of challenge/means						4. Highest		
(3) Originality (Enter data if the nature of the invention is C.)						0. Null		
(4) Project for products based on the invention (development,					t.		stage of development	
sales, etc) (Enter data if the nature of the invention is A or B.)				r B.)	plan	rage of development		
(5) Importance of the invention to the products					4. Hlgh			
(6) Overall judgment by the requesting side					4. Most im	portant		
Rating of evaluation					56 points			
	patent applica					Required (reason:)	
	g of the patent	t app	lication is:			Required		
Special note	<u> </u>	• •		-				

▲ For the responsible person in the	For the boss of the requesting side	For Patent Dept. of the Group	▼ Workflow information
requesting side			

13 ▼For Patent Dept. of the Group

General	Responsible	Mr. Sakaguchi
manager:	Comment	Specification describes only uniform plating in datail, but please modify to include controlling film thickness distribution suitable for the following process. Add method claims in this way.
Responsible person:	Comment	As described in <effect invention="" of="" the="">, detailed embodiment of film thickness control suitable for the following process should be added to the specification. Specific method should be added to method claims.</effect>
	Attachment	·
	Sign of completion	Sakaguchi: Completed

▲ For the responsible	▲ For the boss of the	▲ For Patent Dept. of	Workflow information
person in the	requesting side	the Group	
requesting side		•	·

▼Workflow information

Current user: seimitsu zzchizai/e/ebara_jp

Current approver:

Request ID NTNN-5UL5AZ

Status: completed

14

Requested by:	Approved by:
mizuki nagai/e/ebara_jp	tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp
	zzchizai/e/ebara_jp masamichi nakashiba/e/ebara_ip

▼Approver information

15

Requested by:	Requested on:	CC mail	}
hiroyuki kanda/e/ebara jp	2003/12/26		·

Position of the approver	Name of the approver	Deadline of the approval	Status	Date of approval	CC mail
Boss of the inventor	(Approval not necessary)				
Liaison	tsutomu nahada/e/ebara_jp	2004/01/02	Approved	2003/12/26	
General manager	koji mishima/e/ebara_jp	2004/01/02	Approved	2004/01/05	masao hodai/e/ebara_jp kunihito ide/e/ebara_jp hiroyuki kanda/e/ebara_jp seiji katsuoka/e/ebara_jp masaaki kimbara/e/ebara_jp masaji akahori/e/ebara_jp sota nakagawa/e/ebara_jp
Patent Dept. of	seimitsu	2004/01/12	Approved	2004/01/13	
the Group	zzchizai/e/ebara_jp				

General	masamichi	2004/01/20	Received	2004/01/13	
manager of	nakashiba/e/ebara_jp				
Intellectual			·		
Property Dept.					

▼Comment

CN=tsutomu nakada/0U=e/0=ebara_jp Approved 2003/12/26 12:49:20 I approve.

CN=koji mishima /0U=e/0=ebara_jp Approved 2004/01/05 10:26:25 Modify specification and claims to include electrolytic apparatus not only plating tool. The limitation of the seal should be deleted from the first element.

CN=seimitsu zzchizai /0U=e/0=ebara_jp Approved 2004/01/13 09:41:47 Lapprove.

CN=masamichi nakashiba /0U=e/0=ebara_jp Received 2004/01/13 11:38:55

発明部門メニューへ 事業本部特許部メニューへ

社外秘

一時保存したものに追記する場合、または、承認/否認する場合、上部の「編集」リンクをクリックしてください。 発明等届出書

届出日:2003/11/14

知的財産部受付番号:K1040028 受付日:2004/01/19

|依頼元担当一記入欄||▼依頼元上長一記入欄||▼事業本部特許部一記入欄||▼ワークフロー情報

★は必須入力項目です。

▼依頼元担当一記入欄

② 【依頼元情報】

会社★	01 荏原製作所	部門 V350二プロ開発ー		1開発一
整理番号(Doc.No.)		7		
担当者	会社区分+社員番号:0121559	氏名	:神田 裕之	TEL: 7247
本部名★	PP 精密·電子			

②【基本情報】

LOS THE TAX	
国内/外国★	国内
四法★	特許
発明の名称★	基板のめっき装置及びその方法
キーワード	
関連する製品名	
関連する業務コード	その1 その2
研番	L-
研番依頼元	部署名
職務発明について★	1.職務発明である

③ 【荏原製作所/荏原総合研究所/荏原電産の発明者】

	会社	社員番号/氏名 (会社区分+社員番号)	内線NO/ポストNO/E-mail		発明者 の持分 (%)	米国在住	代表発 明者 ★
1	EK0001/ 荏原製作 所		内線NO : 7247 ポストNO : 716−3 E−mail : kanda.hiroyuki@ebara.com	V350ニプロ 開発ー	E .		Check
H- 1	EK0001/ 荏原製作 所		内線NO : 9293 ポストNO : 716−3 E∼mail : kurashina.keiichi@ebara.com	V350ニプロ 開発ー	E		
3	EK0001/ 荏原製作 所	鈴木 秀直	内線NO : 9025 ポストNO : 716−3 E−mail : suzuki.hidenao@ebara.com	V350ニプロ 開発ー	10		
	EK0001/ 荏原製作 所		内線NO:9293 ポストNO:716 E-mail:nagai.mizuki@ebara.com	V350ニプロ 開発ー	E		

		•	•				
	5 EK0001/ 0113010	内線NO:9427 ポストNO:716 E-mail:mishima	.koji@ebara.com	V350二プロ 開発一	P E	<i>:</i>	
	該当無しおよび予定発明者						
						ı	
4	【荏原総合研究所·荏原電産以	し外の関連会社/	性外の発明者】			·	
	会社コード/名称	氏名	TEL/E-mail	所屬	鼠部門また!	注住所 米	国在住
	1		TEL: E-mail:		·		
	該当無しおよび予定発明者					•	
(2)							
S	【出願人】	Nac =r v± ob at 4 s 1*			IIA TULL		- + +
	コード/名称(略称)	住所連絡先など	• .		権利持 分(%)	費用負 担(%)	手続担 当 ★
	1 EK0001 荏原製作所	本社住所: 連絡先住所:〒 部署: 担当: TEL: FAX: E-MAIL:		,	E	E	担当
		JE-MAIL:	•		<u> </u>		
	該当無しおよび予定出願人						
(e)	【出願緩急】 出願緩急	出願希望日	2003/12/12				
	山神典本教心	理由		発表分 発表 F その他	l:		
ا	I ET 64 FR PE			[C 03/II			-1
Ø 	【契約関係】 契約書有無★ 無無		種類				
		<u></u>	その他	•		• •	-
	相手先 1						
	3			•			
	4						
j	5			-			
	その他		*				
	契約書	╡		• .			
	共同出願契約書作 不要		作成担当				
	成★		相手先その他				
		· ·					
, I		•					

調査状況★	未調査	
調査内容	検索式:	
	資料:	
競合メーカー	·	

②【関連出願公知例】

_			
	当社	せの関連出願公知例★	有
		特願2000-285740号 または文献名:	ファイル
	_	号 または文献名:	ファイル
	_	号 または文献名:	ファイル
		号 または文献名:	ファイル
		号 または文献名 :	ファイル

他	せの関連出願公知例★	有		
	特願2000-285740号 または文献名:	ファイル		
	号 または文献名:	ファイル		
	号 または文献名:	ファイル		
4	号 または文献名:	ファイル		- · · · · · · · · · · · · · · · · · · ·
18 -	号 または文献名:	ファイル		

П			
ш		ш	
н	A I	ш	
н	_	ш	
н		ш	

❷ 【特記事項】

特記事項 2000-285740は荏原と東芝の共願であるが、今回の特許は荏原の出願している擦りめっきを加えたものである。今回の出願は荏原単願で行いたいため、2000-285740の位置付けをどうするかご相談したい。

() 【発明等説明書(明細書素案)】

明細書	図面	その他
		特許.ppt
II	添付者:hiroyuki kanda/e 添付日:2003/11/14	a/ebara_jp 添付者: 添付日:

▲依頼元担当一記入欄 依頼元上長一記入欄 ▼事業本部特許部一記入欄 ▼ワークフロー情報

▼依頼元上長一記入欄

② 【発明部門評価】

発明の性質	B:新事業製品・技術の発明						
①先行技術に対する技術的優 (品質向上、コスト削減、省							
②課題・手段の重要性	4. 最重要						
③独創性 (発明の性質がCのときのみ必	0. 未評価						
④本発明が対象とする製品の (開発、販売など) (発明の性質がA又はBのときの							
⑤本発明が製品に占める重要	(割合) 3. やや大きい						
⑥依頼元総合評価	3. 重要						
評価点	42点						
出願要否 要(理日	要(理由:)						
外国出願要否要	要						
特記事項	記事項						

一記入欄 |▲依頼元上長一記入欄 |事業本部特許部一記入欄 |▼ワークフロー情報

事業本部特許部一記入欄

部長記入欄	担当	坂口さん
	コメント	液交換などがシート・補強に該当しないか注意してみてください。含浸体とウェ ハとの間のめっき駅量が増加し、アノート・より高い位置までめっき液が満たされ る場合に、他社特許との関連で問題がないか確認しておいてください。
担当者記入欄	コメント	本願は含浸めっき+擦りめっき+めっき液添加剤濃度可変とする組合わせ特許であって、出願要と判断いたします。
ľ	添付文書	
	作業終了サイン	坂口:終了

▲依頼元担当一記入欄 ▲依頼元上長

▼ワークフロー情報

現在のユーザ: seimitsu zzchizai/e/ebara_jp 現在の承認者:

要求 ID NTNN-5TA4SN

ステータス: 完了



▼ 承認者情報

(5)

申請者名	申請日	CCメール
hiroyuki kanda/e/ebara_jp	2003/11/14	

Ø

	·			·	
承認者役職	承認者名	承認期限	ステー タス	承認日	CCメール
発明者上司	(承認不要)				
リエソン	tsutomu nakada/e/ebara_jp	2003/11/21	承認	2003/12/26	
部長	koji mishima/e/ebara_jp	2004/01/02	承認		masao hodai/e/ebara_jp kunihito ide/e/ebara_jp hiroyuki kanda/e/ebara_jp satoru yamamoto01/e/ebara_jp seiji katsuoka/e/ebara_jp masaaki kimbara/e/ebara_jp masaji akahori/e/ebara_jp sota nakagawa/e/ebara_jp
事業部側特 許部門	seimitsu zzchizai/e/ebara_jp	2004/01/12	承認	2004/01/16	
知的財産部- 部長	masamichi nakashiba/e/ebara_jp	2004/01/23	承認	2004/01/19	

CN=tsutomu nakada/0U=e/0=ebara_jp 承認 2003/12/26 11:51:23 承認します。
CN=koji mishima/0U=e/0=ebara_jp 承認 2004/01/05 10:52:44 第一クレームからシールは除外すること。ウェットコンタクトも網羅するため。
CN=seimitsu zzchizai/0U=e/0=ebara_jp 承認 2004/01/16 19:20:29 承認します。
CN=masamichi nakashiba/0U=e/0=ebara_jp 承認 2004/01/19 08:45:34

To the menu for the dept. of the inventor(s) To the menu for Patent Dept. of the Group

Confidential

To add data to the temporarily saved form or to approve/refuse the form, click the [Edit] link above.

Notification of Invention

Filed on: 2003/11/14

Intellectual Property Dept's receipt No.: K1040028 Date of receipt: 2004/01/19

For the responsible	▼ For the boss of the	▼ For Patent Dept. of	▼ Workflow information
person in the requesting	requesting side	the Group	
side	-		

Never fail to fill ★-marked columns.

▼For the responsible person in the requesting side

1 [Information of the requesting side]

Company name ★	01 Ebara Corporation	Dept.	V350 Development Department 1, Process Development Office 2
Reference No. (Doc.No.)			
Responsible person	Company category - Name: Hiroyuki Kan		
Group name★	PP Precision Machine	ry	

2 [Basic information]

Domestic/foreign ★	Domestic	
IP category ★	Patent	
Title of the invention	Plating appar	atus and method of substrate
Keyword		
Names of related products		
Related job code	No. 1	No. 2
Job No.	L-	
Requesting dept.	Dept. name	
About service invention *	1. Yes	

3 [For inventors in Ebara Corporation/Ebara Research/Ebara Densan Ltd.]

ſ		Compone	L'Employee No /nome	Francis No /sect	Dona	Chana	1 2 2	D
1		Company	Employee No./name	Extension No./post	Dept.	Share of	Living	Representative
-1			(Company category +	No./E-mail address	code/name	the rights	in U.S.	inventor 🖈
ŀ			employee No.)			(%)		
İ	1	EK0001/	0121559	Extension No.: 7247	V350	Ē	ł	Check
-		Ebara	Hiroyuki Kanda	Post No.: 716-3	Developme			
-		Corporation		E-mail:	nt		•	
1			·	kanda.hiroyuki@ebara	Department			
-1		·		.com	1, Process	,	,	
-		-	·		Developme			
-1					nt Office 2			
ſ	2	EK0001/	0121155	Extension No.: 9293	V350	E		
-		Ebara	Keiichi Kurashina	Post No.: 716-3	Developme			
-1		Corporation		E-mail:	nt			
-	l			kurashina.keiichi@eba	Department			
-				ra.com	1. Process	•		
١	ļ				Developme			į
1			1		nt Office 2			
ŀ	3	EK0001/	0107426	Extension No.: 9025	V350	10		
- 1	۲Į	Ebara	Hidenao Suzuki	Post No.: 716-3	Developme	10		
1	- 1	Corporation	riideriao Suzuki	E-mail:	nt			
1	ı	Corporation					,	
1	- 1			Suzuki.hidenao@ebar	Department			
1	- 1	•	·	a.com	1, Process			
1		,		•	Developme			
ŀ	[nt Office 2			
1	4	EK0001/	0120894	Extension No.: 9293	V350	E		
ı	- 1	Ebara	Mizuki Nagai	Post No.: 716	Developme	·	,	*
ı	1	Corporation	·	E-mail:	nt		,	•
1				nagai.mizuki@ebara.c	Department			
	1			om	1, Process	•		
ı	- 1		-		Developme			
١		`			nt Office 2			•

5 N/	EK0001/ Ebara Corporation	n Ko	13010 oji Mishim	a	Extensi Post No E-mail: mishima om).: 716		nt Dep 1, P Dev	relopme partment rocess relopme	E			
			:					1	· · · · · · · · · · · · · · · · · · ·				
4_				other than	Ebara			ra D					
	Company	/ code/	name	Name		TEL	./E-mail		Dept./	contact	addres	s Livir U.S.	
1						TEL E-m							
N/	A and pote	ential in	ventor(s	s)		<u> </u>	iaii.					•	
			-	<u> </u>			· · · · · · · · · · · · · · · · · · ·						
	[Applicant ode/name		Conta	ct address,	oto		Shore o	f the	riabto	Chara	- f th -	Decar	
	bbreviation	1)	Coma	or address,	eic.		Share o	uie	ngnis	costs	of the	Prosection by: ★	ะนนอก
	(0001	··.		uarter addr			È			Е	<u>()</u>	Respo	nsible
Eb	ara Corpo	ration	1	ct address:								person	
	•		Dept.: TEL:	Respons	sible:								
			E-mail:										
N/	A and pote	ential in	ventor(s)									
6	[Urgency o	of applic	cation fil	inal ·									
	gency		Pre	eferred data	a of filing	g	2003/12/	12					
				ason					•	sed to:			
ļ				•		1			Relea	sed on	:		
L		1			-				Other			-	
	[Related co												
Wr	itten contra	act ★			N/A				Туре				
Pa	rtner				1				Othe	r			
					2	 -	-		7				
					3			-					
		•			4	· · · · · ·	.		_				
				160	5 Other		1	-:	: ك		•	•	
Co	ntract			···	Ouici.		- 00					•	
	eparation o			ments for	Not re	quire	ed			ared by			
joir	nt applicati	on filing	, *						Partr	er]
			 		L		•		_1		<u> </u>	ther	
в [Prior-art se	earch]										•	
	or-art sear			Not done			-	· · · · · · · · · · · · · · · · · · ·		•			
Sea	arch detail	s .	•				Search f		la:				
Cal	mpetitor			- ·		. [Material:			·	·		
COI	inpetitor		•	<u> </u>			· · · · · · · · · · · · · · · · · · ·		<u> </u>				
1	Related ap	plication	on and p	rior art]	<u> </u>	4.				·.		٠	
	rs: ★							N/					
1				2000-28574	0			Fi	le	T	•		
2	Or N		ent title				· ·	Fi	lo.				
_	1		nent title	:			٠	1"	ie				
3	N	0.						Fi	le			-	
4	or No		ent title	<u>:</u>		•		<u> </u>	<u> </u>				
<u> </u>			ent title	<u>:</u>		•		Fil	ie.				

	T							
5	No.				F	île		
L	or document	title				<u> </u>		
045				· ·············	1.0			
Others':		 .				/A		
1	Application N			•	F	ile		
-	or document	title	·	· · · · · ·			_	
2	No.				F	ile		
	or document	title:					」 ·	
3	No.					ile		
	or document	title:						
4	No.	4.41			Fi	ile		
	or document	title:					_ .	
5	No.	A:A1			Fi	le		
<u>·</u>	or document	title:				·		
10 (0-00)	-1 T							
10 [Special no		740	is a jaint annlineting	4 🗀		1:1 0		
Special no		174U	is a joint-application of	or Edara a	na io	sniba. Curr	ent application is adding	
	application	nsilli Silli	Eboro Lwant to diag	osing. I w	oula	iike to make	this application a sole	
L	application	11 01	EDAIA. I WANT TO DISCL	iss now to	evai	uate the pos	sition of 2000-285740.	
11 (Descri	ntion of invent	ion (specification draft)]				· .	
Specification		1011	Drawings		Othe	70		
	Il patent.doc		2 step 1 cell patent.c	loc	Oute	=15		
Size: 5683	•		Size: 68608 bites	100			•	
Attached b			Attached by: hiroyuk	i	Δtta	ched by:		
kanda/e/eb			kanda/e/ebara jp	•	Attached on:			
	n: 2003/11/14		Attached on: 2003/1	1/14	, mashed on.			
· ·		,		•,•				
▲ For the r	esponsible		For the boss of the	▼ For P	atent	Dept. of	▼ Workflow information	
person ir			requesting side	the G				
requestir	ng side					,		
	ss of the requ					•		
12 [Evalua	tion by the dep	ot. of	the inventor(s)]					
Nature of the	ne invention					A. Invention	on for Current	
						products/te	echnologies	
(1) Technic	al superiority	over	prior art			3. Conside	erable	
(Quality	/ improvemen	t, cos	st reduction, energy sa	aving, etc.	.)	·		
	of challenge					4. Highest		
			e nature of the invent		·	0. Null		
			on the invention (dev			4. In the in	itial stage	
			ne nature of the invent	tion is A o	r B.)	·		
(5) Importance of the invention to the products						3. Conside		
(6) Overall judgment by the requesting side						3. Importa	nt	
Rating of evaluation						42 points		
Filing of the patent application is:						Required (reason:)	
Foreign filing of the patent application is:						Required		
Special note	9						·	
	esponsible		or the boss of the	For Pat	ent D	ept. of the	▼ Workflow information	
person in		. re	equesting side		Grou			
requestin	requesting side					:]	·	

13 ▼For Patent Dept. of the Group

General	Responsible	Mr. Sakaguchi			
not be related to the seed repair. In the increase and the liquid is filled up higher check if there is any patent issue with p		Please check the draft carefully if the liquid exchange etc. will not be related to the seed repair. In the case of the liquid quantity increase and the liquid is filled up higher than anode, please check if there is any patent issue with patents of other companies.			
Responsible person:	Comment	This application is a combination of impregnation plating + scrub plating + flexible additive concentration of the plating liquid. I consider this filling is necessary.			
•	Attachment				
	Sign of completion	Sakaguchi: Completed			

▲ For the responsible	▲ For the boss of the	▲ For Patent Dept. of	Workflow information
person in the	requesting side	the Group	
requesting side			

▼Workflow information

Current user: kenichi sasabe/e/ebara_jp

Current approver:

Request ID NTNN-5TA4SN

Status: completed

14

Requested by:	Approved by:
hiroyuki kanda/e/ebara_jp	tsutomu nakada/e/ebara_jp koji mishima/e/ebara_jp seimitsu zzchizai/e/ebara_jp masamichi nakashiba/e/ebara_jp

▼Approver information

15

Requested by:	Requested on:	CC mail
hiroyuki kanda/e/ebara_jp	2003/11/14	

***************************************	-, - : - : - :	, , ,			
16					
Position of the	Name of the	Deadline of	Status	Date of	CC mail
approver	approver	the approval		approval	
Boss of the	Approval not				
inventor	necessary	<u></u>	<u> </u>		
Liaison	tsutomu	2003/11/21	Approved	2003/12/26	
	nahada/e/ebara_jp				
General	koji	2004/01/12	Approved	2004/01/05	masao
manager	mishima/e/ebara_jp	200 1,01/12	Approved	200-7,01703	hodai/e/ebara_jp
manager	misimila cycbara_jp	1.			kunihito
•		1.			ide/e/ebara_jp
•					hiroyuki
•			1		kanda/e/ebara_jp
		1			satoru
•			.]		yamamoto/e/ebara_jp
			,		seiji
	,	,	·		katsuoka/e/ebara_jp
		1			masaaki
					kimbara/e/ebara_jp
					masaji
•			1		akahori/e/ebara_jp
•			· ·		sota
			ļ		nakagawa/e/ebara jp
Patent Dept. of	seimitsu	2004/01/12	Approved	2003/01/16	

the Group	zzchizai/e/ebara jp				
General manager of Intellectual Property Dept.	masamichi nakashiba/e/ebara_jp	2004/01/23	Approved	2004/01/19	

▼Comment

CN=tsutomu nakada/0U=e/0=ebara_jp Approved 2003/12/26 11:51:23 I approve.

CN=koji mishima /0U=e/0=ebara_jp Approved 2004/01/05 10:52:44 Delete seal limitation from the first claim so that it covers wet contact.

CN=seimitsu zzchizai /0U=e/0=ebara_jp Approved 2004/01/16 19:20:29 I approve. CN=masaaki miyazaki/0U=e/0=ebara_jp Approved 2004/01/19 08:45:34

This Page is Inserted by IFW Indexing and Scanning Operations and is not part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images include but are not limited to the items checked:

□ BLACK BORDERS
□ IMAGE CUT OFF AT TOP, BOTTOM OR SIDES
□ FADED TEXT OR DRAWING
□ BLURRED OR ILLEGIBLE TEXT OR DRAWING
□ SKEWED/SLANTED IMAGES
□ COLOR OR BLACK AND WHITE PHOTOGRAPHS
□ GRAY SCALE DOCUMENTS
□ LINES OR MARKS ON ORIGINAL DOCUMENT
□ REFERENCE(S) OR EXHIBIT(S) SUBMITTED ARE POOR QUALITY

IMAGES ARE BEST AVAILABLE COPY.

☐ OTHER:

As rescanning these documents will not correct the image problems checked, please do not report these problems to the IFW Image Problem Mailbox.